



Package Diagrams

Data Sheet

FPGA-DS-02053-8.6

January 2026

Disclaimers

Lattice makes no warranty, representation, or guarantee regarding the accuracy of information contained in this document or the suitability of its products for any particular purpose. All information herein is provided AS IS, with all faults, and all associated risk is the responsibility entirely of the Buyer. The information provided herein is for informational purposes only and may contain technical inaccuracies or omissions, and may be otherwise rendered inaccurate for many reasons, and Lattice assumes no obligation to update or otherwise correct or revise this information. Products sold by Lattice have been subject to limited testing and it is the Buyer's responsibility to independently determine the suitability of any products and to test and verify the same. LATTICE PRODUCTS AND SERVICES ARE NOT DESIGNED, MANUFACTURED, OR TESTED FOR USE IN LIFE OR SAFETY CRITICAL SYSTEMS, HAZARDOUS ENVIRONMENTS, OR ANY OTHER ENVIRONMENTS REQUIRING FAIL-SAFE PERFORMANCE, INCLUDING ANY APPLICATION IN WHICH THE FAILURE OF THE PRODUCT OR SERVICE COULD LEAD TO DEATH, PERSONAL INJURY, SEVERE PROPERTY DAMAGE OR ENVIRONMENTAL HARM (COLLECTIVELY, "HIGH-RISK USES"). FURTHER, BUYER MUST TAKE PRUDENT STEPS TO PROTECT AGAINST PRODUCT AND SERVICE FAILURES, INCLUDING PROVIDING APPROPRIATE REDUNDANCIES, FAIL-SAFE FEATURES, AND/OR SHUT-DOWN MECHANISMS. LATTICE EXPRESSLY DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY OF FITNESS OF THE PRODUCTS OR SERVICES FOR HIGH-RISK USES. The information provided in this document is proprietary to Lattice Semiconductor, and Lattice reserves the right to make any changes to the information in this document or to any products at any time without notice.

Contents

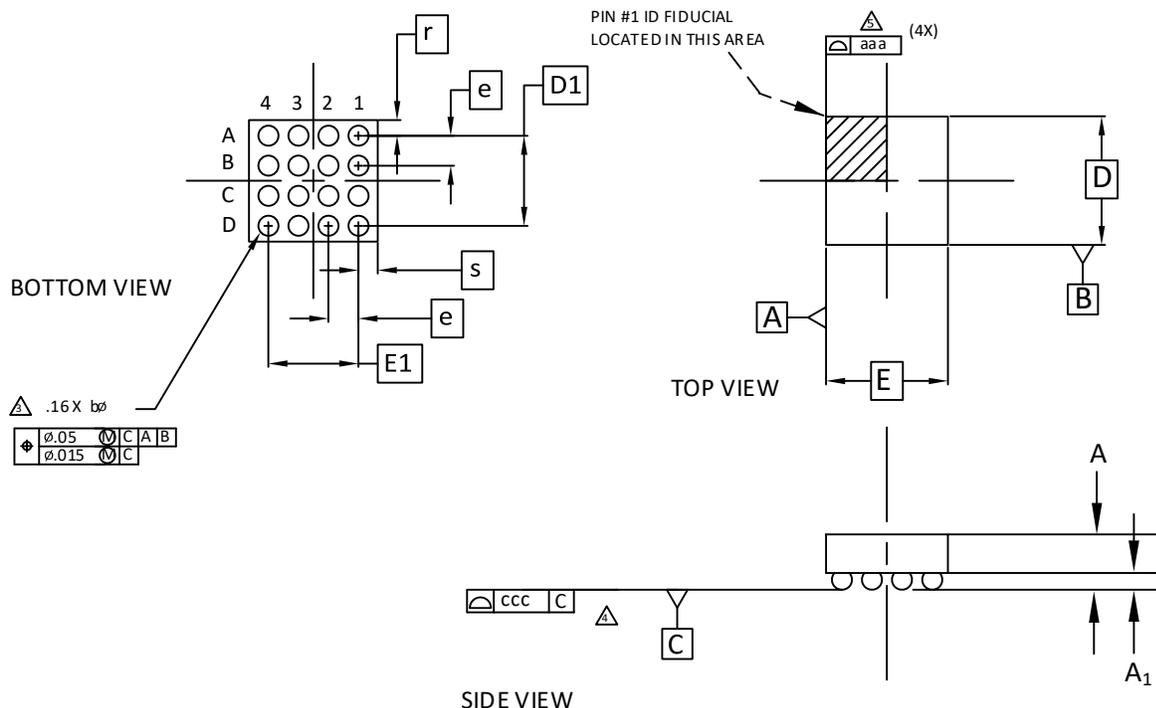
Contents.....	3
1. 16-Ball WLCSP Package Option 1: iCE40™ LP.....	6
2. 16-Ball WLCSP Package Option 2: iCE40 UltraLite™	7
3. 20-Pin (300-Mil) CERDIP Package	8
4. 20-Pin LCC Package.....	9
5. 20-Pin PLCC Package.....	10
6. 20-Pin Plastic DIP Package	11
7. 24-Pin (300-Mil) CERDIP	12
8. 24-Pin Plastic DIP	13
9. 24-Pin QFNS Package	14
10. 25-Ball WLCSP Package (0.40 mm Pitch)	15
11. 25-Ball WLCSP Package (0.35 mm Pitch)	16
12. 28-Pin LCC Package.....	17
13. 28-Pin PLCC Package.....	18
14. 28-Pin Plastic DIP Package	19
15. 28-Pin SSOP Package.....	20
16. 30-Ball WLCSP Package.....	21
17. 32-Pin QFN Package Option 1: Power Manager II, iCE40	22
18. 32-Pin QFN Package Option 2: MachXO2™ 256HC/ZE.....	23
19. 32-Pin QFN Package Option 3: MachXO2 1200HC/ZE	24
20. 36-Ball ucBGA Package	25
21. 36-Ball ucfBGA Package: iCE40 Ultra™	26
22. 36-Ball WLCSP Package Option 1.....	27
23. 36-Ball WLCSP Package Option 2.....	28
24. 36-Ball WLCSP Package Option 3.....	29
25. 44-Pin JLCC Package.....	30
26. 44-Pin PLCC Package.....	31
27. 44-Pin TQFP Package	32
28. 44-Pin LQFP Package.....	33
29. 48-Pin TQFP Package	34
30. 48-Pin LQFP Package.....	35
31. 48-Pin QFN Package: L-ASC10, iCE40 Ultra, iCE40 UltraPlus™, MachXO2	36
32. 49-Ball caBGA Package	37
33. 49-Ball ucBGA Package	38
34. 49-Ball WLCSP Package.....	39
35. 56-Ball csBGA Package.....	40
36. 64-Ball csBGA Package.....	41
37. 64-Pin QFNS Package.....	42
38. 64-Ball ucBGA Package	43
39. 64-Ball ucfBGA Package	44
40. 64-Pin LQFP Package.....	45
41. 68-Pin JLCC Package.....	46
42. 68-Pin PLCC Package.....	47
43. 69-Ball WLCSP Package.....	48
44. 72-Pin QFN Package.....	49
45. 72-Pin QFN Package Option 2: MachXO3D.....	50
46. 72-Pin WLCSP Package.....	51
47. 80-Ball ckfBGA Package	52
48. 80-Ball ctfBGA Package	53
49. 81-Ball csBGA Package.....	54
50. 81-Ball csfBGA Package.....	55

51.	81-Ball ucBGA Package	56
52.	81-Ball WLCSP Package	57
53.	84-Pin CPGA Package	58
54.	84-Pin PLCC Package	59
55.	84-Pin QFN Package	60
56.	84-Ball USG/WLCSP Package (7.492 mm x 3.054 mm Body)	61
57.	84-Ball USG/WLCSP Package (7.275 mm x 3.054 mm Body)	62
58.	84-Ball USG/WLCSP Package Option 1 (7.275 mm x 3.054 mm Body)	63
59.	100-Ball caBGA Package	64
60.	100-Ball csBGA Package	65
61.	100-Ball fpBGA Package	66
62.	100-Pin PQFP Package	67
63.	100-Pin LQFP/TQFP Package Option 1: MachXO3, MachXO2, MachXO™, ispMACH® 4000	68
64.	100-Pin VQFP Package Option 2: iCE40	69
65.	104-Ball CTG/fcCSP Package	70
66.	120-Pin PQFP Package	71
67.	121-Ball caBGA Package (9 mm x 9 mm Body)	72
68.	121-Ball csBGA Package	73
69.	121-Ball csfBGA Package	74
70.	121-Ball ucBGA Package	75
71.	128-Pin PQFP Package	76
72.	128-Pin LQFP Package	77
73.	132-Ball csBGA Package Option 1: MachXO2, MachXO, LatticeXP2™	78
74.	132-Ball csBGA Package Option 2: iCE40	79
75.	132-Ball csBGA Package Option 3	80
76.	132-Ball ucBGA Package	81
77.	133-Pin CPGA Package	82
78.	144-Ball csBGA Package	83
79.	144-Ball fpBGA Package	84
80.	144-Pin LQFP/TQFP Package	85
81.	160-Pin PQFP Package	86
82.	176-Pin LQFP/TQFP Package	87
83.	184-Ball csBGA Package	88
84.	196-Ball caBGA Package	89
85.	196-Ball csBGA Package	90
86.	208-Ball ftBGA Package	91
87.	208-Ball fpBGA Package	92
88.	208-Pin PQFP Package	93
89.	225-Ball ucBGA Package	94
90.	237-Ball ftBGA Package	95
91.	256-Ball ASG256/FOWLP Package	96
92.	256-Ball BBG/caBGA Package Option 1	97
93.	256-Ball BBG/caBGA Package Option 2	98
94.	256-Ball caBGA Package	99
95.	256-Ball csfBGA Package	100
96.	256-Ball CBG256/csfBGA Package	101
97.	256-Ball CBG256/csfBGA Package	102
98.	256-Ball ftBGA Package Option 1: ispMACH 4000, MachXO, LatticeXP2	103
99.	256-Ball ftBGA Package Option 2: LatticeECP3™	104
100.	256-Ball ftBGA Package Option 3: MachXO2	105
101.	256-Ball fpBGA Package	106
102.	256-Ball SBGA Package	107

103. 272-Ball BGA Package	108
104. 284-Ball csBGA Package	109
105. 285-Ball csfBGA Package	110
106. 289-Ball csBGA Package (9.5 mm × 9.5 mm Body)	111
107. 320-Ball SBGA Package	112
108. 324-Ball caBGA Package	113
109. 324-Ball csfBGA Package	114
110. 324-Ball ftBGA Package	115
111. 328-Ball csBGA Package	116
112. 332-Ball caBGA Package	117
113. 352-Ball SBGA Package	118
114. 381-Ball caBGA Package Option 1: All Except LAE5UM-45F	119
115. 381-Ball caBGA Package Option 2: LAE5UM-45F	120
116. 388-Ball BGA Package	121
117. 388-Ball fpBGA Package	122
118. 400-Ball BBG/caBGA Package Option 1	123
119. 400-Ball BBG/caBGA Package Option 2	124
120. 416-Ball fpBGA Package	125
121. 432-Ball SBGA Package	126
122. 484-Ball BBG/caBGA Package Option 1	127
123. 484-Ball BBG/caBGA Package Option 2	128
124. 484-Ball BBG/caBGA Package Option 3	129
125. 484-Ball BFG484/PBGA Package	130
126. 484-Ball fcBGA Package	131
127. 484-Ball fpBGA Package	132
128. 516-Ball fpBGA Package	133
129. 554-Ball caBGA Package	134
130. 672-Ball fpBGA Package	135
131. 672-Ball LFG672/fcBGA Package	136
132. 676-Ball fpBGA Package	137
133. 676-Ball fcBGA Package	138
134. 680-Ball fpBGA Package	139
135. 680-Ball fpSBGA Package	140
136. 756-Ball caBGA Package	141
137. 900-Ball fpBGA Package	142
138. 1020-Ball Organic fcBGA Package	143
139. 1020-Ball Organic fcBGA Package Rev. 2	144
140. 1036-Ball ftSBGA Package	145
141. 1152-Ball Organic fcBGA Package Option 1: LatticeSC™/SCM40	146
142. 1152-Ball Organic fcBGA Package Option 2: LatticeSC/SCM80 and SC/SCM115	147
143. 1152-Ball Ceramic fcBGA Package	148
144. 1152-Ball fpBGA Package	149
145. 1156-Ball fpBGA Package	150
146. 1704-Ball Organic fcBGA Package	151
147. 1704-Ball Ceramic fcBGA Package	152
Appendix A – Package Archive	153
32-Pin QFN (Punch Singulated) Package	153
Technical Support Assistance	154
Revision History	155

1. 16-Ball WLCSP Package Option 1: iCE40™ LP

Dimensions in Millimeters



NOTES:

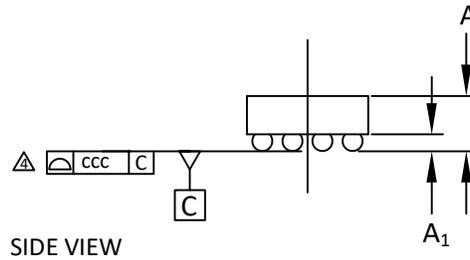
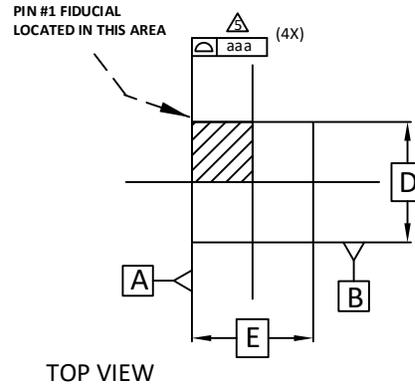
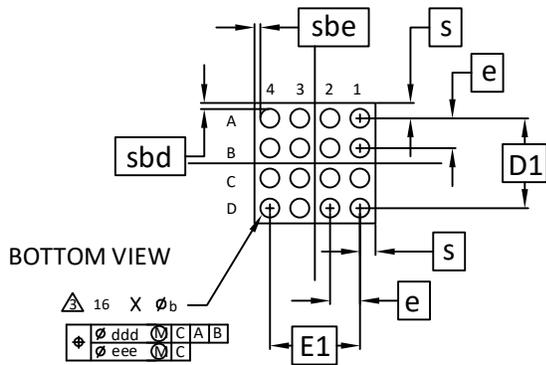
1. ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M - 1994.
2. ALL DIMENSIONS ARE IN MILLIMETERS.

3. DIMENSION "b" IS MEASURES AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM C.
4. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.
5. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

REF.	Min.	Nom.	Max.
A	0.413	0.452	0.491
A1	0.122	0.152	0.182
b	0.188	0.218	0.248
D	1.40 BSC		
E	1.48 BSC		
D1	1.05 BSC		
E1	1.05 BSC		
e	0.35 BSC		
aaa	0.03		
ccc	0.03		
r	-	0.175	-
s	-	0.215	-

2. 16-Ball WLCSP Package Option 2: iCE40 UltraLite™

Dimensions in Millimeters



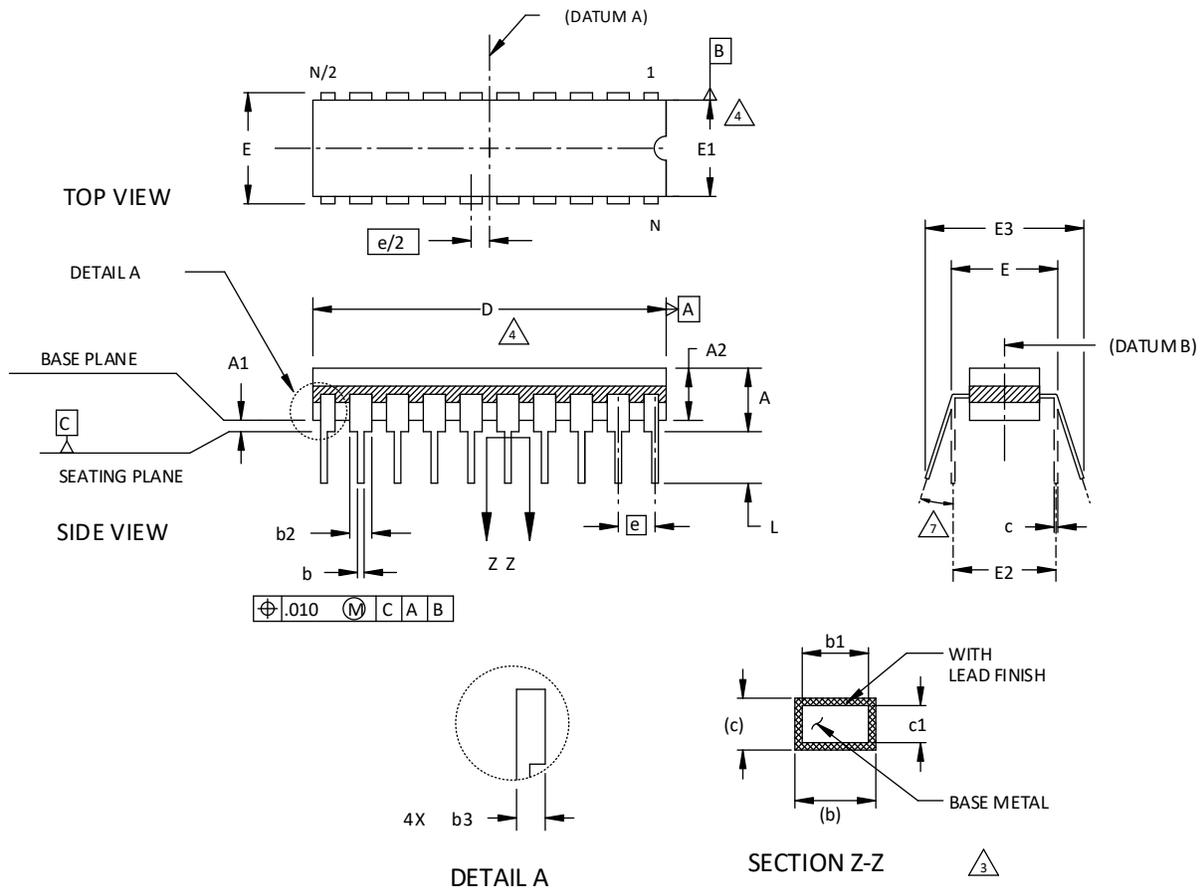
NOTES:

1. ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M - 1994.
 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- DIMENSION "b" IS MEASURES AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM C.
 - PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.
 - BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

REF.	Min.	Nom	Max.
A	0.413	0.452	0.491
A1	0.122	0.152	0.182
b	0.188	0.218	0.248
D	1.409 BSC		
E	1.409 BSC		
D1	1.05 BSC		
E1	1.05 BSC		
e	0.35 BSC		
s	-	0.180	-
sbD	0.067	0.071	0.072
sbE	0.067	0.071	0.072
aaa	0.03		
ccc	0.03		
ddd	0.050		
eee	0.015		

3. 20-Pin (300-Mil) CERDIP Package

Dimensions in Inches



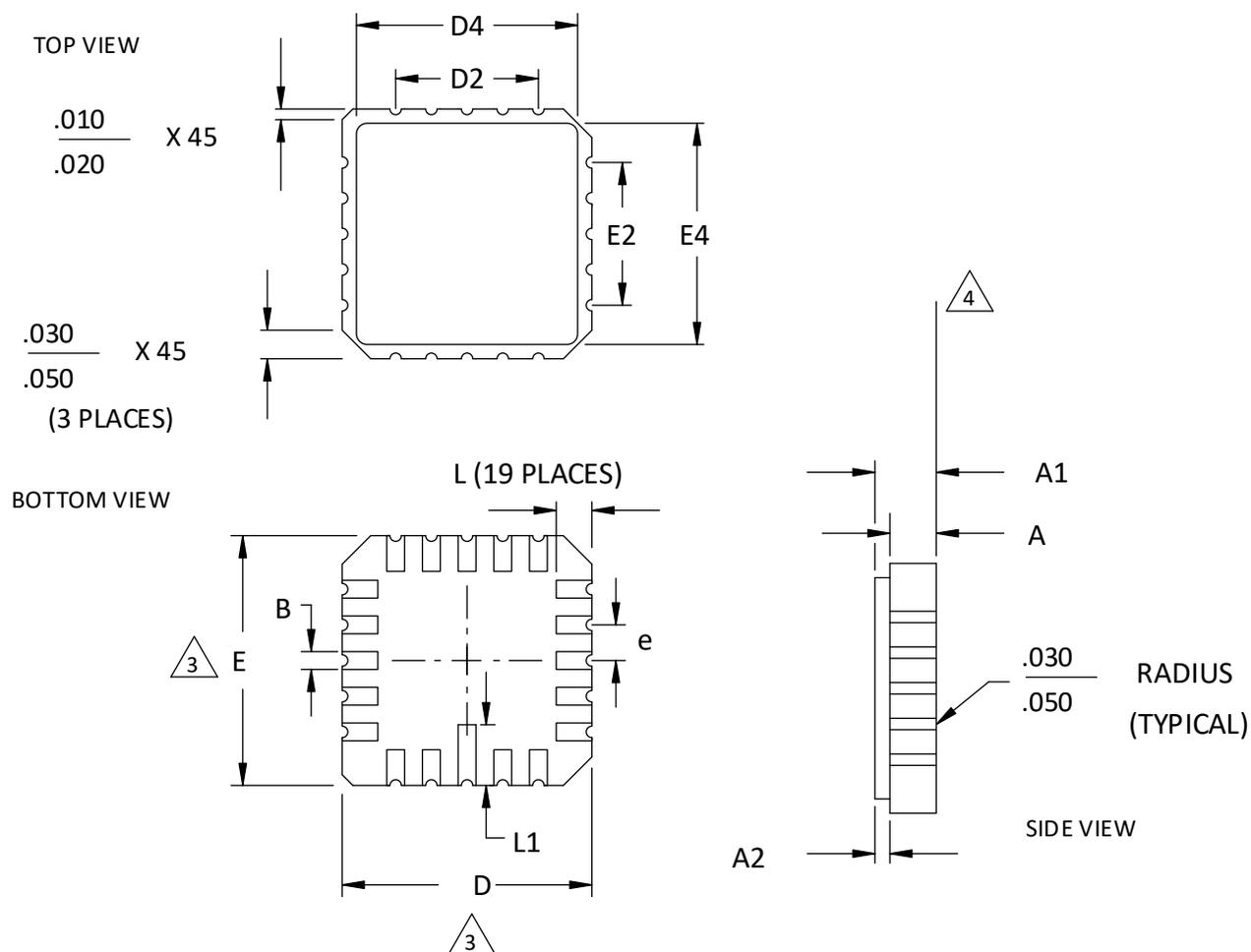
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN INCHES.
3. MEASUREMENTS TO BE TAKEN AT A MINIMUM OF .060 INCHES FROM THE LEAD TIP.
4. DIMENSIONS D AND E1 INCLUDE ALLOWANCE FOR GLASS OVERRUN AND MENISCUS, AND LID TO BASE MISMATCH.
5. DIMENSIONS A, A1 AND L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-003.
6. E3 IS TO BE MEASURED AT THE LEAD TIPS.
7. ALLOWED LEAD TIP POSITION RANGE.

SYMBOL	INCHES		
	MIN.	NOM.	MAX.
A	-	-	.200
A1	.015	-	-
A2	.140	-	.175
b	.015	-	.023
b1	.015	.018	.021
b2	.045	-	.065
b3	.023	-	.045
c	.008	-	.014
c1	.008	.010	.012
D	.942	.950	.970
E	.308	-	.325
E1	.280	.288	.296
E2	.300 REF		
E3	.325	-	.410
e	.100 BSC		
L	.125	-	.200
N	20		

4. 20-Pin LCC Package

Dimensions in Inches



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5.

2. ALL DIMENSIONS ARE IN INCHES.

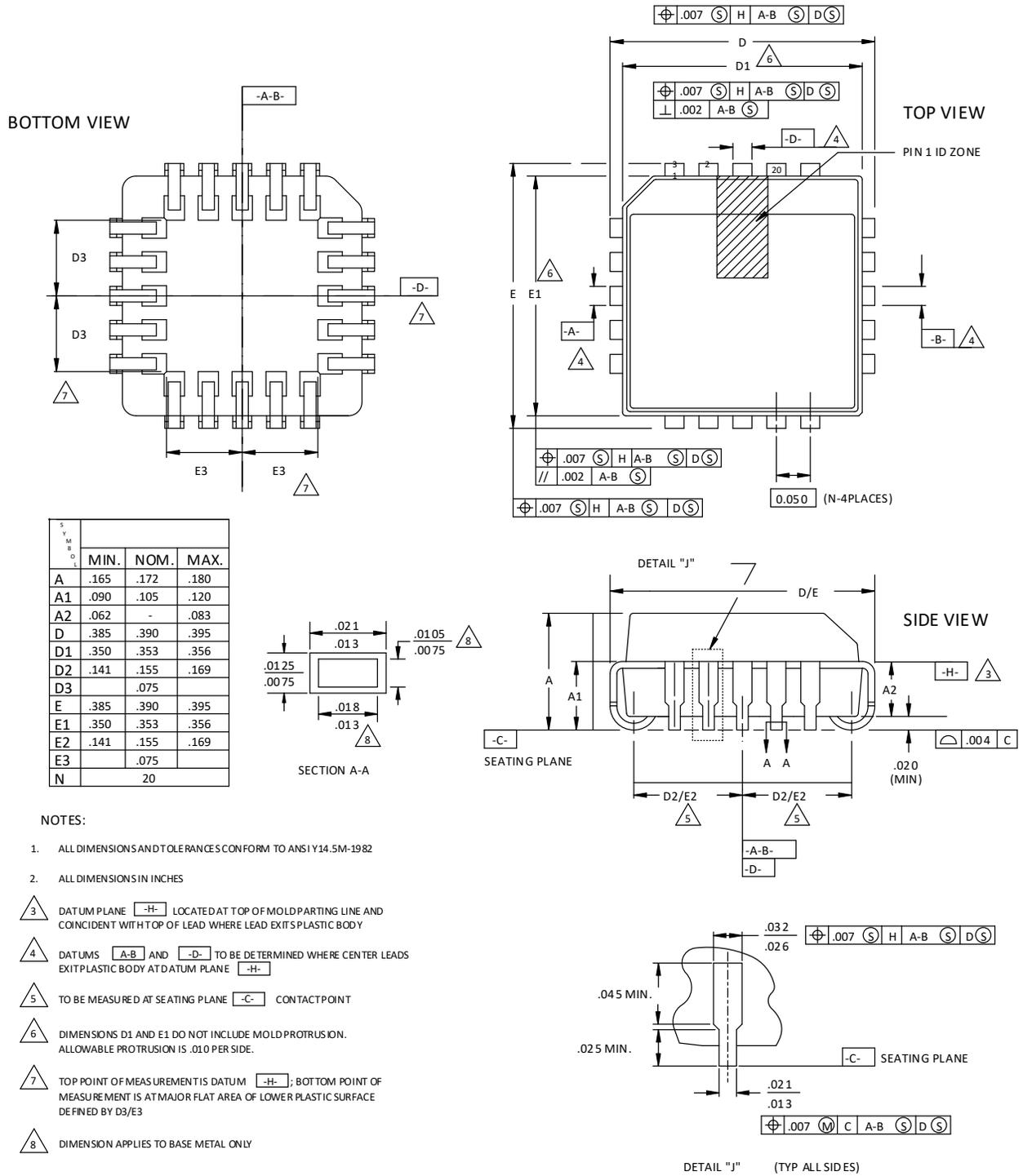
3. DIMENSIONS D AND E MAY HAVE MATERIAL PROTRUSION OF .010 INCHES MAXIMUM ABOVE THE DIMENSION SHOWN NOT TO EXCEED .005 INCHES MAXIMUM PER SIDE.

4. FLATNESS TOLERANCE IS .004 INCHES PER INCH.

SYMBOL	INCHES	
	MIN.	MAX.
A	.054	.074
A1	.064	.089
A2	.007	.015
B	.022	.028
D	.342	.358
D2	.200	
D4	.270	.315
E	.342	.358
E2	.200	
E4	.270	.315
e	.050 BSC	
L	.042	.058
L1	.075	.095

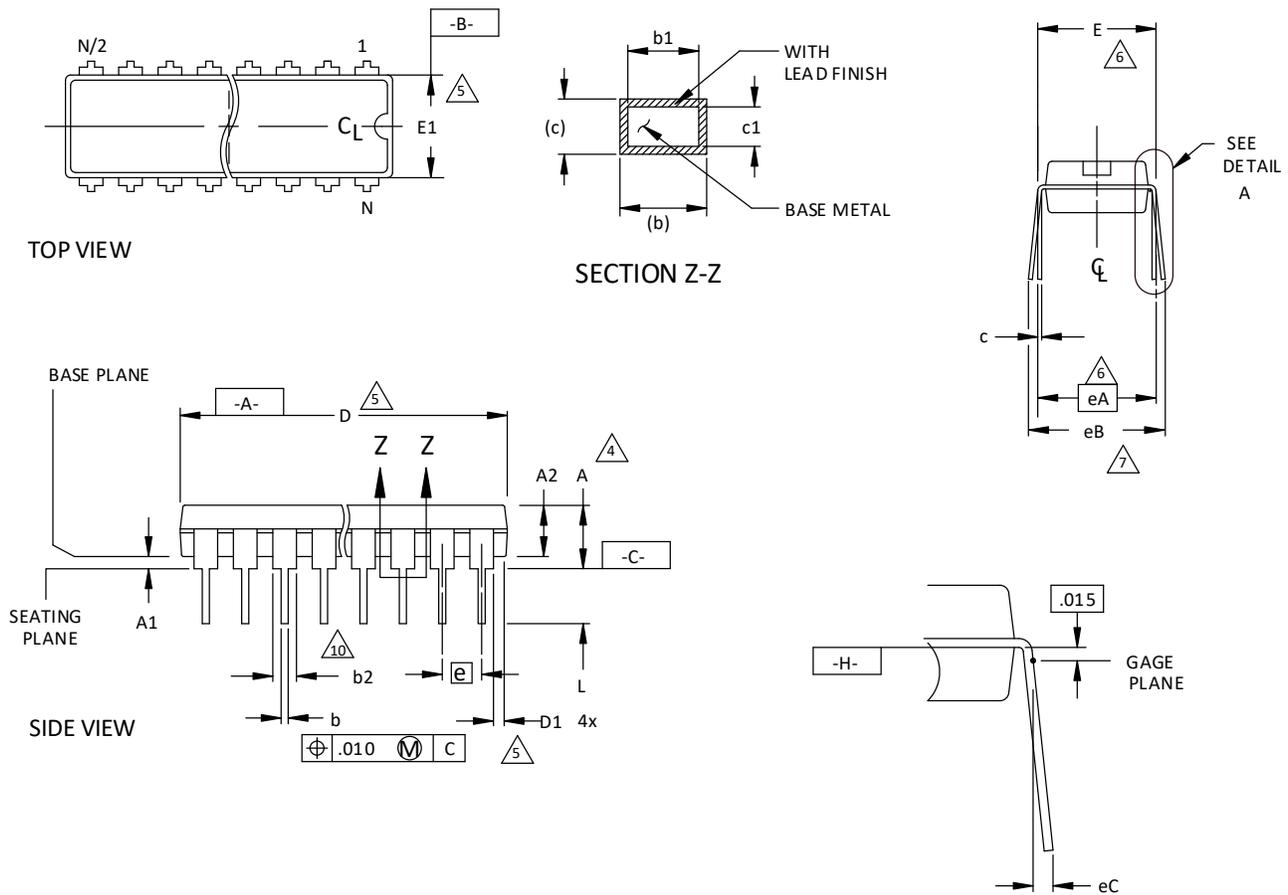
5. 20-Pin PLCC Package

Dimensions in Inches



6. 20-Pin Plastic DIP Package

Dimensions in Inches



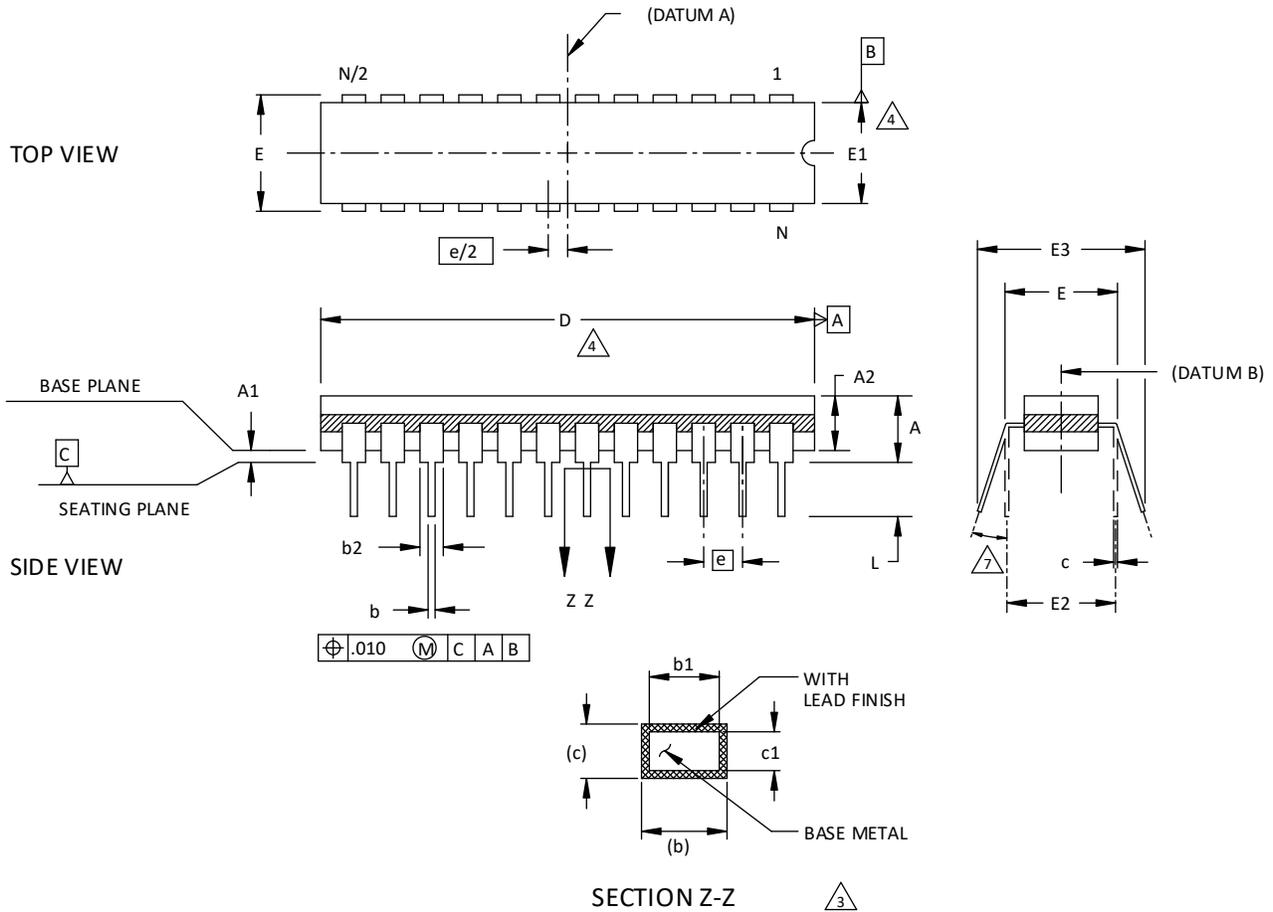
NOTES:

1. CONTROLLING DIMENSION: INCH.
2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M
3. DISTANCE BETWEEN LEADS INCLUDING DAMBAR PROTRUSIONS TO BE .005 MINIMUM.
4. DIMENSIONS A, A1 & L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-3.
5. DIMENSIONS D, D1 AND E1 DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010
6. E AND eA MEASURED WITH THE LEADS CONSTRAINED TO BE PERPENDICULAR TO DATUM C-C
7. eB AND eC ARE MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED.
8. N IS THE MAXIMUM NUMBER OF LEAD POSITIONS.
9. POINTED OR ROUNDED LEAD TIPS ARE PREFERRED TO EASE INSERTION
10. b2 MAXIMUM DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSIONS. DAMBAR PROTRUSIONS SHALL NOT EXCEED .010
11. DATUM PLANE E-H- COINCIDENT WITH THE BOTTOM OF LEAD, WHERE LEAD EXITS BODY

N = 20				
SYMBOL	INCHES			NOTES
	MIN.	NOM.	MAX.	
A	-	-	.210	4
A1	.015	-	-	4
A2	.115	.130	.195	
b	.014	.018	.022	
b1	.014	.018	.020	
b2	.045	.060	.070	10
c	.008	.010	.014	
c1	.008	.010	.011	
D	.980	1.030	1.060	5
D1	.005	-	-	5
E	.300	.310	.325	6
E1	.240	.250	.280	5
e	.100 BSC			
eA	.300 BSC			6
eB	-	-	.430	7
eC	.000	-	.060	7
L	.115	.130	.150	4

7. 24-Pin (300-Mil) CERDIP

Dimensions in Inches



NOTES:

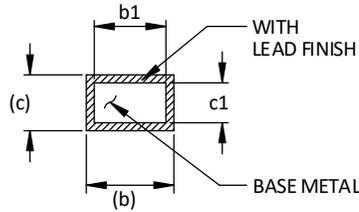
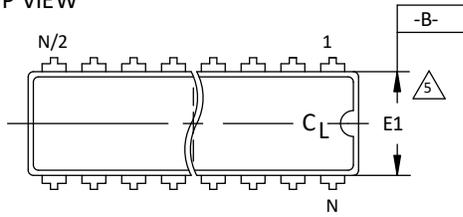
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN INCHES.
3. MEASUREMENTS TO BE TAKEN AT A MINIMUM OF .060 INCHES FROM THE LEAD TIP.
4. DIMENSIONS D AND E1 INCLUDE ALLOWANCE FOR GLASS OVERRUN AND MENISCUS, AND LID TO BASE MISMATCH.
5. DIMENSIONS A, A1 AND L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-003.
6. E3 IS TO BE MEASURED AT THE LEAD TIPS.
7. ALLOWED LEAD TIP POSITION RANGE.

SYMBOL	INCHES		
	MIN.	NOM.	MAX.
A	-	-	.200
A1	.015	-	-
A2	.140	-	.175
b	.015	-	.023
b1	.015	.018	.021
b2	.045	-	.065
c	.008	-	.014
c1	.008	.010	.012
D	1.242	1.250	1.270
E	.308	-	.325
E1	.280	.288	.296
E2	.300 REF		
E3	.325	-	.410
e	.100 BSC		
L	.125	-	.200
N	24		

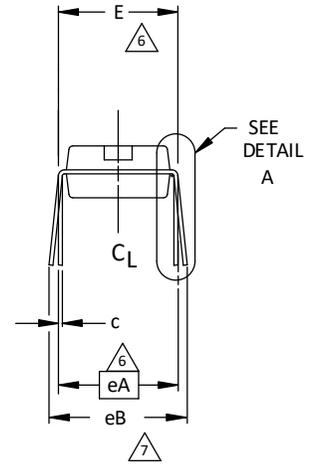
8. 24-Pin Plastic DIP

Dimensions in Inches

TOP VIEW

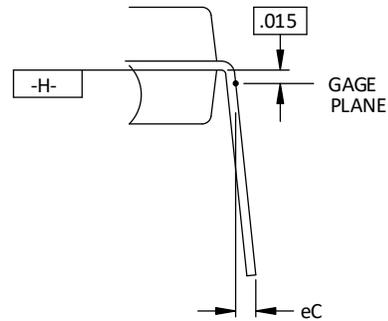
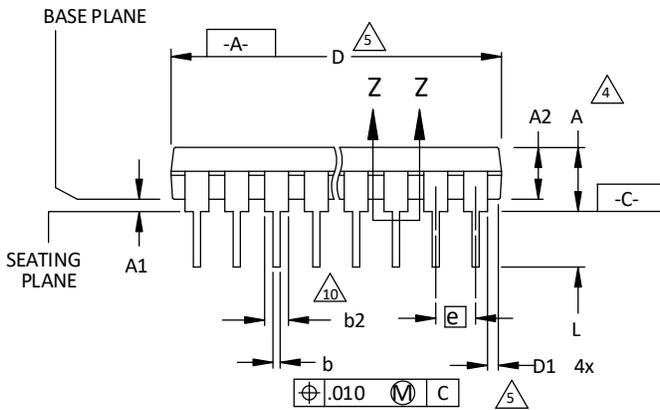


SECTION Z-Z



SEE
DETAIL
A

SIDE VIEW



DETAIL A

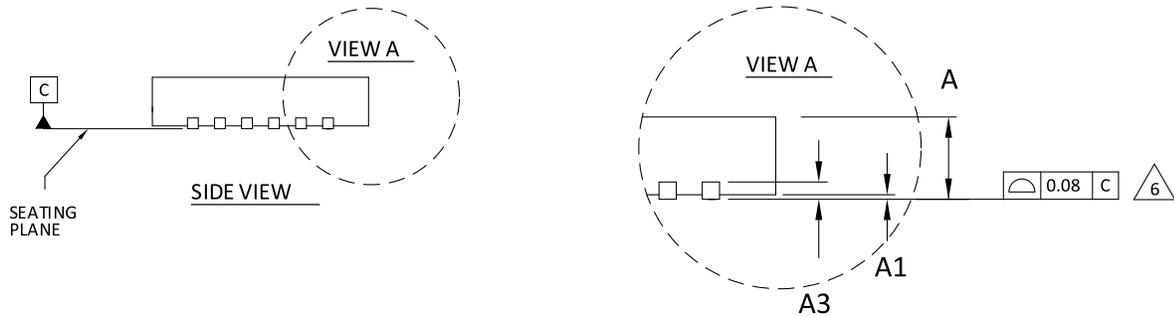
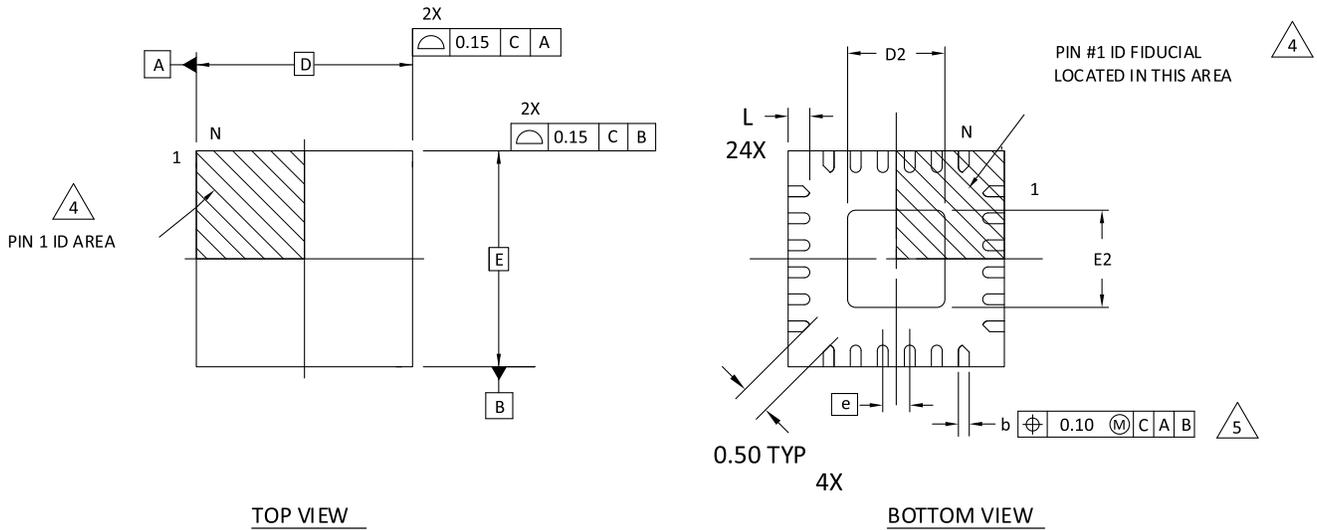
NOTES:

1. CONTROLLING DIMENSION: INCH.
2. DIMENSION IN G AND TOLERANCING PER ANSI Y14.5M
3. DISTANCE BETWEEN LEADS INCLUDING DAMBAR PROTRUSIONS TO BE .005 MINIMUM.
4. DIMENSIONS A, A1 & L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-3.
5. DIMENSIONS D, D1 AND E1 DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010
6. E AND eA MEASURED WITH THE LEADS CONSTRAINED TO BE PERPENDICULAR TO DATUM -C-
7. eB AND eC ARE MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED.
8. N IS THE MAXIMUM NUMBER OF LEAD POSITIONS.
9. POINTED OR ROUNDED LEAD TIPS ARE PREFERRED TO EASE INSERTION
10. b2 MAXIMUM DIMENSIONS DOES NOT INCLUDE DAMBAR PROTRUSIONS. DAMBAR PROTRUSIONS SHALL NOT EXCEED .010
11. DATUM PLANE -H- COINCIDENT WITH THE BOTTOM OF LEAD, WHERE LEAD EXITS BODY

		N = 24			
SYMBOL	INCHES				N _{POS}
		MIN.	NOM.	MAX.	
A	-	-	.210		4
A1	.015	-	-		4
A2	.115	.130	.195		
b	.014	.018	.022		
b1	.014	.018	.020		
b2	.045	.060	.070		10
c	.008	.010	.014		
c1	.008	.010	.011		
D	1.230	1.250	1.280		5
D1	.005	-	-		5
E	.300	.310	.325		6
E1	.240	.250	.280		5
e	.100 BSC				
eA	.300 BSC				6
eB	-	-	.430		7
eC	.000	-	.060		7
L	.115	.130	.150		

9. 24-Pin QFNS Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSIZ14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DRAWING CONFORMS TO JEDEC MO-220, VARIATION VGGD-9.

EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

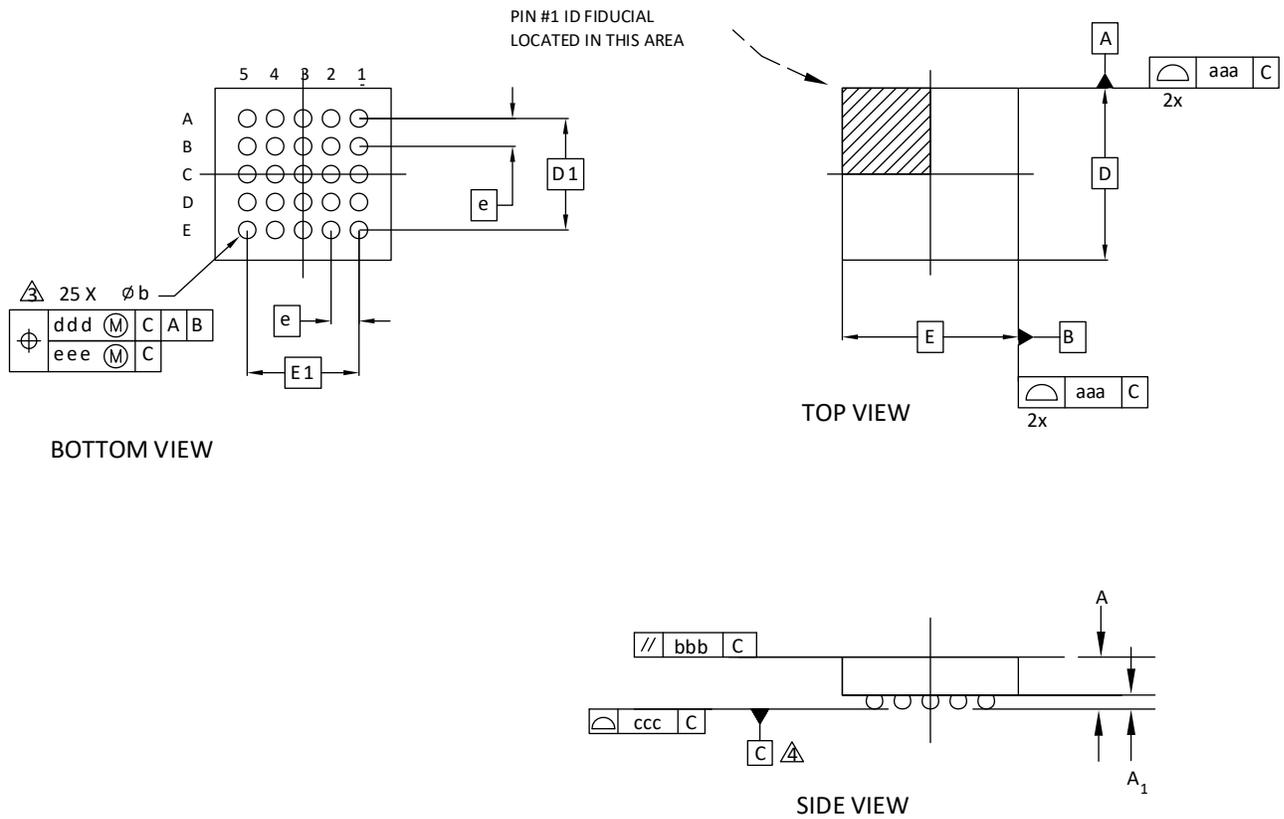
DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.

APPLIES TO EXPOSED PORTION OF TERMINALS.

SYMBOL	MIN.	NOM.	MAX.
A	0.80	0.90	1.00
A1	0.00	0.02	0.05
A3	0.2 REF		
D	4.0 BSC		
D2	1.05	-	2.45
E	4.0 BSC		
E2	1.05	-	2.45
b	0.18	0.25	0.30
e	0.50 BSC		
L	0.45	0.50	0.55

10. 25-Ball WLCSP Package (0.40 mm Pitch)

Dimensions in Millimeters



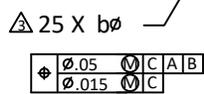
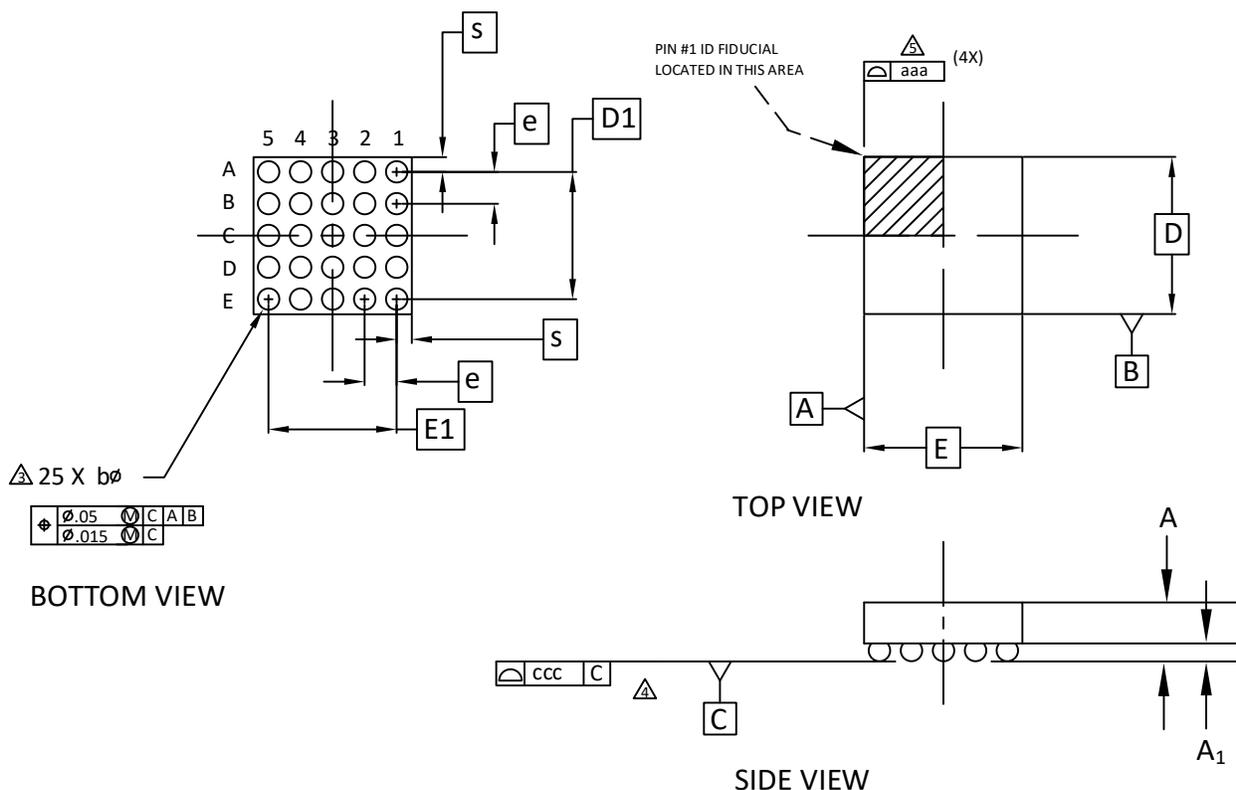
Notes:

- 1 ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M - 1994.
- 2 ALL DIMENSIONS ARE IN MILLIMETERS.
- 3 DIMENSION "b" IS MEASURED AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM C.
- 4 PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.

REF.	Min.	Nom.	Max.
A	0.535	0.575	0.615
A1	0.170	0.200	0.230
b	0.220	0.250	0.280
D	2.492 BSC		
E	2.546 BSC		
D1	1.60 BSC		
E1	1.60 BSC		
e	0.40 BSC		
aaa	0.025		
bbb	0.060		
ccc	0.015		
ddd	0.150		
eee	0.050		

11. 25-Ball WLCSP Package (0.35 mm Pitch)

Dimensions in Millimeters



BOTTOM VIEW

TOP VIEW

SIDE VIEW

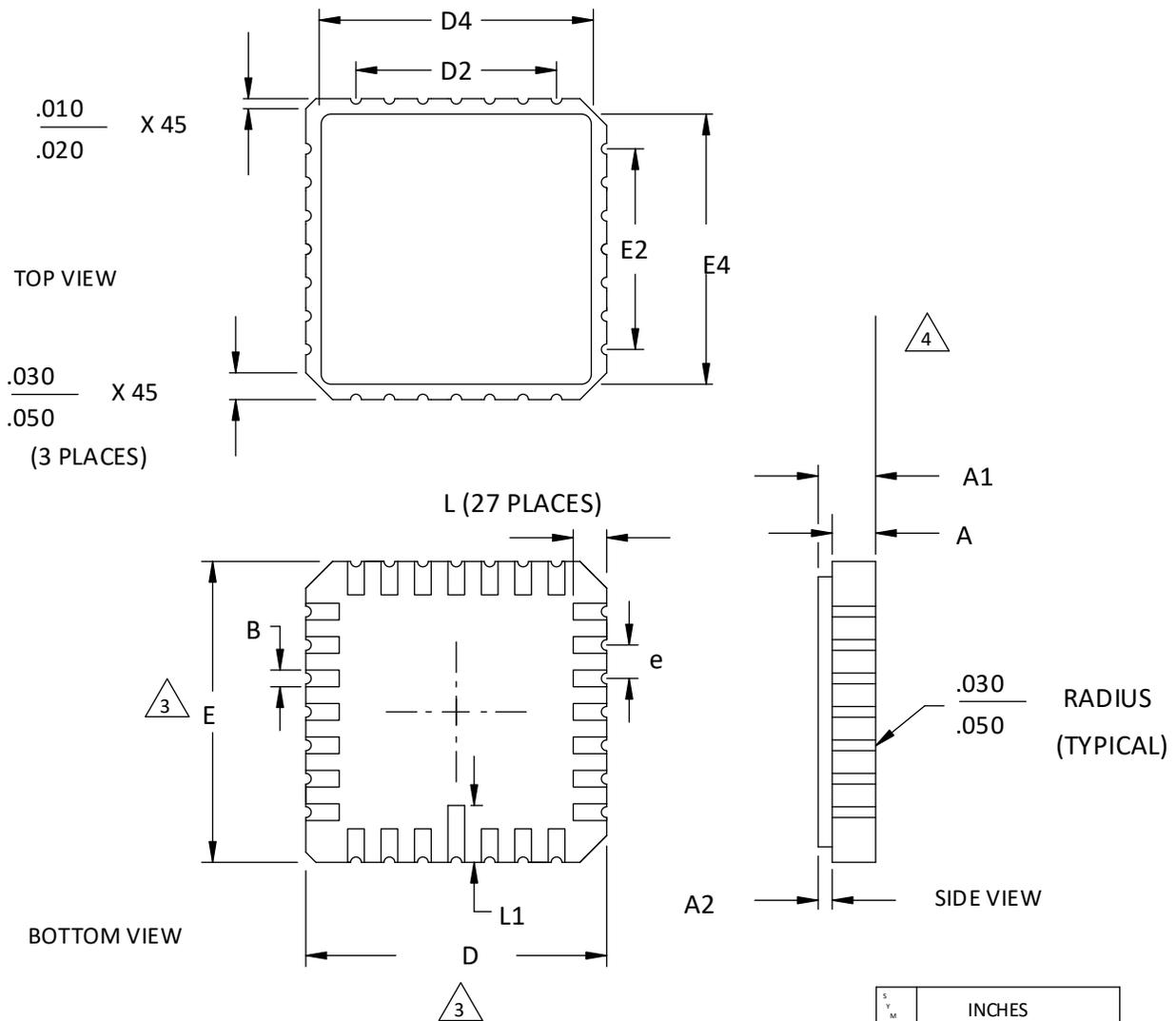
Notes:

- 1 ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M - 1994.
- 2 ALL DIMENSIONS ARE IN MILLIMETERS.
- △ DIMENSION "b" IS MEASURED AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM C.
- △ PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.
- △ BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

REF.	Min.	Nom.	Max.
A	0.413	0.452	0.491
A1	0.122	0.152	0.182
b	0.188	0.218	0.248
D	1.71 BSC		
E	1.71 BSC		
D1	1.40 BSC		
E1	1.40 BSC		
e	0.35 BSC		
aaa	0.03		
ccc	0.03		
s	-	0.015	-

12. 28-Pin LCC Package

Dimensions in Inches



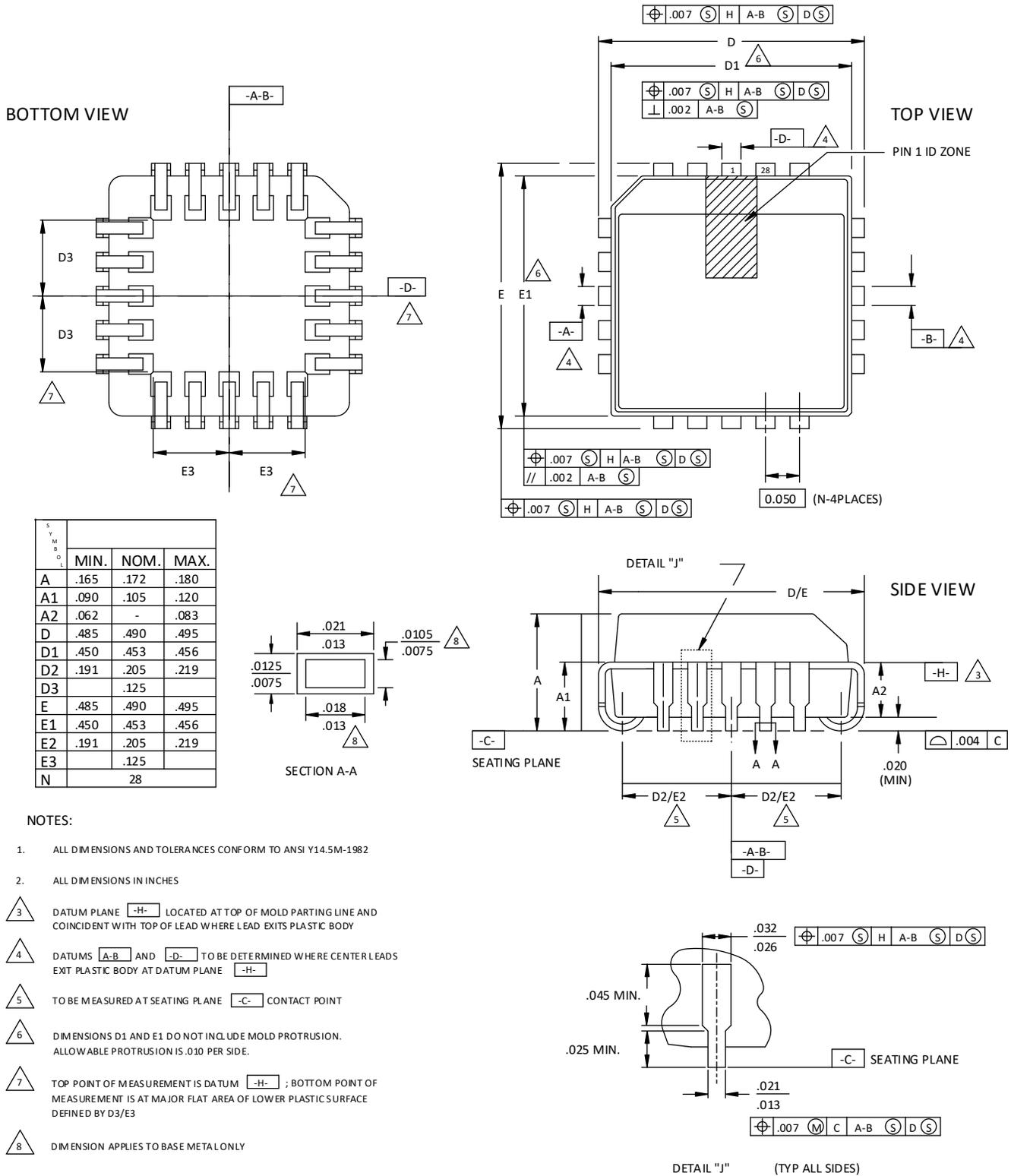
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5.
2. ALL DIMENSIONS ARE IN INCHES.
3. DIMENSIONS D AND E MAY HAVE MATERIAL PROTRUSION OF .010 INCHES MAXIMUM ABOVE THE DIMENSION SHOWN NOT TO EXCEED .005 INCHES MAXIMUM PER SIDE.
4. FLATNESS TOLERANCE IS .004 INCHES PER INCH.

SYMBOL	INCHES	
	MIN.	MAX.
A	.054	.074
A1	.064	.089
A2	.007	.015
B	.022	.028
D	.440	.460
D2	.300	
D4	.370	.403
E	.440	.460
E2	.300	
E4	.370	.403
e	.050 BSC	
L	.042	.058
L1	.075	.095

13. 28-Pin PLCC Package

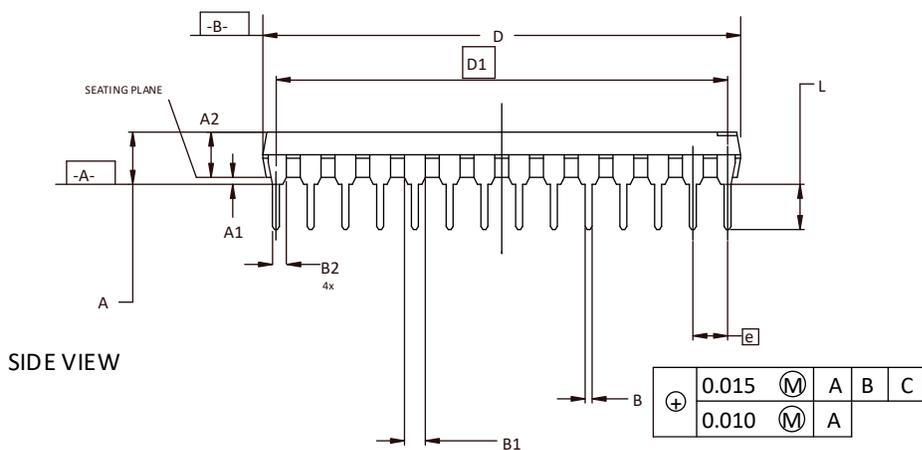
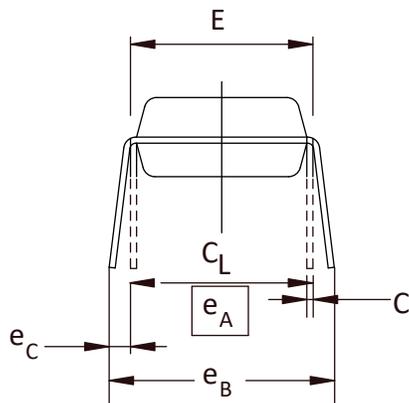
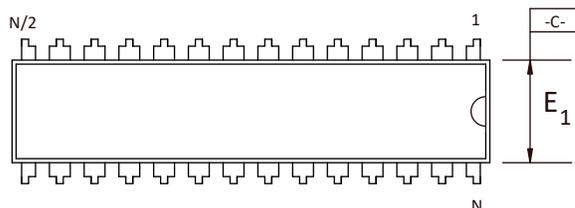
Dimensions in Inches



14. 28-Pin Plastic DIP Package

Dimensions in Inches

TOP VIEW



NOTE:

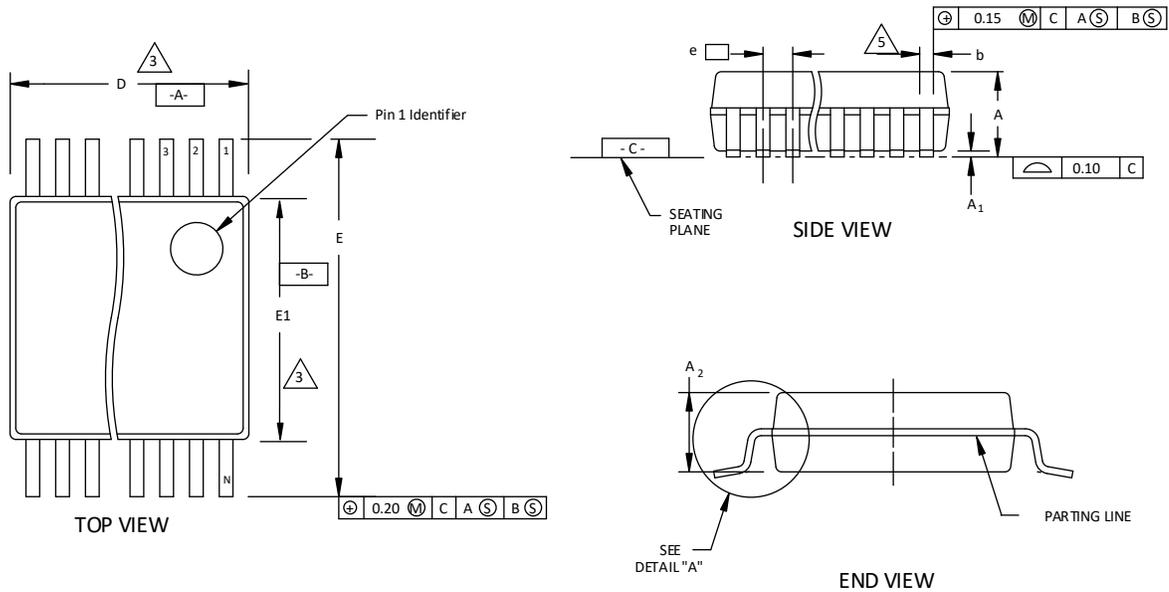
- 1 CONTROLLING DIMENSION: INCHES
- 2 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1982
- 3 ALL END LEADS IN THIS FAMILY ARE 1/2 LEADS
- 4 DIMENSION A, A1, AND L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-3
- 5 D AND E1 DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSION. MOLD FLASH AND PROTRUSION SHALL NOT EXCEED 0.010
- 6 E AND eA MEASURED WITH THE LEADS CONSTRAINED TO BE PERPENDICULAR TO PLANE A
- 7 eB AND eC ARE MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED. eC MUST BE ZERO OR GREATER
- 8 N IS THE NUMBER OF TERMINAL POSITIONS
- 9 B1 AND B2 MAXIMUM DIMENSIONS DO NOT INCLUDE DAMBAR PROTRUSIONS. DAMBAR PROTRUSIONS SHALL NOT EXCEED 0.010

SYMBOL	INCHES		
	MIN.	NOM.	MAX.
A	-	-	.180
A ₁	.015	-	-
A ₂	.120	.135	.150
B	.014	.018	.022
B ₁	.045	.050	.060
B ₂	.030	.040	.045
C	.008	.010	.015
D	1.345	1.365	1.385
D1	1.300 BSC		
E	.300	.310	.325
E ₁	.275	.285	.295
e	.100 BSC		
e _A	.300 BSC		
e _B	-	-	.430
e _C	.000	-	.060
L	.110	.130	.150
N	28		

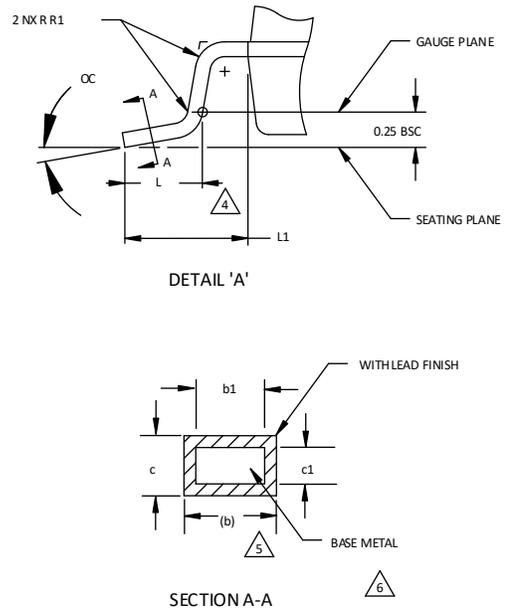
⊕	0.015	(M)	A	B	C
	0.010	(M)	A		

15. 28-Pin SSOP Package

Dimensions in Millimeters



SYMBOL	COMMON DIMENSIONS		
	MIN.	NOM.	MAX.
A	--	--	2.0
A ₁	0.05	--	--
A ₂	1.65	1.75	1.85
b	0.22	-	0.38
b ₁	0.22	0.30	0.33
c	0.09	--	0.25
c ₁	0.09	0.15	0.21
D	9.90	10.20	10.50
E ₁	5.00	5.30	5.60
e	0.65 BSC		
E	7.40	7.80	8.20
L	0.55	0.75	0.95
L ₁	1.25 REF.		
N	28		
OC	0	4	8
R ₁	0.09	--	--



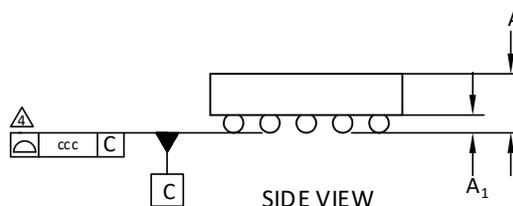
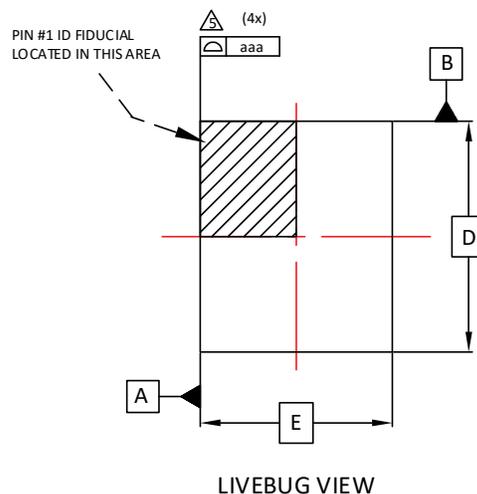
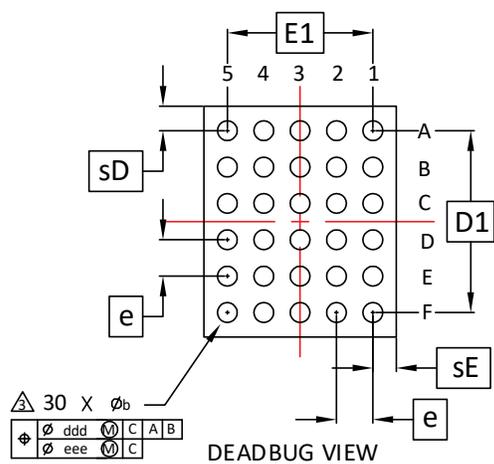
NOTES:

1. CONTROLLING DIMENSION: MILLIMETERS.
2. DIMENSIONING & TOLERANCES PER ANSI.Y14.5M-1982.
3. "D" & "E₁" DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS, BUT DO INCLUDE MOLD MISMATCH AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.20mm PER SIDE.
4. TO BE DETERMINED AT THE SEATING PLANE

5. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION /INTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13mm TOTAL IN EXCESS OF b DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR INTRUSION SHALL NOT REDUCE DIMENSION b BY MORE THAN 0.07mm AT LEAST MATERIAL CONDITION.
6. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 & 0.25mm FROM THE LEAD TIP
7. "N" IS THE NUMBER OF TERMINAL POSITIONS

16. 30-Ball WLCSP Package

Dimensions in Millimeters



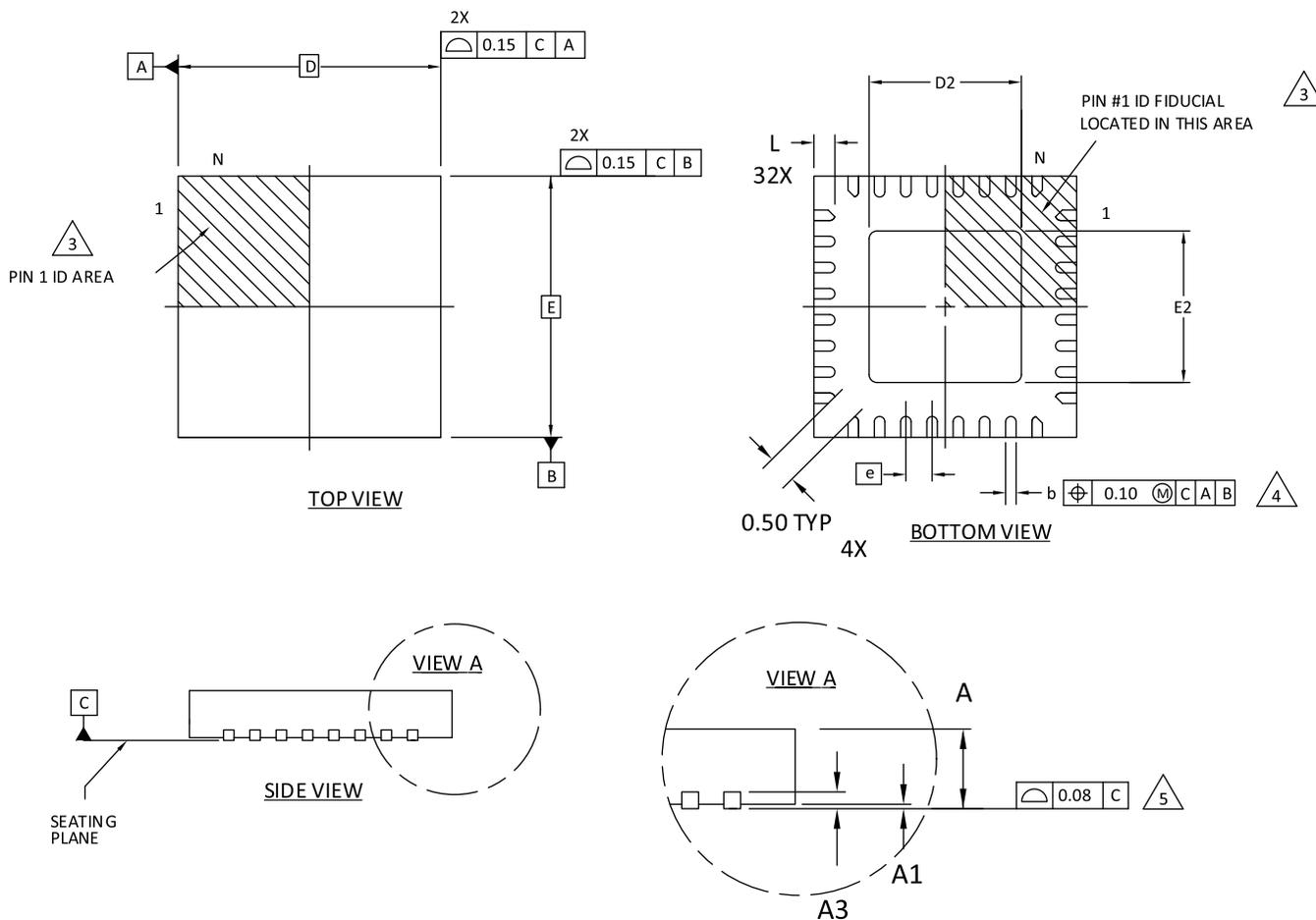
Notes:

1. ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M – 1994.
2. ALL DIMENSIONS ARE IN MILLIMETERS
3. DIMENSION “b” IS MEASURED AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM C.
4. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.
5. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

REF.	Min.	Nom.	Max.
A	–	–	0.600
A1	0.140	–	–
b	0.230	0.260	0.290
D	2.537 BSC		
E	2.114 BSC		
D1	2.00 BSC		
E1	1.60 BSC		
e	0.40		
sD	–	0.27	–
sE	–	0.26	–
aaa	0.030		
ccc	0.050		
ddd	0.015		
eee	0.050		

17. 32-Pin QFN Package Option 1: Power Manager II, iCE40

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.

3. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

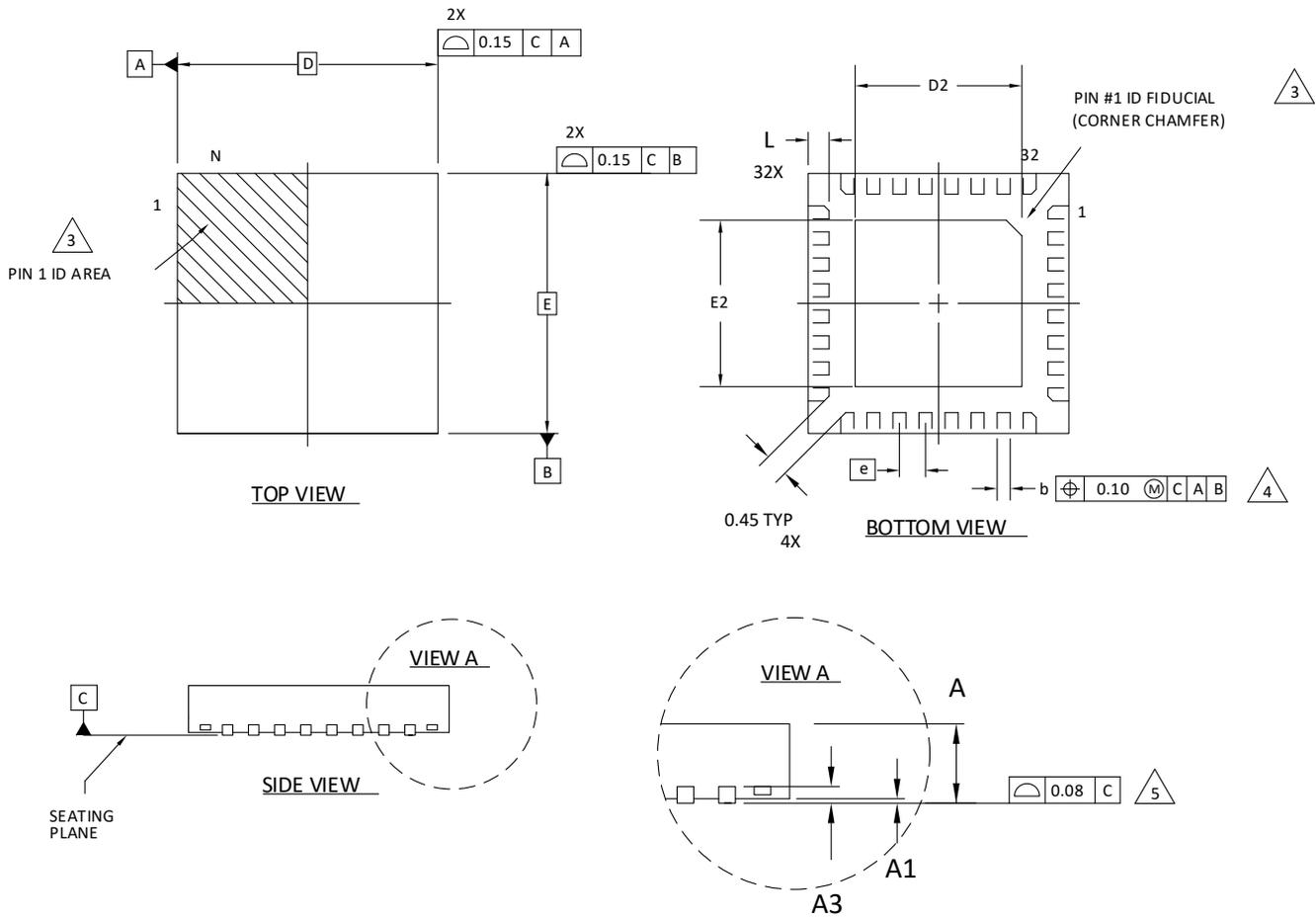
4. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.

5. APPLIES TO EXPOSED PORTION OF TERMINALS.

SYMBOL	MIN.	NOM.	MAX.
A	0.80	0.90	1.00
A1	0.00	0.02	0.05
A3	0.2 REF		
D	5.0 BSC		
D2	1.25	2.70	3.75
E	5.0 BSC		
E2	1.25	2.70	3.75
b	0.18	0.24	0.30
e	0.50 BSC		
L	0.30	0.40	0.50

18. 32-Pin QFN Package Option 2: MachXO2™ 256HC/ZE

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.

 EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

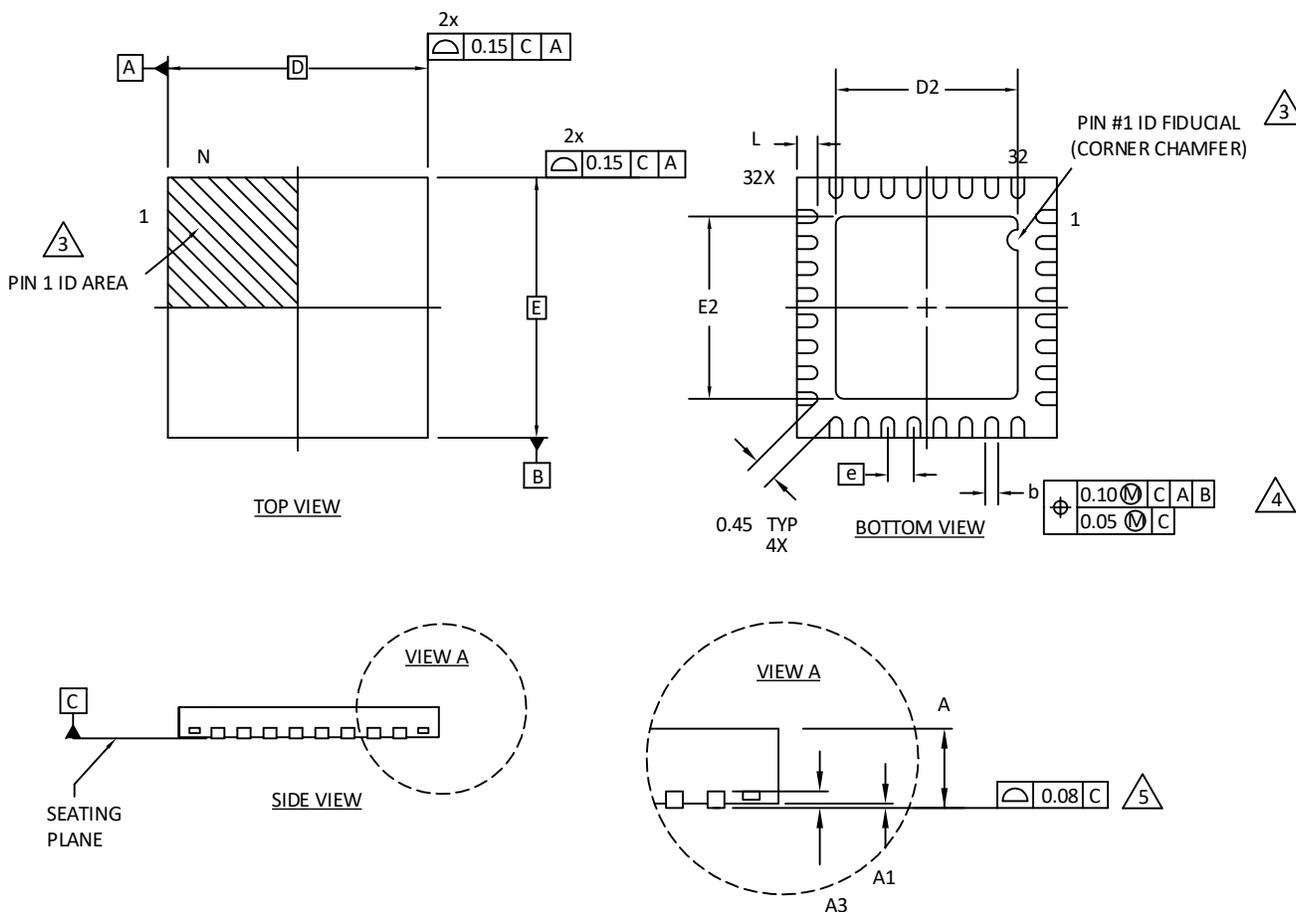
 DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.

 APPLIES TO EXPOSED PORTION OF TERMINALS.

SYMBOL	MIN.	NOM.	MAX.
A	0.50	0.55	0.60
A1	0.00	0.02	0.05
A3	0.2 REF		
D	5.0 BSC		
D2	3.10	3.20	3.30
E	5.0 BSC		
E2	3.10	3.20	3.30
b	0.20	0.25	0.30
e	0.50 BSC		
L	0.35	0.40	0.45

19. 32-Pin QFN Package Option 3: MachXO2 1200HC/ZE

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.

3. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

4. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.

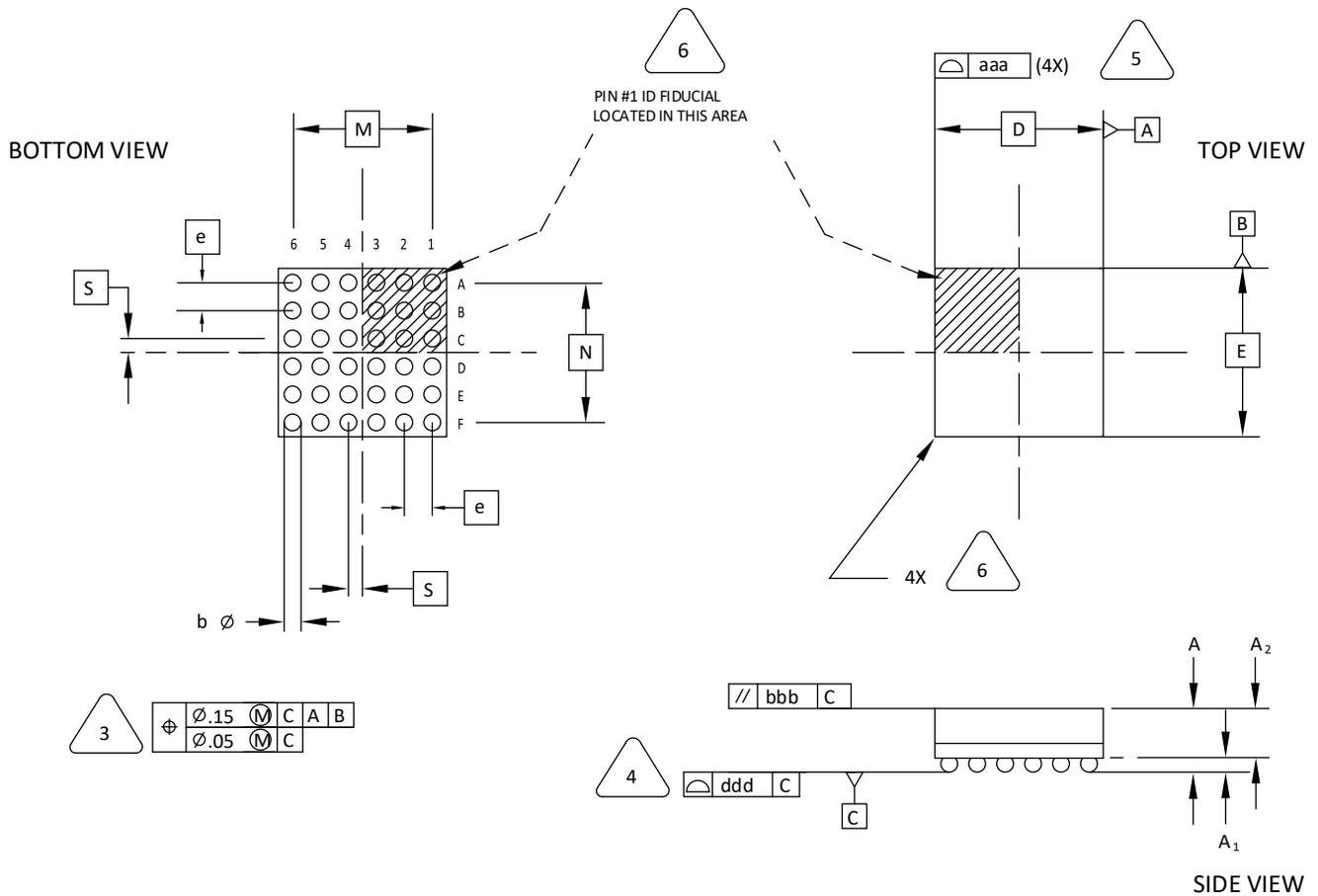
5. APPLIES TO EXPOSED PORTION OF TERMINALS.

6. JEDEC REFERENCE MO-248 AND DR-4.2.

SYMBOL	MIN.	NOM.	MAX.
A	0.50	0.55	0.65
A1	0.00	0.02	0.05
A3	0.02 REF		
D	5.0 BSC		
D2	3.40	3.50	3.60
E	5.0 BSC		
E2	3.40	3.50	3.60
b	0.18	0.25	0.30
e	0.50 BSC		
L	0.35	0.40	0.45

20. 36-Ball ucBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.

3 DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM **C**

4 PRIMARY DATUM **C** AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

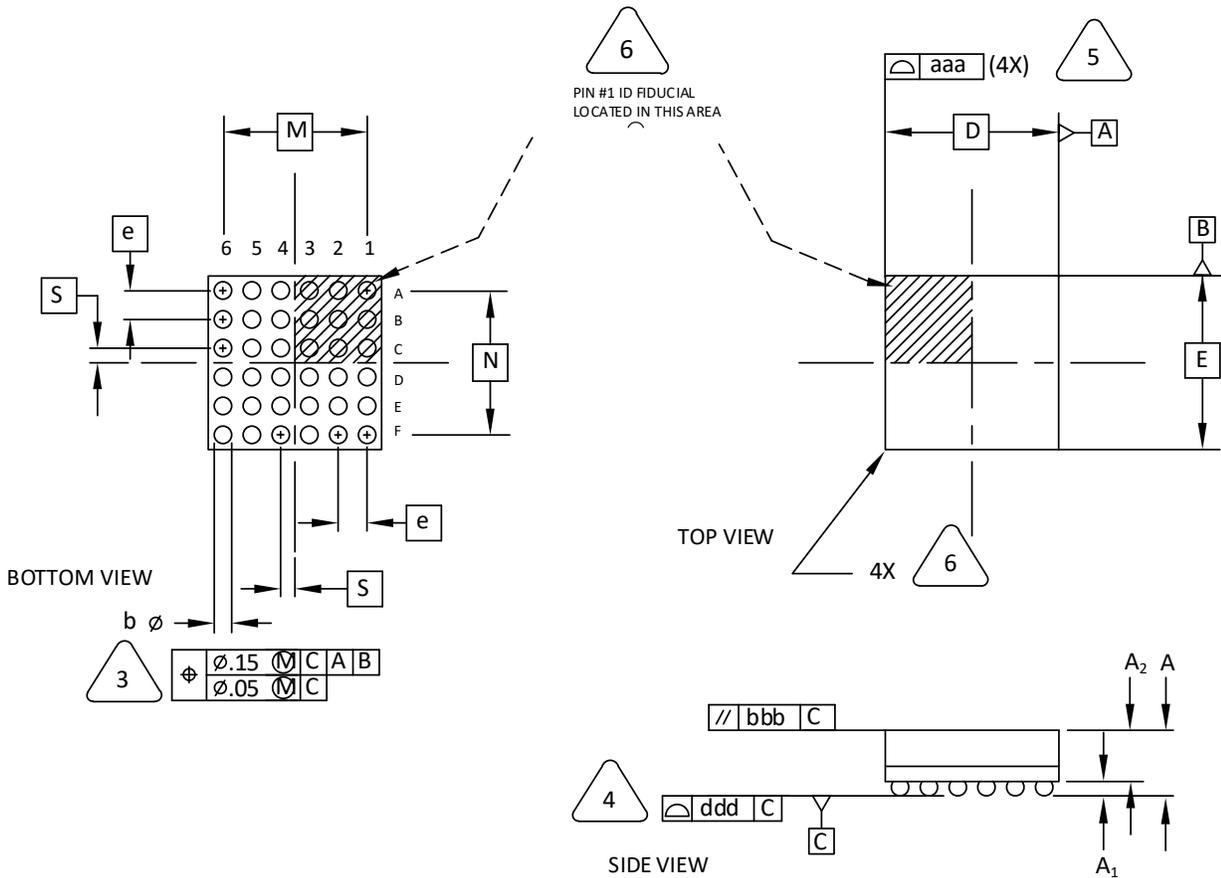
5 BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

6 EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.00
A1	0.10	-	
A2	-	-	0.90
D/E	2.50 BSC		
M/N	2.00 BSC		
S	0.20 BSC		
b	0.20	0.25	0.30
e	0.40 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.10

21. 36-Ball ucbBGA Package: iCE40 Ultra™

Dimensions in Millimeters



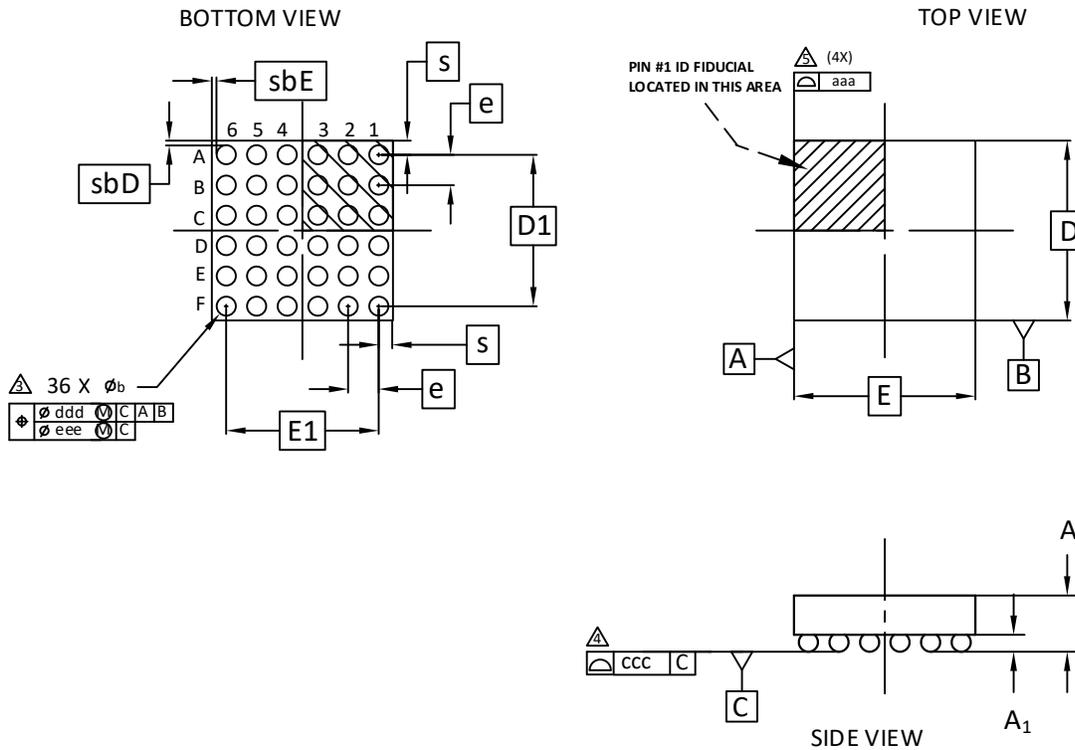
NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
 2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C .
4. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	0.81	0.91
A1	0.12	-	-
A2	-	-	0.70
D/E	2.50 BSC		
M/N	2.00 BSC		
S	0.20 BSC		
b	0.20	0.25	0.30
e	0.40 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.10

22. 36-Ball WLCSP Package Option 1

Dimensions in Millimeters



NOTES:

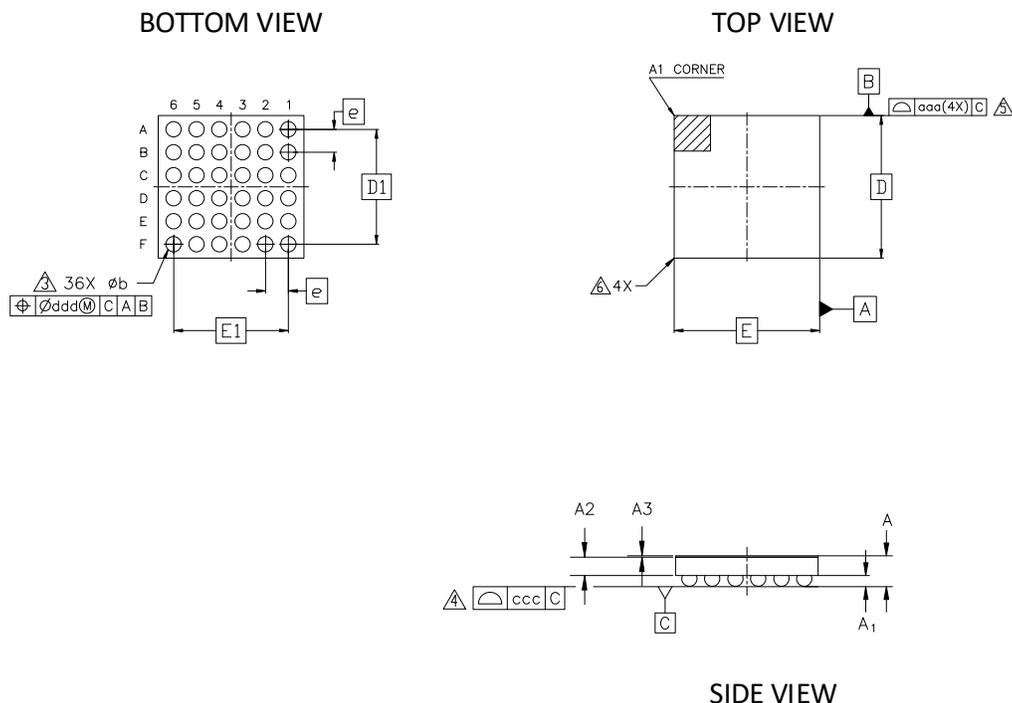
1. ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M - 1994.
 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- △ DIMENSION “b” IS MEASURES AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM [C].
 - △ PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.
 - △ BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

REF.	Min.	Nom.	Max.
A	0.413	0.452	0.491
A1	0.122	0.152	0.182
b	0.188	0.218	0.248
D	2.078 BSC		
E	2.078 BSC		
D1	1.75 BSC		
E1	1.75 BSC		
e	0.35 BSC		
s	0.157	0.164	0.172
sbD	0.051	0.055	0.056
sbE	0.051	0.055	0.056
aaa	0.030		
ccc	0.030		
ddd	0.015		
eee	0.050		

**This Package Outline Drawing and related information apply to iCE40 Ultra devices.*

23. 36-Ball WLCSP Package Option 2

Dimensions in Millimeters



NOTES:

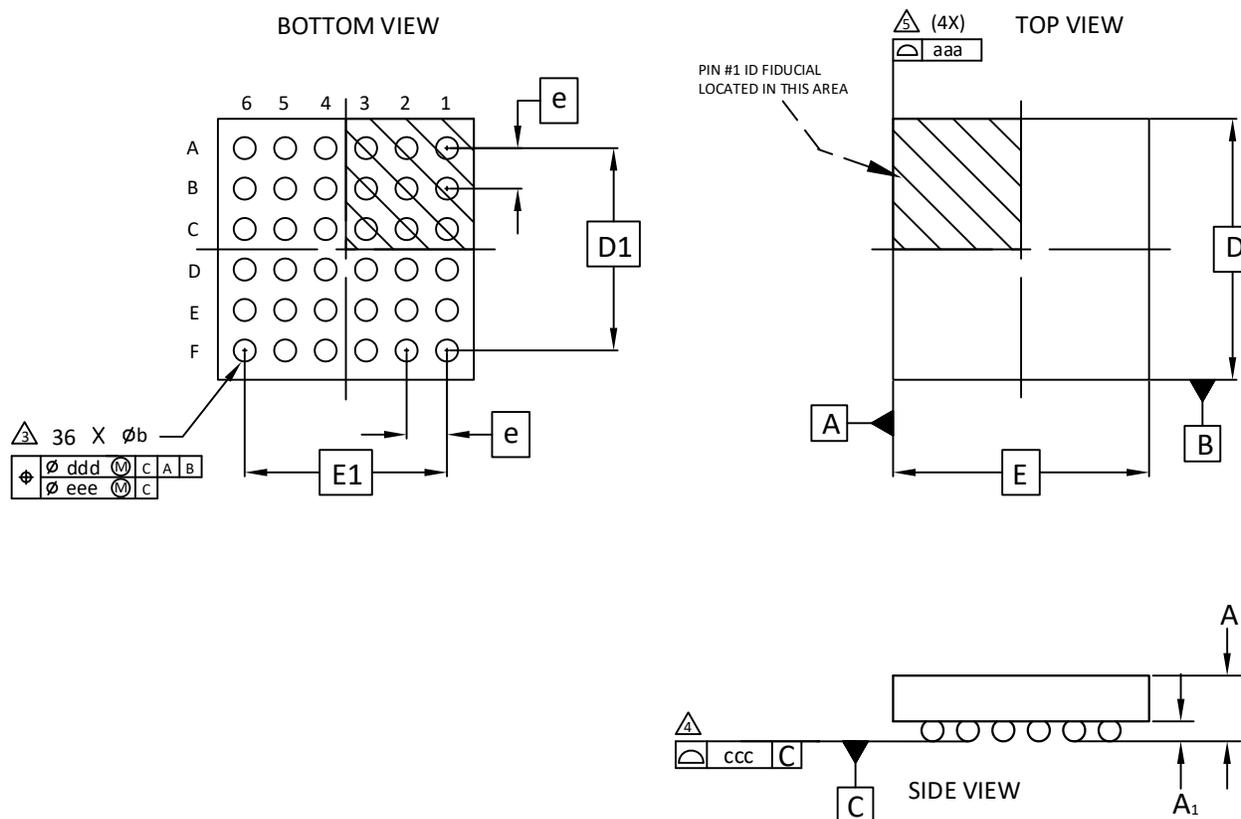
1. ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M - 1994.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DIMENSION “b” IS MEASURED AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM [C].
4. PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.
5. BILLATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
7. JEDEC REFERENCE JEP95 DG 4.18.

SYMBOL	Min.	Nom.	Max.
A	0.502	0.541	0.580
A1	0.164	0.194	0.224
A2	0.322 ±0.025		
A3	0.025		
b	0.200	0.250	0.300
D	2.482 BSC		
E	2.536 BSC		
D1	2.000 BSC		
E1	2.000 BSC		
e	0.40 BSC		
aaa	0.030		
ccc	0.050		
ddd	0.015		

**This Package Outline Drawing and related information apply to MachXO2 and MachXO3™ devices.*

24. 36-Ball WLCSP Package Option 3

Dimensions in Millimeters



NOTES:

- ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M - 1994.
 - ALL DIMENSIONS ARE IN MILLIMETERS.
- \triangle DIMENSION "b" IS MEASURES AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM [C].
 - \triangle PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.
 - \triangle BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

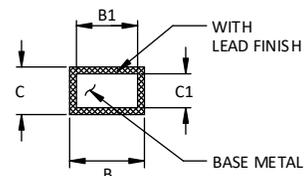
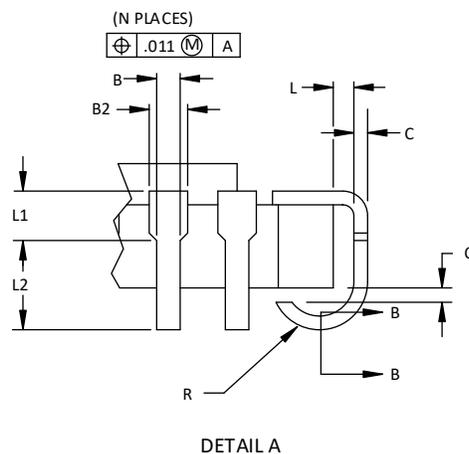
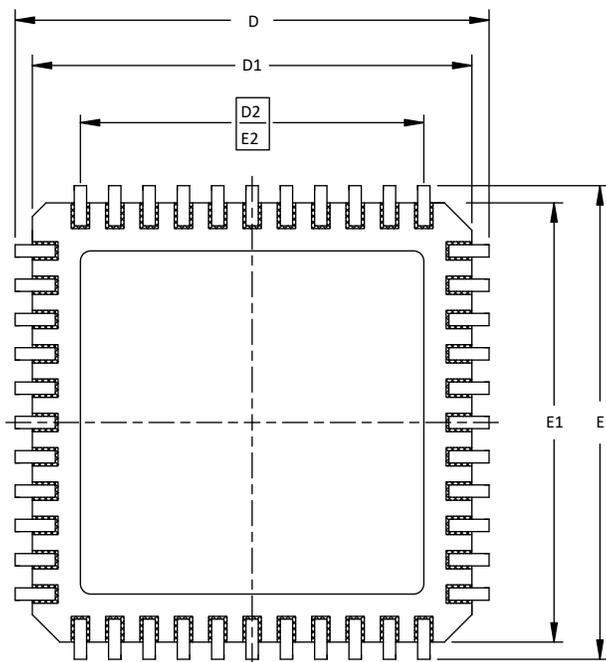
REF.	Min.	Nom.	Max.
A	-	-	0.600
A1	0.113	-	-
b	0.188	0.218	0.248
D	2.535 BSC		
E	2.583 BSC		
D1	2.00 BSC		
E1	2.00 BSC		
e	0.40 BSC		
aaa	0.030		
ccc	0.050		
ddd	0.050		
eee	0.015		

**This Package Outline Drawing and related information apply to CrossLink™ devices.*

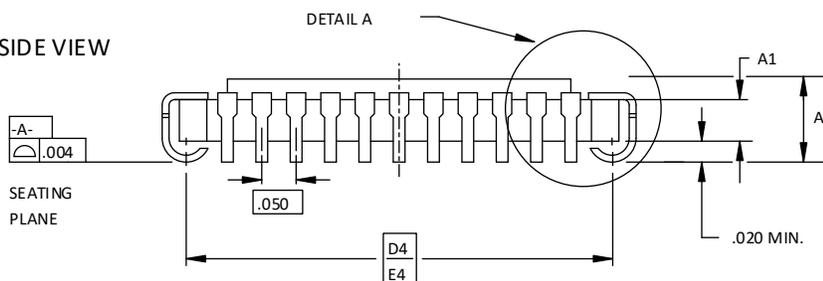
25. 44-Pin JLCC Package

Dimensions in Inches

BOTTOM VIEW



SIDE VIEW



-A-
SEATING PLANE
.004

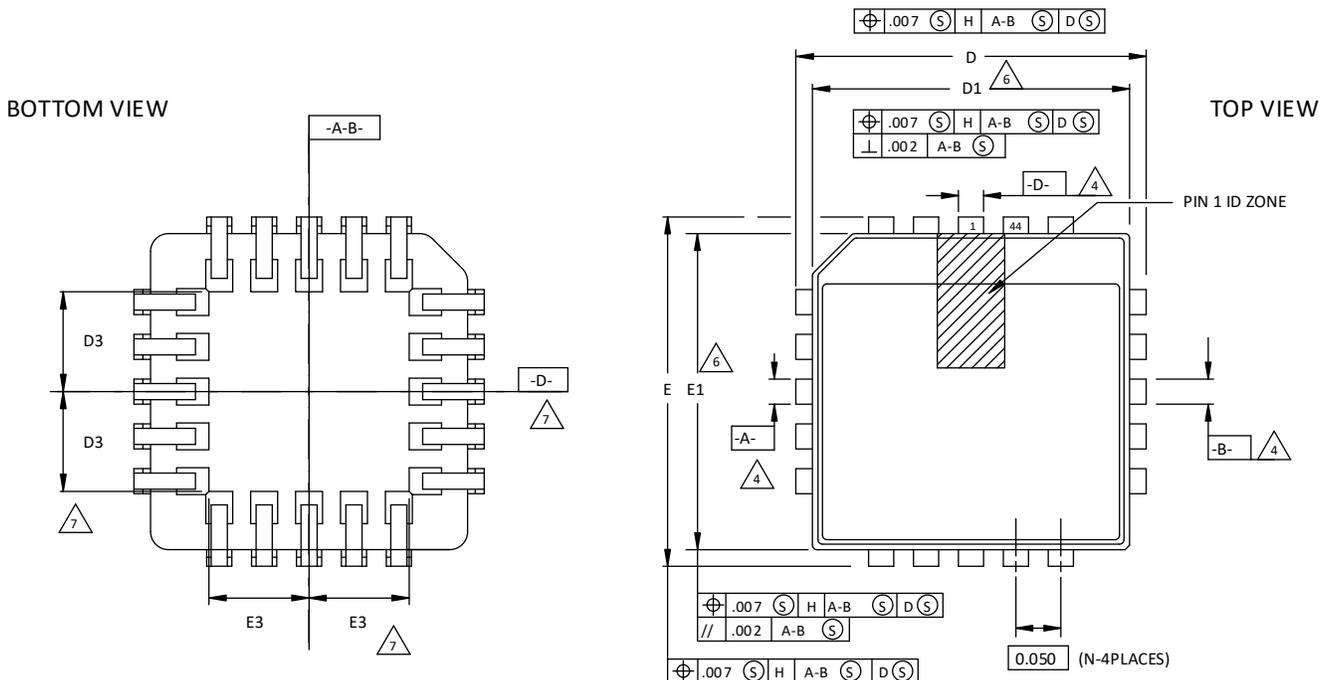
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN INCHES.
3. CORNER CHAMFERS AND/OR NOTCHES ARE OPTIONAL.

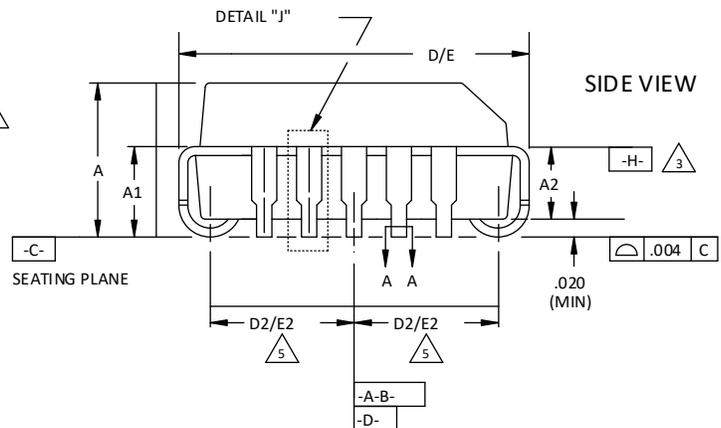
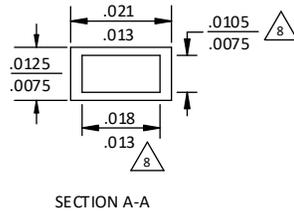
SYMBOL	INCHES		
	MIN.		MAX.
A	.115	-	.190
A1	.065 REF		
B	.013	-	.023
B1	.013	-	.020
B2	.022	-	.035
C	.007	-	.013
C1	.007	-	.010
D/E	.675	.690	.700
D1/E1	.620	-	.660
D2/E2	.500 BSC		
D4/E4	.630 BSC		
L	.005	-	-
L1	.020	-	-
L2	.025	-	-
Q	.003	-	-
R	.020	-	.040
N	44		

26. 44-Pin PLCC Package

Dimensions in Inches



SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	.165	.172	.180
A1	.090	.105	.120
A2	.062	-	.083
D	.685	.690	.695
D1	.650	.653	.656
D2	.291	.305	.319
D3		.225	
E	.685	.690	.695
E1	.650	.653	.656
E2	.291	.305	.319
E3		.225	
N	44		



NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1982

2. ALL DIMENSIONS IN INCHES

3. DATUM PLANE **-H-** LOCATED AT TOP OF MOLD PARTING LINE AND COINCIDENT WITH TOP OF LEAD WHERE LEAD EXITS PLASTIC BODY

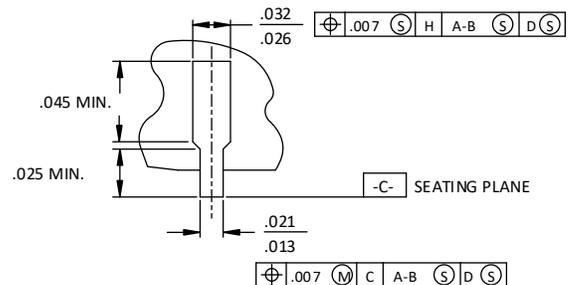
4. DATUMS **-A-B** AND **-D-** TO BE DETERMINED WHERE CENTER LEADS EXIT PLASTIC BODY AT DATUM PLANE **-H-**

5. TO BE MEASURED AT SEATING PLANE **-C-** CONTACT POINT

6. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS .010 PER SIDE.

7. TOP POINT OF MEASUREMENT IS DATUM **-H-**; BOTTOM POINT OF MEASUREMENT IS AT MAJOR FLAT AREA OF LOWER PLASTIC SURFACE DEFINED BY D3/E3

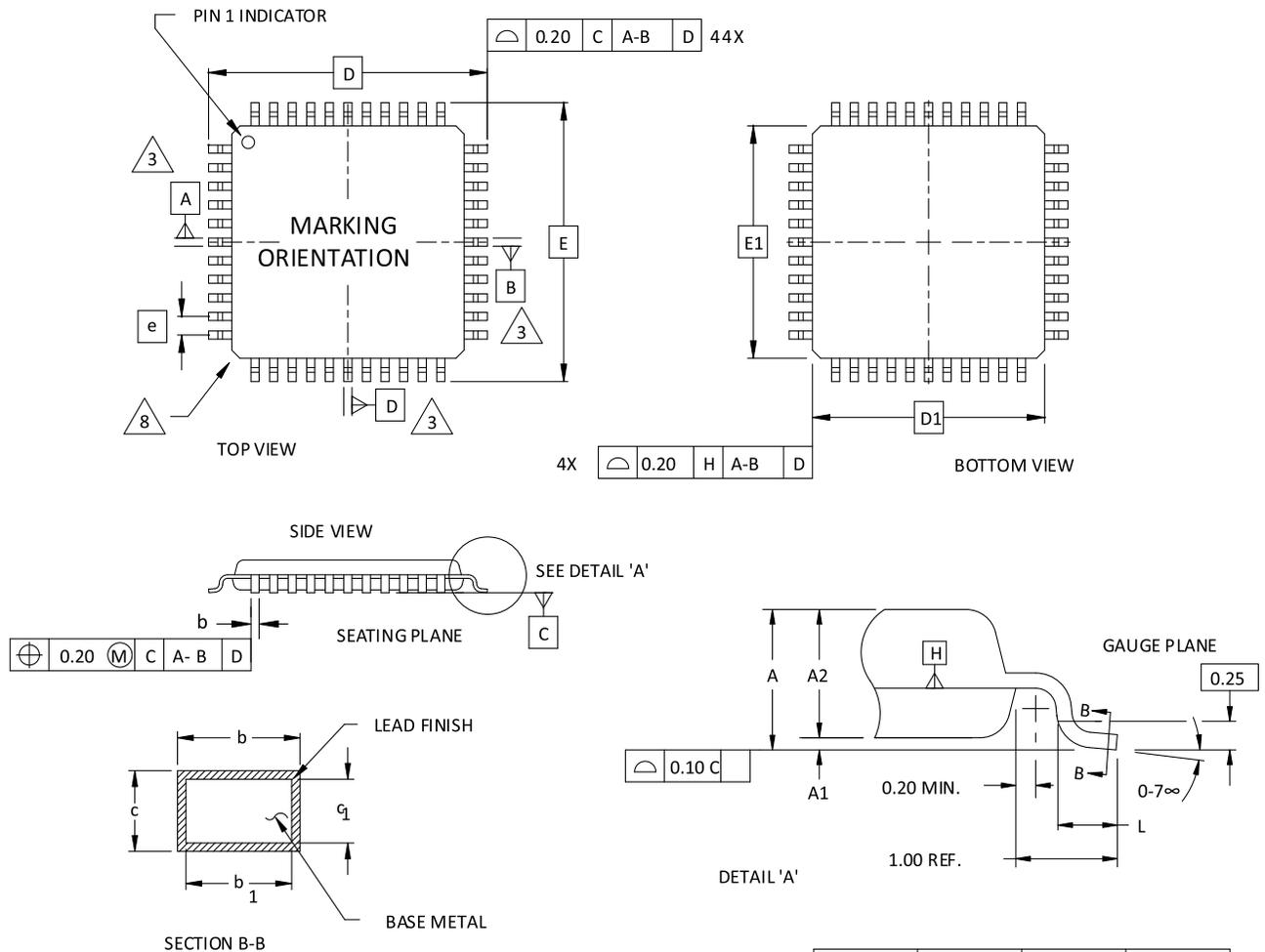
8. DIMENSION APPLIES TO BASE METAL ONLY



DETAIL "J" (TYP ALL SIDES)

28. 44-Pin LQFP Package

Dimensions in Millimeters



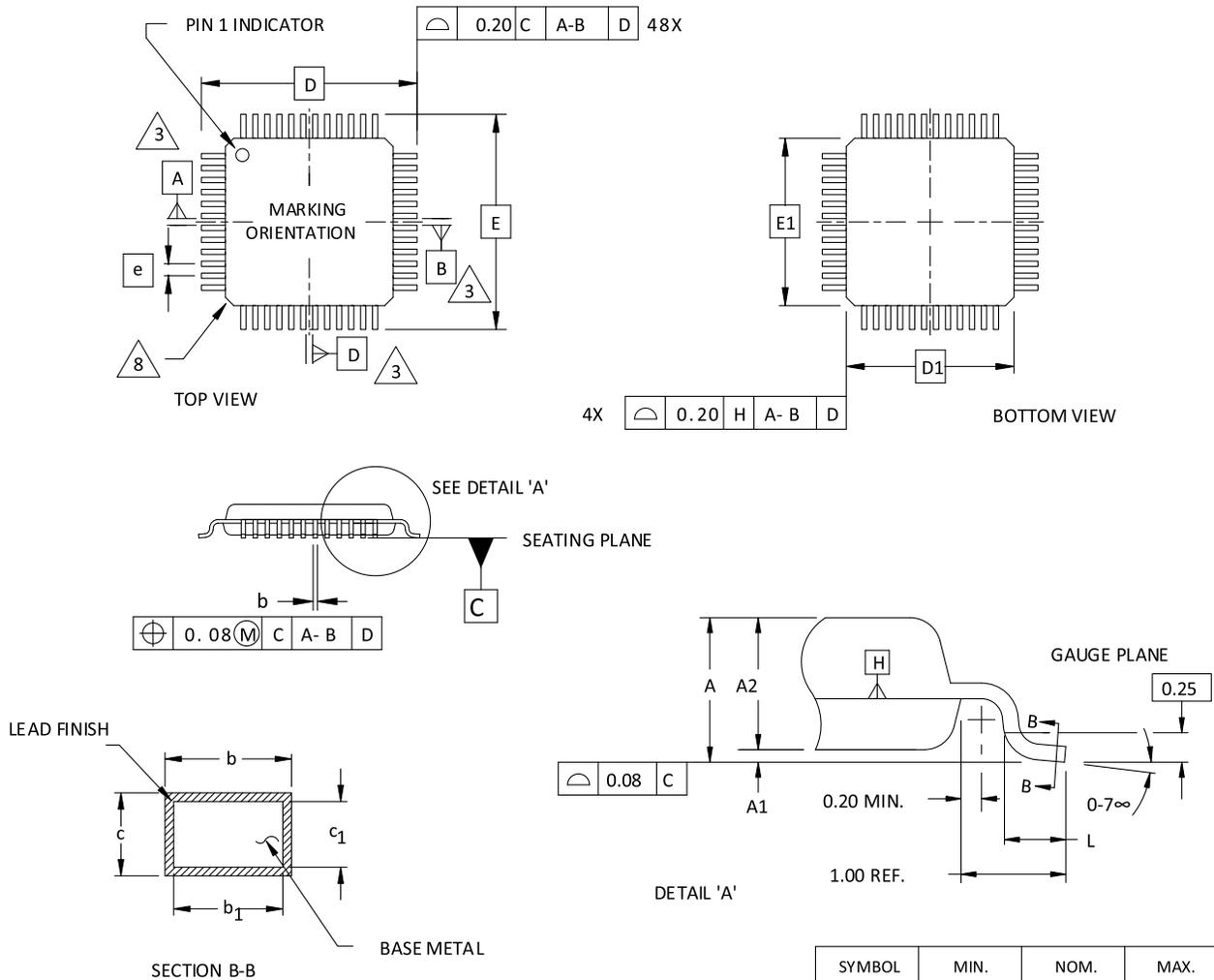
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 - 1982.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
5. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
6. SECTION B-B:
THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
7. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
8. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.60
A1	0.05	-	0.15
A2	1.35	1.40	1.45
D	12.00 BSC		
D1	10.00 BSC		
E	12.00 BSC		
E1	10.00 BSC		
L	0.45	0.60	0.75
N	44		
e	0.80 BSC		
b	0.30	0.37	0.45
b1	0.30	0.35	0.40
c	0.09	0.15	0.20
C1	0.09	0.13	0.16

29. 48-Pin TQFP Package

Dimensions in Millimeters



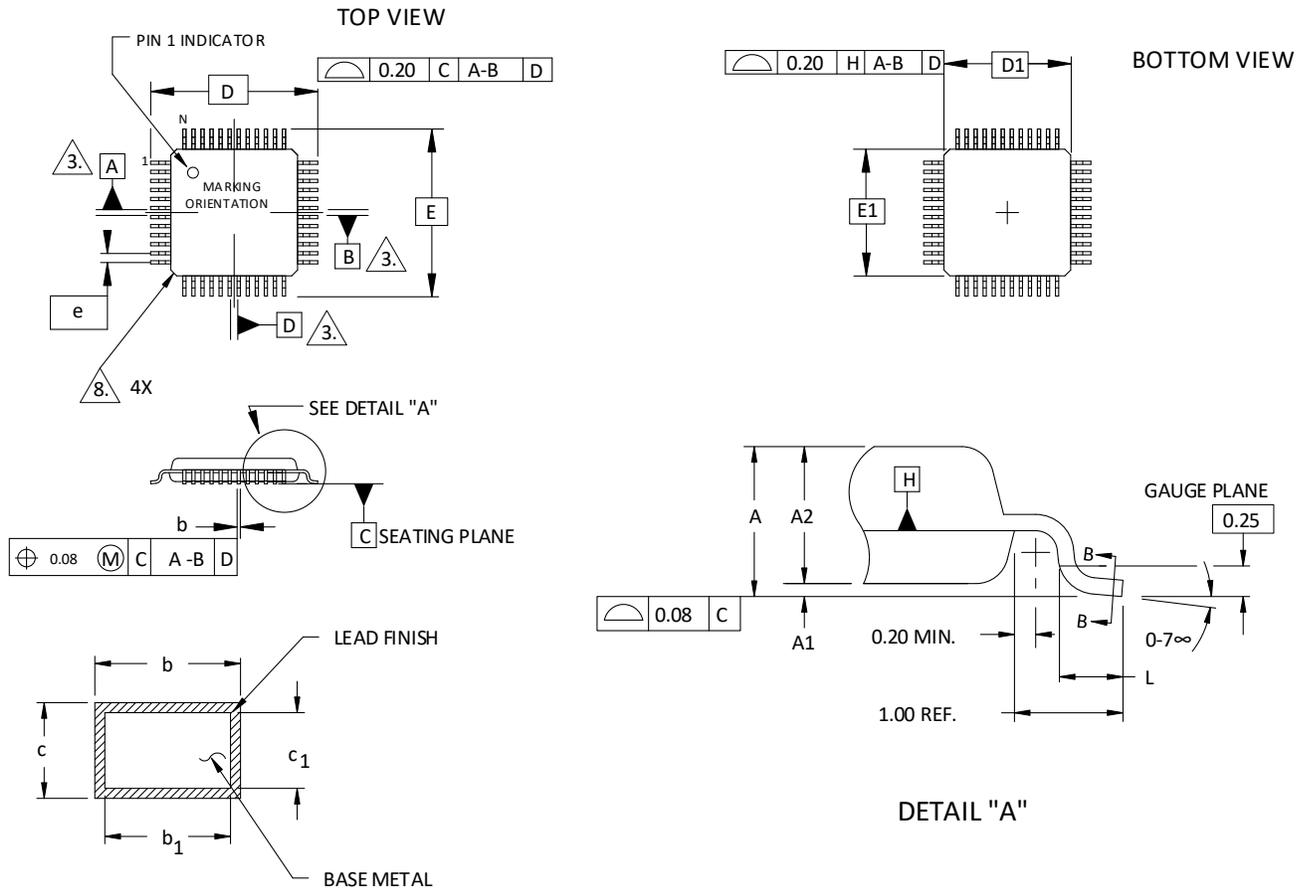
NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5 - 1982.
- ALL DIMENSIONS ARE IN MILLIMETERS.
- DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
- DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- SECTION B-B:
THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
- EXACT SHAPE OF EACH CORNER IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.20
A1	0.05	-	0.15
A2	.95	1.00	1.05
D	9.00 BSC		
D1	7.00 BSC		
E	9.00 BSC		
E1	7.00 BSC		
L	0.45	0.60	0.75
N	48		
e	0.50 BSC		
b	0.17	0.22	0.27
b1	0.17	0.20	0.23
c	0.09	0.15	0.20
c1	0.09	0.13	0.16

30. 48-Pin LQFP Package

Dimensions in Millimeters



SECTION B - B

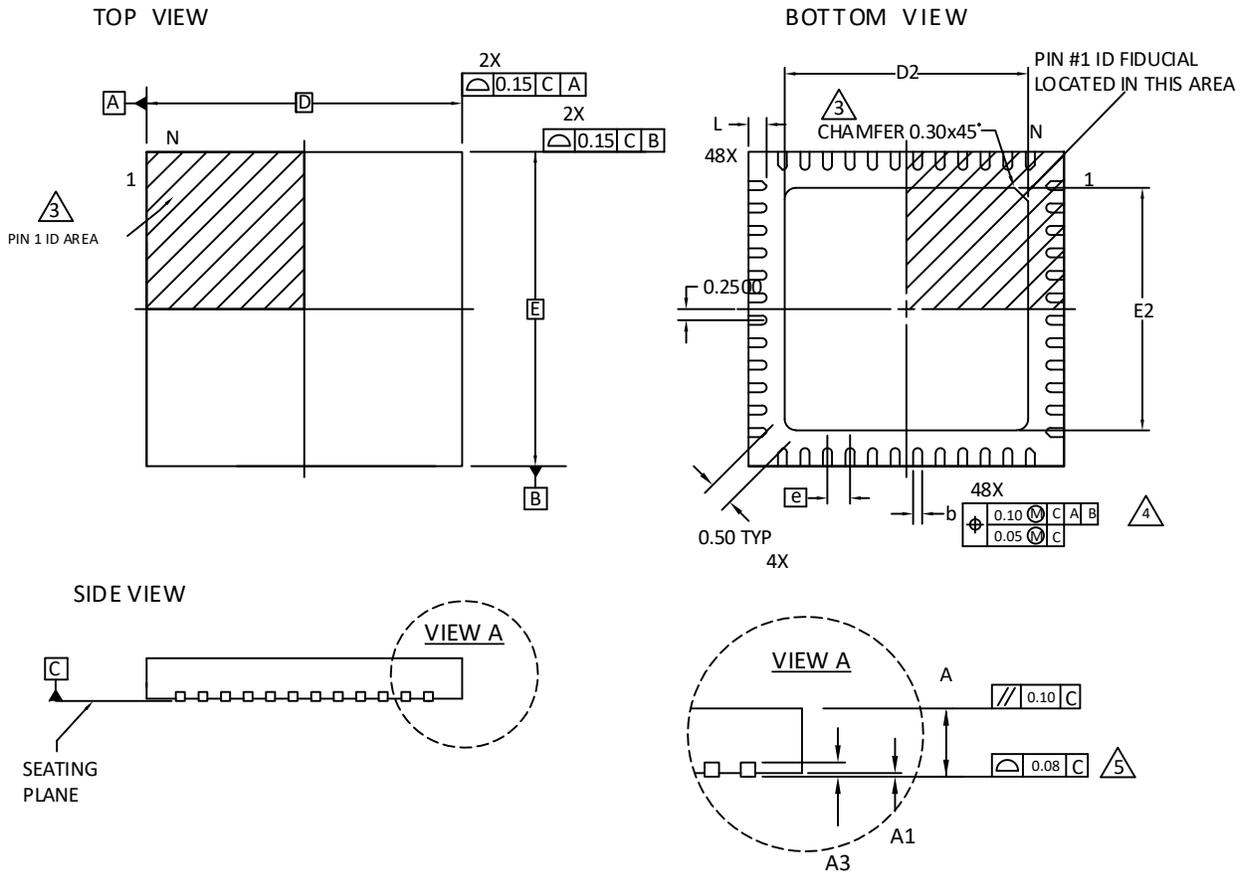
NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5 - 1982.
- ALL DIMENSIONS ARE IN MILLIMETERS.
- DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
- DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- SECTION B-B:
THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
- EXACT SHAPE OF EACH CORNER IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.60
A1	0.05	-	0.15
A2	1.35	1.40	1.45
D	9.00 BSC		
D1	7.00 BSC		
E	9.00 BSC		
E1	7.00 BSC		
L	0.45	0.60	0.75
N	48		
e	0.50 BSC		
b	0.17	0.22	0.27
b1	0.17	0.20	0.23
c	0.09	0.15	0.20
c1	0.09	0.13	0.16

31. 48-Pin QFN Package: L-ASC10, iCE40 Ultra, iCE40 UltraPlus™, MachXO2

Dimensions in Millimeters



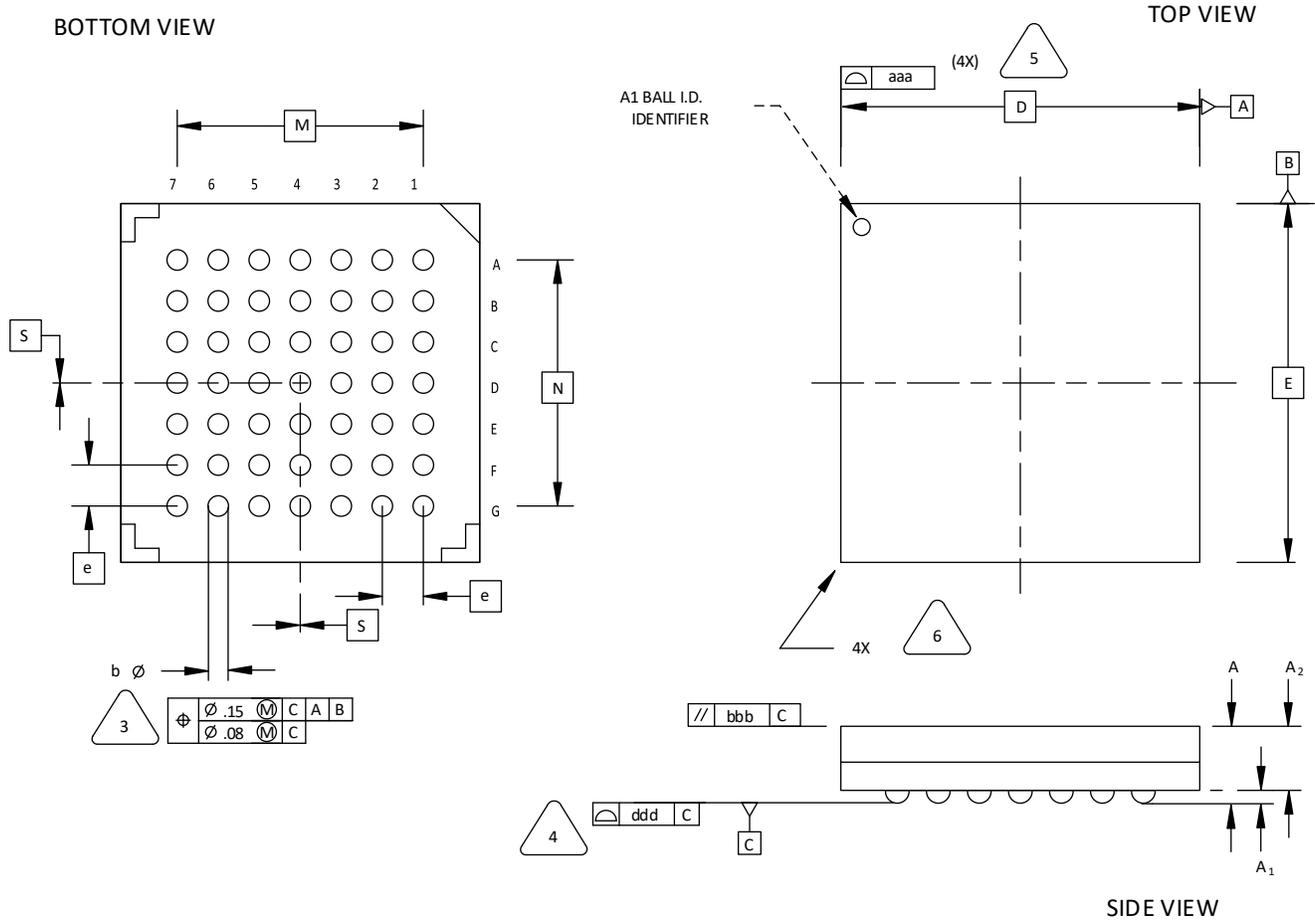
NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
 - ALL DIMENSIONS ARE IN MILLIMETERS.
- (3) EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
- (4) DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.
- (5) APPLIES TO EXPOSED PORTION OF TERMINALS.

SYMBOL	MIN.	NOM.	MAX.
A	0.80	0.90	1.00
A1	0.00	0.02	0.05
A3	0.2 REF		
D	7.0 BSC		
D2	5.20	5.35	5.50
E	7.0 BSC		
E2	5.20	5.35	5.50
b	0.15	0.225	0.30
e	0.50 BSC		
L	0.35	0.40	0.45

32. 49-Ball caBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM $\square C$



PRIMARY DATUM $\square C$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

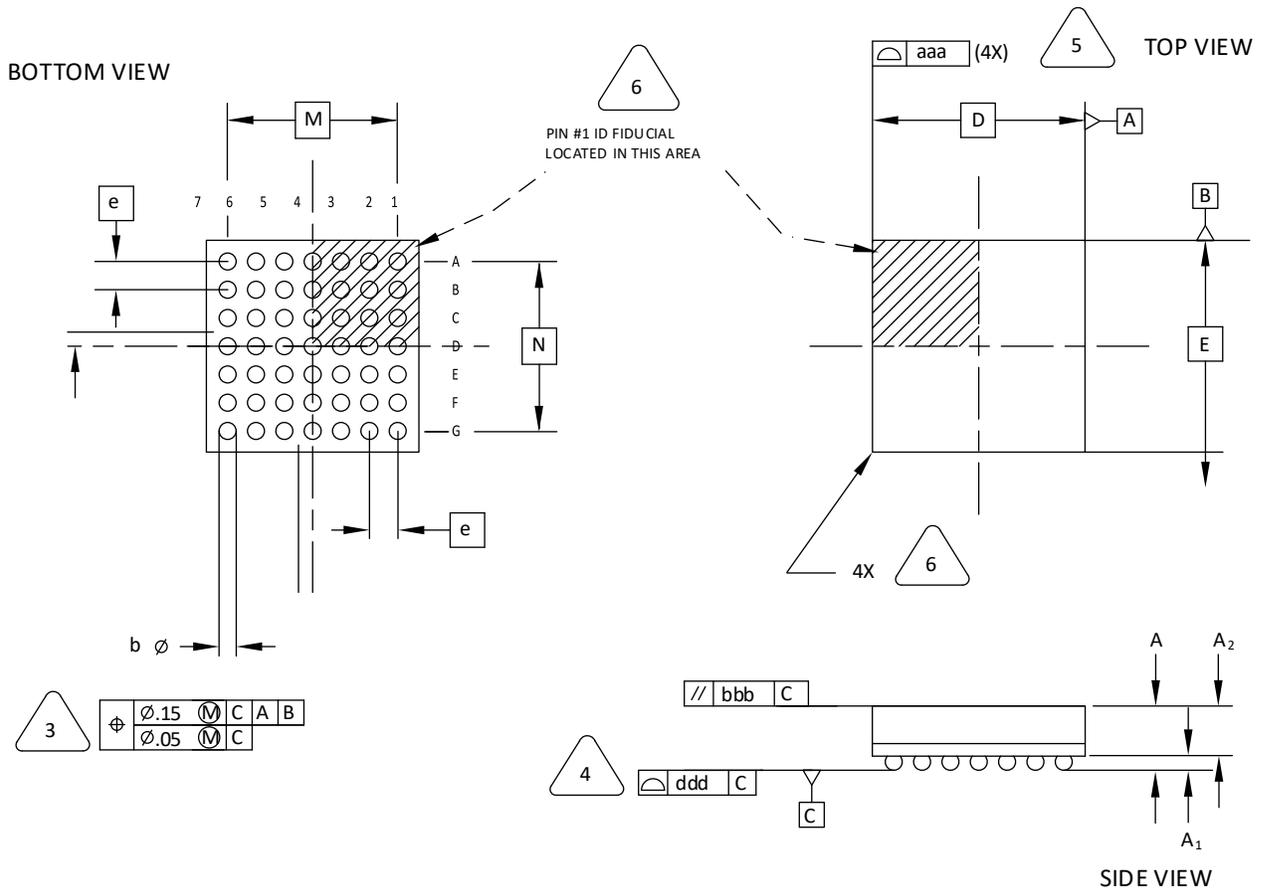


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.30	1.40	1.50
A1	0.31	0.36	0.41
A2	0.99	1.04	1.09
D/E	7.00 BSC		
M/N	4.80 BSC		
S	0 BSC		
b	0.40	0.46	0.52
e	0.80 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.12

33. 49-Ball ucBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

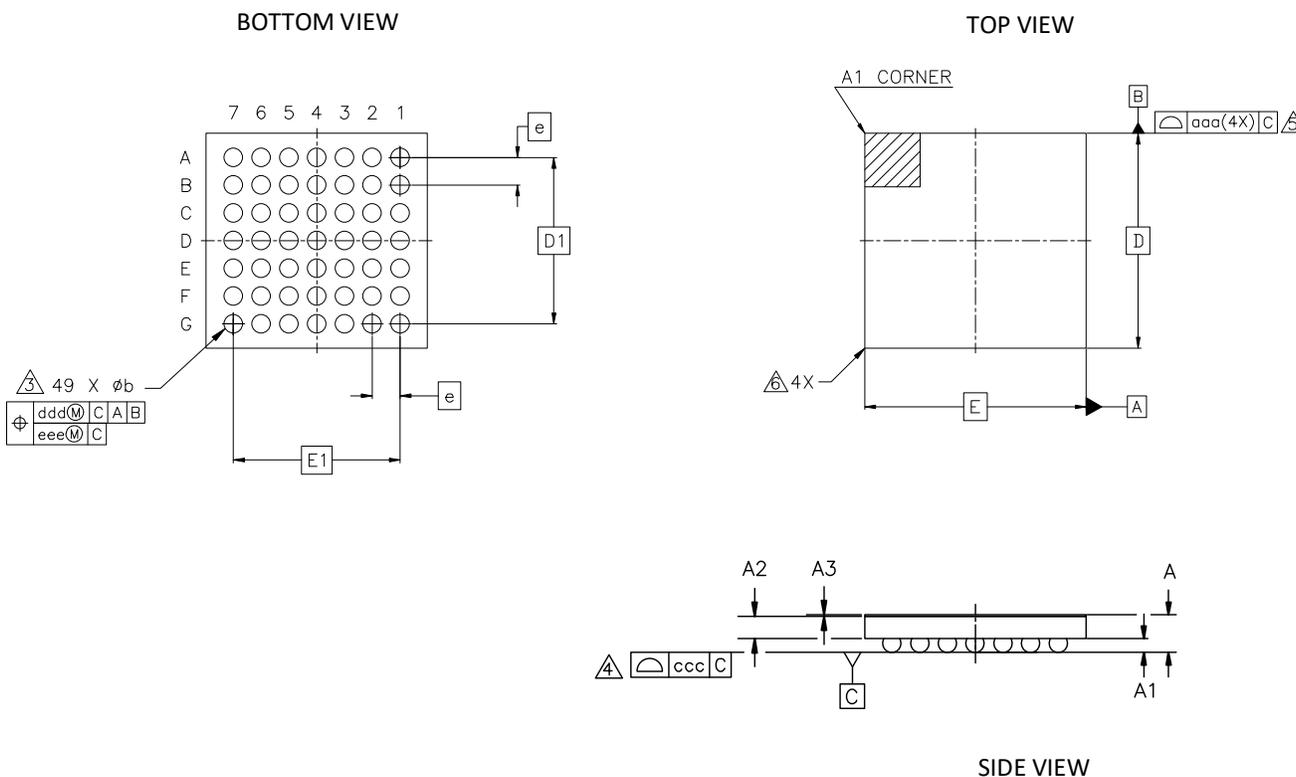


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.00
A1	0.10	-	-
A2	-	-	0.90
D/E	3.00 BSC		
M/N	2.40 BSC		
b	0.20	0.25	0.30
e	0.40 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.10

34. 49-Ball WLCSP Package

Dimensions in Millimeters



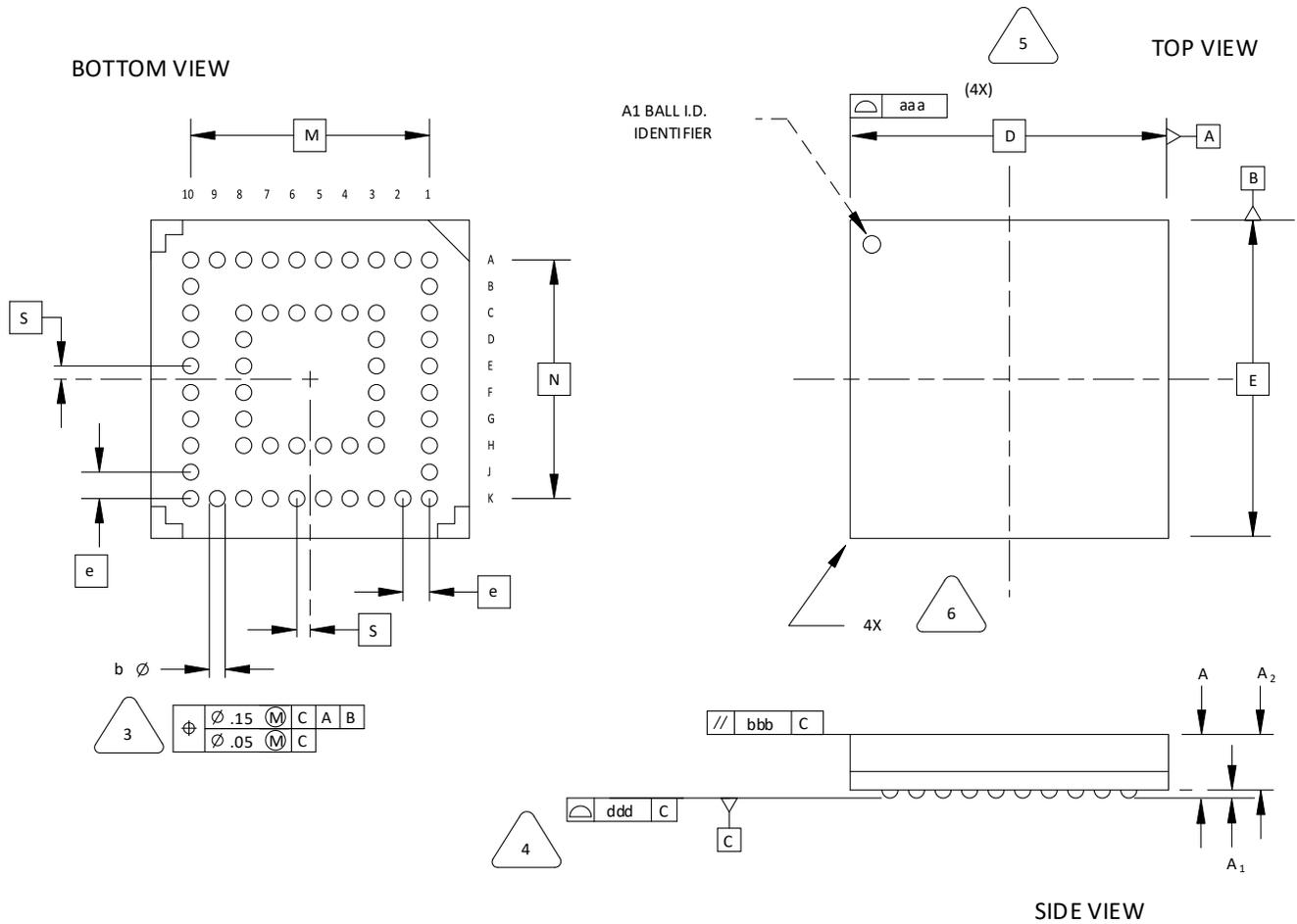
Notes:

1. ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M - 1994.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DIMENSION "b" IS MEASURED AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM C.
4. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.
5. BILLATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
7. JEDEC REFERENCE JEP95 DG 4.18.

SYMBOL	Min.	Nom.	Max.
A	0.507	0.546	0.585
A1	0.169	0.199	0.229
A2	0.322 ±0.025		
A3	0.025		
b	0.200	0.250	0.300
D	3.102 BSC		
E	3.190 BSC		
D1	2.400 BSC		
E1	2.400 BSC		
e	0.40 BSC		
aaa	0.030		
ccc	0.050		
ddd	0.015		

35. 56-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM $\square C$



PRIMARY DATUM $\square C$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

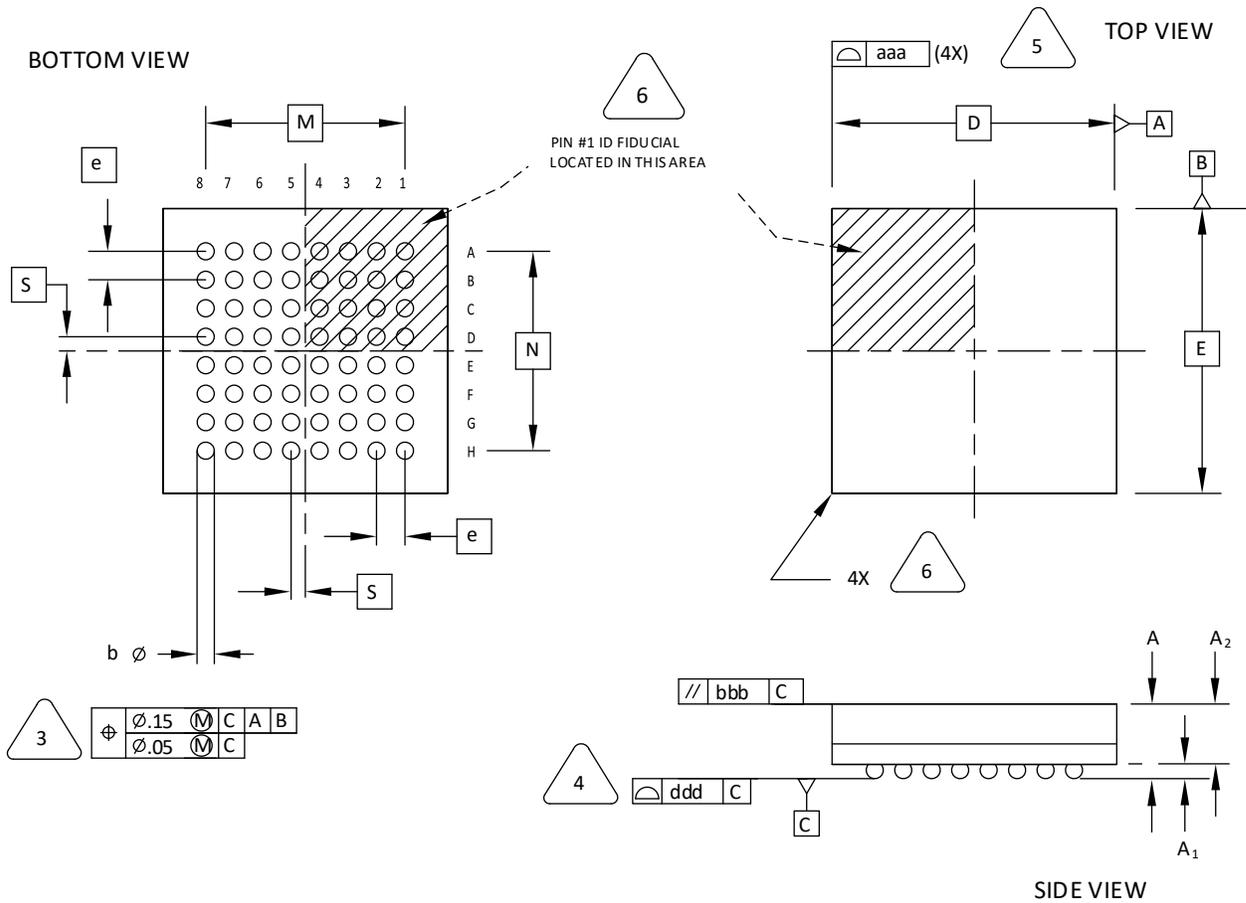


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.10	1.23	1.35
A1	0.15	-	-
A2	-	-	1.10
D/E	6.00 BSC		
M/N	4.50 BSC		
S	0.25 BSC		
b	0.25	0.30	0.35
e	0.50 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.08

36. 64-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.

3 DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]

4 PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

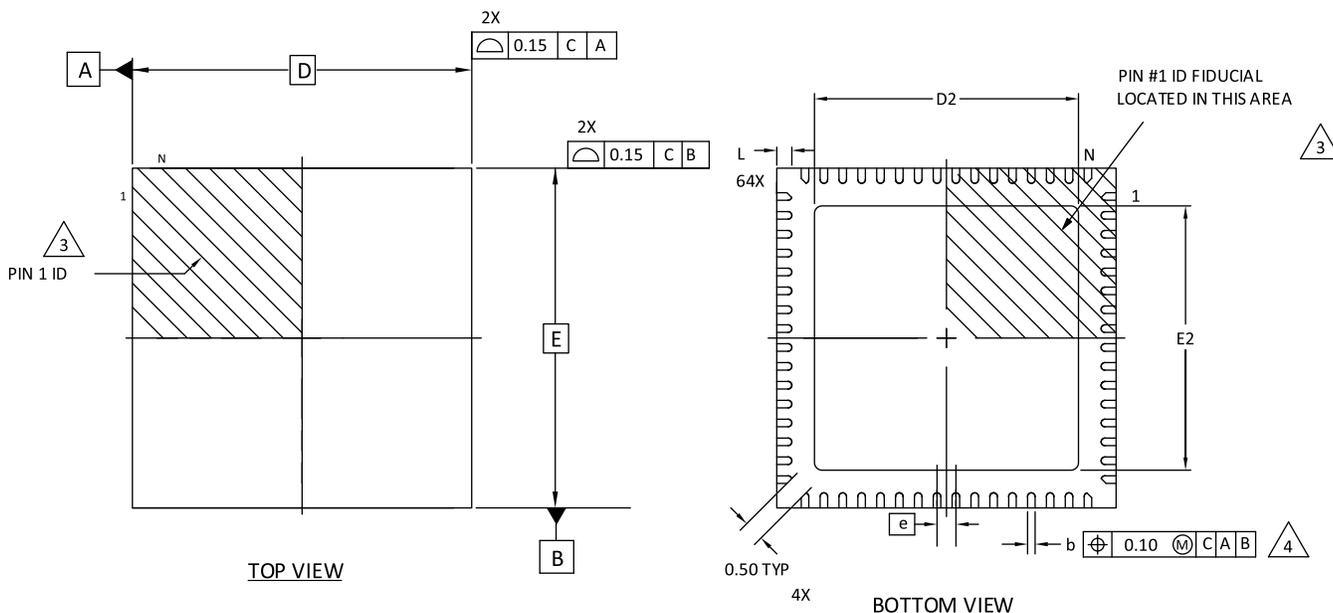
5 BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

6 EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
A1	0.15	-	-
A2	-	-	0.85
D/E	5.00 BSC		
M/N	3.50 BSC		
S	0.25 BSC		
b	0.25	0.30	0.35
e	0.50 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.08

37. 64-Pin QFNS Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.

EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

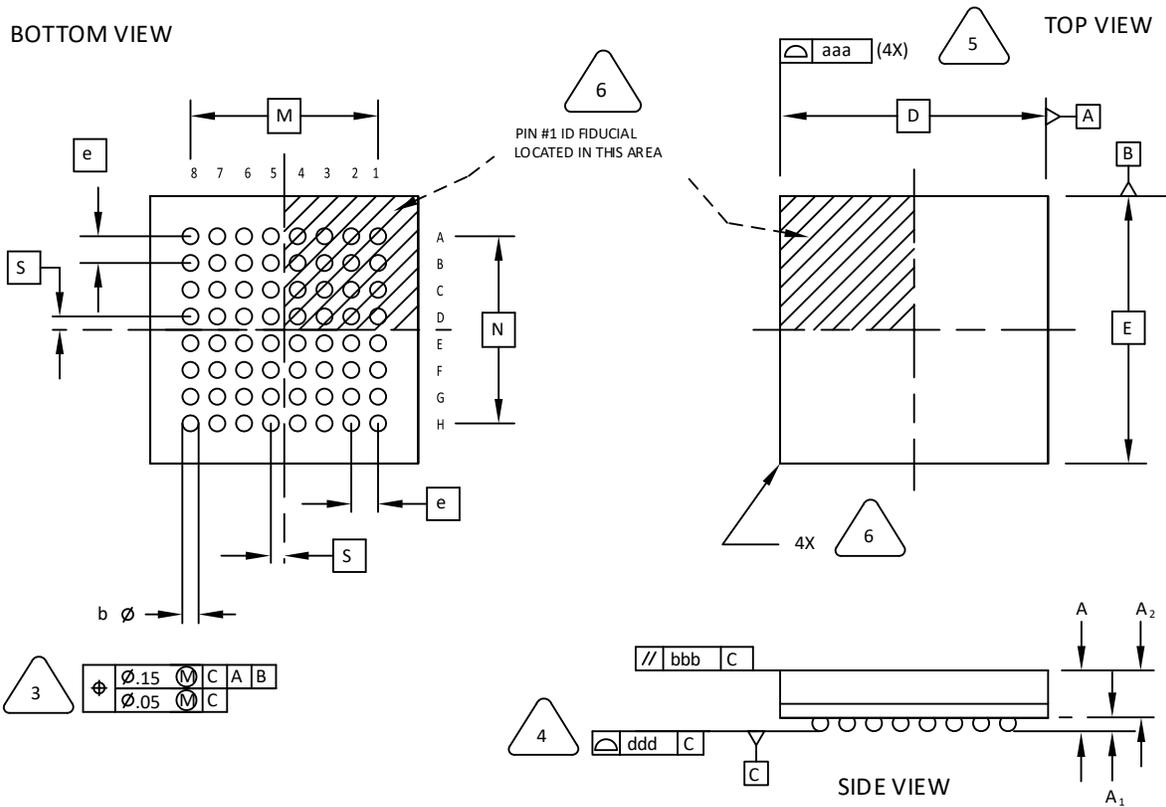
DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.

APPLIES TO EXPOSED PORTION OF TERMINALS.

SYMBOL	MIN.	NOM.	MAX.
A	0.80	0.90	1.00
A1	0.00	0.02	0.05
A3	0.2 REF		
D	9.0 BSC		
D2	5.00	-	7.50
E	9.0 BSC		
E2	5.00	-	7.50
b	0.18	0.24	0.30
e	0.50 BSC		
L	0.30	0.40	0.50

38. 64-Ball ucBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



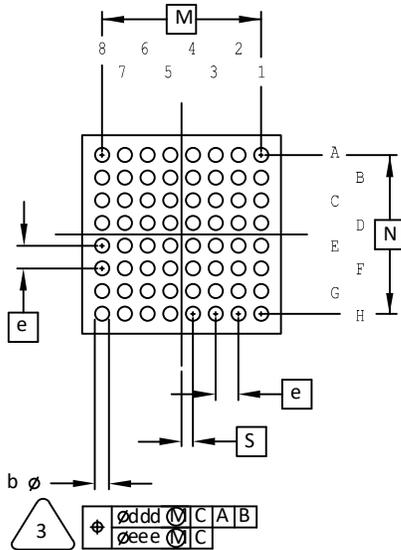
EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.00
A1	0.10	-	-
A2	-	-	0.90
D/E	4.00 BSC		
M/N	2.80 BSC		
s	0.20 BSC		
b	0.20	0.25	0.30
e	0.40 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.08

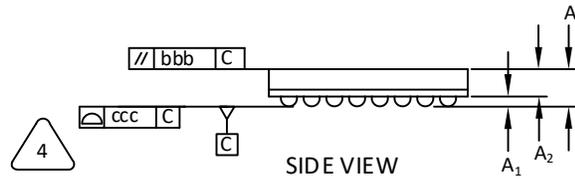
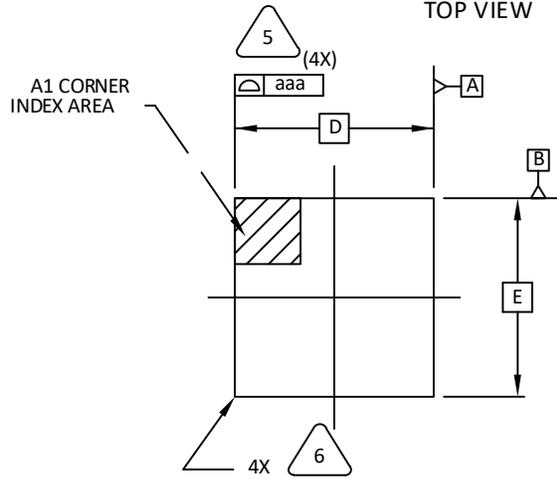
39. 64-Ball ucfBGA Package

Dimensions in Millimeters

BOTTOM VIEW



TOP VIEW



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C].



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

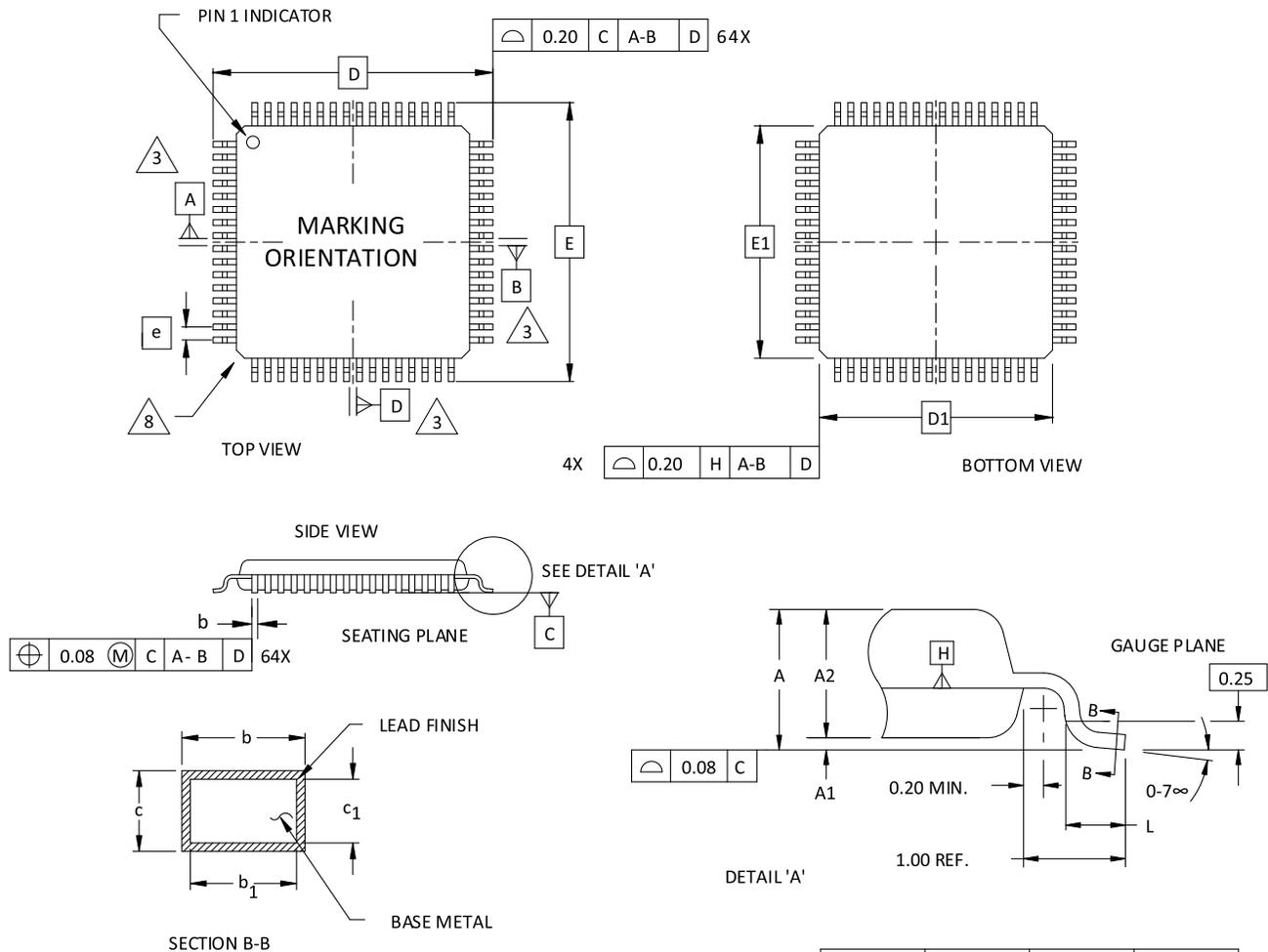


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.00
A1	0.11	-	-
A2	0.62	-	-
D/E	3.50BSC		
M/N	2.80BSC		
S	0.20BSC		
b	0.20	0.25	0.30
e	0.40BSC		
aaa	0.10		
bbb	0.10		
ccc	0.08		
ddd	0.15		
eee	0.08		

40. 64-Pin LQFP Package

Dimensions in Millimeters



NOTES:

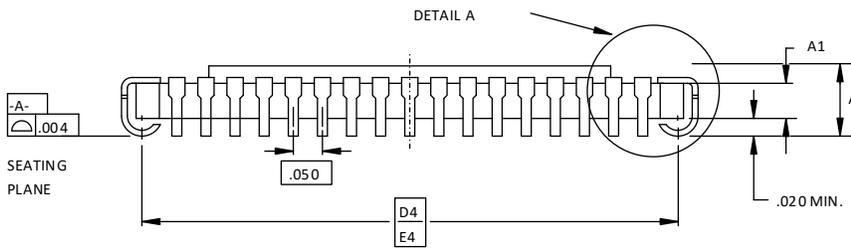
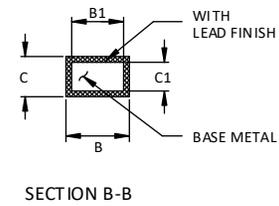
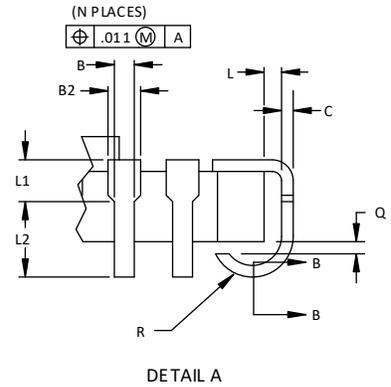
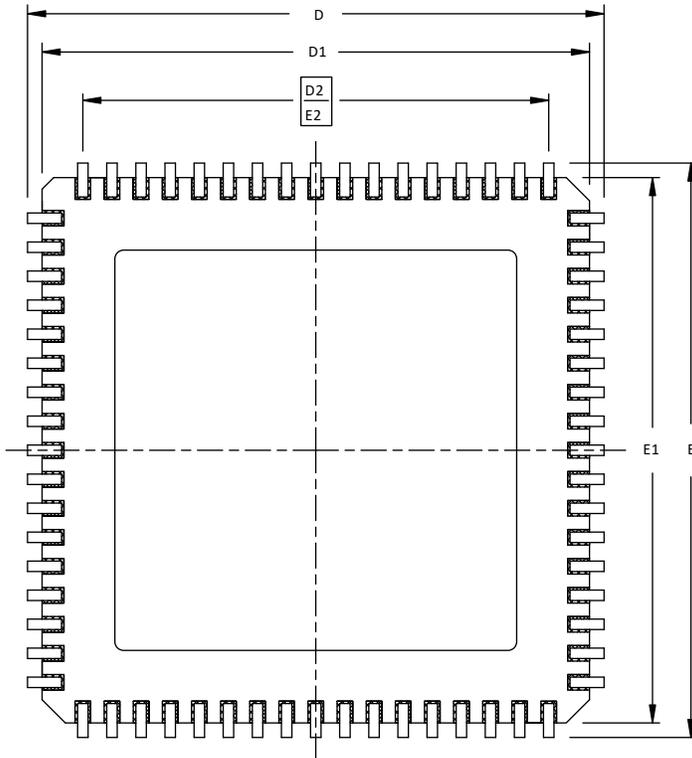
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 - 1982.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
5. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
6. SECTION B-B:
THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
7. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
8. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.60
A1	0.05	-	0.15
A2	1.35	1.40	1.45
D	12.00 BSC		
D1	10.00 BSC		
E	12.00 BSC		
E1	10.00 BSC		
L	0.45	0.60	0.75
N	64		
e	0.50 BSC		
b	0.17	0.22	0.27
b1	0.17	0.20	0.23
c	0.09	-	0.20
c1	0.09	-	0.16

41. 68-Pin JLCC Package

Dimensions in Inches

BOTTOM VIEW



SIDE VIEW

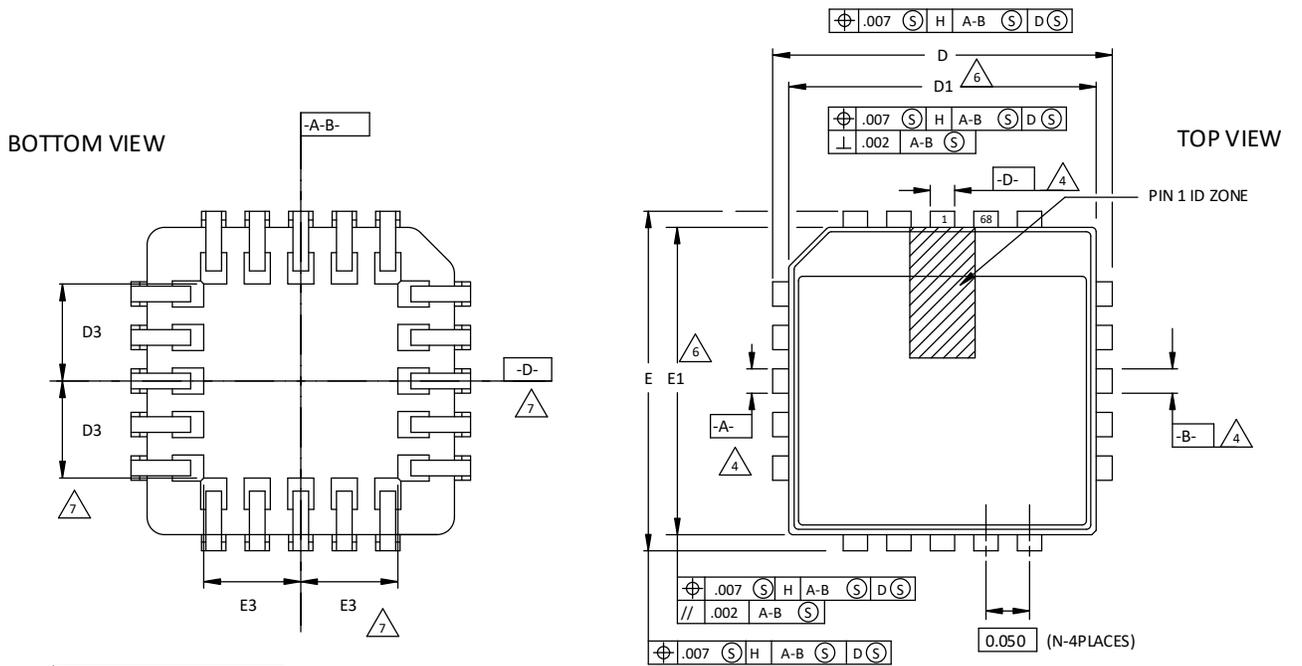
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN INCHES.
3. CORNER CHAMFERS AND/OR NOTCHES ARE OPTIONAL.

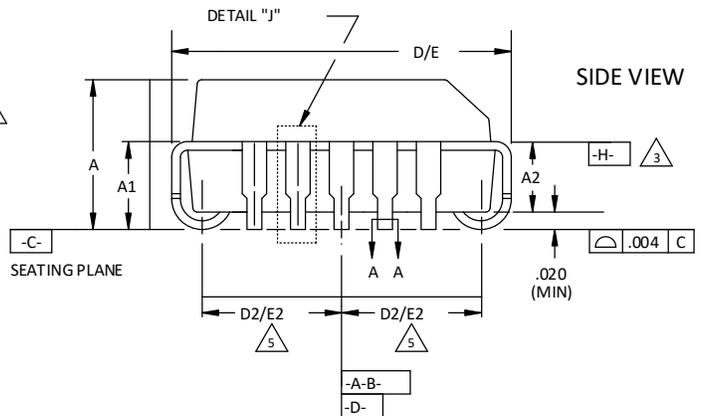
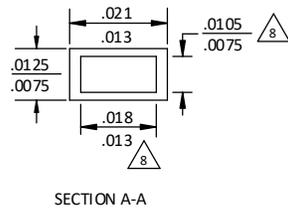
SYMBOL	INCHES	
	MIN.	MAX.
A	.115	-.190
A1	.080 REF	
B	.013	-.023
B1	.013	-.020
B2	.022	-.035
C	.007	-.013
C1	.007	-.010
D/E	.975	.990 1.000
D1/E1	.920	-.960
D2/E2	.800 BSC	
D4/E4	.930 BSC	
L	.005	-
L1	.020	-
L2	.025	-
Q	.003	-
R	.020	-.040
N	68	

42. 68-Pin PLCC Package

Dimensions in Inches



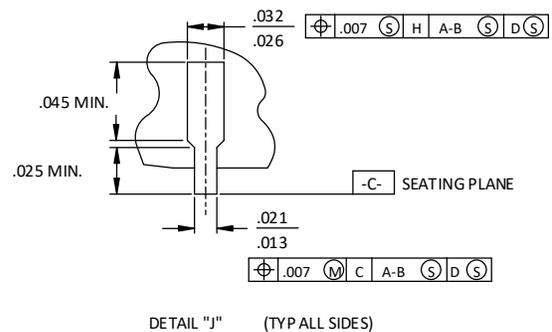
SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	.165	.172	.180
A1	.090	.105	.120
A2	.062	-	.083
D	.985	.990	.995
D1	.950	.954	.958
D2	.441	.455	.469
D3		.375	
E	.985	.990	.995
E1	.950	.954	.958
E2	.441	.455	.469
E3		.375	
N	68		



NOTES:

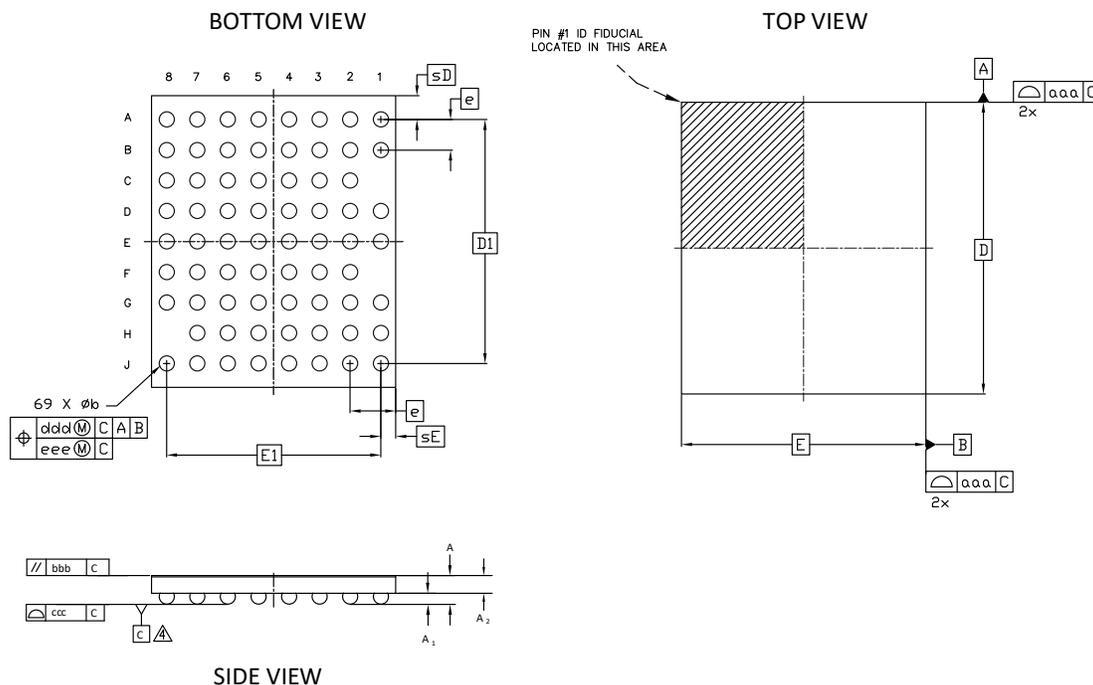
- ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1982
- ALL DIMENSIONS IN INCHES

- 3 DATUM PLANE \square -H- LOCATED AT TOP OF MOLD PARTING LINE AND COINCIDENT WITH TOP OF LEAD WHERE LEAD EXITS PLASTIC BODY
- 4 DATUMS \square -A-B- AND \square -D- TO BE DETERMINED WHERE CENTER LEADS EXIT PLASTIC BODY AT DATUM PLANE \square -H-
- 5 TO BE MEASURED AT SEATING PLANE \square -C- CONTACT POINT
- 6 DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION \leq .010 PER SIDE.
- 7 TOP POINT OF MEASUREMENT IS DATUM \square -H- ; BOTTOM POINT OF MEASUREMENT IS AT MAJOR FLAT AREA OF LOWER PLASTIC SURFACE DEFINED BY D3/E3
- 8 DIMENSION A APPLIES TO BASE METAL ONLY



43. 69-Ball WLCSP Package

Dimensions in Inches



NOTES:

1. ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M - 1994
2. ALL DIMENSIONS ARE IN MILLIMETERS.

3 DIMENSION "b" IS MEASURED AT THE MAXIMUM BUMP DIAMETER, PARALLEL TO PRIMARY DATUM C

4 PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.

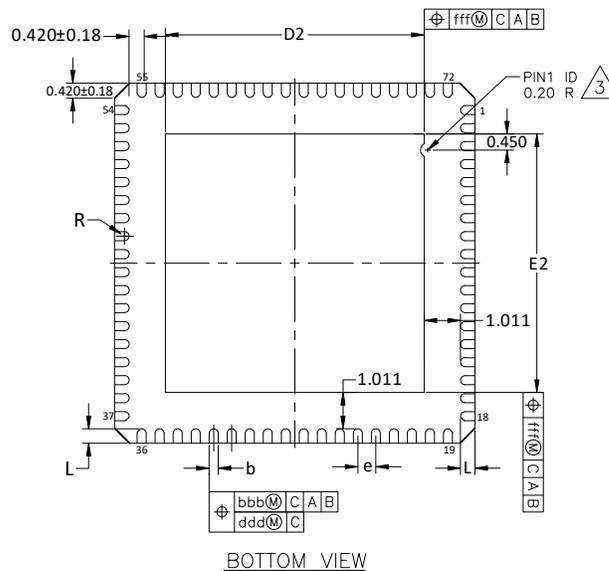
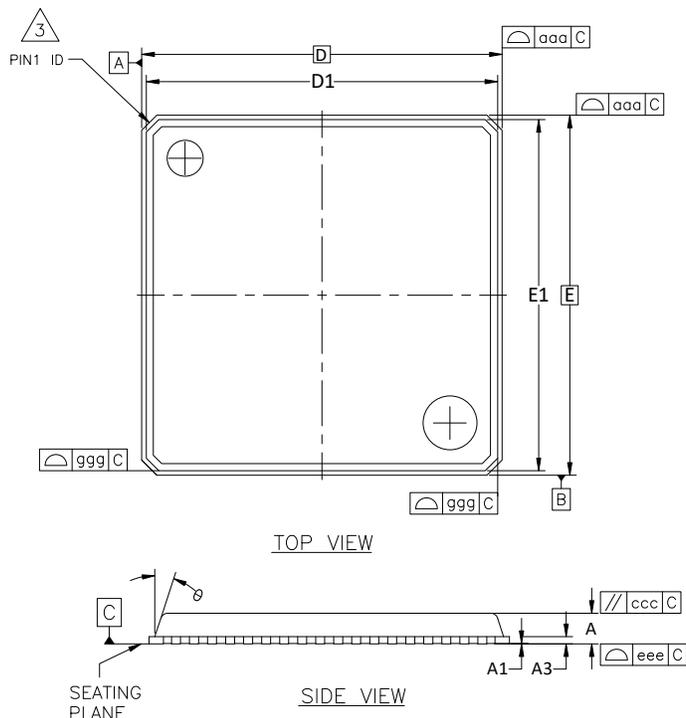
5 JEDEC REFERENCE: JEP95 DR4.18

REF	MIN.	NOM.	MAX.
A	0.598	0.611	0.676
A1	0.206	0.236	0.266
A2	0.350±0.025		
b	0.300		
D	6.218 BSC		
E	5.192 BSC		
D1	5.200 BSC		
E1	4.550 BSC		
e	0.650 BSC		
sD	0.509 REF		
sE	0.310 REF		
aaa	0.03		
bbb	0.060		
ccc	0.05		
ddd	0.015		
eee	0.050		

**This Package Outline Drawing and related information applies to MachXO3D™ devices.*

45. 72-Pin QFN Package Option 2: MachXO3D

Dimensions in Millimeters



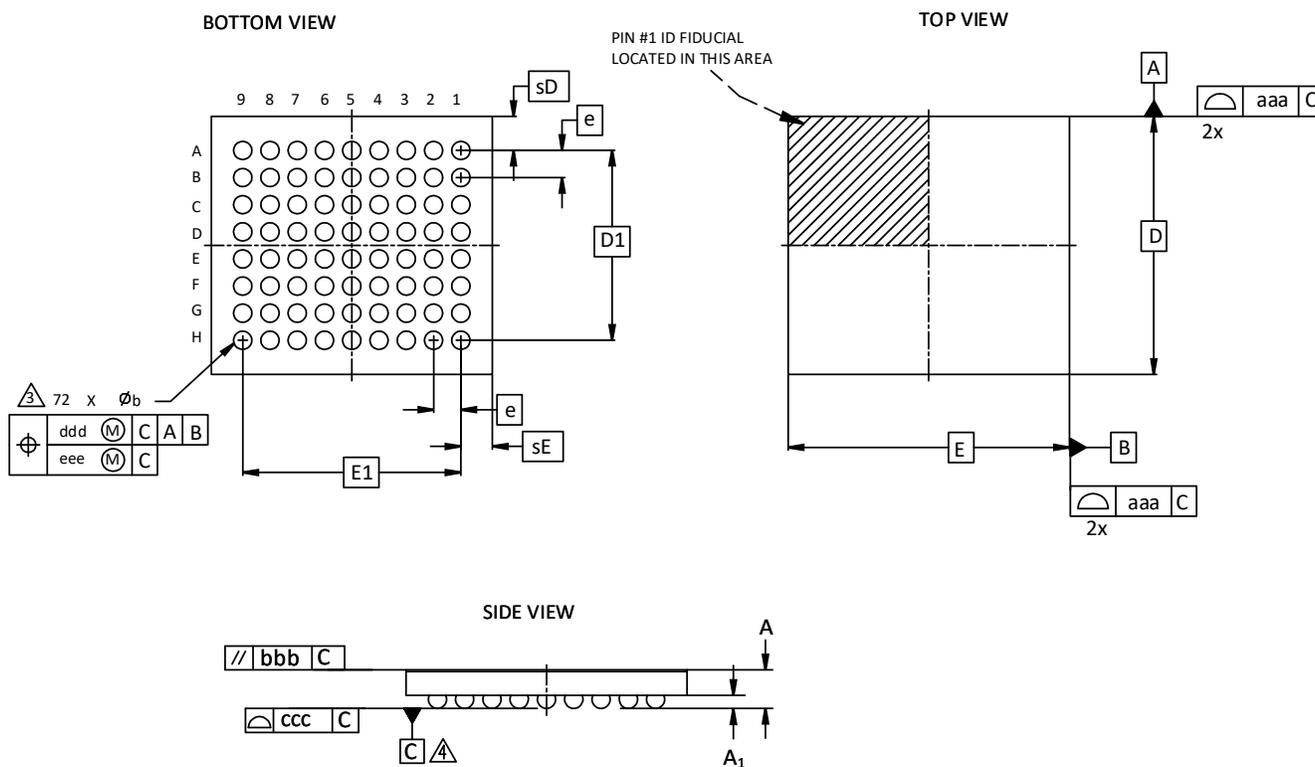
NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
4. DIMENSION *b* APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.
5. APPLIES TO EXPOSED PORTION OF TERMINALS.
6. JEDEC STANDARD REFERENCE: MO-220 K.01

SYMBOL	MIN.	NOM.	MAX.
A	-	-	0.90
A1	0.00	0.01	0.05
A3	0.2 REF		
D/E	10.0 BSC		
D1/E1	9.75 BSC		
D2/E2	7.078	7.178	7.278
b	0.20	0.25	0.30
e	0.50 BSC		
L	0.30	0.40	0.50
aaa	0.100		
bbb	0.100		
ccc	0.100		
ddd	0.050		
eee	0.050		
fff	0.100		
ggg	0.200		

46. 72-Pin WLCSP Package

Dimensions in Millimeters



NOTES:

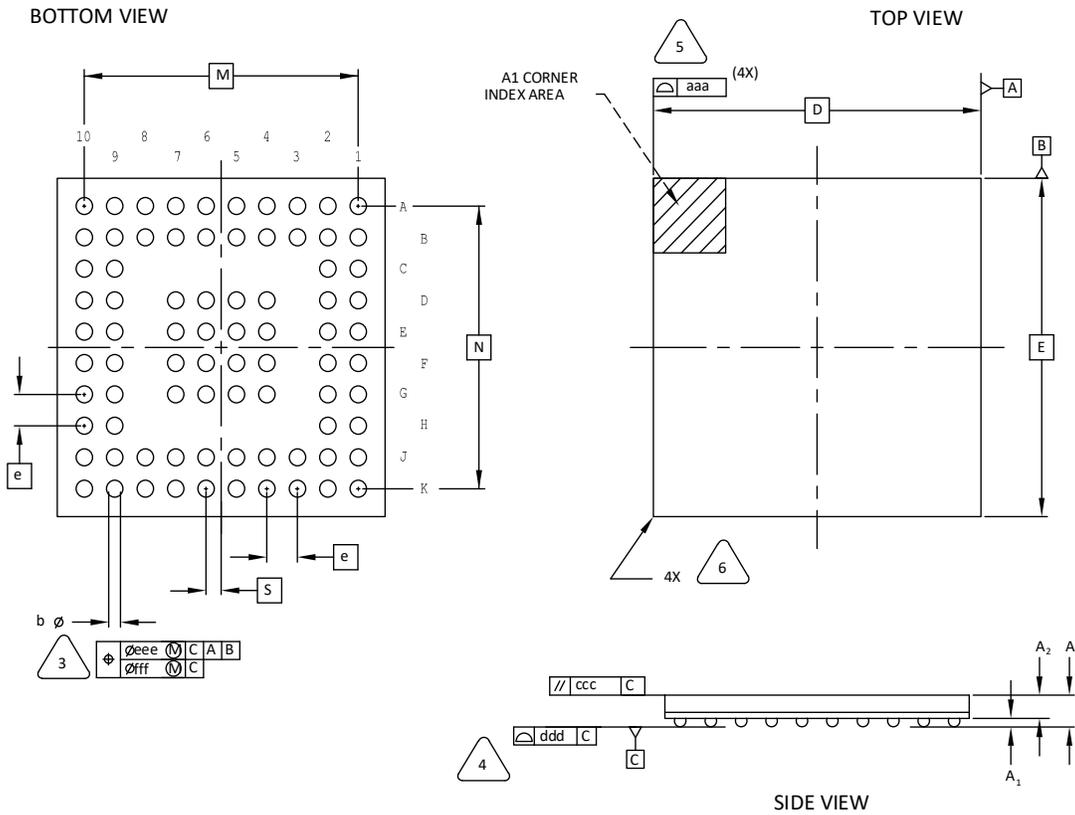
1. ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M – 1994.
 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- DIMENSION “b” IS MEASURED AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM C.
- PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.

REF.	Min.	Nom.	Max.
A	–	–	0.608
A1	0.164	0.194	0.224
b	0.239	0.269	0.299
D	3.8074 BSC		
E	4.1251 BSC		
D1	2.800 BSC		
E1	3.200 BSC		
e	0.40 BSC		
sD	0.485	–	0.515
sE	0.445	–	0.475
aaa	0.03		
bbb	0.060		
ccc	0.03		
ddd	0.015		
eee	0.050		

**This Package Outline Drawing and related information apply to CrossLink-NX devices.*

47. 80-Ball ckbBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM \square C



PRIMARY DATUM \square C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

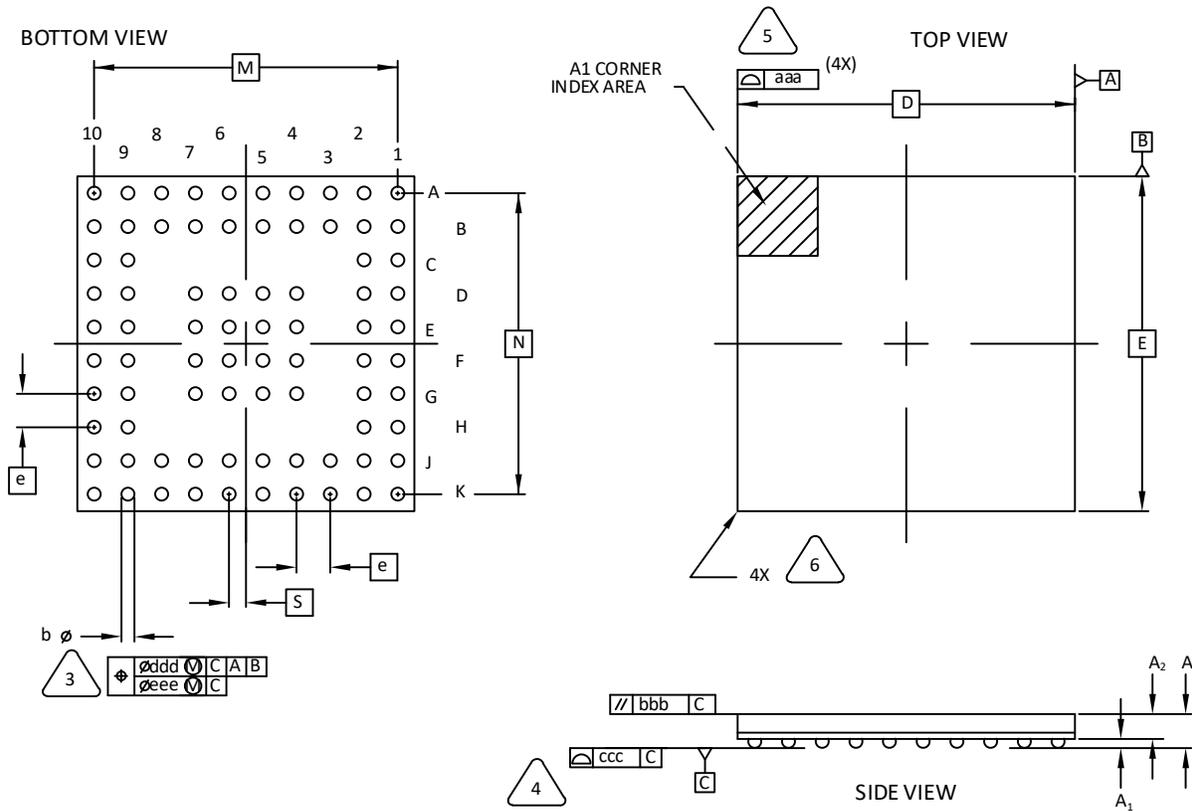
- JEDEC REFERENCE JEP95 DR 4.5

REF	MIN.	NOM.	MAX.
A	-	-	1.20
A1	0.22	-	-
A2	0.73	-	-
D/E	7.00 BSC		
M/N	5.85 BSC		
S	0.325 BSC		
b	0.30	0.35	0.40
e	0.65 BSC		
aaa	0.15		
ccc	0.20		
ddd	0.10		
eee	0.15		
fff	0.08		

**This Package Outline Drawing and related information apply to CrossLink devices.*

48. 80-Ball ctfBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM \square C.



PRIMARY DATUM \square C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

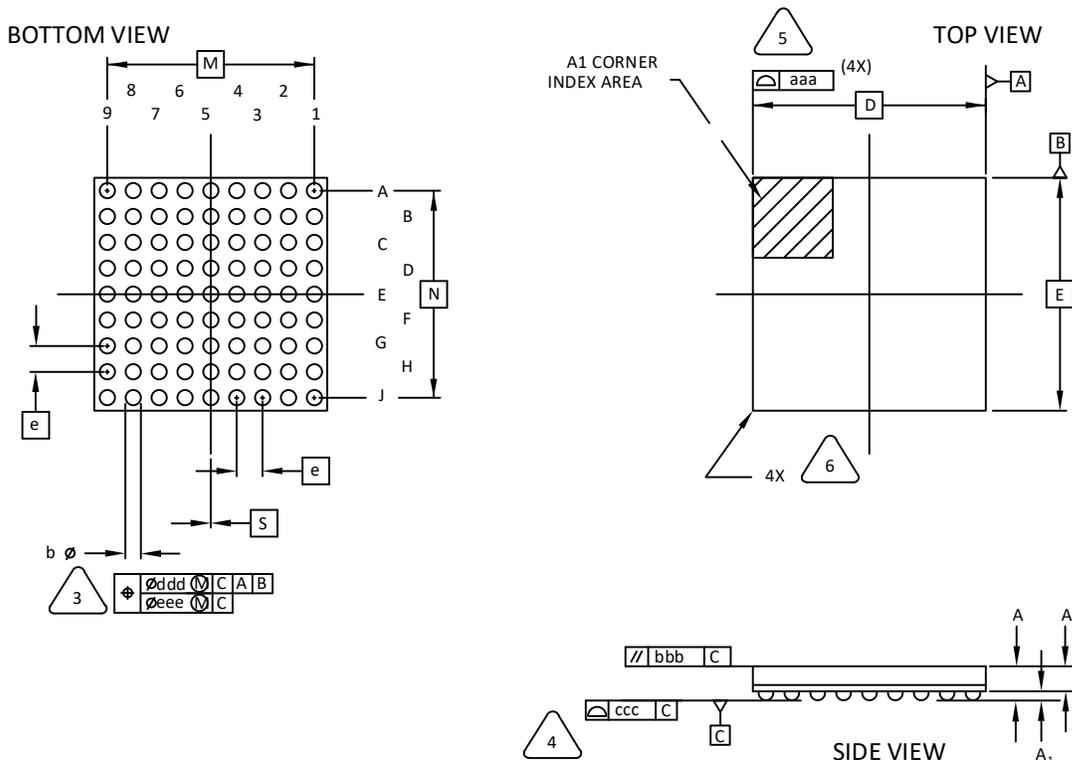


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.00
A1	0.11	-	-
A2	0.61	-	-
D/E	6.50 BSC		
M/N	5.85 BSC		
S	0.325 BSC		
b	0.20	0.25	0.30
e	0.65 BSC		
aaa	0.10		
bbb	0.10		
ccc	0.08		
ddd	0.15		
eee	0.05		

50. 81-Ball csfBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

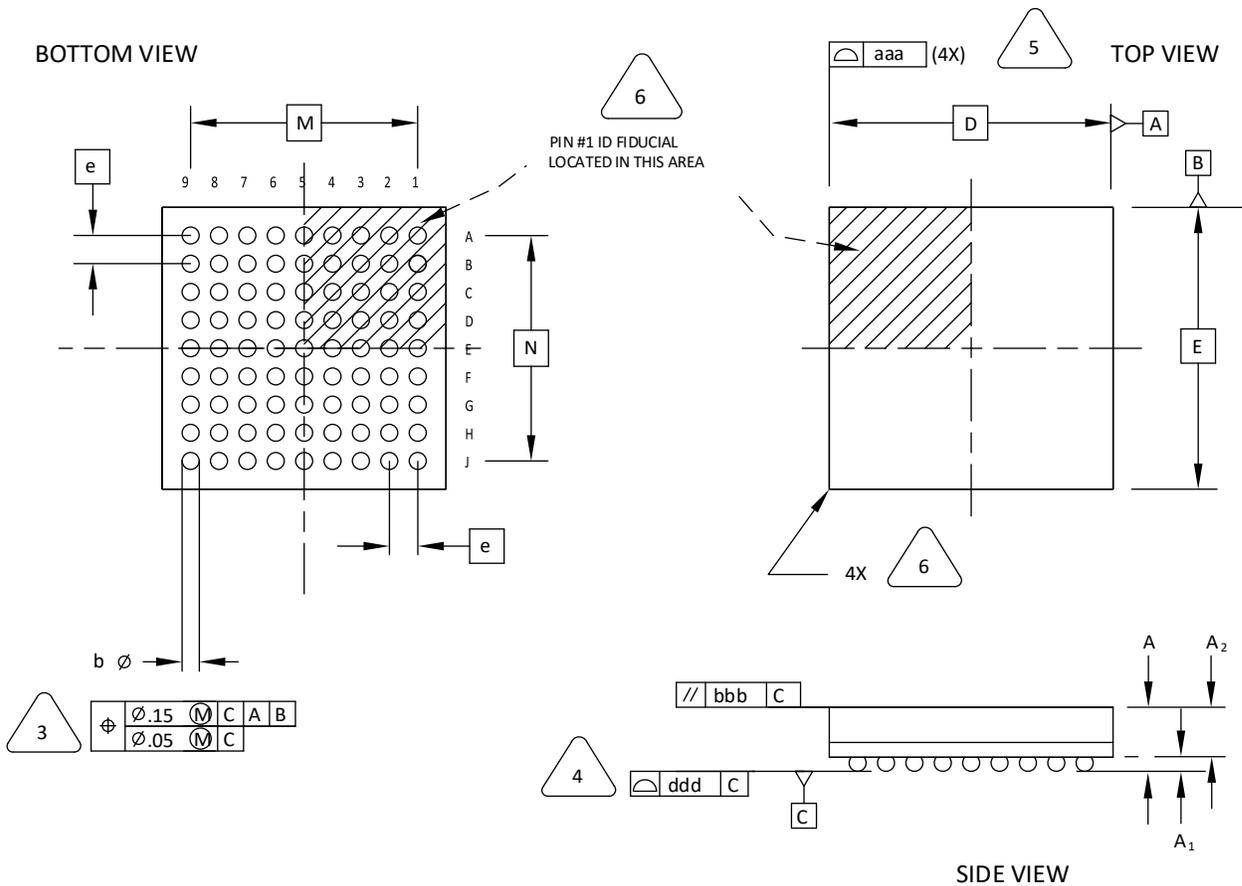


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.00
A1	0.11	-	-
A2	0.64	-	-
D/E	4.50 BSC		
M/N	4.00 BSC		
S	0.00 BSC		
b	0.20	0.25	0.30
e	0.50 BSC		
aaa	0.10		
bbb	0.10		
ccc	0.08		
ddd	0.15		
eee	0.08		

51. 81-Ball ucBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

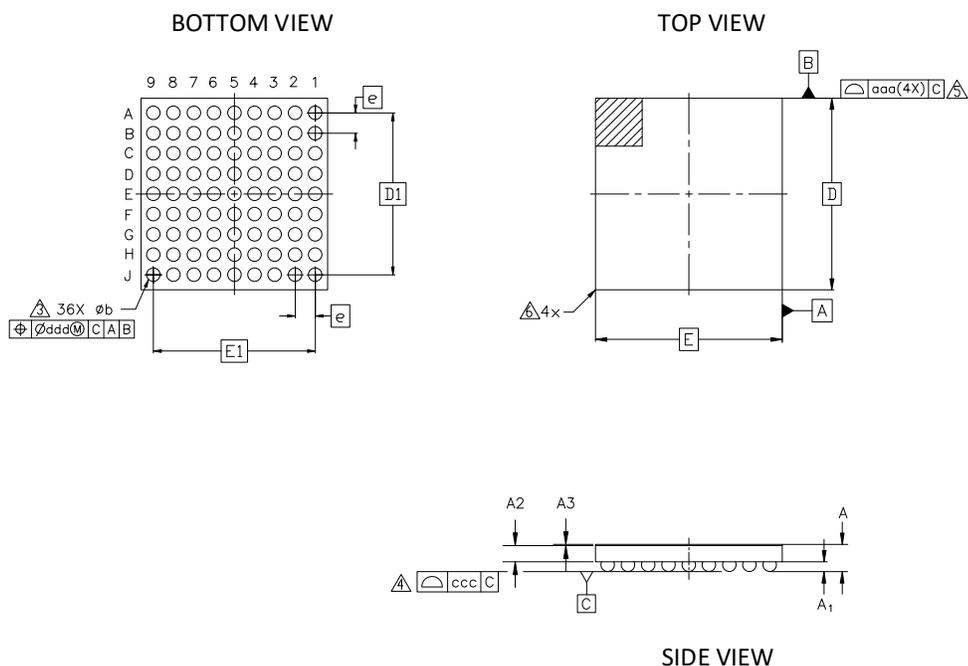


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.00
A1	0.10	-	-
A2	-	-	0.90
D/E	4.00 BSC		
M/N	3.20 BSC		
b	0.20	0.25	0.30
e	0.40 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.10

52. 81-Ball WLCSP Package

Dimensions in Millimeters



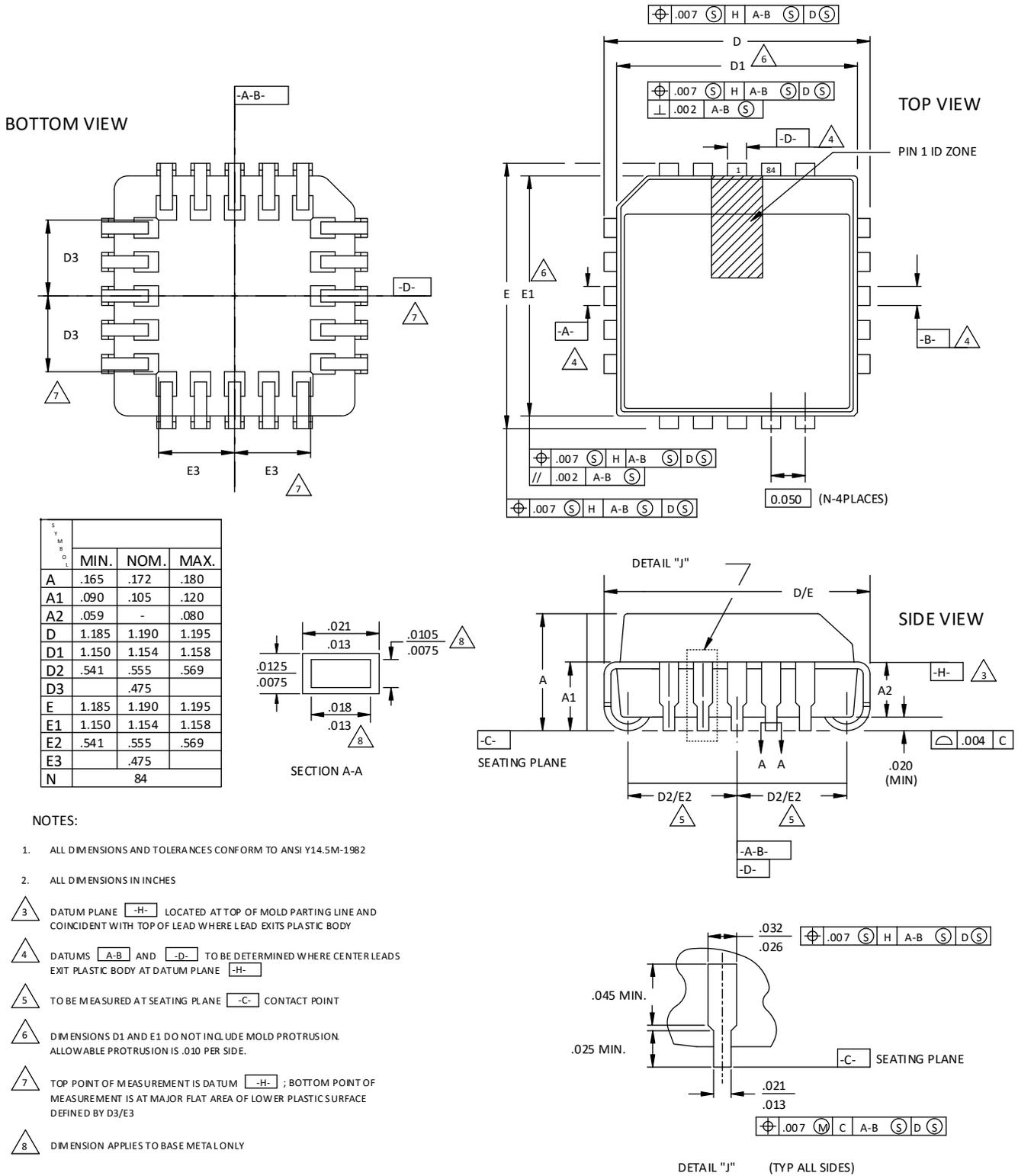
Notes:

1. ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M - 1994.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DIMENSION “b” IS MEASURED AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM [C].
4. PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.
5. BILLATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
7. JEDEC REFERENCE JEP95 DG 4.18.

REF.	Min.	Nom.	Max.
A	0.502	0.541	0.580
A1	0.164	0.194	0.224
A2	0.322 ±0.025		
A3	0.025		
b	0.200	0.250	0.300
D	3.792 BSC		
E	3.688 BSC		
D1	3.20 BSC		
E1	3.20 BSC		
e	0.40 BSC		
aaa	0.030		
ccc	0.050		
ddd	0.015		

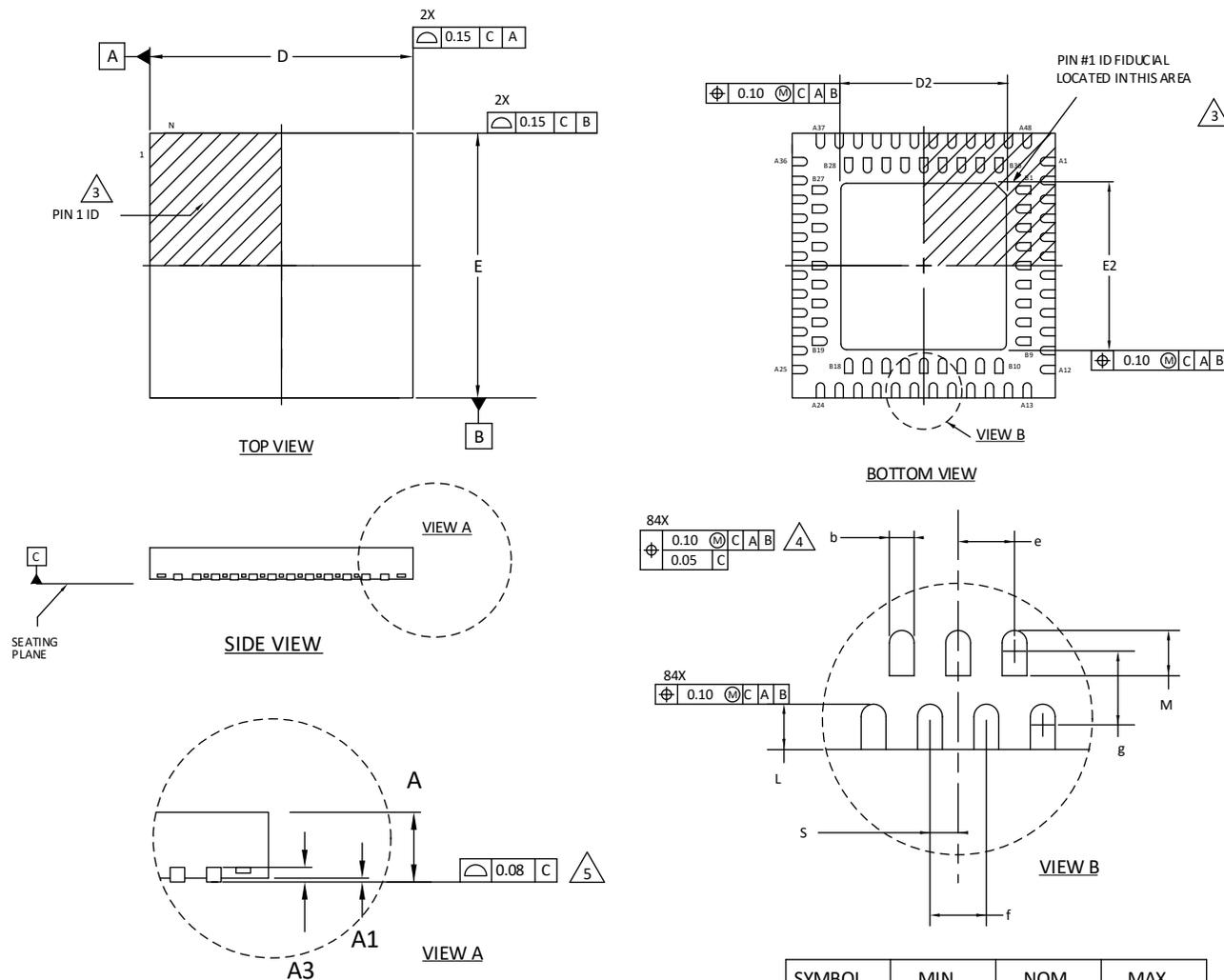
54. 84-Pin PLCC Package

Dimensions in Inches



55. 84-Pin QFN Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.

EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

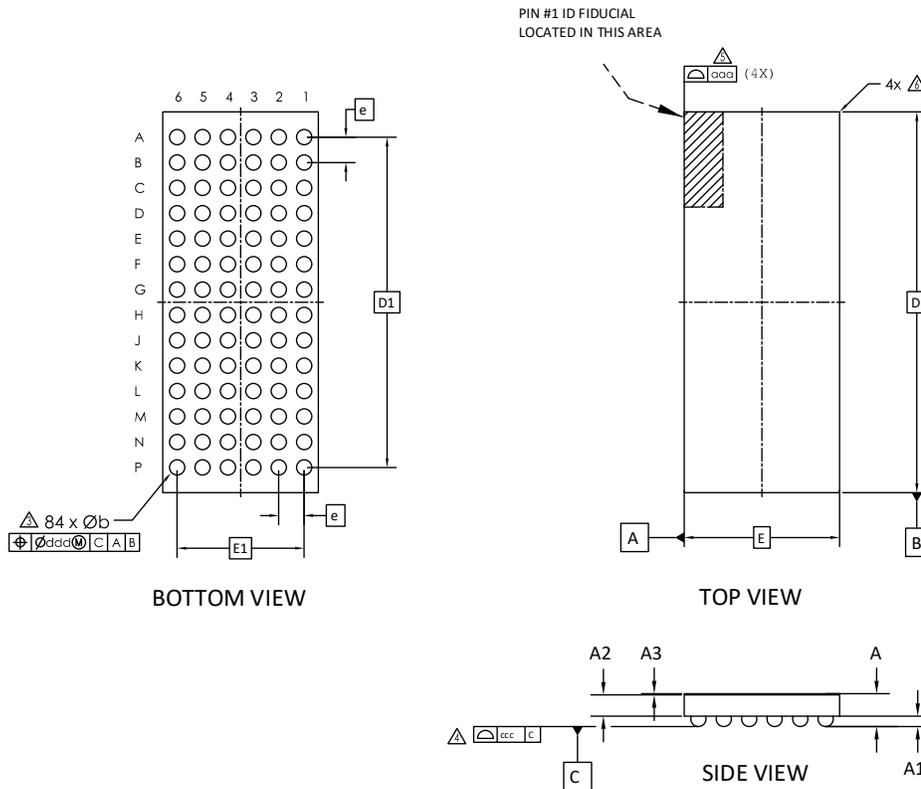
DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.

APPLIES TO EXPOSED PORTION OF TERMINALS.

SYMBOL	MIN.	NOM.	MAX.
A	0.75	0.85	0.95
A1	0.00	0.02	0.05
A3	0.15 REF		
D	7.0 BSC		
D2	4.30	-	4.50
E	7.0 BSC		
E2	4.30	-	4.50
b	0.17	0.22	0.27
e	0.50 BSC		
f	0.50 BSC		
g	0.65 BSC		
s	0.25 BSC		
L	0.30	0.40	0.50
M	0.30	0.40	0.50

56. 84-Ball USG/WLCSP Package (7.492 mm x 3.054 mm Body)

Dimensions in Millimeters



NOTES:

- 1 DIMENSIONS AND TOLERANCES PER ASME Y14.5M - 1994.
- 2 ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

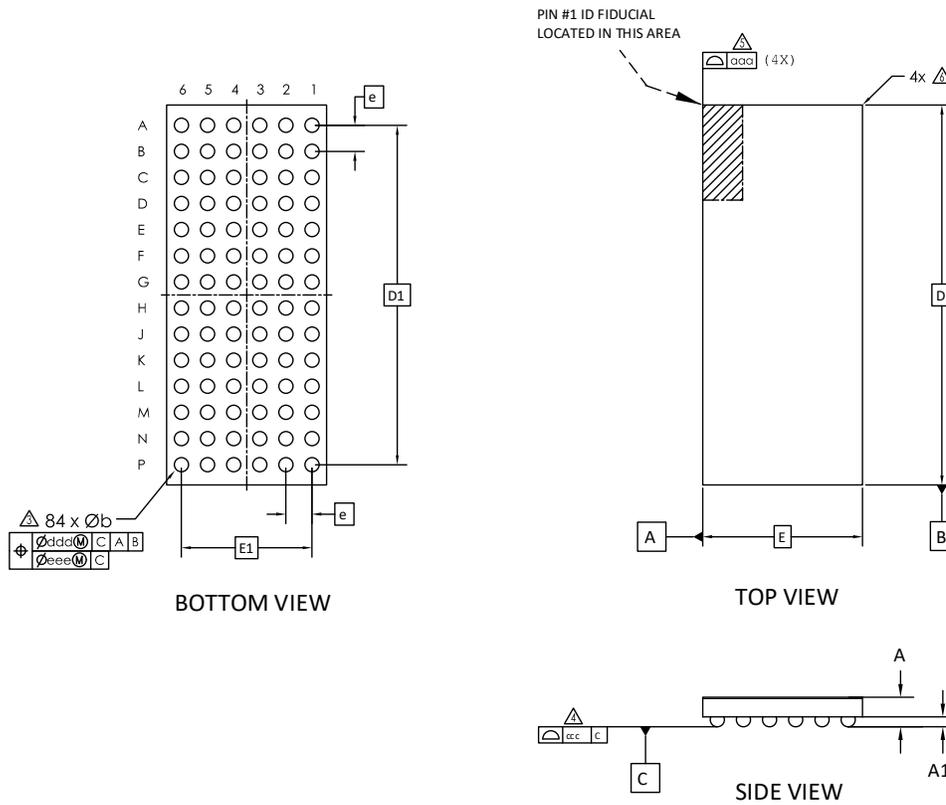
- 7 JEDEC REFERENCE JEP95 DG 4.18

REF	MIN.	NOM.	MAX.
A	0.572	0.611	0.650
A1	0.206	0.236	0.266
A2	0.350 ±0.025		
A3	0.025		
b	0.250	0.300	0.350
D	7.492 BSC		
E	3.054 BSC		
D1	6.50 BSC		
E1	2.50 BSC		
e	0.50 BSC		
aaa	0.030		
ccc	0.050		
ddd	0.015		

**This Package Outline Drawing and related information apply to CrossLinkU™-NX devices.*

57. 84-Ball USG/WLCSP Package (7.275 mm x 3.054 mm Body)

Dimensions in Millimeters



NOTES:

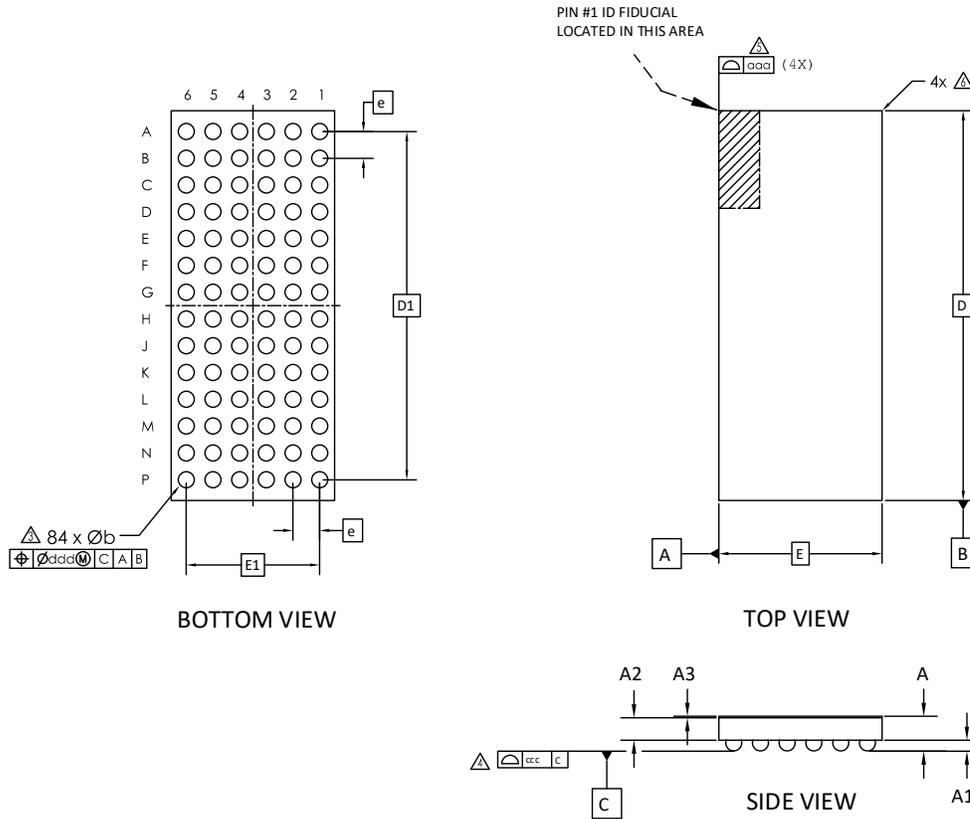
- 1 DIMENSIONS AND TOLERANCES PER ASME Y14.5M - 1994.
- 2 ALL DIMENSIONS ARE IN MILLIMETERS.
- 3 DIMENSION "b" IS MEASURED AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM $\square C$
- 4 PRIMARY DATUM $\square C$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.
- 5 BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
- 6 EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
- 7 JEDEC REFERENCE JEP95 DG 4.18

REF	MIN.	NOM.	MAX.
A	-	-	0.608
A1	0.164	-	-
b	0.200	0.250	0.300
D	7.275 BSC		
E	3.054 BSC		
D1	6.50 BSC		
E1	2.50 BSC		
e	0.50 BSC		
aaa	0.030		
ccc	0.050		
ddd	0.050		
eee	0.015		

**This Package Outline Drawing and related information apply to CrossLink™-NX-33 devices.*

58. 84-Ball USG/WLCSP Package Option 1 (7.275 mm x 3.054 mm Body)

Dimensions in Millimeters



NOTES:

- 1 DIMENSIONS AND TOLERANCES PER ASME Y14.5M - 1994.
- 2 ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM **C**



PRIMARY DATUM **C** AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

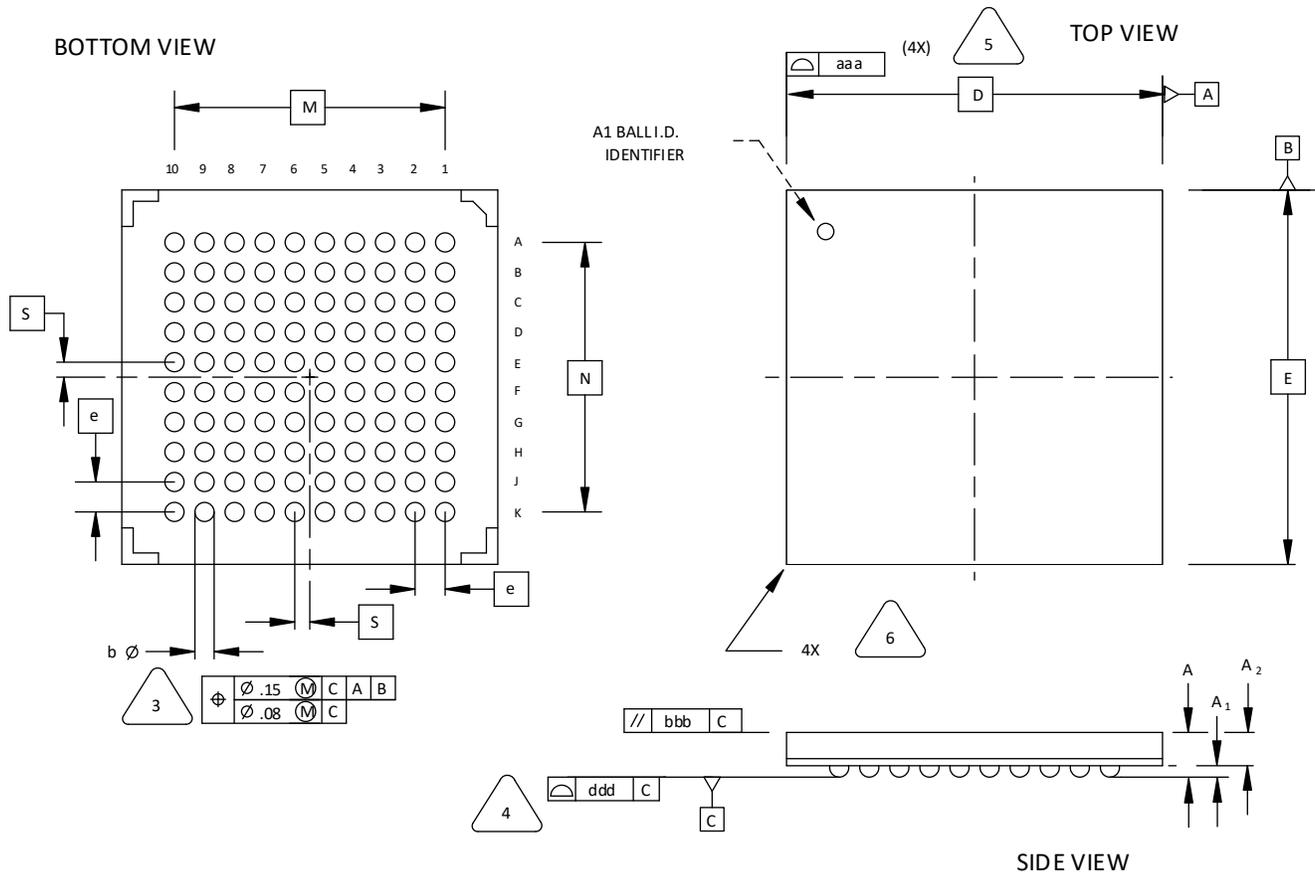
- 7 JEDEC REFERENCE JEP95 DG 4.18

REF	MIN.	NOM.	MAX.
A	0.572	0.611	0.650
A1	0.206	0.236	0.266
A2	0.350 ±0.025		
A3	0.025		
b	0.250	0.300	0.350
D	7.275 BSC		
E	3.054 BSC		
D1	6.50 BSC		
E1	2.50 BSC		
e	0.50 BSC		
aaa	0.030		
ccc	0.050		
ddd	0.015		

**This Package Outline Drawing and related information apply to CrossLink-NX-33 devices. This version is for a specific customer only.*

59. 100-Ball caBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM \square C



PRIMARY DATUM \square C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

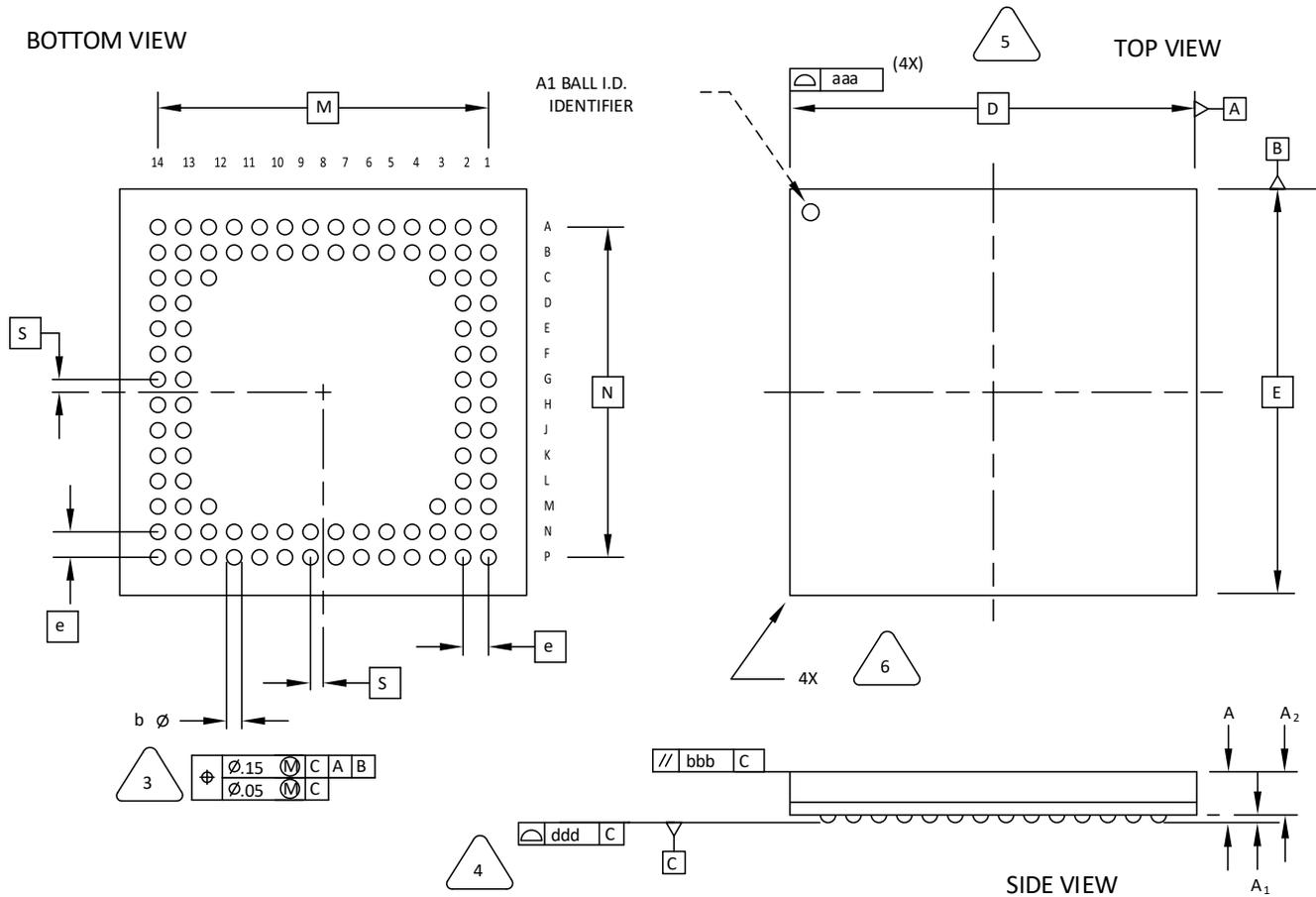


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.30	1.40	1.50
A1	0.31	0.36	0.41
A2	0.99	1.04	1.09
D/E	10.00 BSC		
M/N	7.20 BSC		
S	0.40 BSC		
b	0.40	0.46	0.52
e	0.80 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.12

60. 100-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

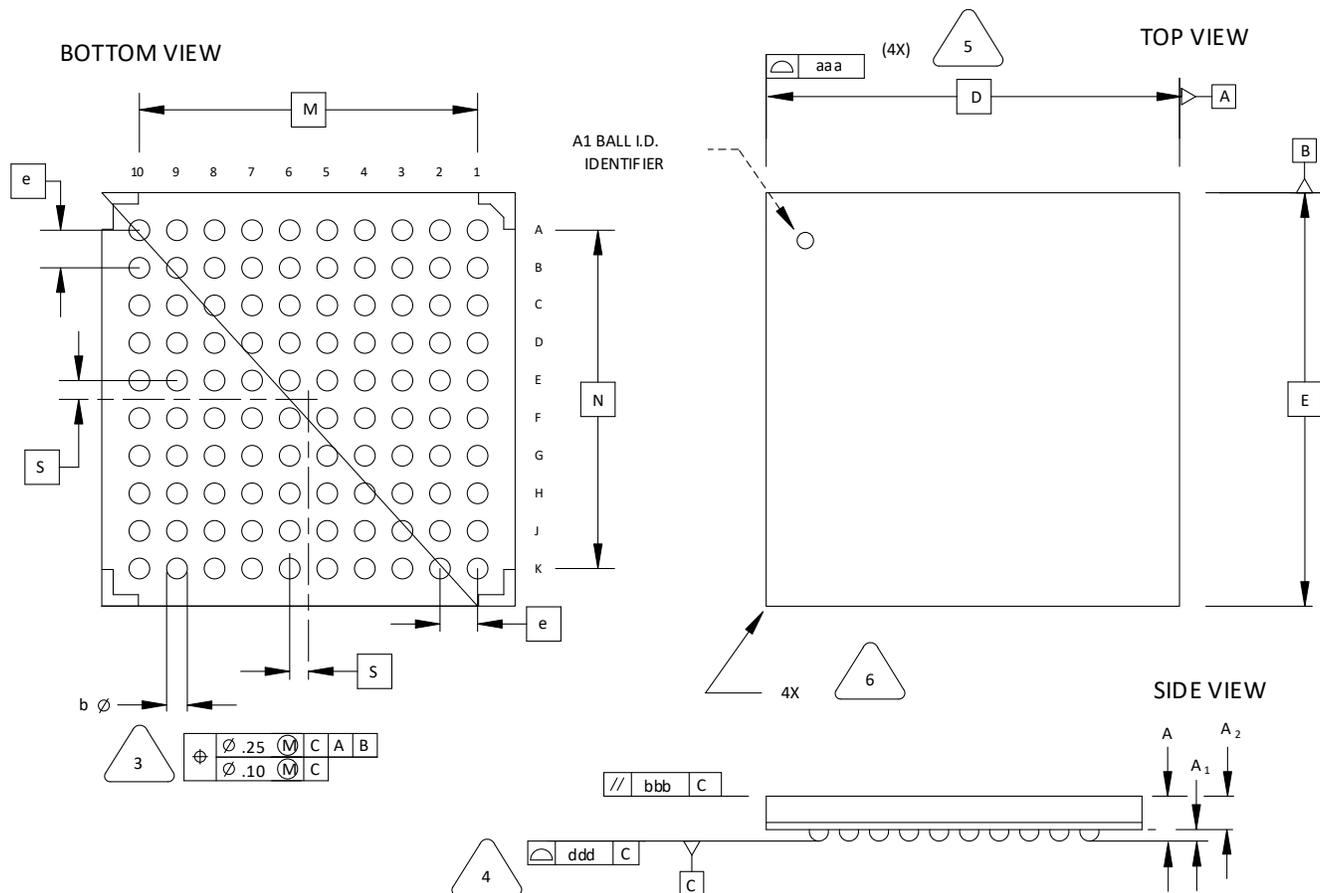


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	0.90	1.23	1.35
A1	0.15	-	-
A2	-	-	1.10
D/E	8.00 BSC		
M/N	6.50 BSC		
S	0.25 BSC		
b	0.25	0.30	0.35
e	0.50 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.08

61. 100-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM $\square C$



PRIMARY DATUM $\square C$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

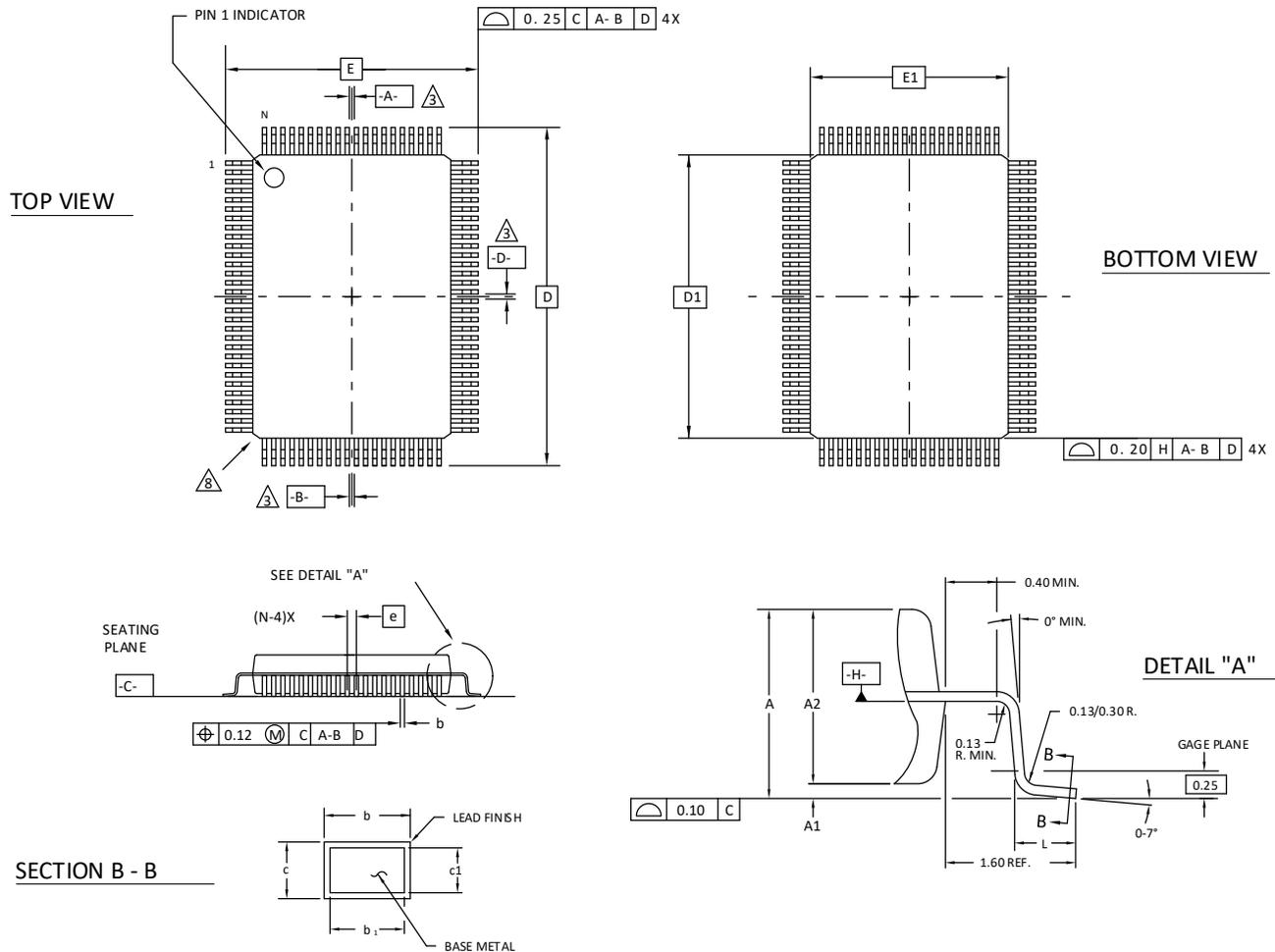


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.30	1.50	1.70
A1	0.30	0.50	0.70
A2	1.10 REF		
D/E	11.00 BSC		
M/N	9.00 BSC		
S	0.50 BSC		
b	0.40	0.55	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ddd	-	-	0.20

62. 100-Pin PQFP Package

Dimensions in Millimeters



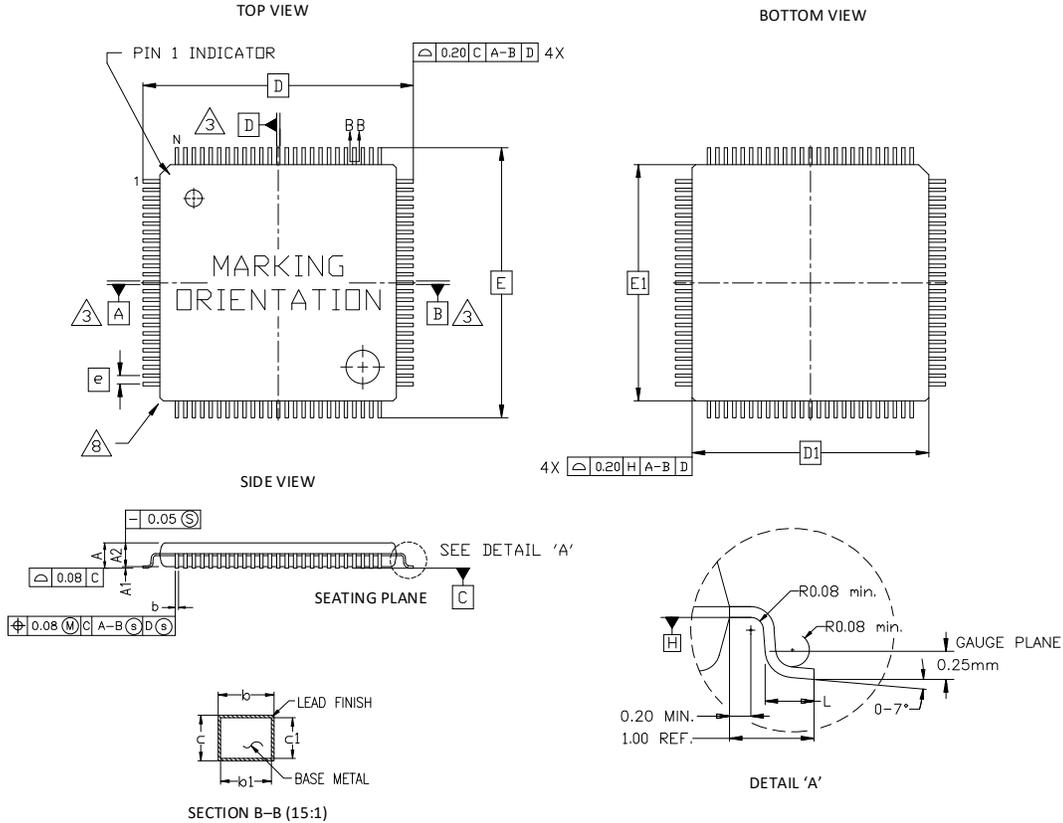
NOTES:

1. 0 DIMENSIONING AND TOLERANCING PER ANSI Y14.5 - 1982.
2. 0 ALL DIMENSIONS ARE IN MILLIMETERS.
3. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
4. 0 DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
5. 0 THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
6. 0 SECTION B-B: THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
7. 0 A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
8. EXACT SHAPE OF EACH CORNER IS OPTIONAL.
9. EXACT SHAPE OF EXPOSED HEATSINK IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	3.40
A1	0.25	-	0.50
A2	2.50	2.70	2.90
D	23.20 BSC		
D1	20.00 BSC		
E	17.20 BSC		
E1	14.00 BSC		
L	0.73	0.88	1.03
N	100		
e	0.65 BSC		
b	0.22	-	0.40
b1	0.22	0.30	0.36
c	0.11	-	0.23
c1	0.11	0.15	0.19

63. 100-Pin LQFP/TQFP Package Option 1: MachXO3, MachXO2, MachXO™, ispMACH® 4000

Dimensions in Millimeters



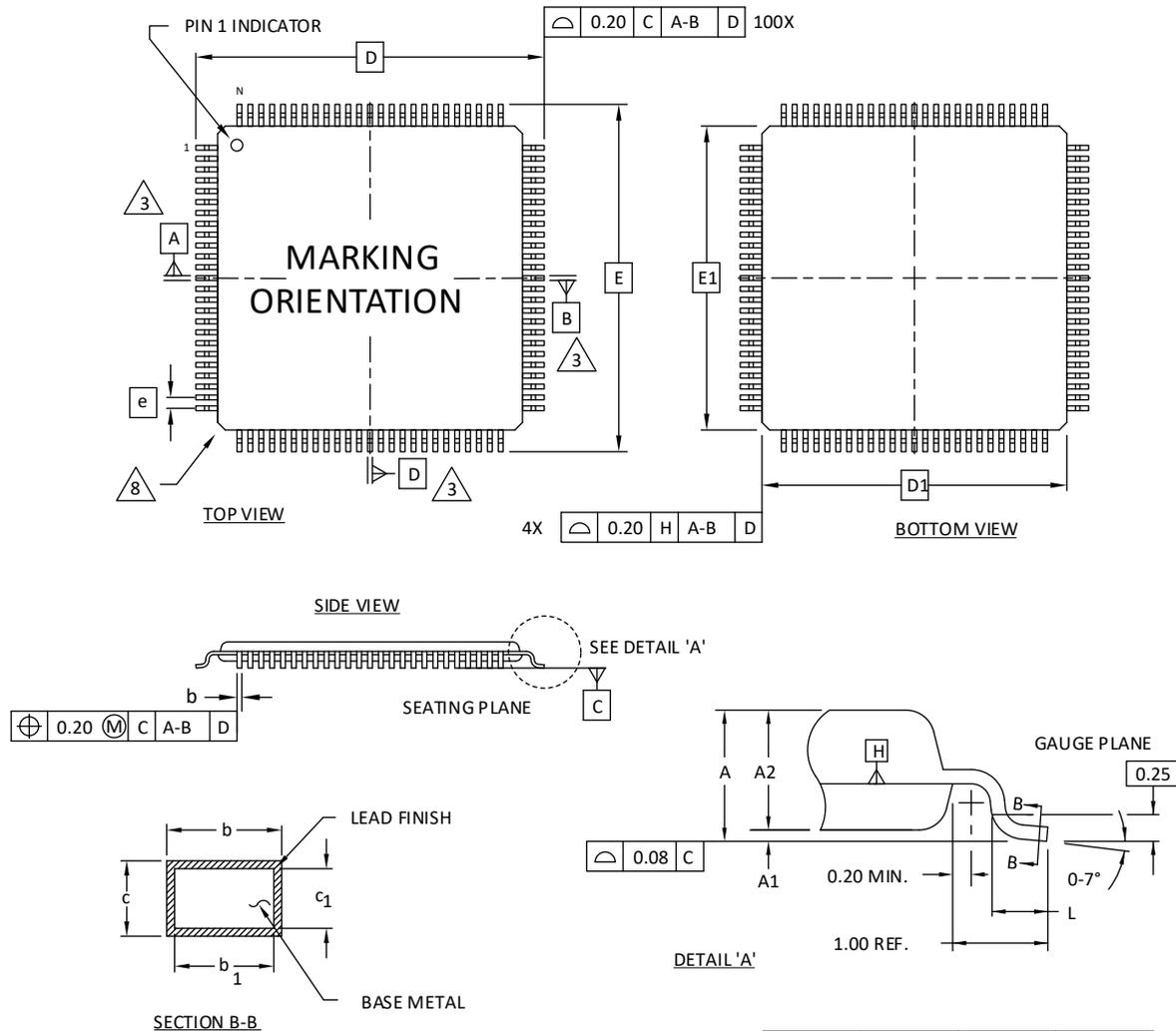
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 - 1982.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
5. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
6. SECTION B-B:
THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
7. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
8. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.40	1.50	1.60
A1	0.05	0.10	0.15
A2	1.35	1.40	1.45
D	16.00 BSC		
D1	14.00 BSC		
E	16.00 BSC		
E1	14.00 BSC		
L	0.45	0.60	0.75
N	100		
e	0.50 BSC		
b	0.17	0.22	0.27
b1	0.17	0.20	0.23
c	0.09	—	0.20
c1	0.09	—	0.16

64. 100-Pin VQFP Package Option 2: iCE40

Dimensions in Millimeters



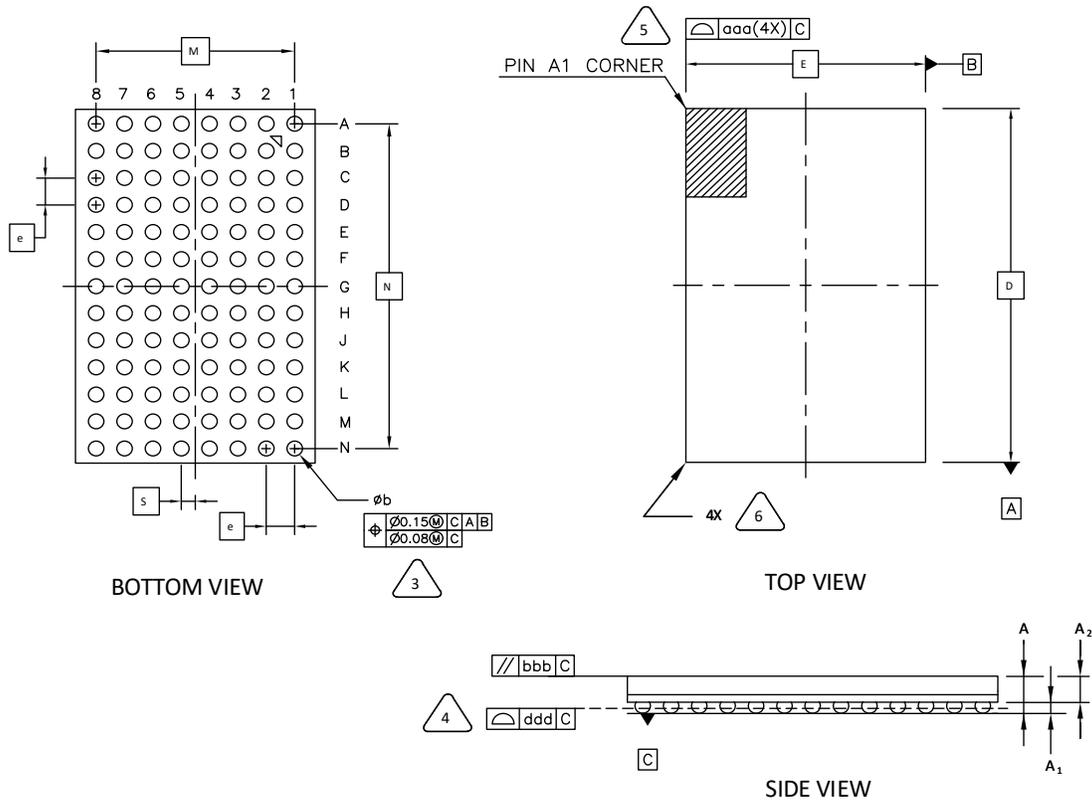
NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5 - 1982.
- ALL DIMENSIONS ARE IN MILLIMETERS.
- DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
- DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- SECTION B-B:
THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
- EXACT SHAPE OF EACH CORNER IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.20
A1	0.05	-	0.15
A2	0.95	1.00	1.05
D	16.00 BSC		
D1	14.00 BSC		
E	16.00 BSC		
E1	14.00 BSC		
L	0.45	0.60	0.75
N	100		
e	0.50 BSC		
b	0.17	0.22	0.27
b1	0.17	0.20	0.23
c	0.09	0.15	0.20
c1	0.09	0.13	0.16

65. 104-Ball CTG/fcCSP Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.



3. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



4. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



5. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

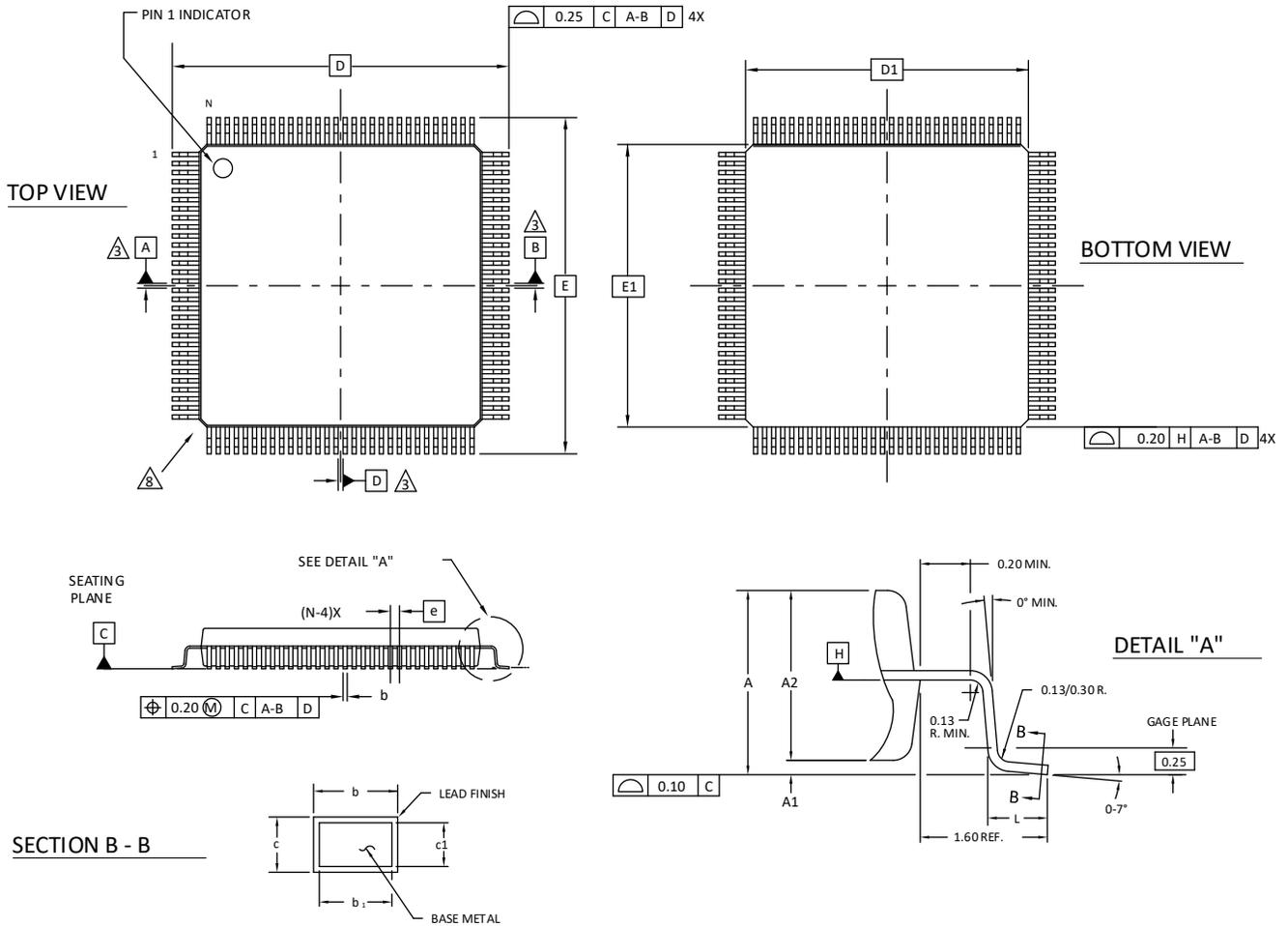
7. JEDEC REFERENCE JEP95 DR 4.5

REF	MIN.	NOM.	MAX.
A	0.826	0.896	0.966
A1	0.220	0.270	0.320
A2	0.546	0.626	0.706
E	5.5 BSC		
D	8.5 BSC		
M	4.55 BSC		
N	7.80 BSC		
S	0.325		
b	0.30	0.35	0.40
e	0.65 BSC		
aaa	0.15		
bbb	0.20		
ddd	0.10		

**This Package Outline Drawing and related information apply to CrossLinkU-NX devices.*

66. 120-Pin PQFP Package

Dimensions in Millimeters



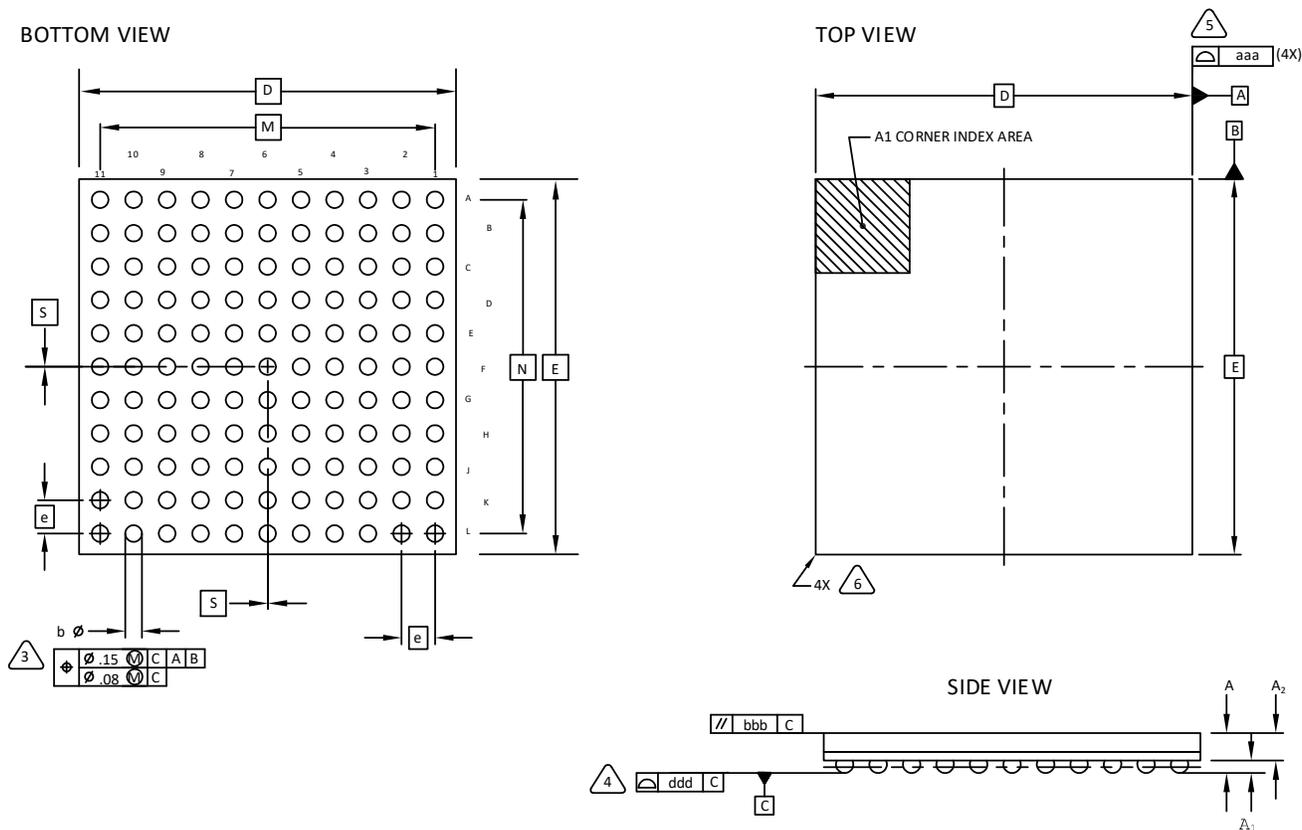
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 - 1982.
 2. ALL DIMENSIONS ARE IN MILLIMETERS.
 3. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
 4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
 5. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
 6. SECTION B-B: THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
 7. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
8. EXACT SHAPE OF EACH CORNER IS OPTIONAL.
9. EXACT SHAPE OF EXPOSED HEATSINK IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	4.10
A1	0.25	-	0.50
A2	3.20	3.40	3.60
D	31.20 BSC		
D1	28.00 BSC		
E	31.20 BSC		
E1	28.00 BSC		
L	0.73	0.88	1.03
N	120		
e	0.80 BSC		
b	0.29	-	0.45
b1	0.29	0.35	0.41
c	0.11	-	0.23
c1	0.11	0.15	0.19

67. 121-Ball caBGA Package (9 mm x 9 mm Body)

Dimensions in Millimeters



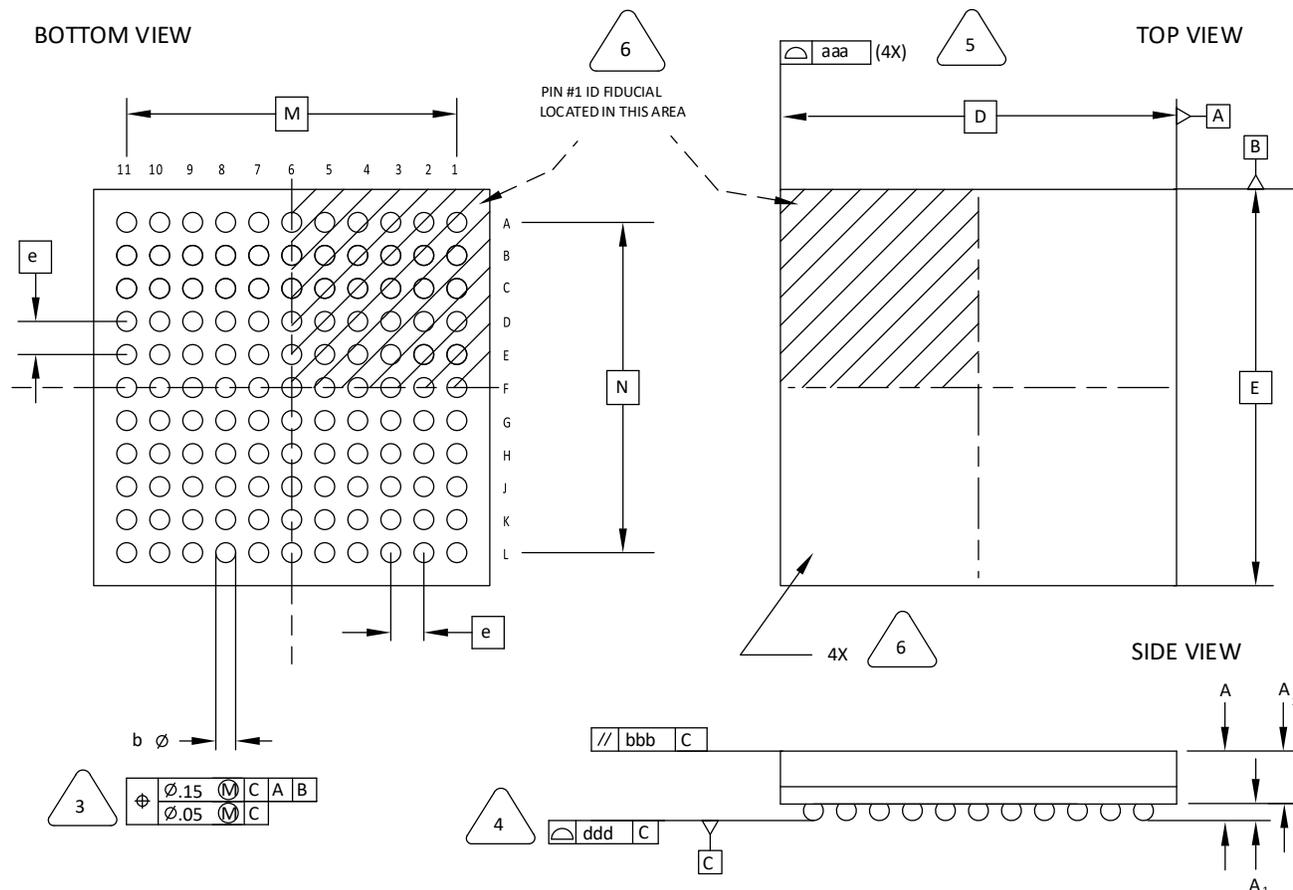
NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14. 5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
4. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	—	—	1.10
A1	0.15	—	—
A2	0.55	—	—
D/E	9.00 BSC		
M/N	8.00 BSC		
S	0.00 BSC		
b	0.30	0.40	0.50
e	0.80 BSC		
aaa	0.15		
bbb	0.20		
ddd	0.10		

68. 121-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

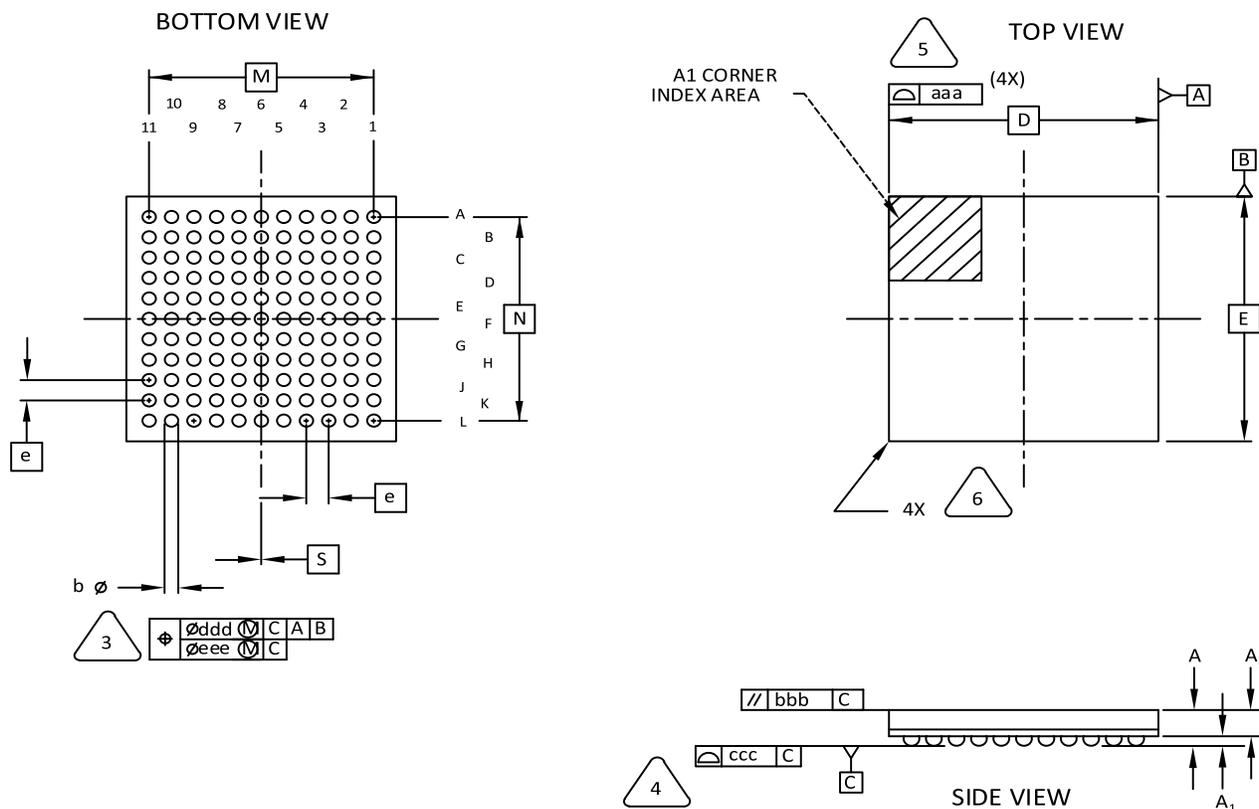


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.00
A1	0.10	-	-
A2	-	-	0.90
D/E	6.00 BSC		
M/N	5.00 BSC		
b	0.20	0.25	0.30
e	0.50 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.10

69. 121-Ball csfBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C].



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



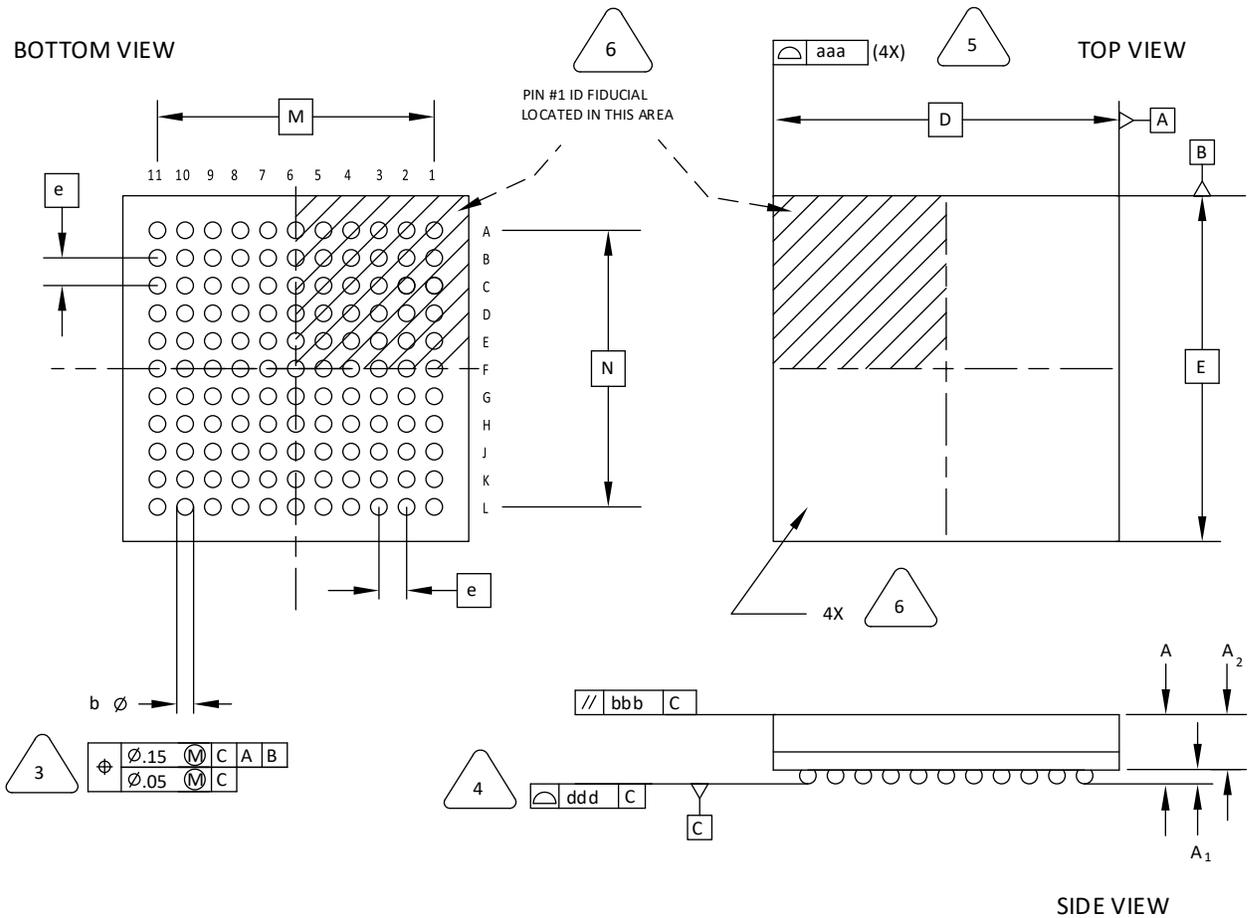
EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.00
A1	0.15	0.24	-
A2	-	0.66	-
D/E	6.00 BSC		
M/N	5.00 BSC		
S	0.00 BSC		
b	0.25	0.30	0.35
e	0.50 BSC		
aaa	0.10		
bbb	0.10		
ccc	0.08		
ddd	0.15		
eee	0.05		

*This Package Outline Drawing and related information apply to CrossLink-NX and Certus™-NX devices.

70. 121-Ball ucBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

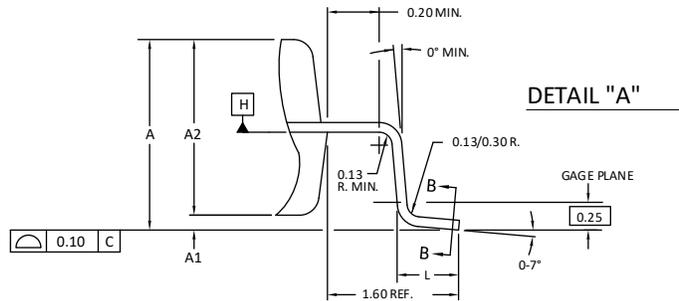
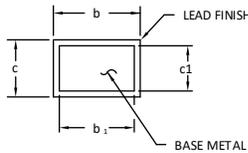
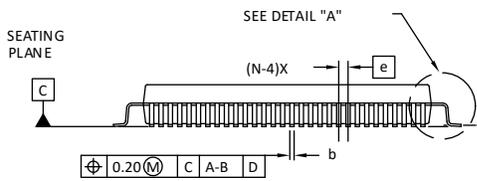
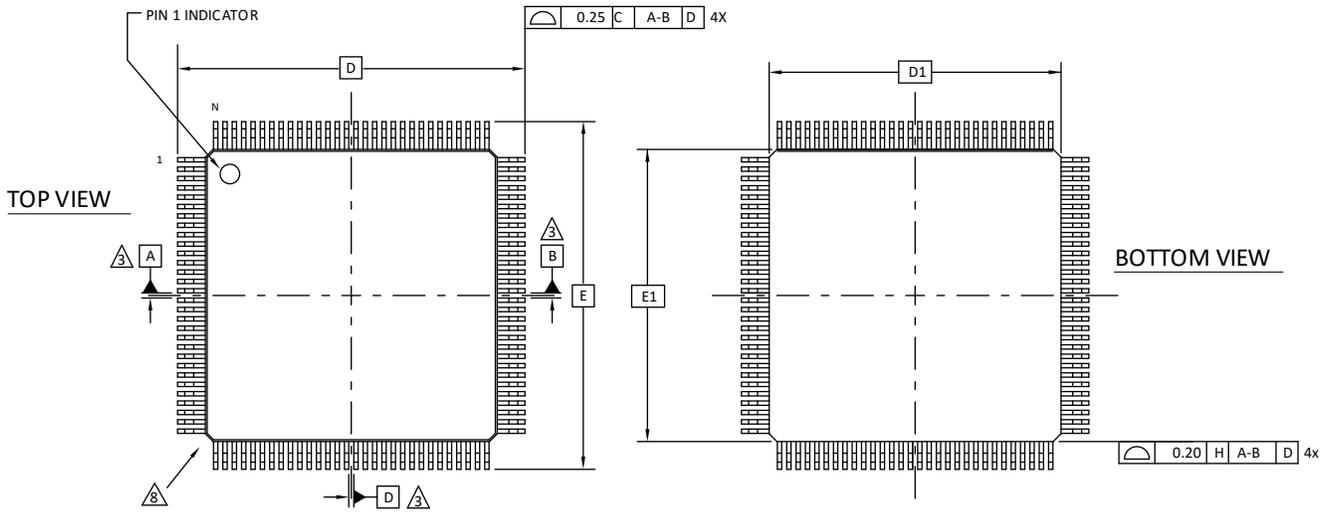


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.00
A1	0.10	-	-
A2	-	-	0.90
D/E	5.00 BSC		
M/N	4.00 BSC		
b	0.20	0.25	0.30
e	0.40 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.10

71. 128-Pin PQFP Package

Dimensions in Millimeters



SECTION B - B

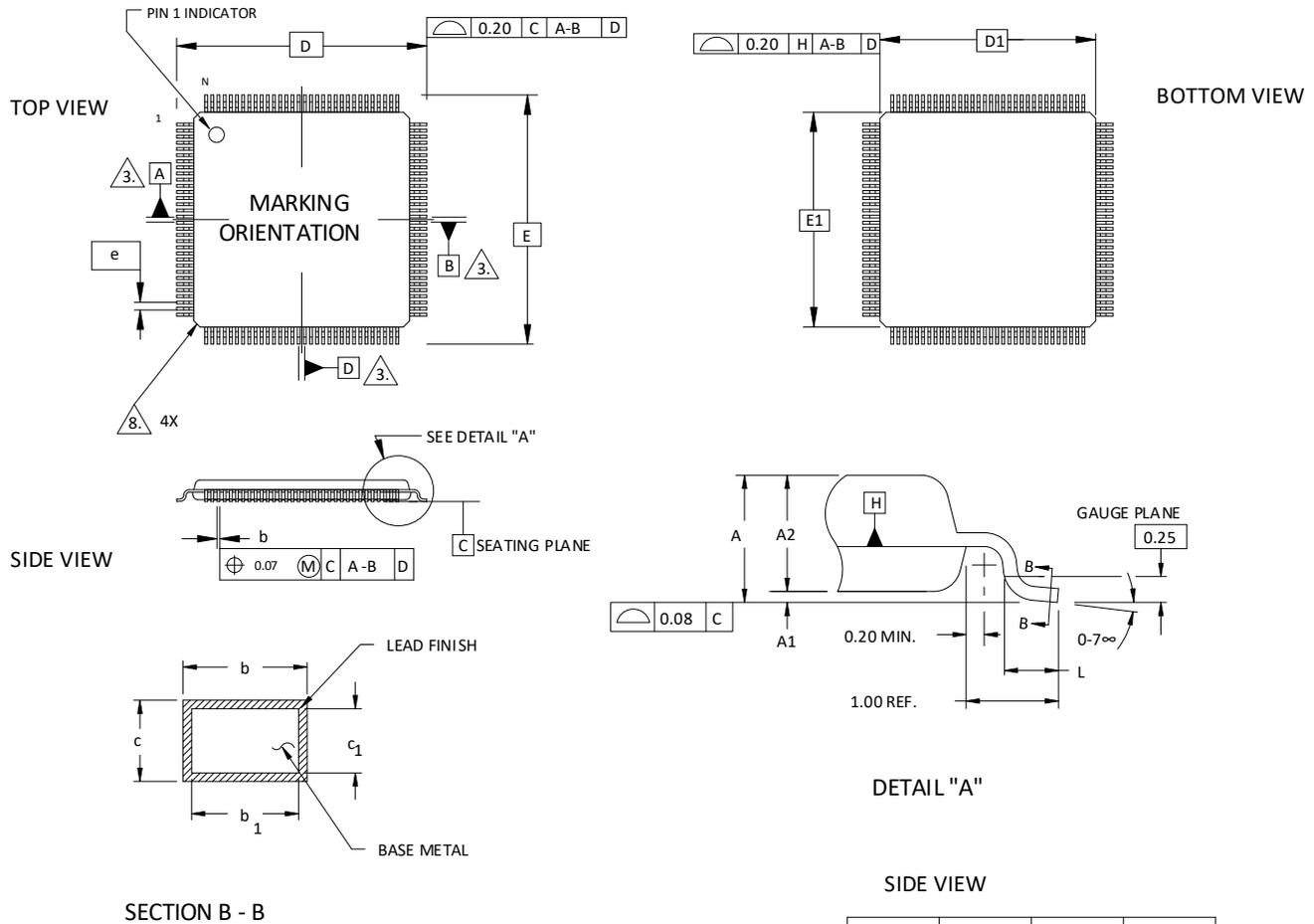
NOTES:

1. 0 DIMENSIONING AND TOLERANCING PER ANSI Y14.5 - 1982.
 2. 0 ALL DIMENSIONS ARE IN MILLI METERS.
 3. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
 4. 0 DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
 5. 0 THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
 6. 0 SECTION B-B: THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
 7. 0 A1 IS DERNED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
8. EXACT SHAPE OF EACH CORNER IS OPTIONAL.
9. EXACT SHAPE OF EXPOSED HEATSINK IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	4.10
A1	0.25	-	0.50
A2	3.20	3.40	3.60
D	31.20 BSC		
D1	28.00 BSC		
E	31.20 BSC		
E1	28.00 BSC		
L	0.73	0.88	1.03
N	128		
e	0.80 BSC		
b	0.29	-	0.45
b1	0.29	0.35	0.41
c	0.11	-	0.23
c1	0.11	0.15	0.19

72. 128-Pin LQFP Package

Dimensions in Millimeters



NOTES:

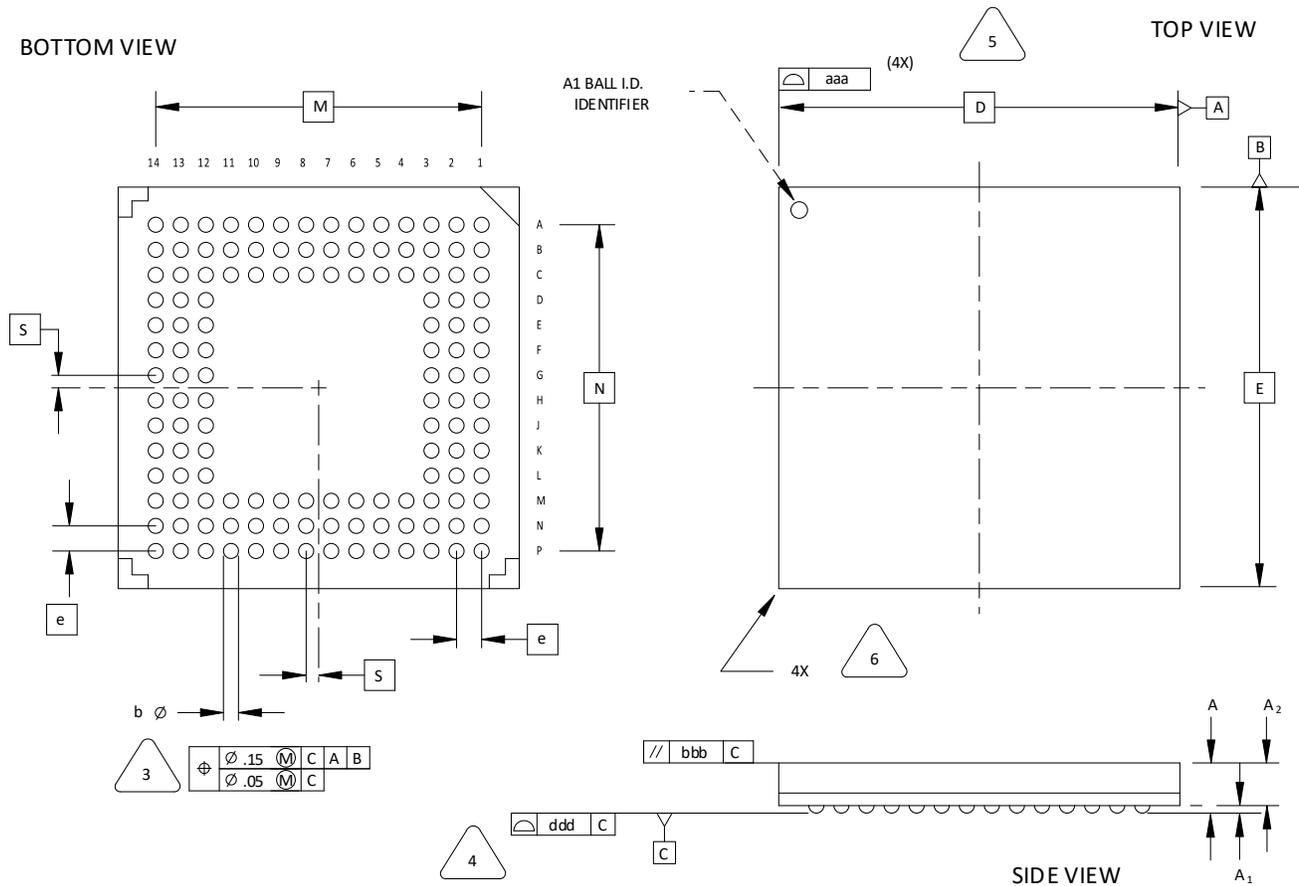
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 - 1982.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
5. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
6. SECTION B-B:
THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
7. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
8. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

SIDE VIEW

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.60
A1	0.05	-	0.15
A2	1.35	1.40	1.45
D	16.00 BSC		
D1	14.00 BSC		
E	16.00 BSC		
E1	14.00 BSC		
L	0.45	0.60	0.75
N	128		
e	0.40 BSC		
b	0.13	0.18	0.23
b1	0.13	0.16	0.19
c	0.09	0.15	0.20
c1	0.09	0.13	0.16

73. 132-Ball csBGA Package Option 1: MachXO2, MachXO, LatticeXP2™

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM **C**.



PRIMARY DATUM **C** AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

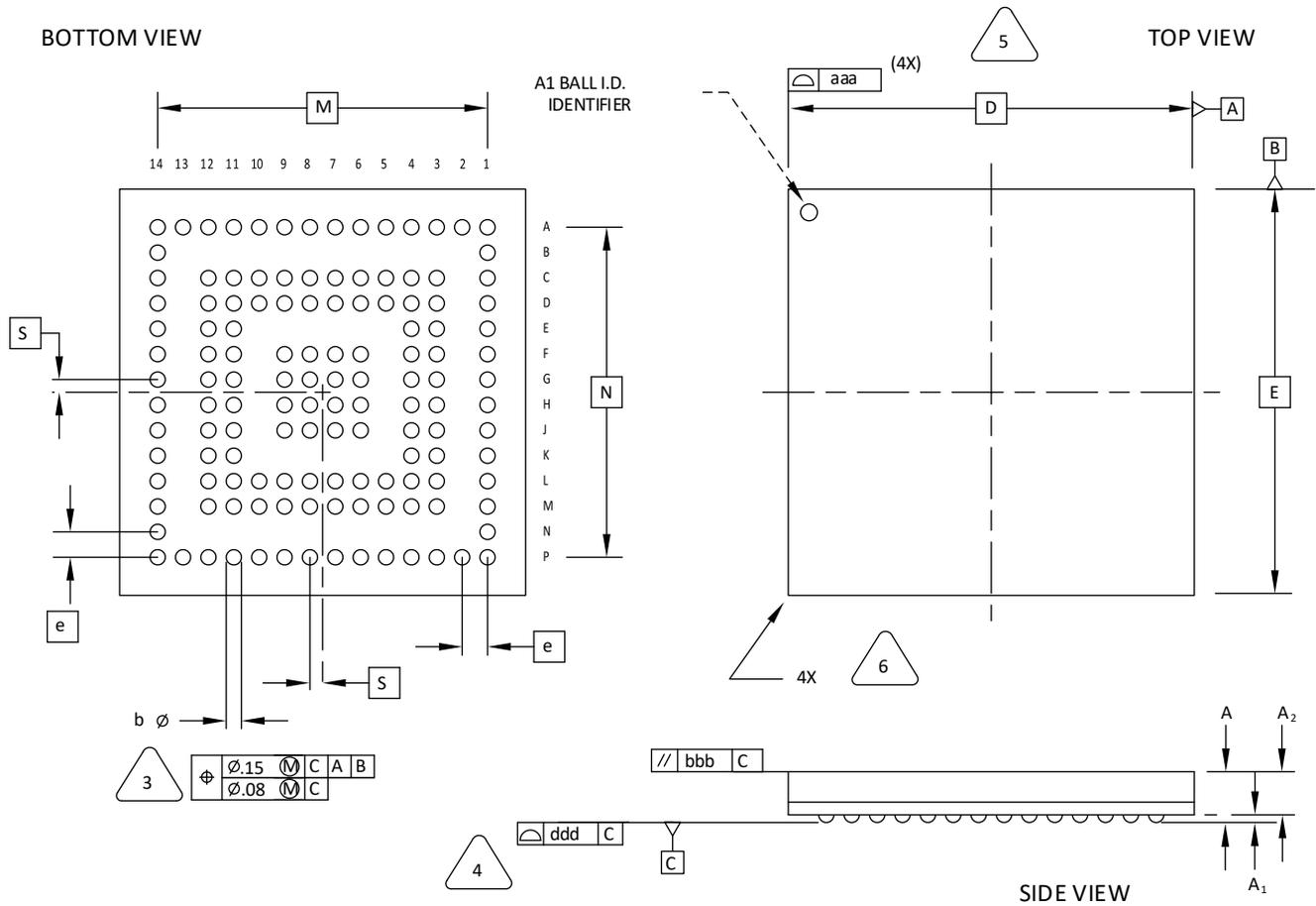


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	0.90	1.23	1.35
A1	0.15	-	-
A2	-	-	1.10
D/E	8.00 BSC		
M/N	6.50 BSC		
S	0.25 BSC		
b	0.25	0.30	0.35
e	0.50 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.08

74. 132-Ball csBGA Package Option 2: iCE40

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM \square C.



PRIMARY DATUM \square C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



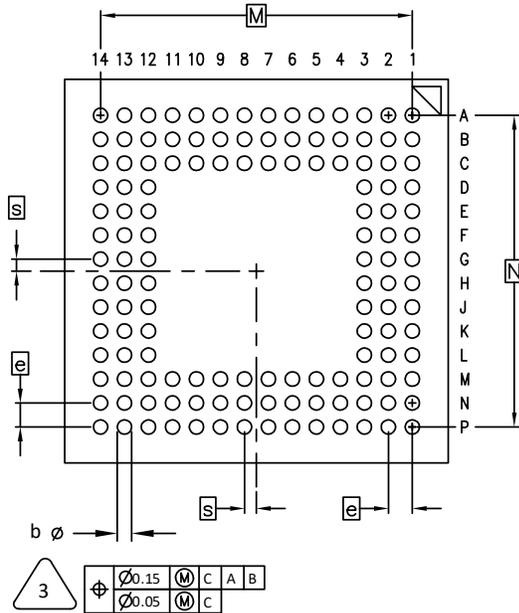
EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.00
A1	0.15	-	-
A2	-	-	0.85
D/E	8.00 BSC		
M/N	6.50 BSC		
S	0.25 BSC		
b	0.25	0.30	0.35
e	0.50 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.08

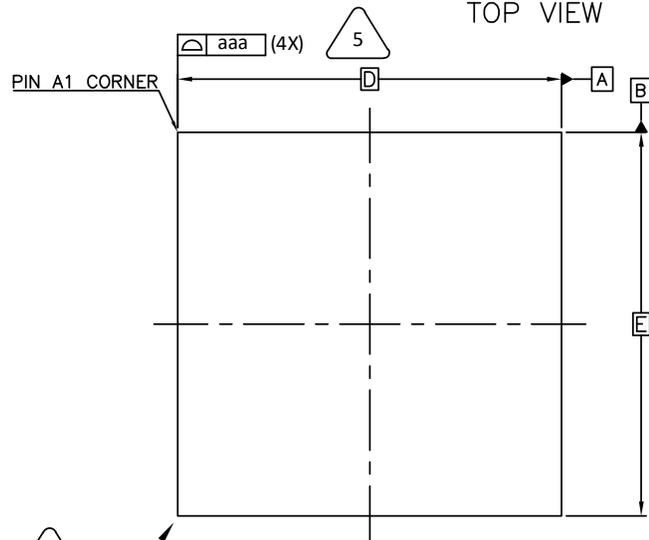
75. 132-Ball csBGA Package Option 3

Dimensions in Millimeters

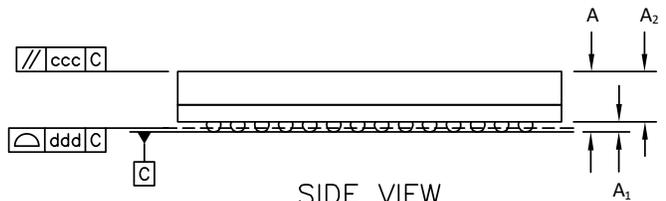
BOTTOM VIEW



TOP VIEW



SIDE VIEW



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

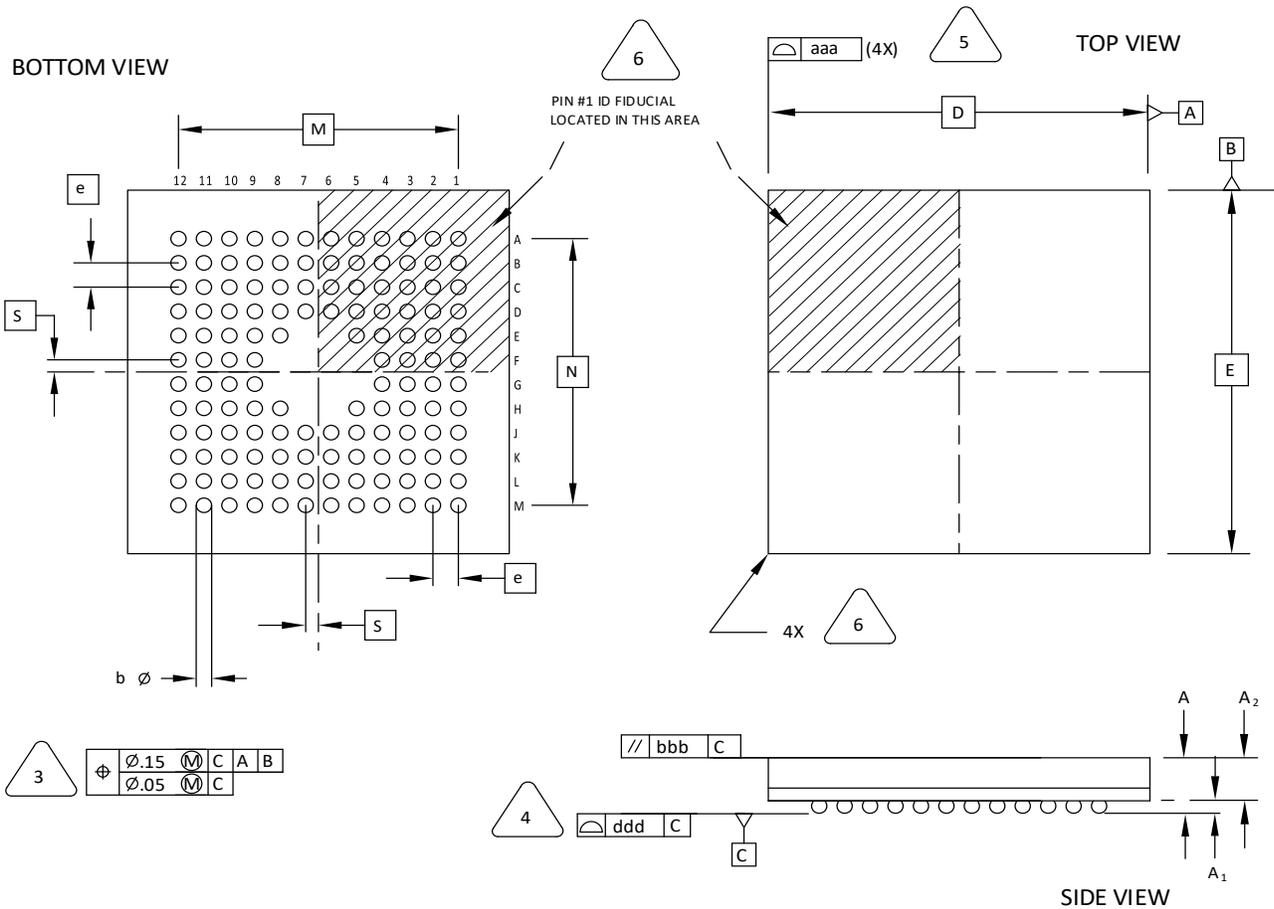
- JEDEC REFERENCE: JEP95 DR4.5

SYMBOL	MIN.	NOM.	MAX.
A	1.186	1.262	1.338
A1	0.160	0.210	0.260
A2	0.972	1.052	1.132
D/E	8.00 BSC		
M/N	6.50 BSC		
S	0.25 BSC		
b	0.27	0.32	0.37
e	0.50 BSC		
aaa	0.15		
ccc	0.20		
ddd	0.08		

**This Package Outline Drawing and related information apply to MachXO2 and MachXO3 automotive devices.*

76. 132-Ball ucBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM \boxed{C}



PRIMARY DATUM \boxed{C} AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

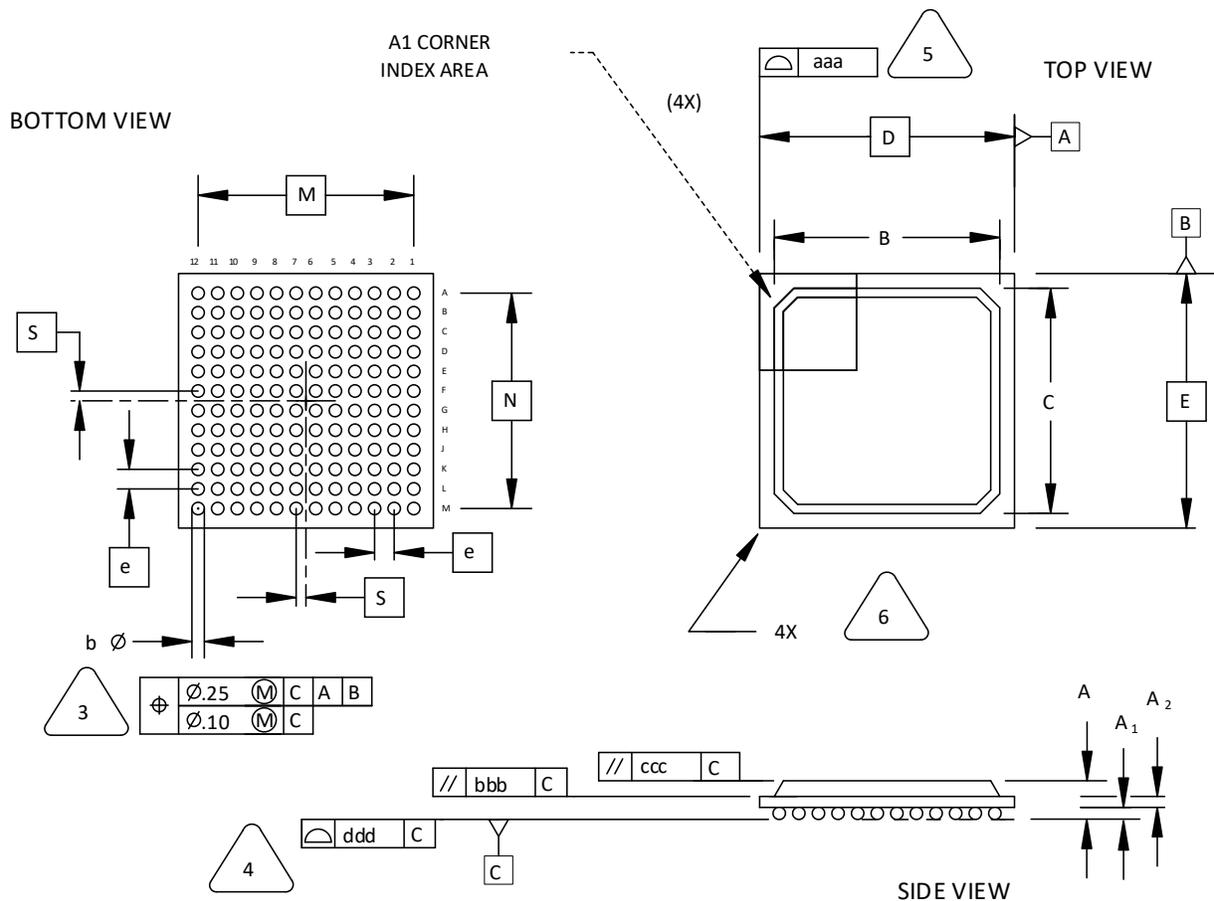


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.00
A1	0.10	-	-
A2	-	-	0.90
D/E	6.00 BSC		
M/N	4.40 BSC		
S	0.20 BSC		
b	0.20	0.25	0.30
e	0.40 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.08

79. 144-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM $\square C$



PRIMARY DATUM $\square C$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

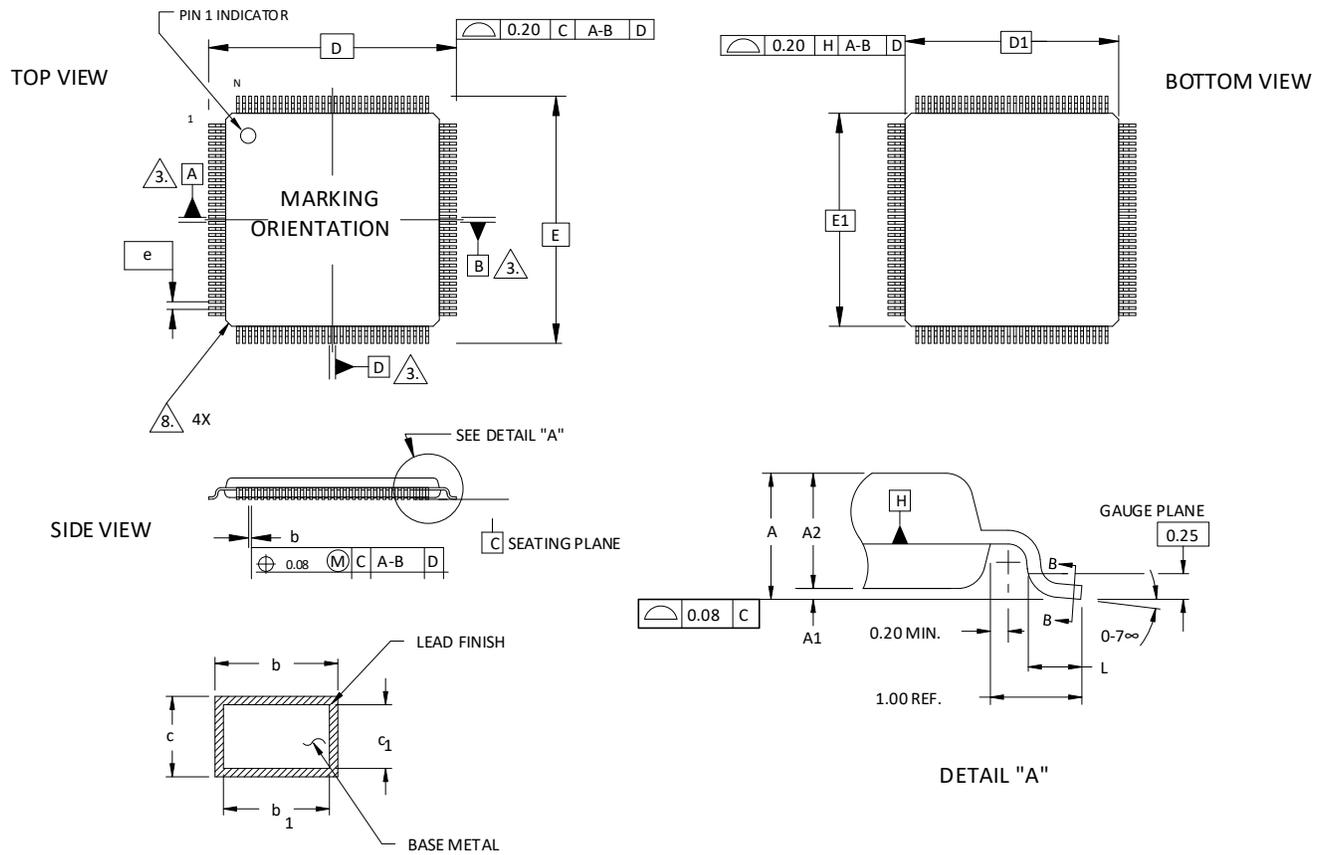


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.30	1.70	2.10
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	11.00	11.60	12.20
D/E	13.00 BSC		
M/N	11.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

80. 144-Pin LQFP/TQFP Package

Dimensions in Millimeters



SECTION B - B

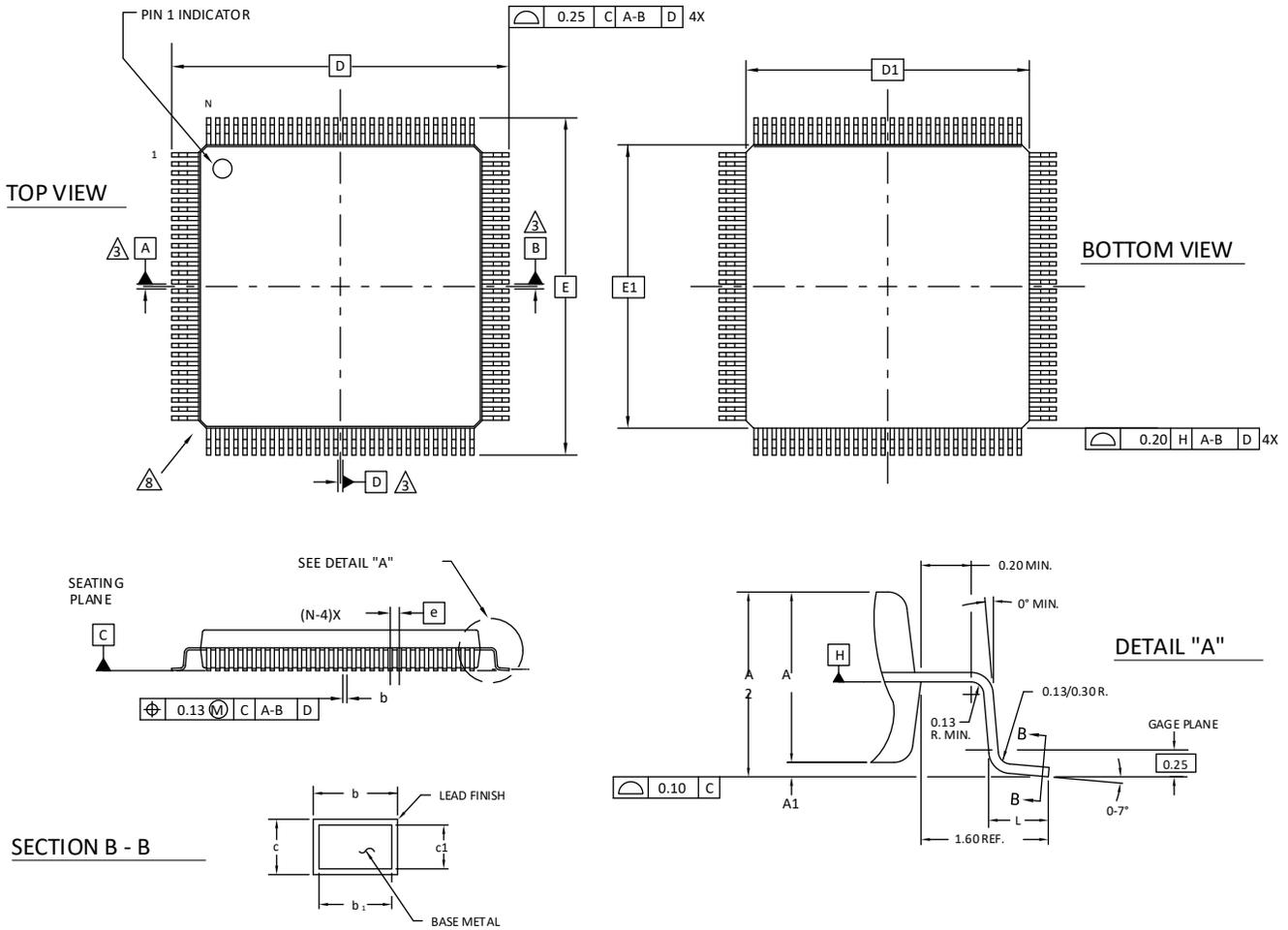
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 - 1982.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
5. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
6. SECTION B-B:
THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
7. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
8. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.60
A1	0.05	-	0.15
A2	1.35	1.40	1.45
D	22.00 BSC		
D1	20.00 BSC		
E	22.00 BSC		
E1	20.00 BSC		
L	0.45	0.60	0.75
N	144		
e	0.50 BSC		
b	0.17	0.22	0.27
b1	0.17	0.20	0.23
c	0.09	0.15	0.20
c1	0.09	0.13	0.16

81. 160-Pin PQFP Package

Dimensions in Millimeters



NOTES:

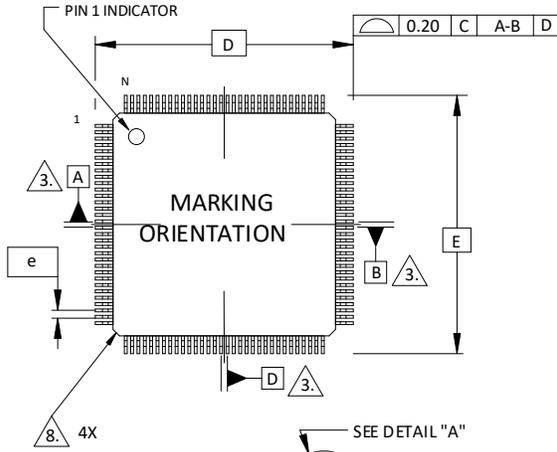
- 0 DIMENSIONING AND TOLERANCING PER ANSI Y 14.5 - 1982.
- 0 ALL DIMENSIONS ARE IN MILLIMETERS.
- DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
- 0 DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- 0 THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 0 SECTION B-B: THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- 0 A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
- EXACT SHAPE OF EACH CORNER IS OPTIONAL.
- EXACT SHAPE OF EXPOSED HEATSINK IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	4.10
A1	0.25	-	0.50
A2	3.20	3.40	3.60
D	31.20 BSC		
D1	28.00 BSC		
E	31.20 BSC		
E1	28.00 BSC		
L	0.73	0.88	1.03
N	160		
e	0.65 BSC		
b	0.22	-	0.40
b1	0.22	0.30	0.36
c	0.11	-	0.23
c1	0.11	0.15	0.19

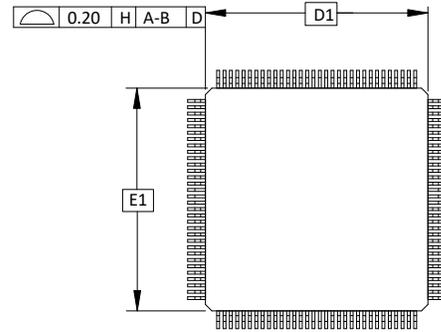
82. 176-Pin LQFP/TQFP Package

Dimensions in Millimeters

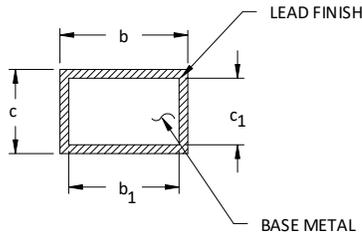
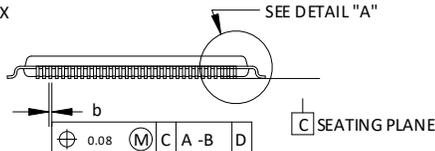
TOP VIEW



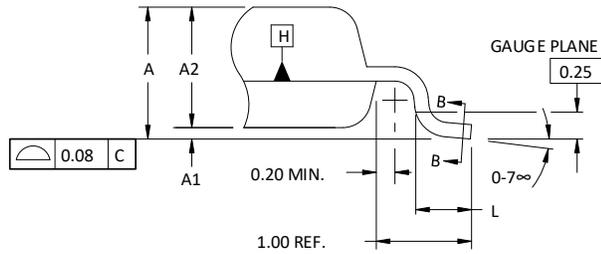
BOTTOM VIEW



SIDE VIEW



SECTION B - B



DETAIL "A"

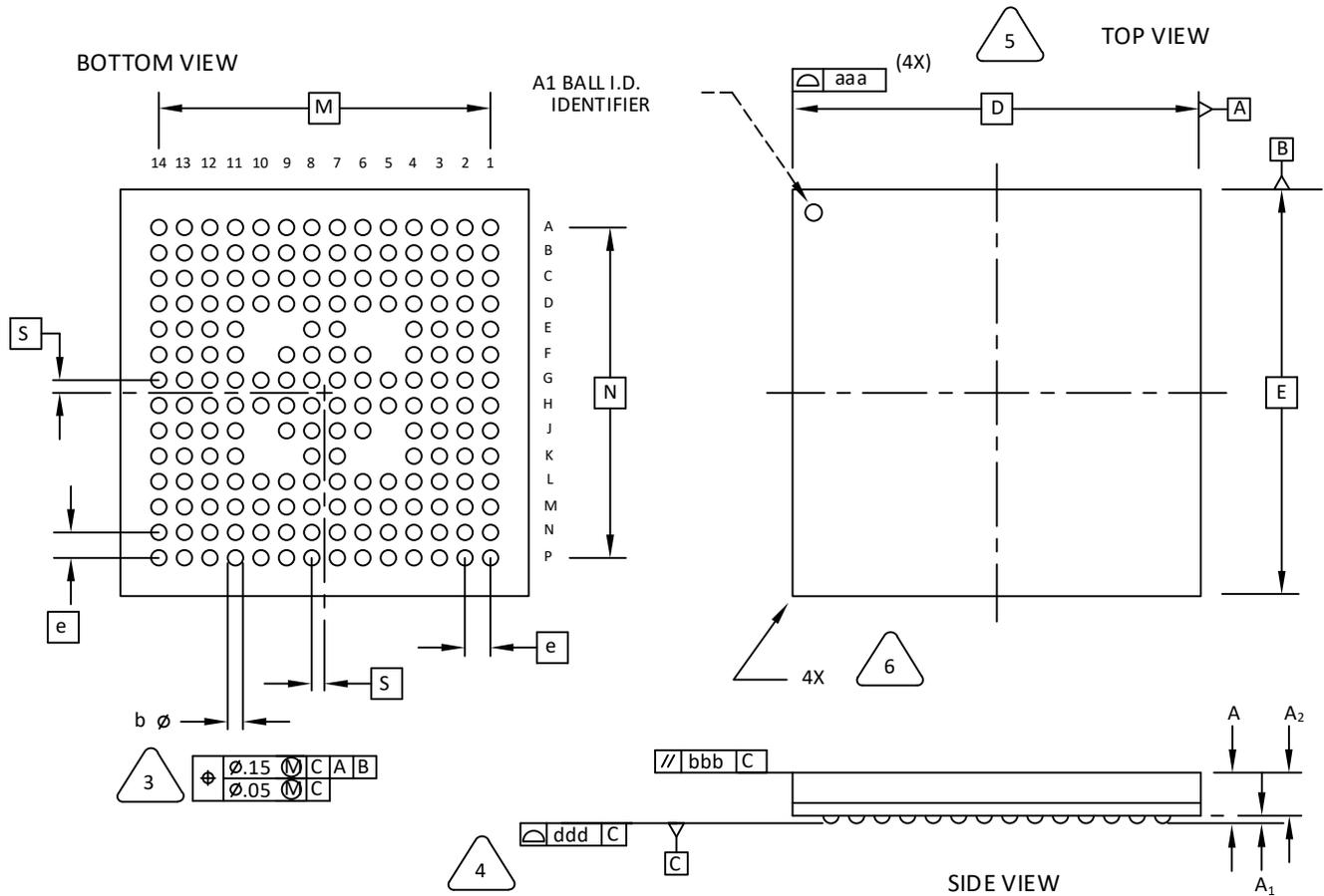
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 - 1982.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
5. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
6. SECTION B-B:
THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
7. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
8. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.60
A1	0.05	-	0.15
A2	1.35	1.40	1.45
D	26.00 BSC		
D1	24.00 BSC		
E	26.00 BSC		
E1	24.00 BSC		
L	0.45	0.60	0.75
N	176		
e	0.50 BSC		
b	0.17	0.22	0.27
b1	0.17	0.20	0.23
c	0.09	0.15	0.20
c1	0.09	0.13	0.16

83. 184-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

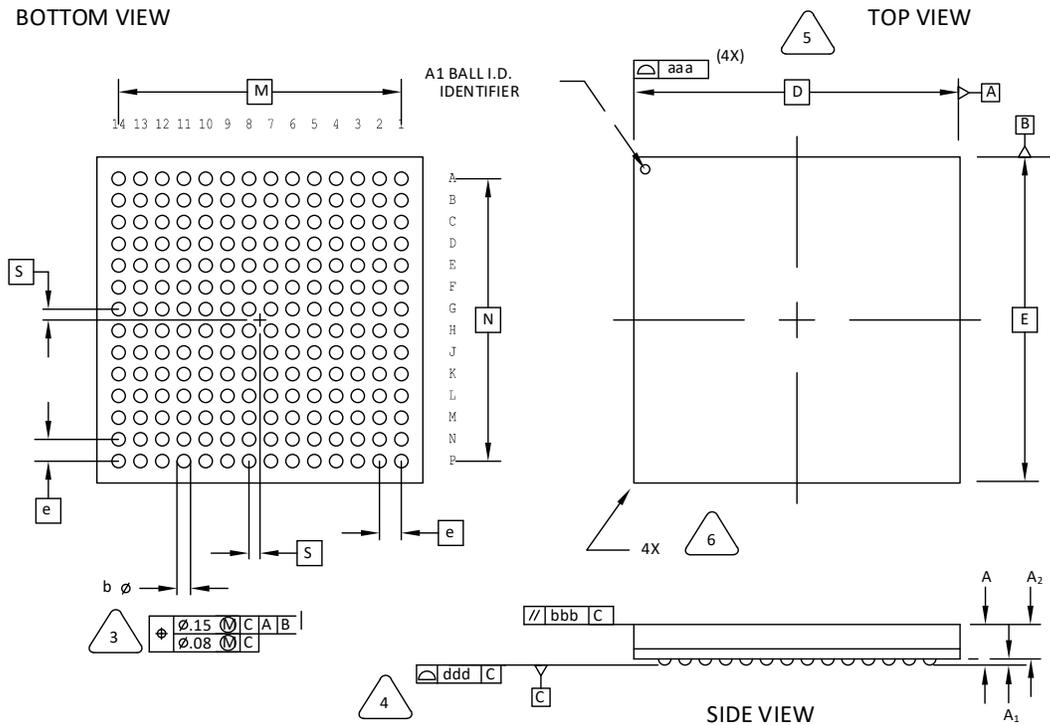


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.20	1.35	1.50
A1	0.16	-	-
A2	-	-	1.34
D/E	8.00 BSC		
M/N	6.50 BSC		
S	0.25 BSC		
b	0.25	0.30	0.35
e	0.50 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.08

84. 196-Ball caBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM $\square C$



PRIMARY DATUM $\square C$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

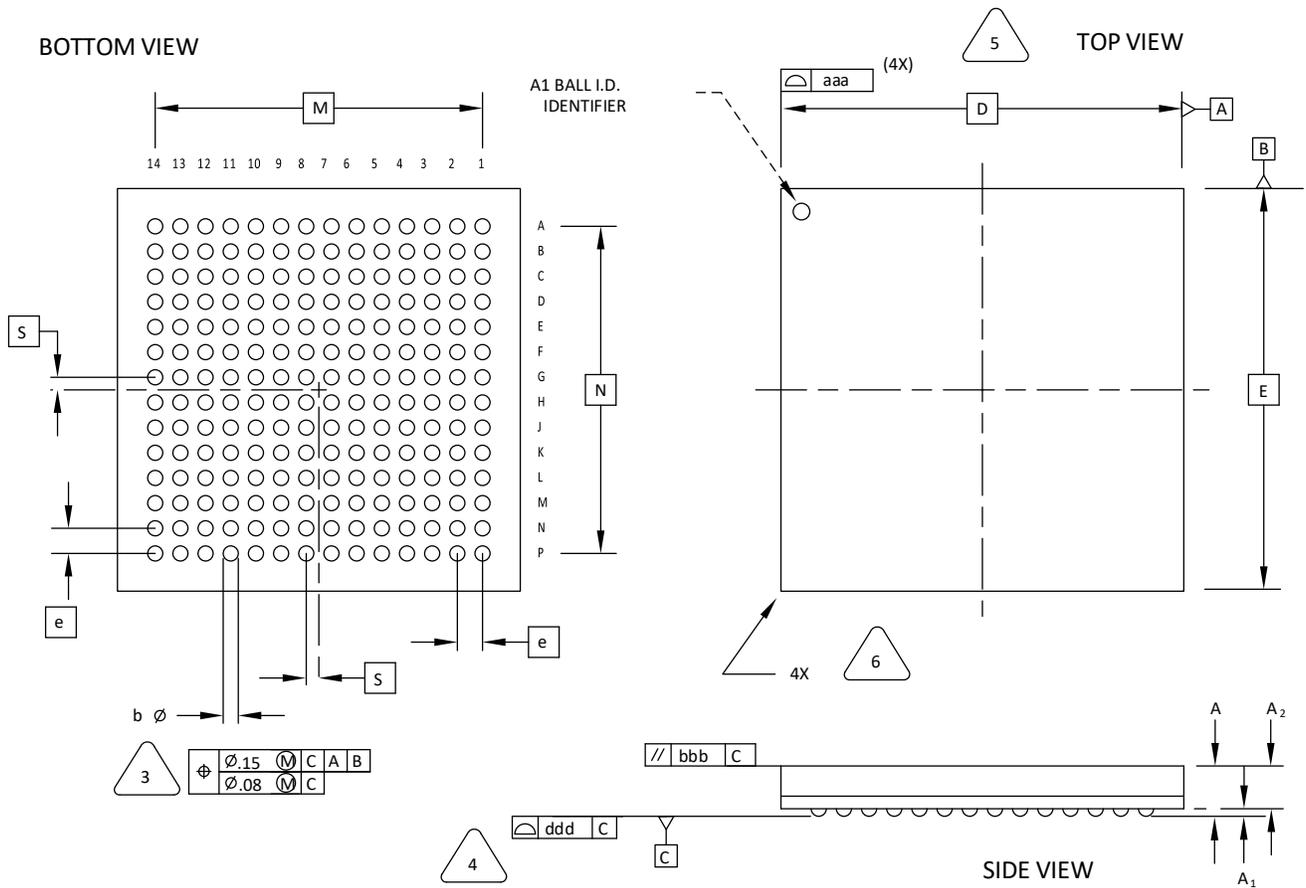
7. JEDEC REFERENCE: JEP95DR4.5

SYMBOL	MIN.	NOM.	MAX.
A	1.316	1.392	1.468
A1	0.36	0.41	0.46
A2	0.982		
D/E	12.00 BSC		
M/N	10.40 BSC		
S	0.40 BSC		
b	0.45	0.50	0.55
e	0.80 BSC		
aaa	0.15		
bbb	0.20		
ddd	0.15		

**This Package Outline Drawing and related information apply to the Certus-NX devices.*

85. 196-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM $\square C$



PRIMARY DATUM $\square C$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



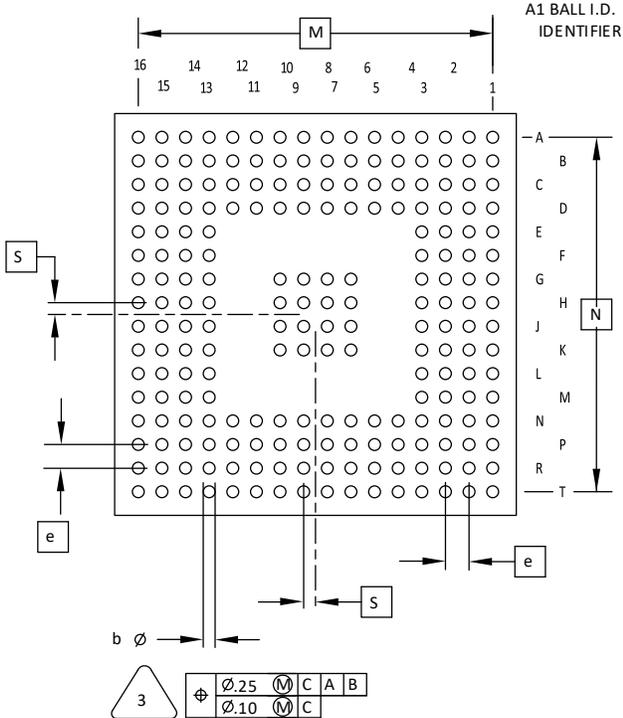
EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.00
A1	0.15	-	-
A2	-	-	0.85
D/E	8.00 BSC		
M/N	6.50 BSC		
S	0.25 BSC		
b	0.25	0.30	0.35
e	0.50 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.08

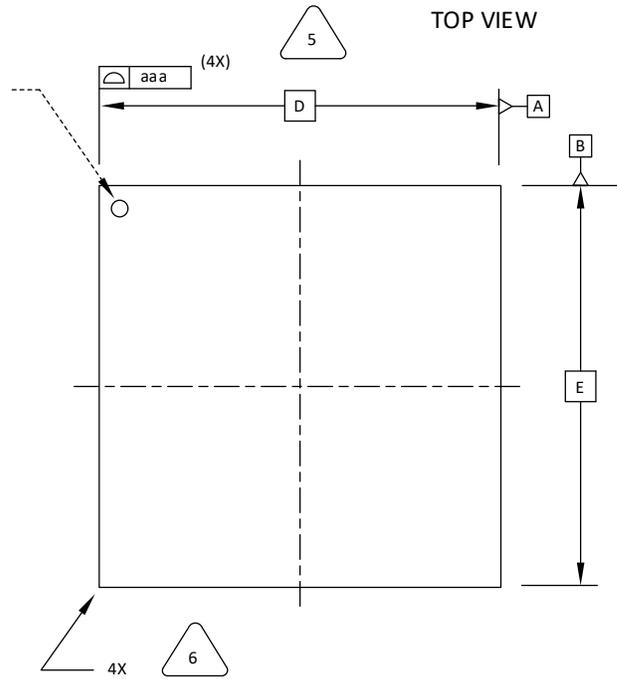
86. 208-Ball ftBGA Package

Dimensions in Millimeters

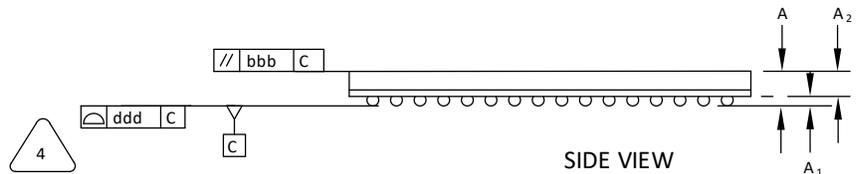
BOTTOM VIEW



TOP VIEW



SIDE VIEW



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

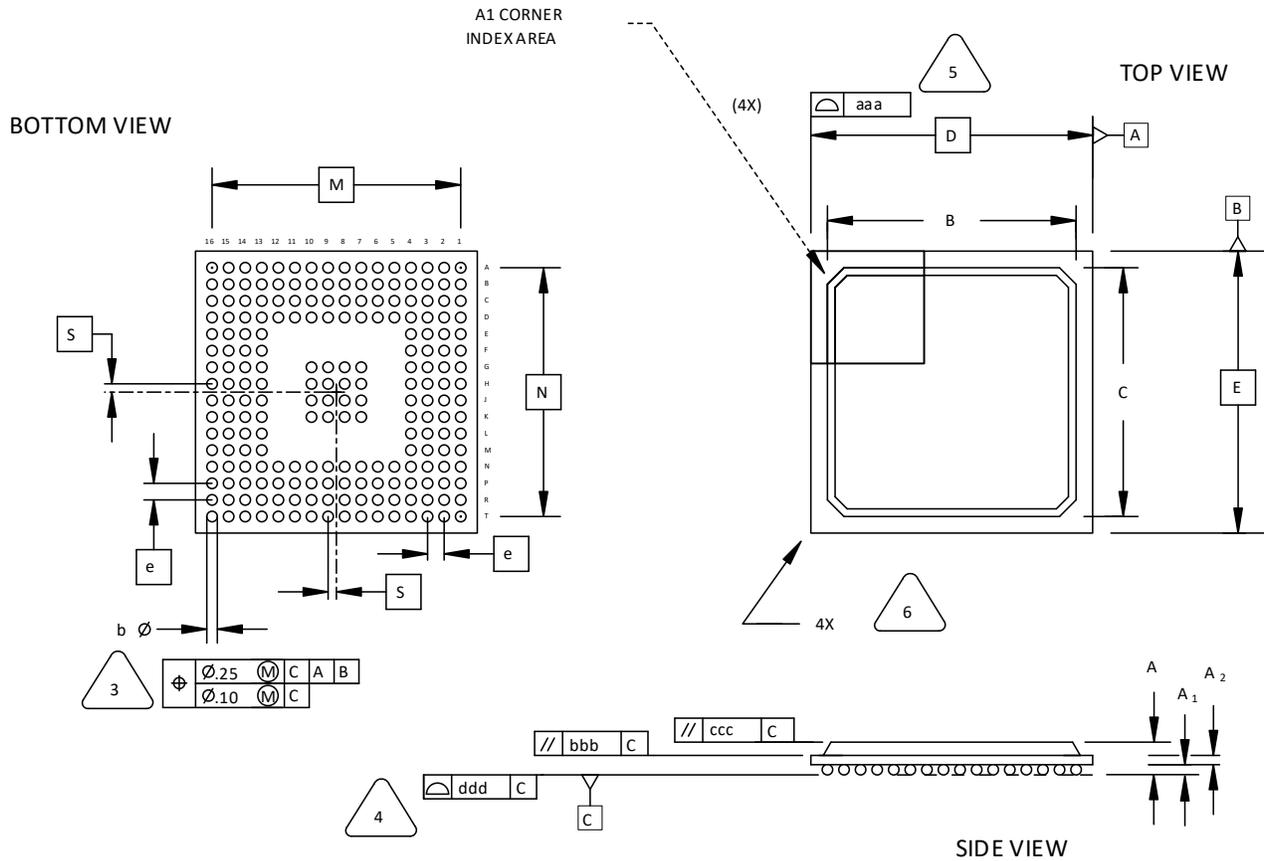


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.25	1.40	1.55
A1	0.30	-	-
A2	-	-	1.25
D/E	17.0 BSC		
M/N	15.0 BSC		
S	0.50 BSC		
b	0.40	0.50	0.60
e	1.0 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ddd	-	-	0.12

87. 208-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM **C**



PRIMARY DATUM **C** AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

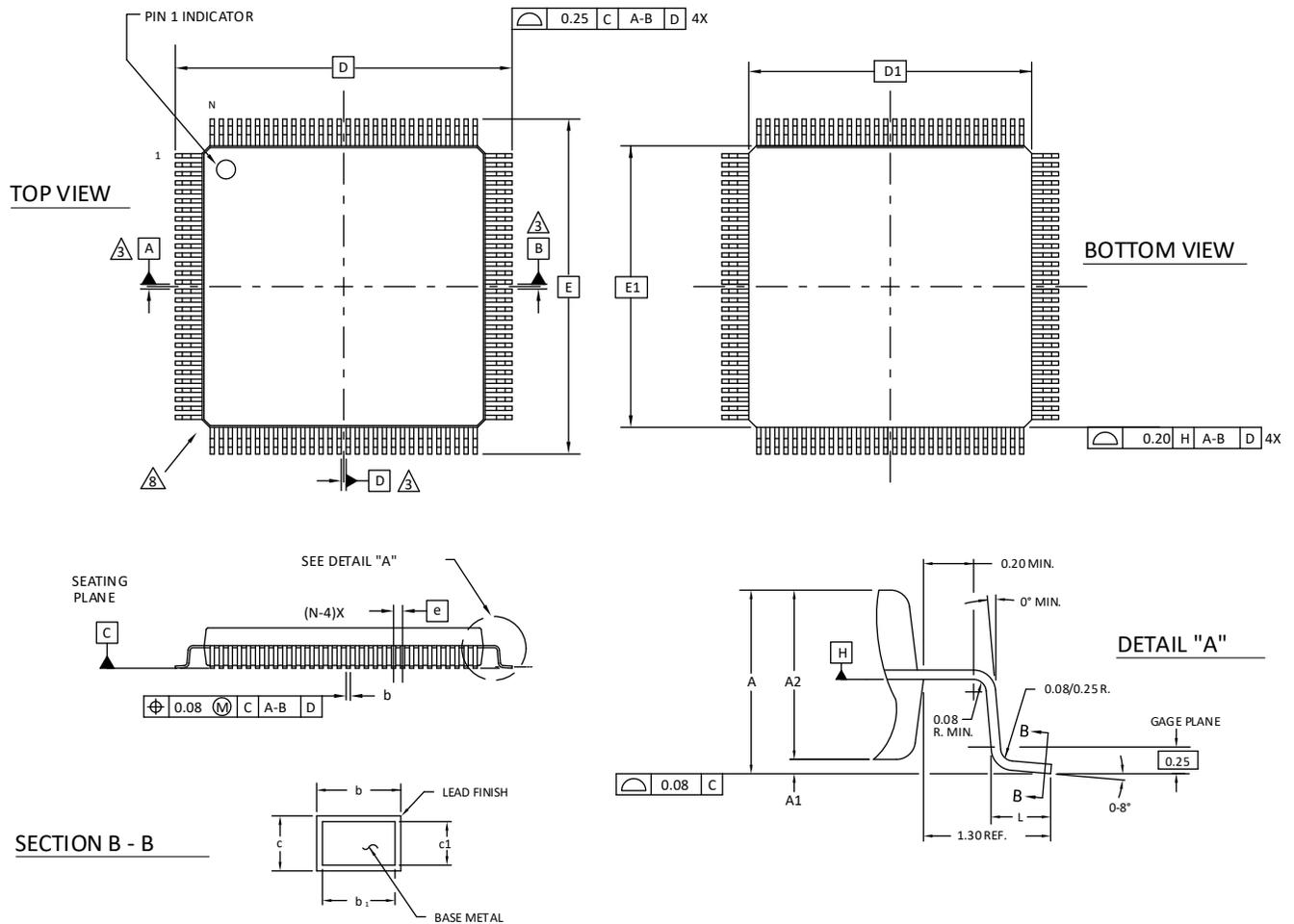


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.30	1.70	2.10
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	14.80	15.30	15.80
D/E	17.00 BSC		
M/N	15.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

88. 208-Pin PQFP Package

Dimensions in Millimeters



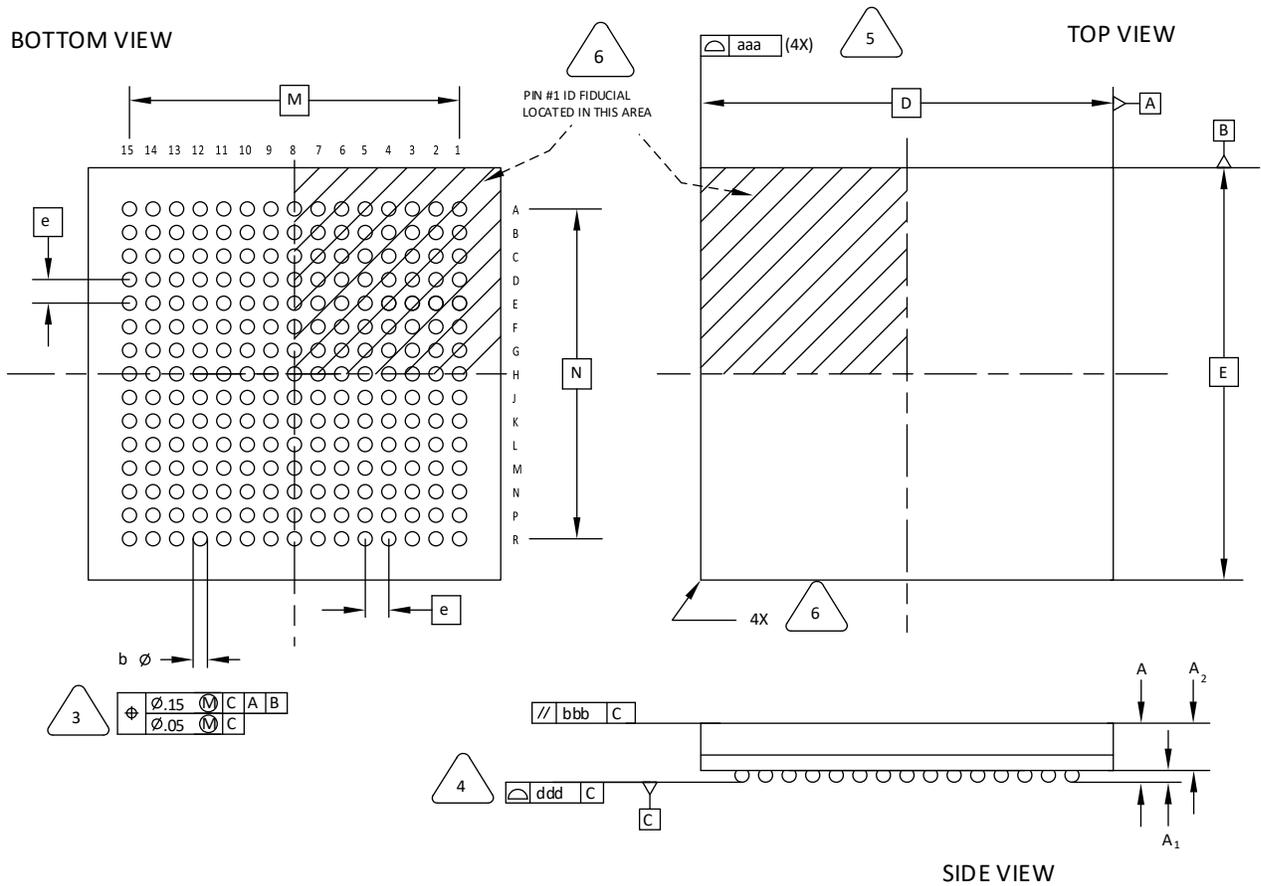
NOTES:

- 0 DIMENSIONING AND TOLERANCING PER ANSI Y14.5 - 1982.
- 0 ALL DIMENSIONS ARE IN MILLIMETERS.
- DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
- 0 DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- 0 THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 0 SECTION B-B: THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- 0 A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
- EXACT SHAPE OF EACH CORNER IS OPTIONAL.
- EXACT SHAPE OF EXPOSED HEATSINK IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	4.10
A1	0.25	-	0.50
A2	3.20	3.40	3.60
D	30.60 BSC		
D1	28.00 BSC		
E	30.60 BSC		
E1	28.00 BSC		
L	0.45	0.60	0.75
N	208		
e	0.50 BSC		
b	0.17	-	0.27
b1	0.17	0.20	0.23
c	0.09	-	0.20
c1	0.09	0.12	0.16

89. 225-Ball ucBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.

3 DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C

4 PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

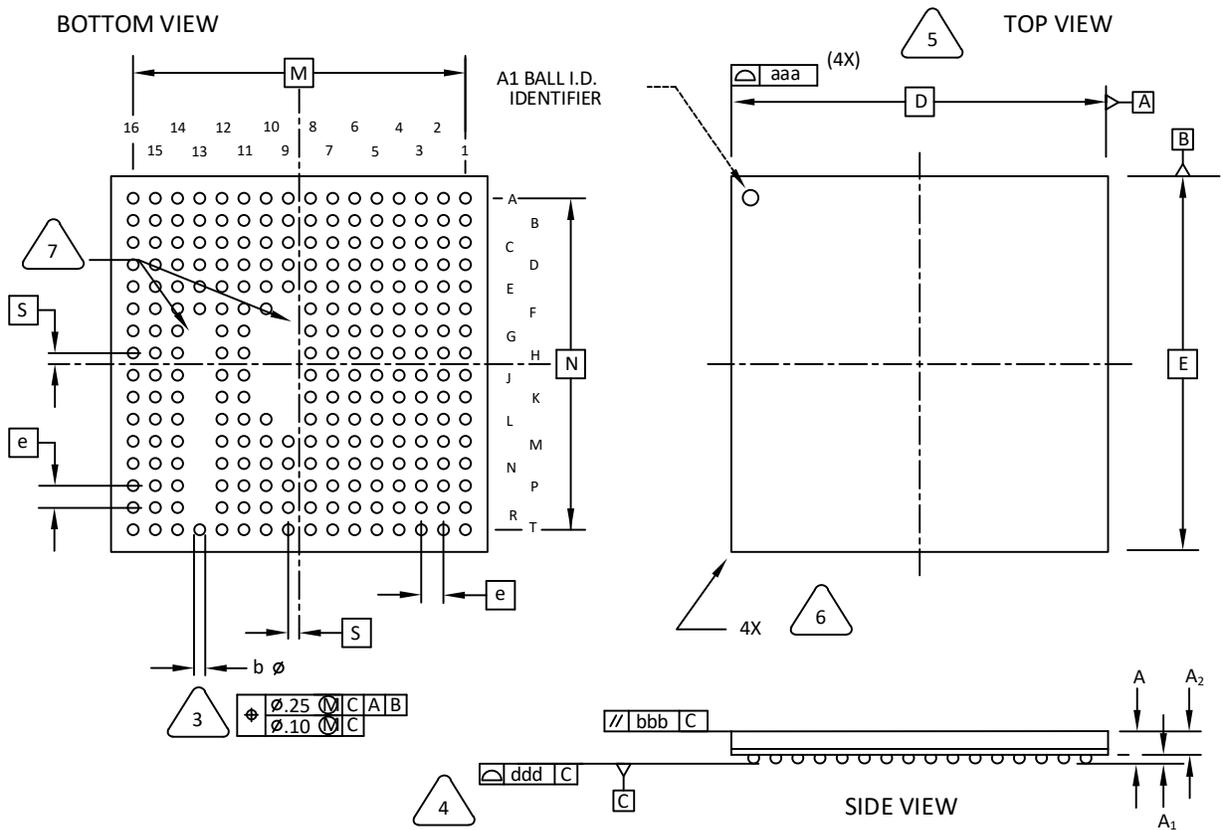
5 BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

6 EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.00
A1	0.10	-	-
A2	-	-	0.90
D/E	7.00 BSC		
M/N	5.60 BSC		
b	0.20	0.25	0.30
e	0.40 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.10

90. 237-Ball ftBGA Package

Dimensions in Millimeters



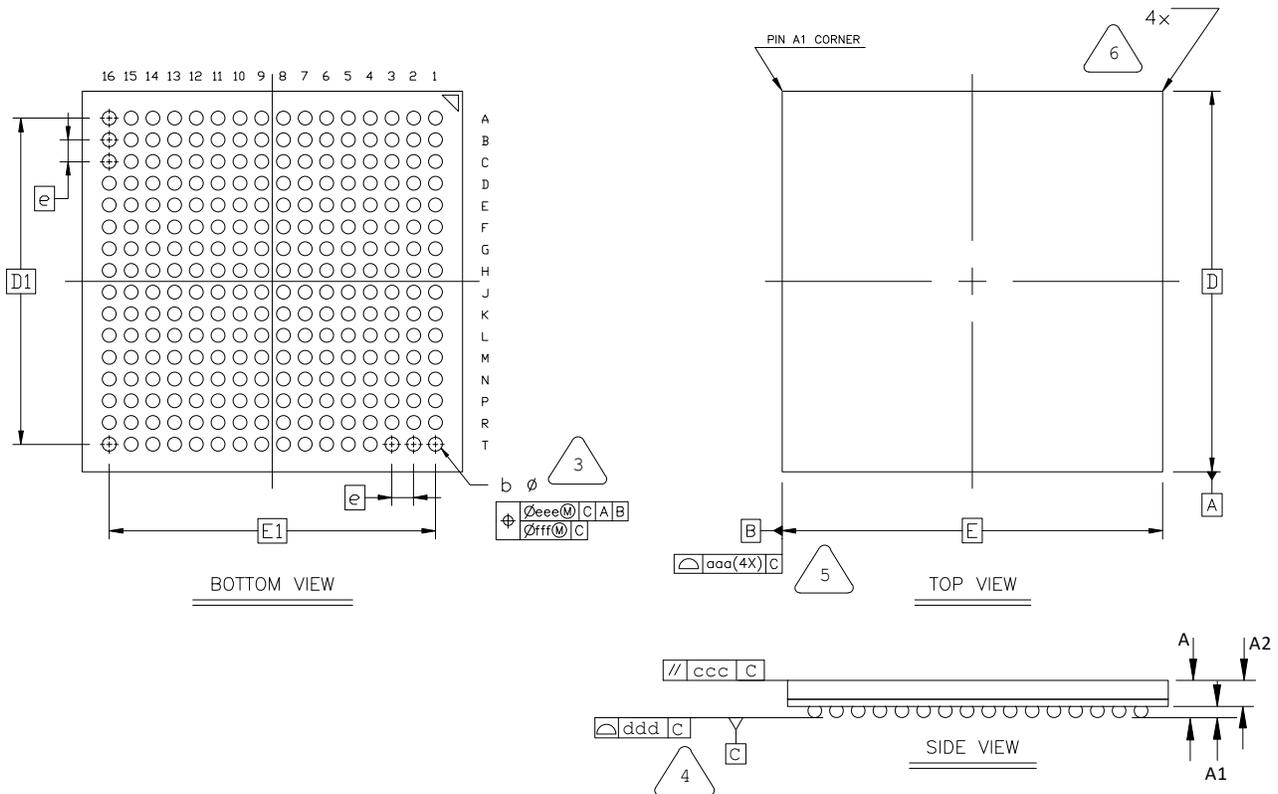
NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
 2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]
4. PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
7. DEPOPULATED 13G TO 13R, 10G TO 10K, AND 9F TO 9L.

SYMBOL	MIN.	NOM.	MAX.
A	1.40	1.55	1.70
A1	0.30	-	-
A2	-	-	1.24
D/E	17.0 BSC		
M/N	15.0 BSC		
S	0.50 BSC		
b	0.40	0.50	0.60
e	1.0 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ddd	-	-	0.15

92. 256-Ball BBG/caBGA Package Option 1

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.

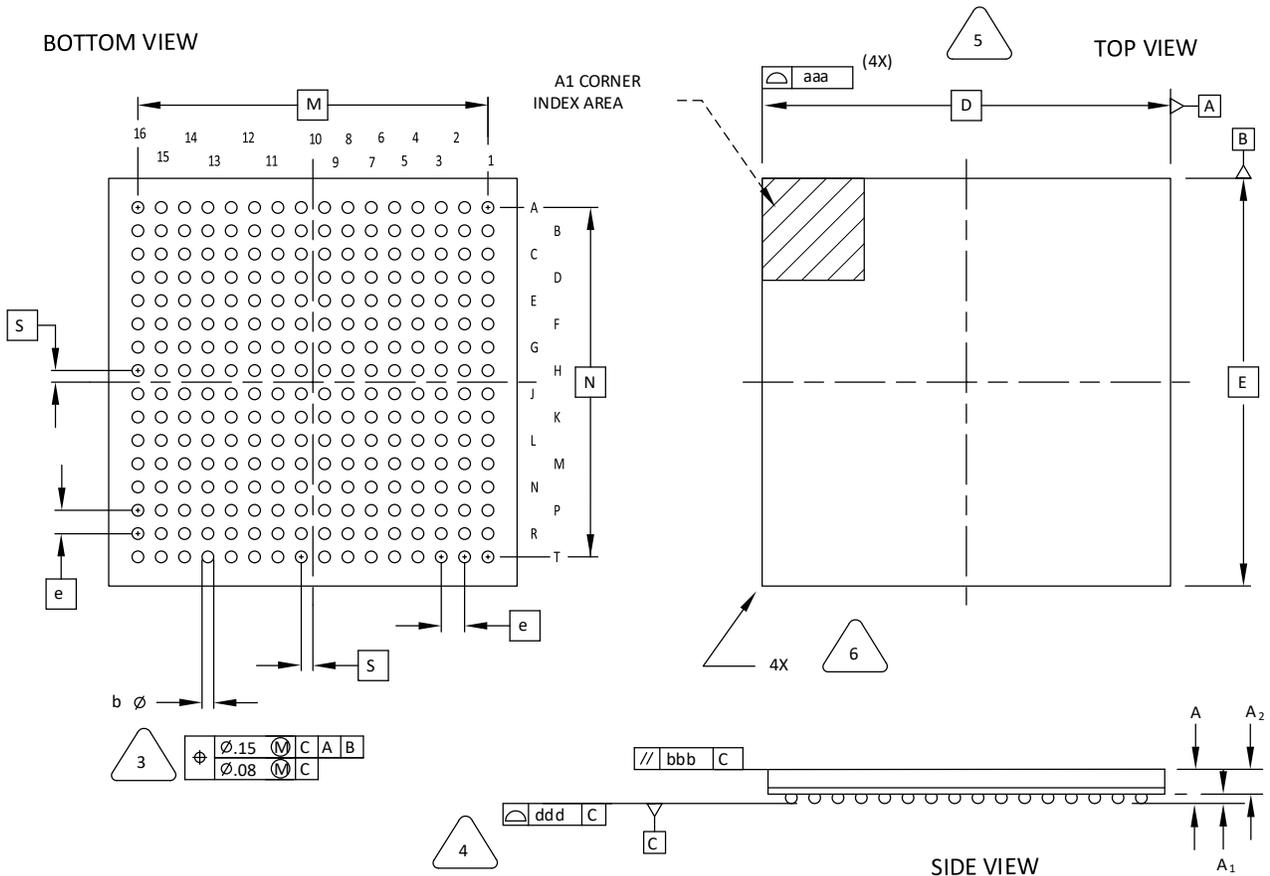
-  DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C
-  PRIMARY DATUM C AND SEATING PLACE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
-  BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
-  EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
-  JEDEC REFERENCE: MO-275A_01

SYMBOL	MIN.	NOM.	MAX.
A	1.296	1.372	1.500
A1	0.36	0.41	0.46
A2	0.882	0.962	1.042
D/E	14.00 BSC		
D1/E1	12.00 BSC		
n	256		
b	0.45	0.50	0.55
e	0.80 BSC		
aaa	0.15		
ccc	0.20		
ddd	0.15		
eee	0.15		
fff	0.08		

*This Package Outline Drawing and related information apply to CrossLink-NX, Certus-NX, and MachXO5™-NX devices.

93. 256-Ball BBG/caBGA Package Option 2

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

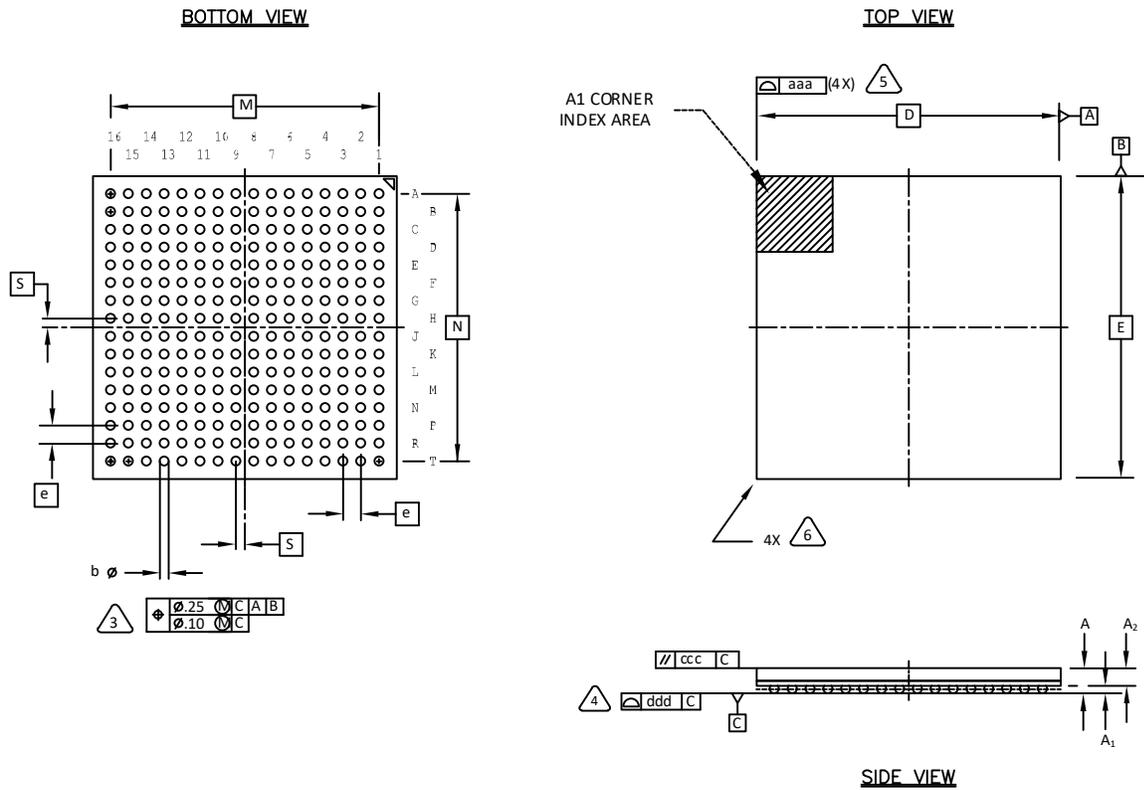
1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C].
4. PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
7. REFERENCE JEDEC MO-275, VARIATION JJAB-2.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.70
A1	0.25	-	-
A2	0.65	-	-
D/E	14.0 BSC		
M/N	12.0 BSC		
S	0.40 BSC		
b	0.40	0.45	0.50
e	0.80 BSC		
aaa	-	-	0.15
bbb	-	-	0.20
ddd	-	-	0.20

**This Package Outline Drawing and related information applies to MachXO3, MachXO2, and ECP5™ devices.*

94. 256-Ball caBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

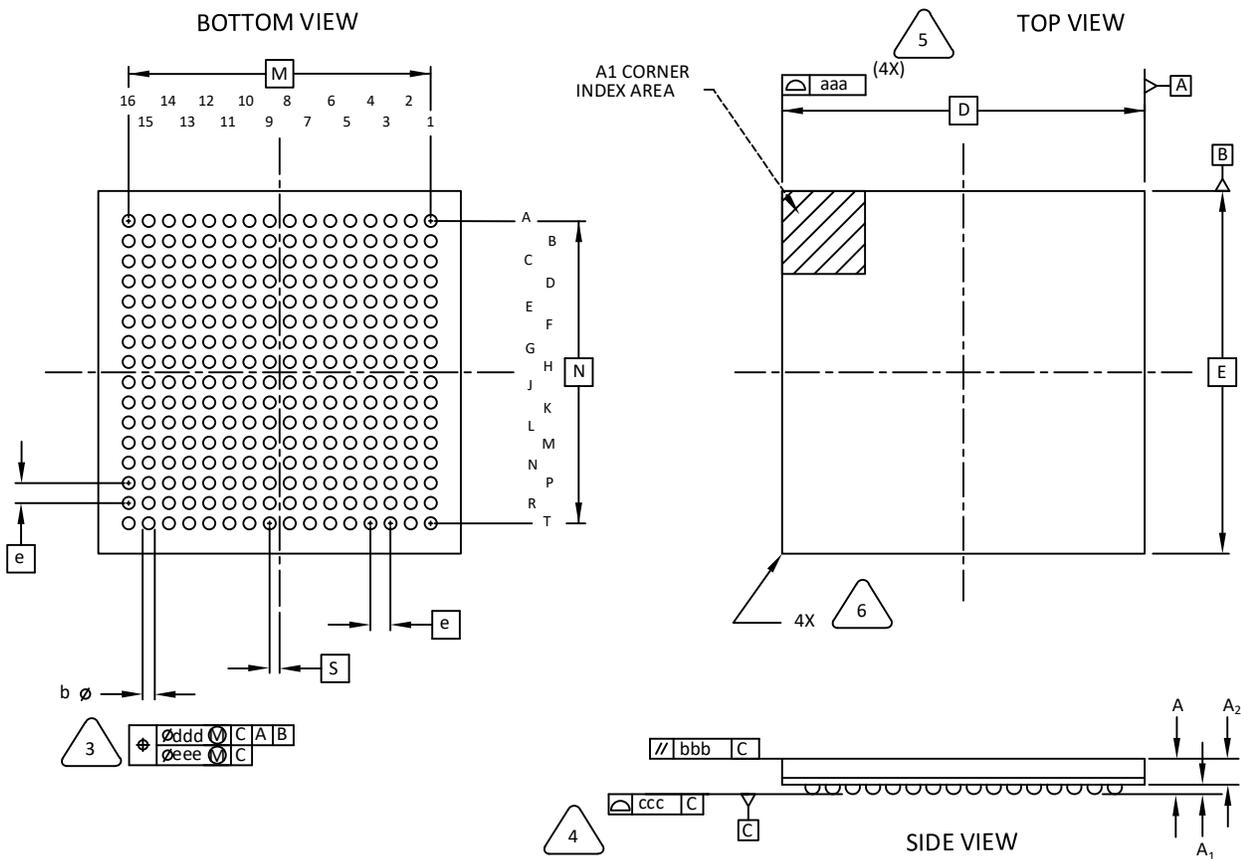
- JEDEC REFERENCE: JEP95 DR4.14

SYMBOL	MIN.	NOM.	MAX.
A	1.316	1.392	1.468
A1	0.36	0.41	0.46
A2	0.902	0.982	1.062
D/E	17.00 BSC		
M/N	15.00 BSC		
S	0.50 BSC		
b	0.45	0.50	0.55
e	1.00 BSC		
aaa	0.20		
ccc	0.20		
ddd	0.20		

**This package Outline Drawing applies to MachXO3D-4300HC-FTG256 device.*

95. 256-Ball csfBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C].



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

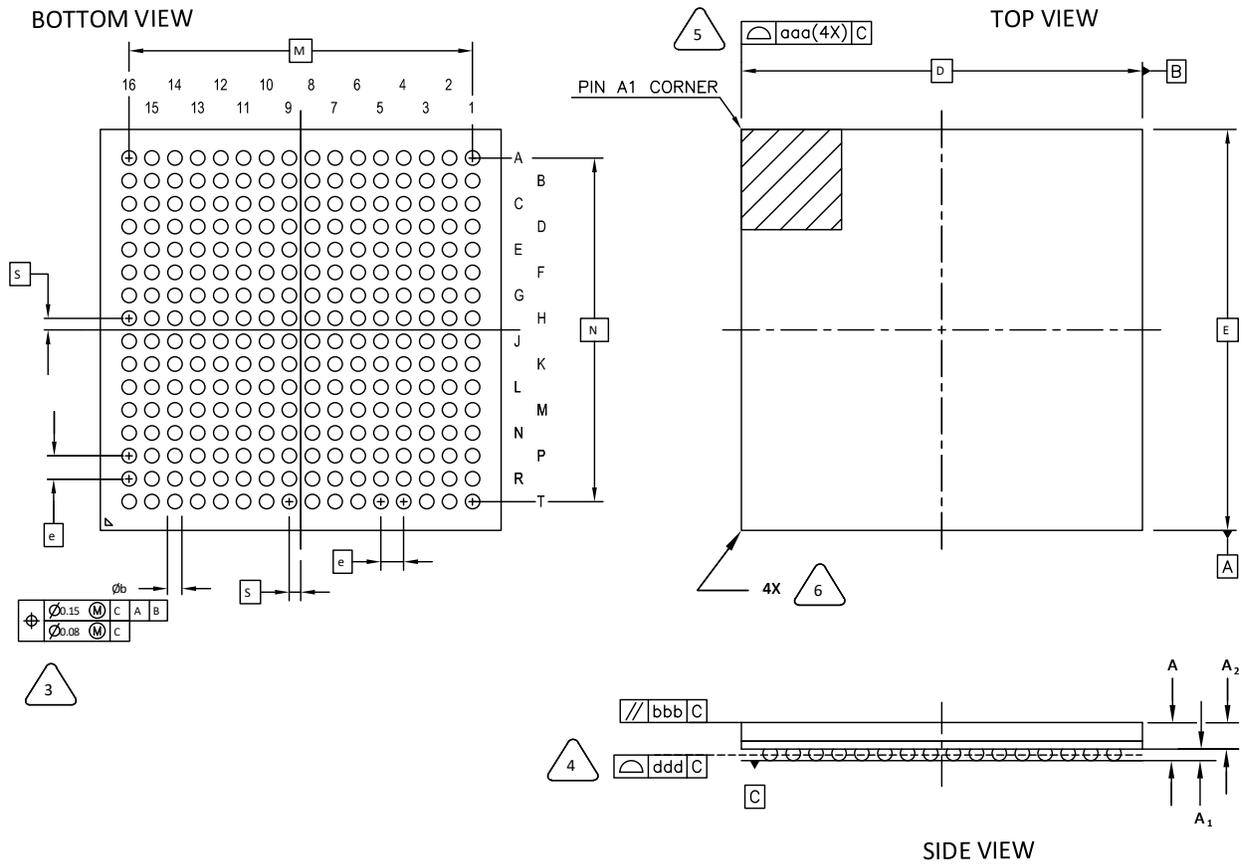


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.00
A1	0.15	0.24	-
A2	-	0.66	-
D/E	9.00 BSC		
M/N	7.50 BSC		
S	0.25 BSC		
b	0.25	0.30	0.35
e	0.50 BSC		
aaa	0.10		
bbb	0.10		
ccc	0.08		
ddd	0.15		
eee	0.05		

96. 256-Ball CBG256/csfBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

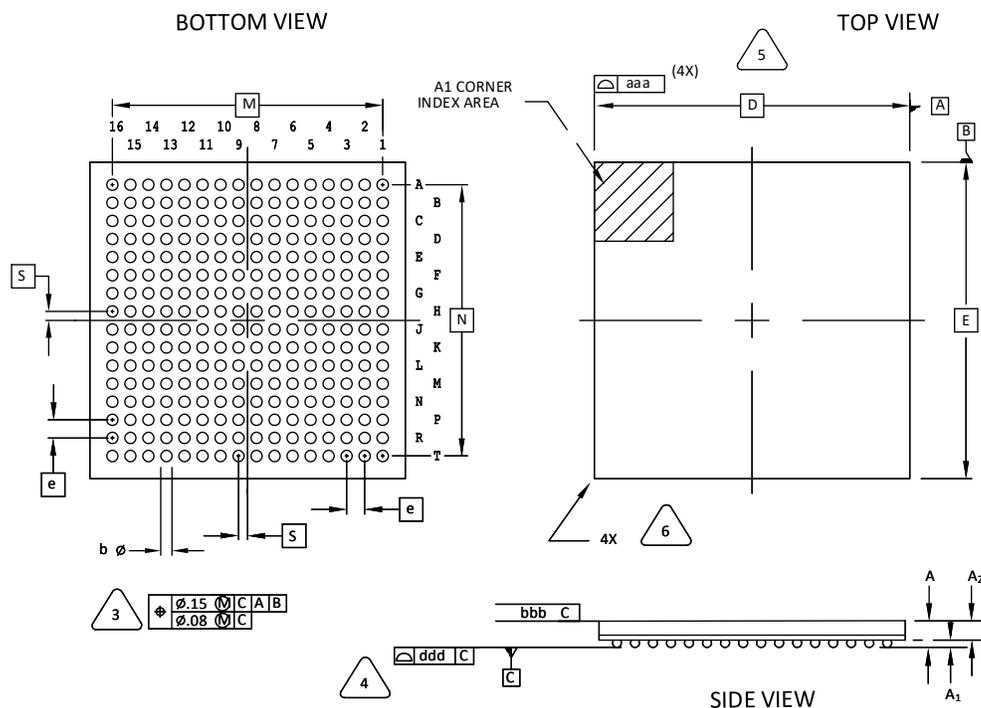
REFERENCE: JEDEC JEP 95 DR 4.5

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.327
A1	0.27	-	-
A2	0.812	-	-
D/E	14.0 BSC		
M/N	12.0 BSC		
S	0.40 BSC		
b	0.45	0.50	0.55
e	0.80 BSC		
aaa	-	-	0.15
bbb	-	-	0.20
ddd	-	-	0.20

*This Package Outline Drawing and related information apply to Mach™-NX devices.

97. 256-Ball CBG256/csfBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C].



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

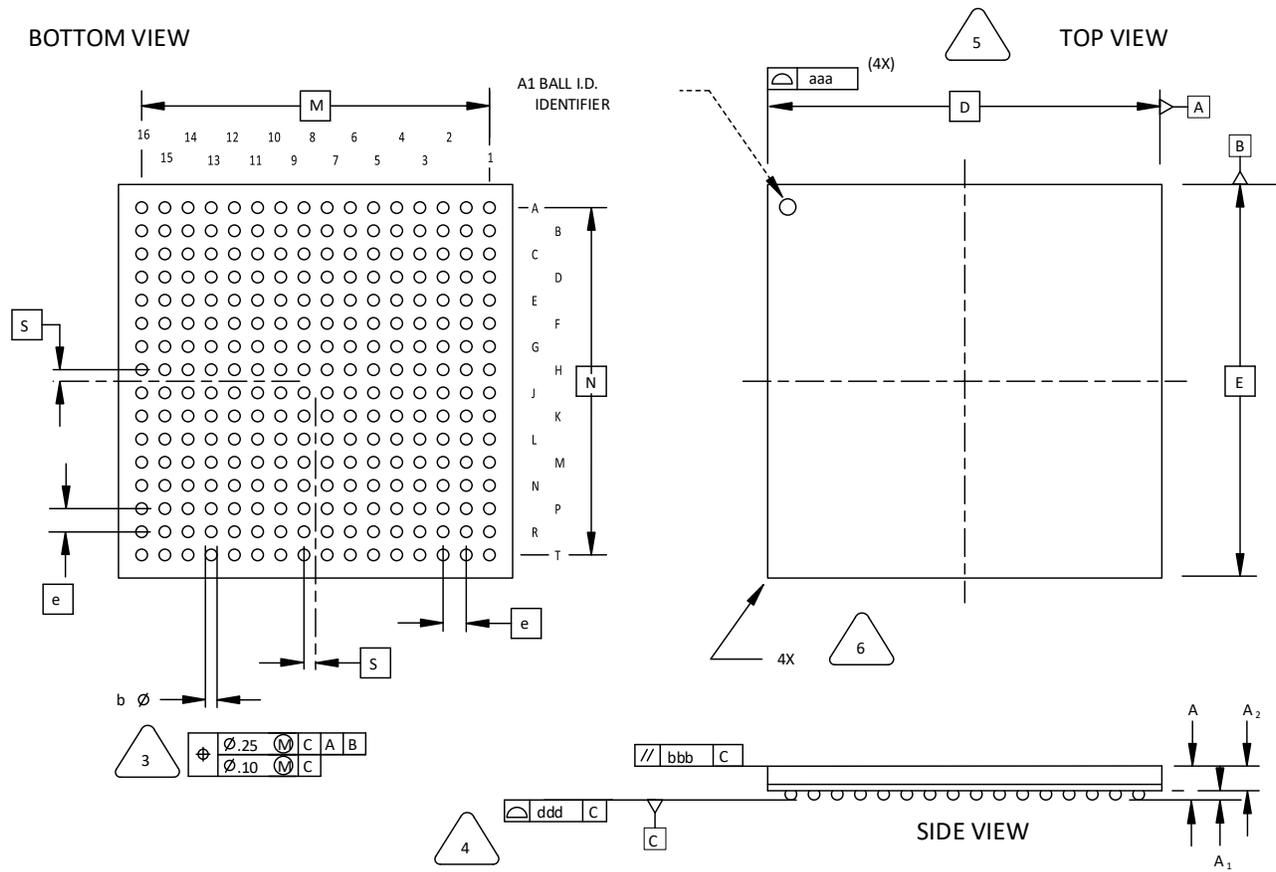
- REFERENCE JEDEC: JEP95 DR 4.5

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.20
A1	0.27	-	-
A2	0.60	-	-
D/E	14.0 BSC		
M/N	12.0 BSC		
S	0.40 BSC		
b	0.45	0.50	0.55
e	0.80 BSC		
aaa	-	-	0.15
bbb	-	-	0.20
ddd	-	-	0.20

**This Package Outline Drawing and related information apply to CertusPro-NX devices.*

98. 256-Ball ftBGA Package Option 1: ispMACH 4000, MachXO, LatticeXP2

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM \square C



PRIMARY DATUM \square C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

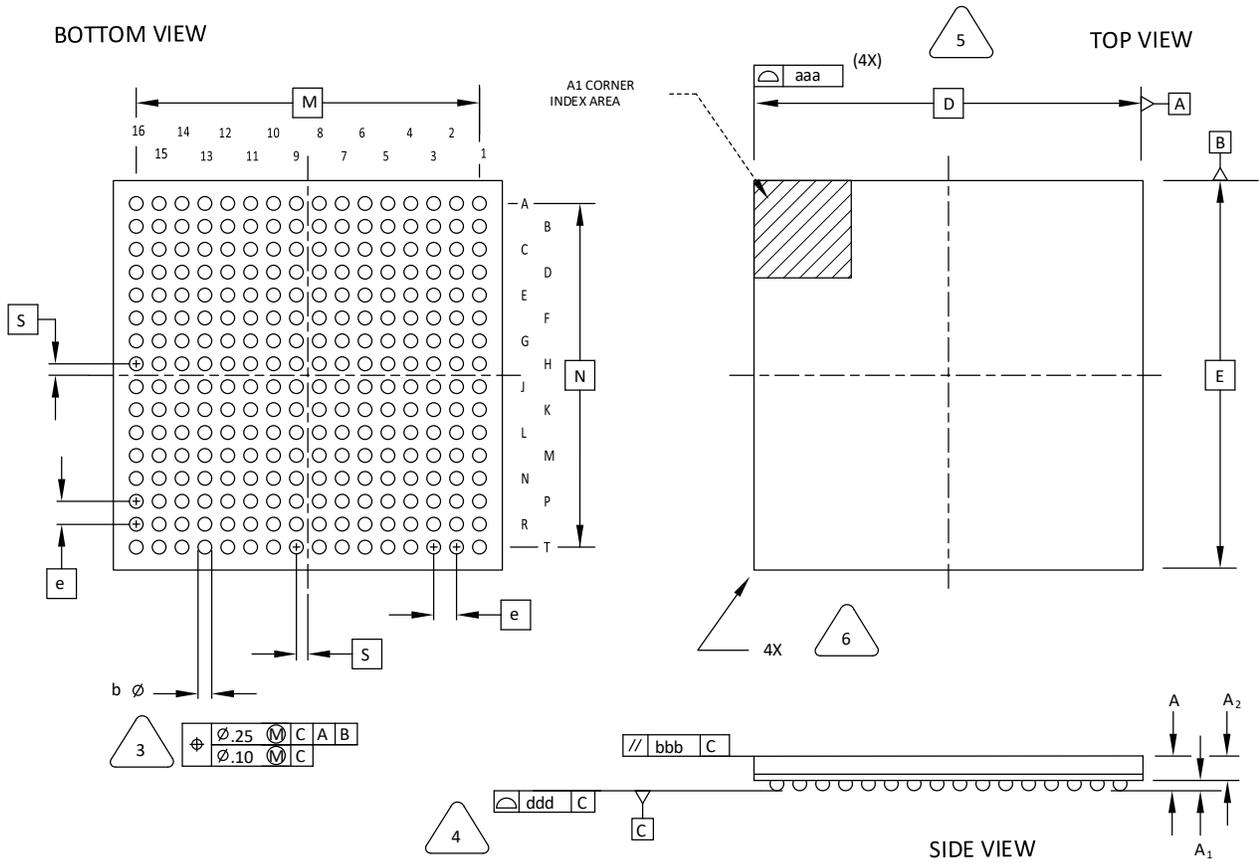


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.25	1.40	1.55
A1	0.30	-	-
A2	-	-	1.25
D/E	17.0 BSC		
M/N	15.0 BSC		
S	0.50 BSC		
b	0.40	0.50	0.60
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ddd	-	-	0.12

99. 256-Ball ftBGA Package Option 2: LatticeECP3™

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C].



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

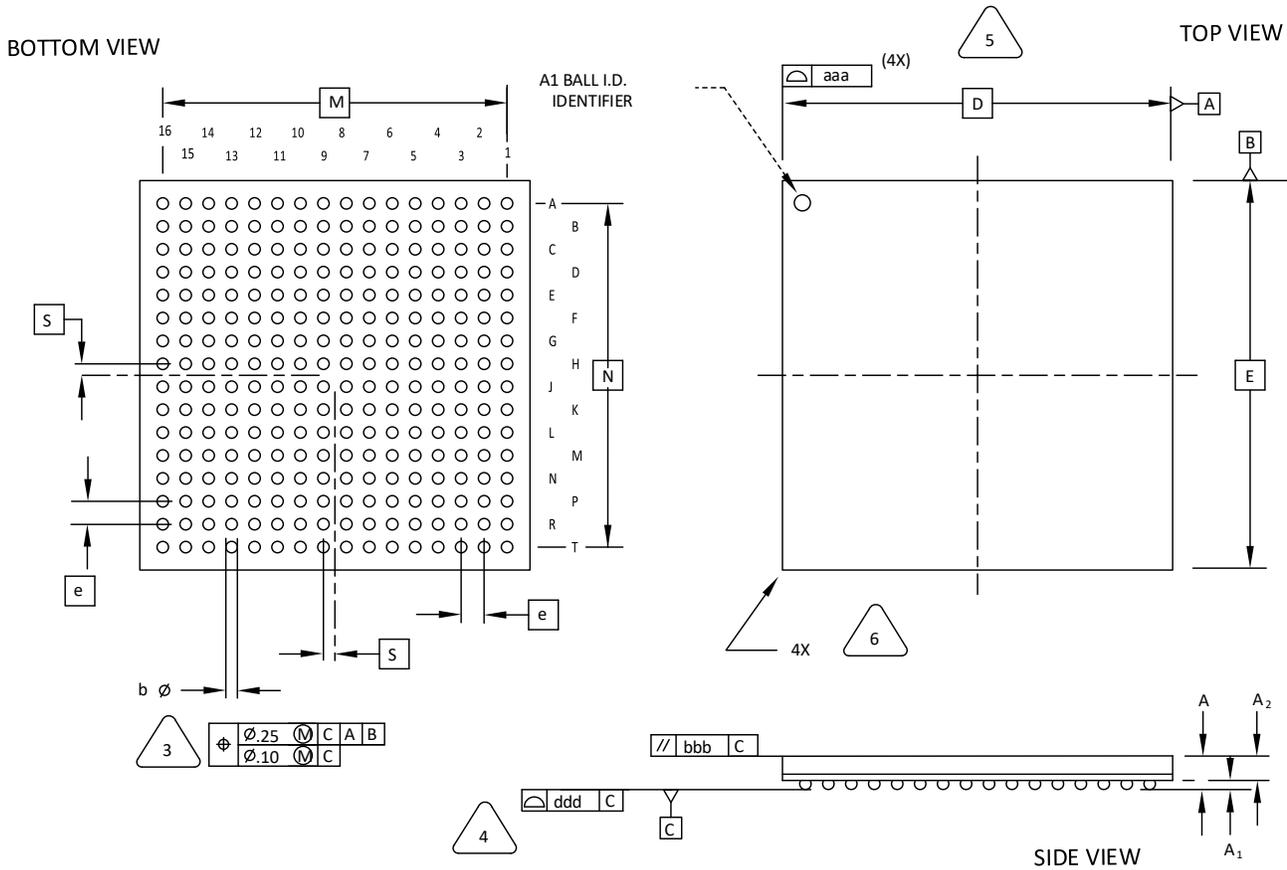


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.30	1.70	2.10
A1	0.30	0.50	0.70
A2	1.40 REF		
D/E	17.0 BSC		
M/N	15.0 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.0 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ddd	-	-	0.20

100. 256-Ball ftBGA Package Option 3: MachXO2

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

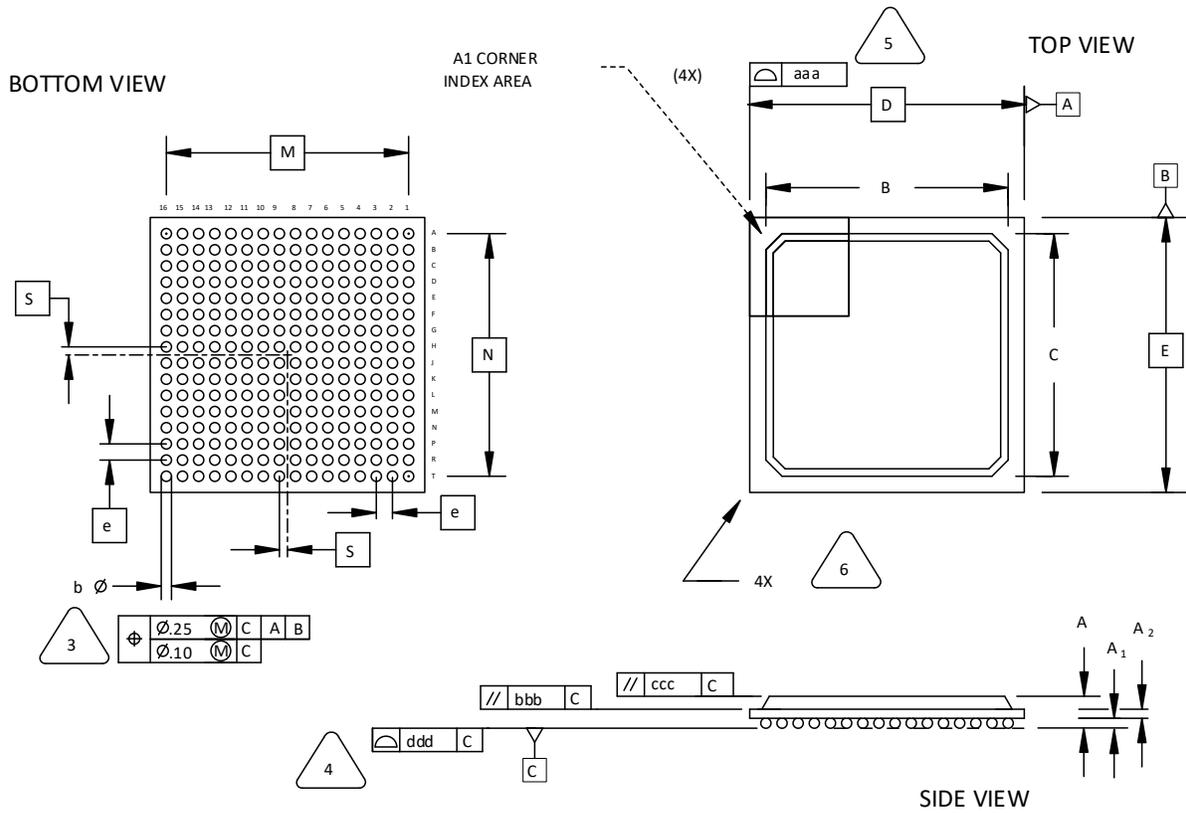


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.40	1.55	1.70
A1	0.30	-	-
A2	1.00	-	-
D/E	17.0 BSC		
M/N	15.0 BSC		
S	0.50 BSC		
b	0.40	0.50	0.60
e	1.0 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ddd	-	-	0.12

101. 256-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM $\square C$



PRIMARY DATUM $\square C$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

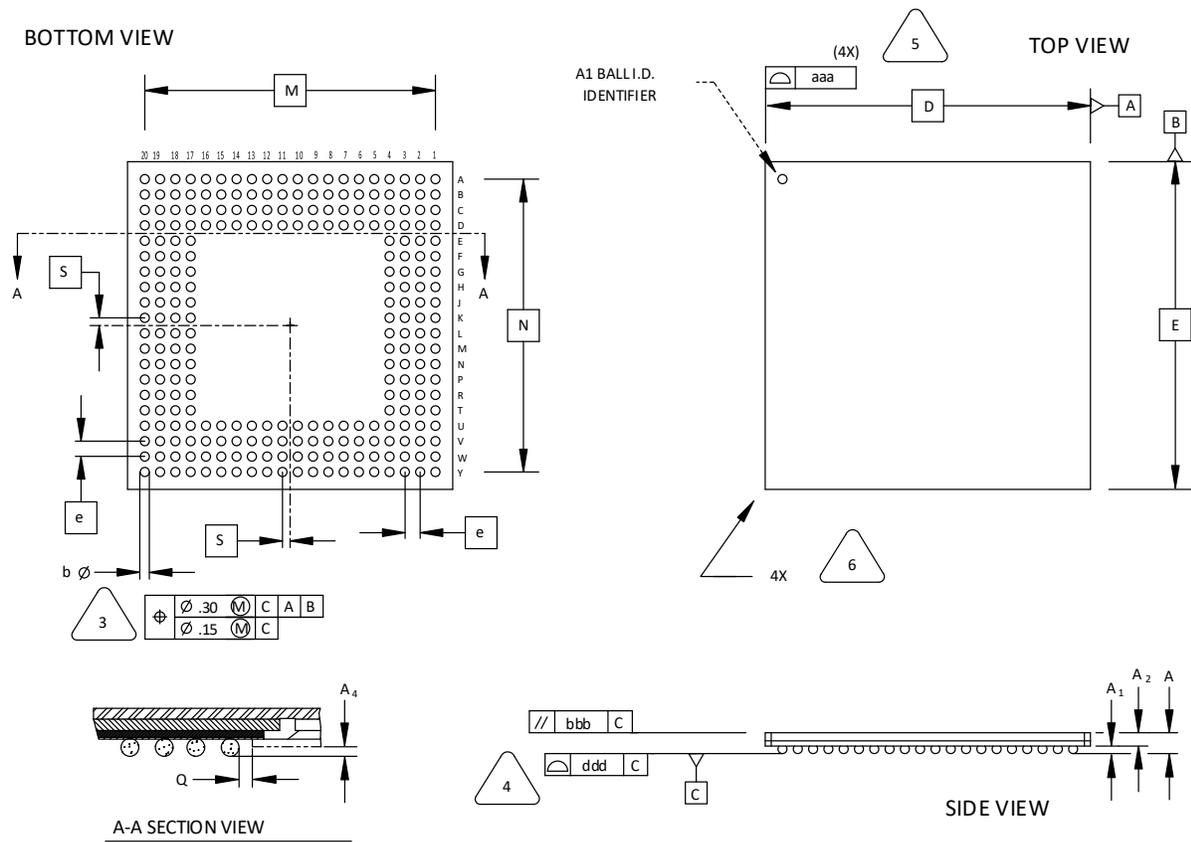


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.30	1.70	2.10
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	14.80	15.30	15.80
D/E	17.00 BSC		
M/N	15.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

102. 256-Ball SBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM **C**.



PRIMARY DATUM **C** AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

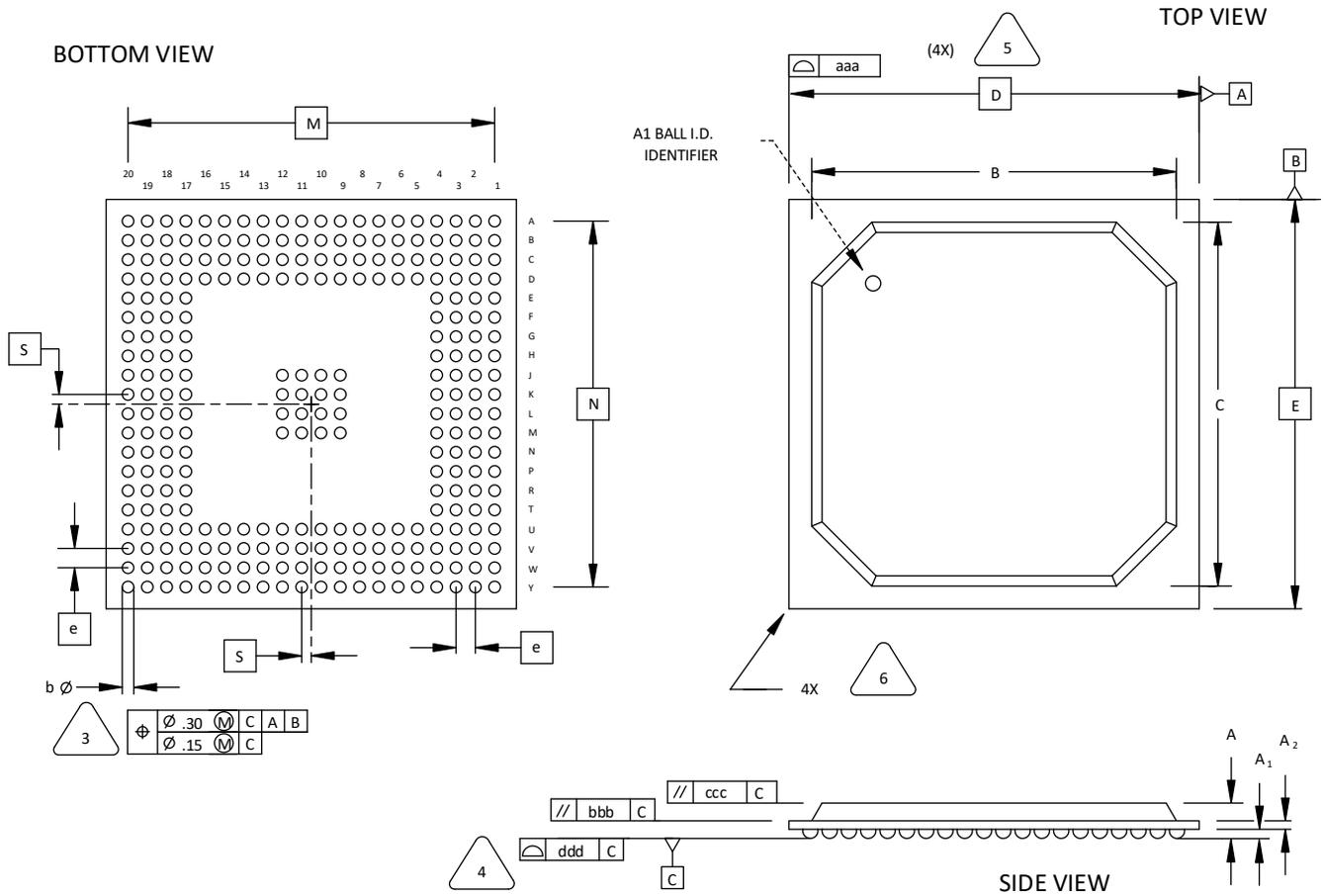


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.70
A1	0.50	0.65	0.80
A2	0.80	0.90	1.00
D/E	27.00 BSC		
M/N	24.13 BSC		
S	0.635 BSC		
b	0.60	0.75	0.90
e	1.27 BSC		
Q	0.25	-	-
A4	0.10	-	-
aaa	-	-	0.20
bbb	-	-	0.25
ddd	-	-	0.20

103. 272-Ball BGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

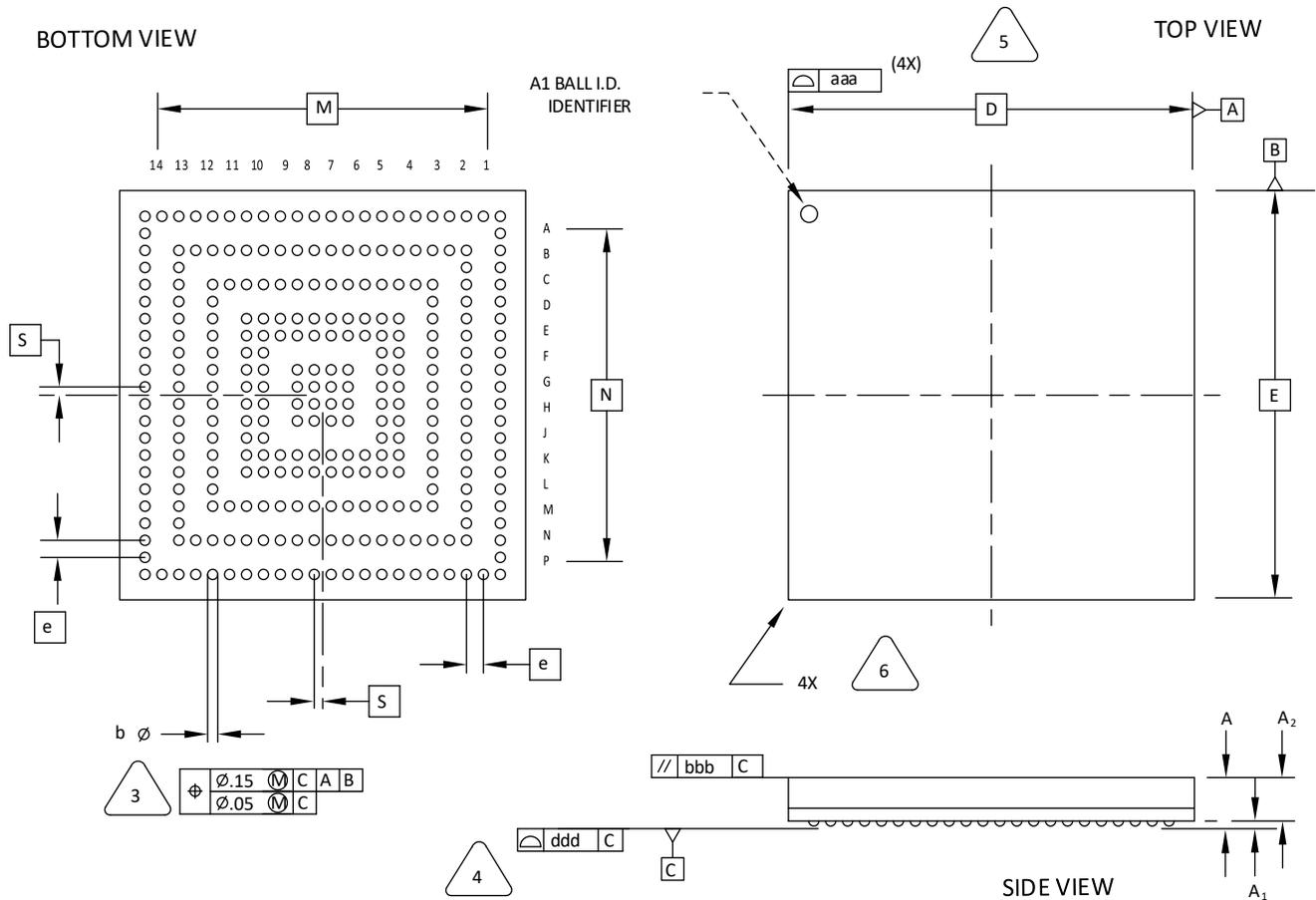


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.90	2.25	2.80
A1	0.50	0.65	0.80
A2	0.28	0.54	0.80
B/C	23.80	24.30	24.80
D/E	27.00 BSC		
M/N	24.13 BSC		
S	0.635 BSC		
b	0.60	0.75	0.90
e	1.27 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

104. 284-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.

3 DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM **C**.

4 PRIMARY DATUM **C** AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

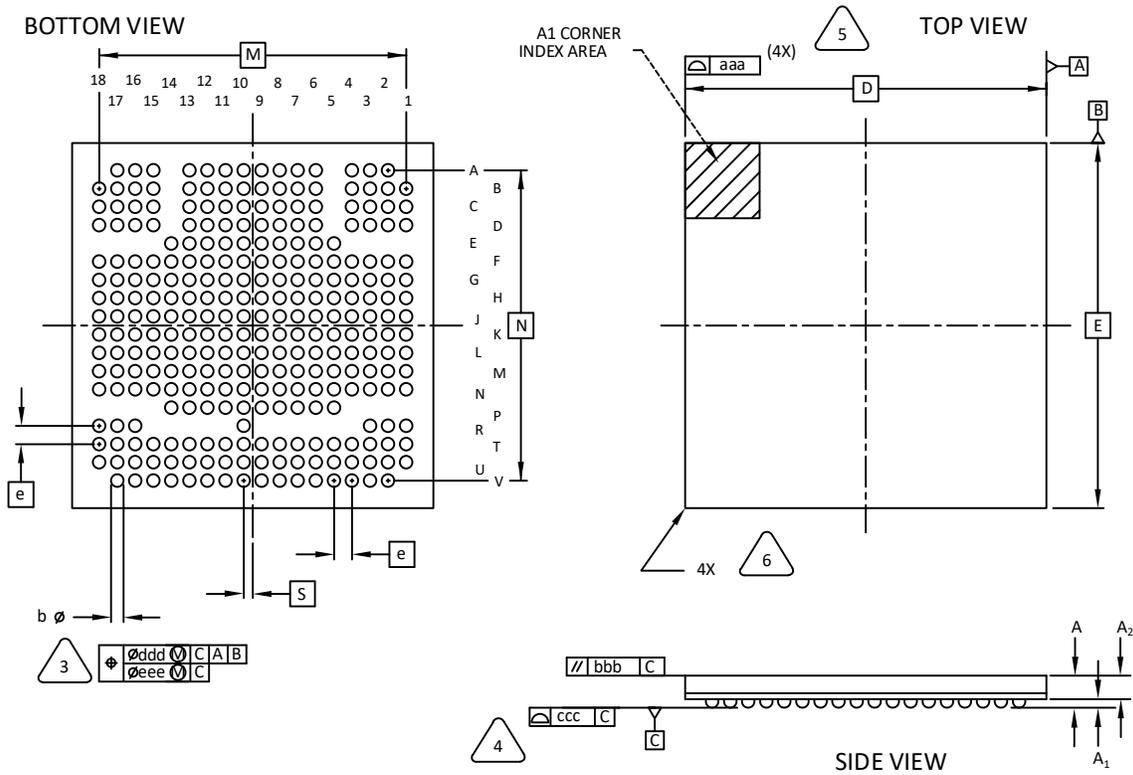
5 BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

6 EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.00
A1	0.15	-	-
A2	-	-	0.85
D/E	12.00 BSC		
M/N	10.50 BSC		
S	0.25 BSC		
b	0.25	0.31	0.37
e	0.50 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.08

105. 285-Ball csfBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

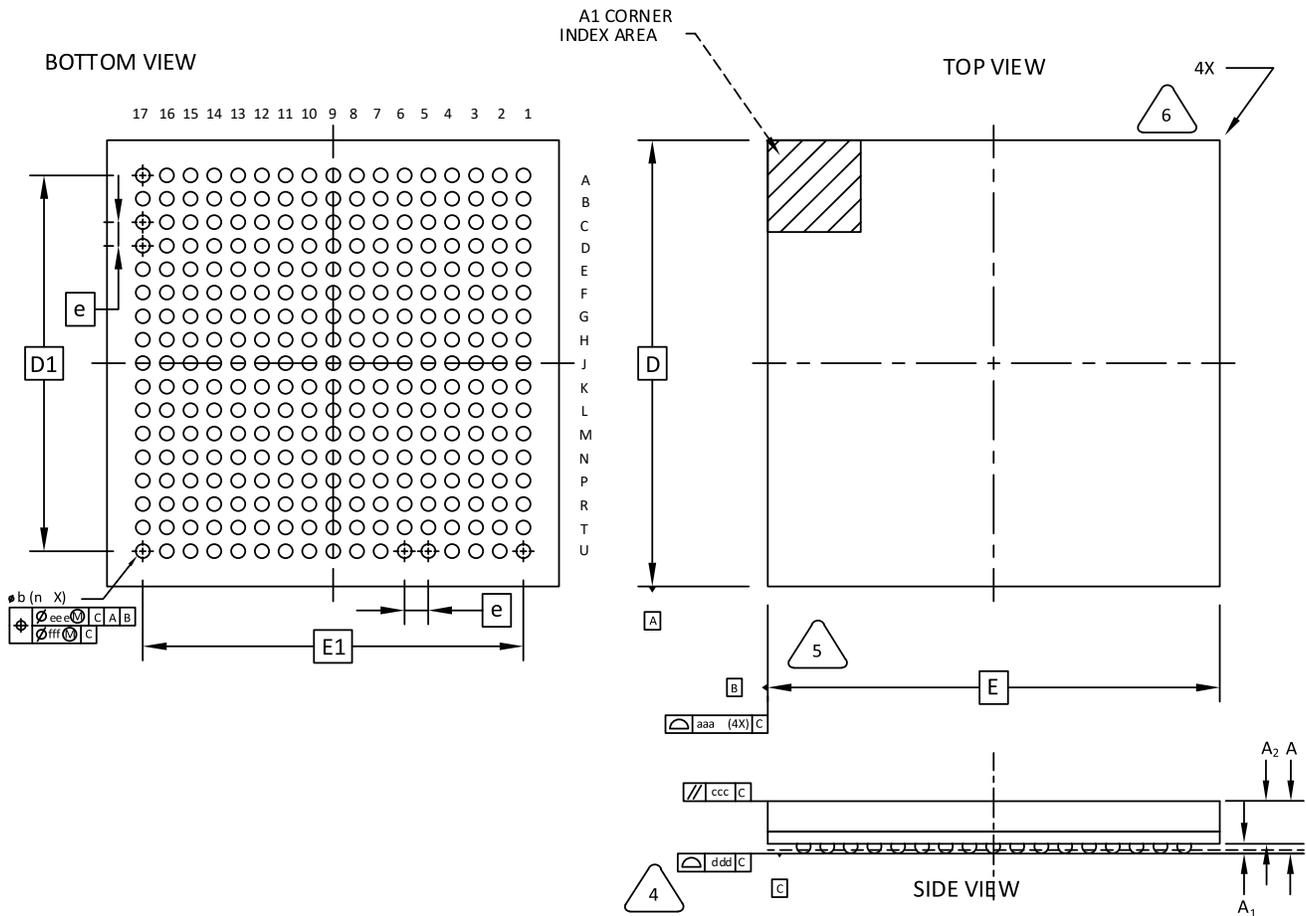
1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.

- 3. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C].
- 4. PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 5. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
- 6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.30
A1	0.15	-	-
A2	-	-	1.00
D/E	10.00 BSC		
M/N	8.50 BSC		
S	0.25 BSC		
b	0.25	0.30	0.35
e	0.50 BSC		
aaa	0.10		
bbb	0.10		
ccc	0.08		
ddd	0.15		
eee	0.05		

106. 289-Ball csBGA Package (9.5 mm × 9.5 mm Body)

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

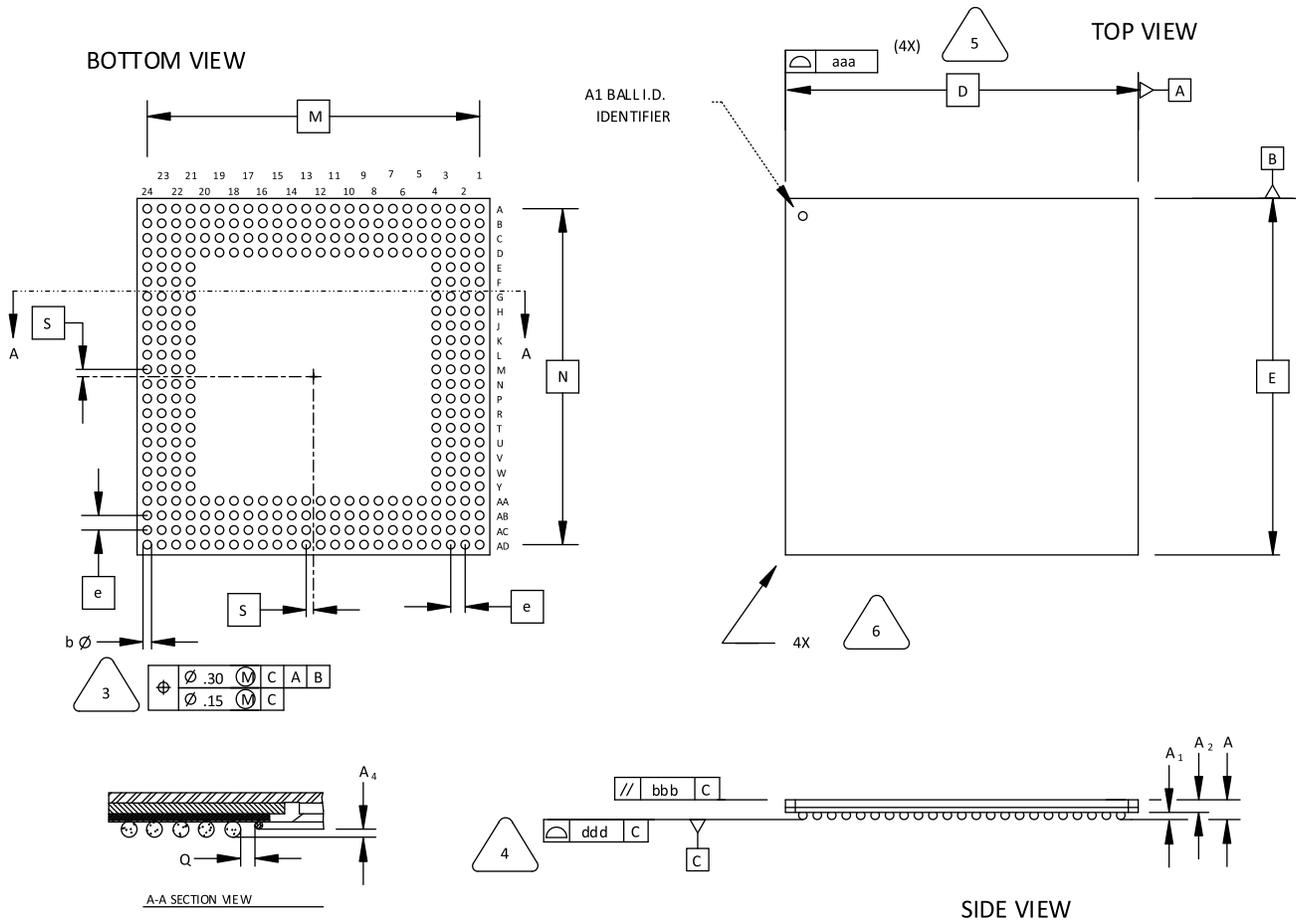
- 7 JEDEC REFERENCE: MO-276N

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.20
A1	0.15	-	-
A2	-	-	1.20
D/E	9.5 BSC		
D1/E1	8.0 BSC		
b	0.25	0.30	0.35
e	0.50 BSC		
aaa	-	-	0.15
ccc	-	-	0.20
ddd	-	-	0.08
eee	-	-	0.15
fff	-	-	0.05

*This Package Outline Drawing and related information apply to CrossLink-NX devices.

107. 320-Ball SBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

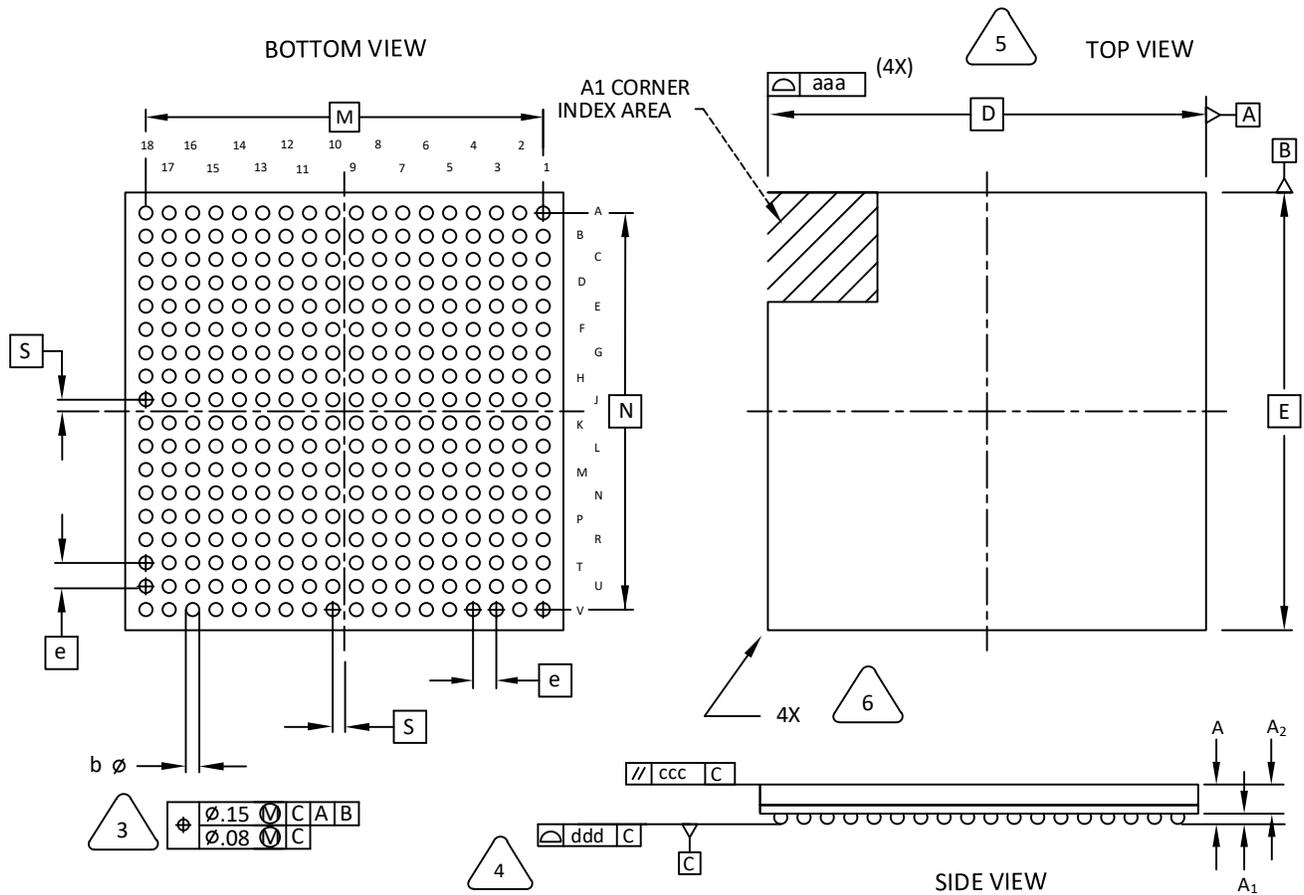


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.70
A1	0.50	0.65	0.80
A2	0.80	0.90	1.00
D/E	31.00 BSC		
M/N	29.21 BSC		
S	0.635 BSC		
b	0.60	0.75	0.90
e	1.27 BSC		
Q	0.25	-	-
A4	0.10	-	-
aaa	-	-	0.20
bbb	-	-	0.25
ddd	-	-	0.20

108. 324-Ball caBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM \square C.



PRIMARY DATUM \square C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

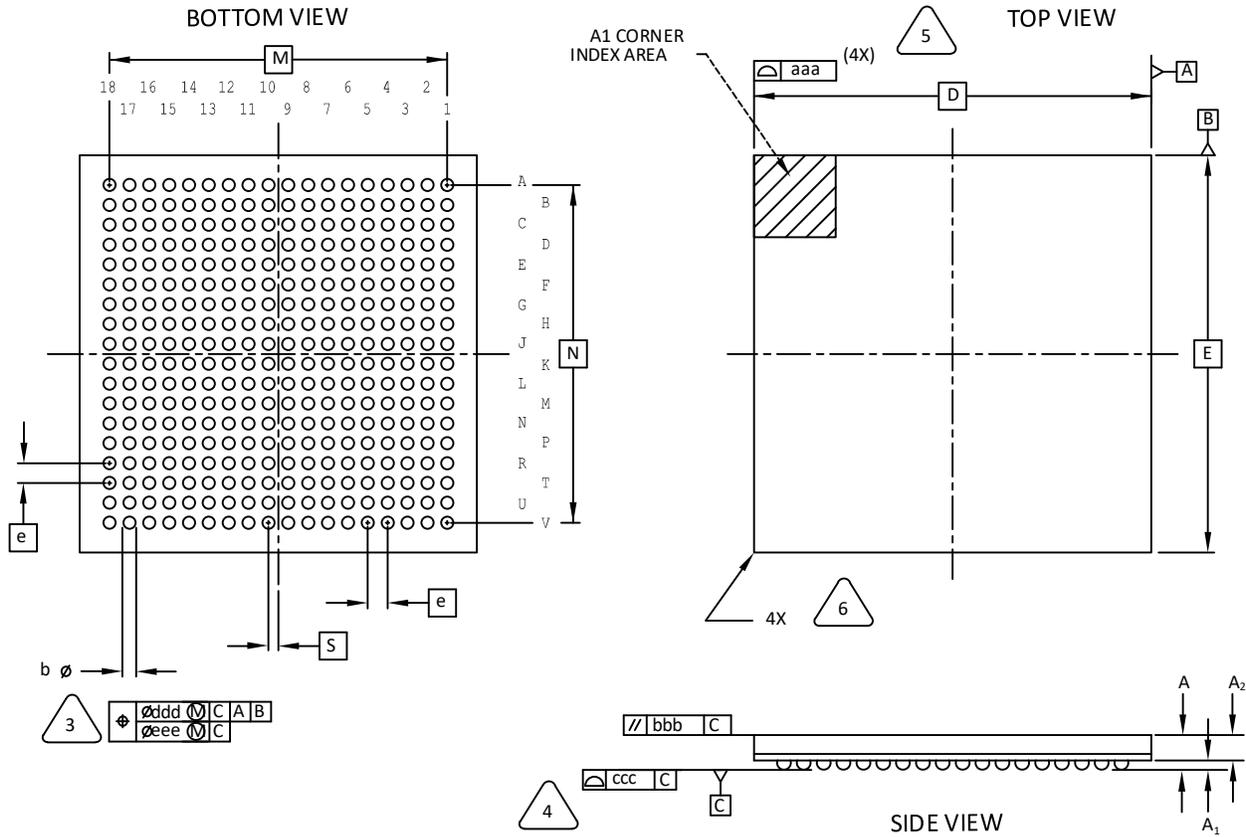


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.70
A1	0.25	0.35	-
A2	0.80	1.00	-
D/E	15.0 BSC		
M/N	13.6 BSC		
S	0.40 BSC		
b	0.40	0.45	0.50
e	0.80 BSC		
aaa	-	-	0.15
ccc	-	-	0.20
ddd	-	-	0.20

109. 324-Ball csfBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C].



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

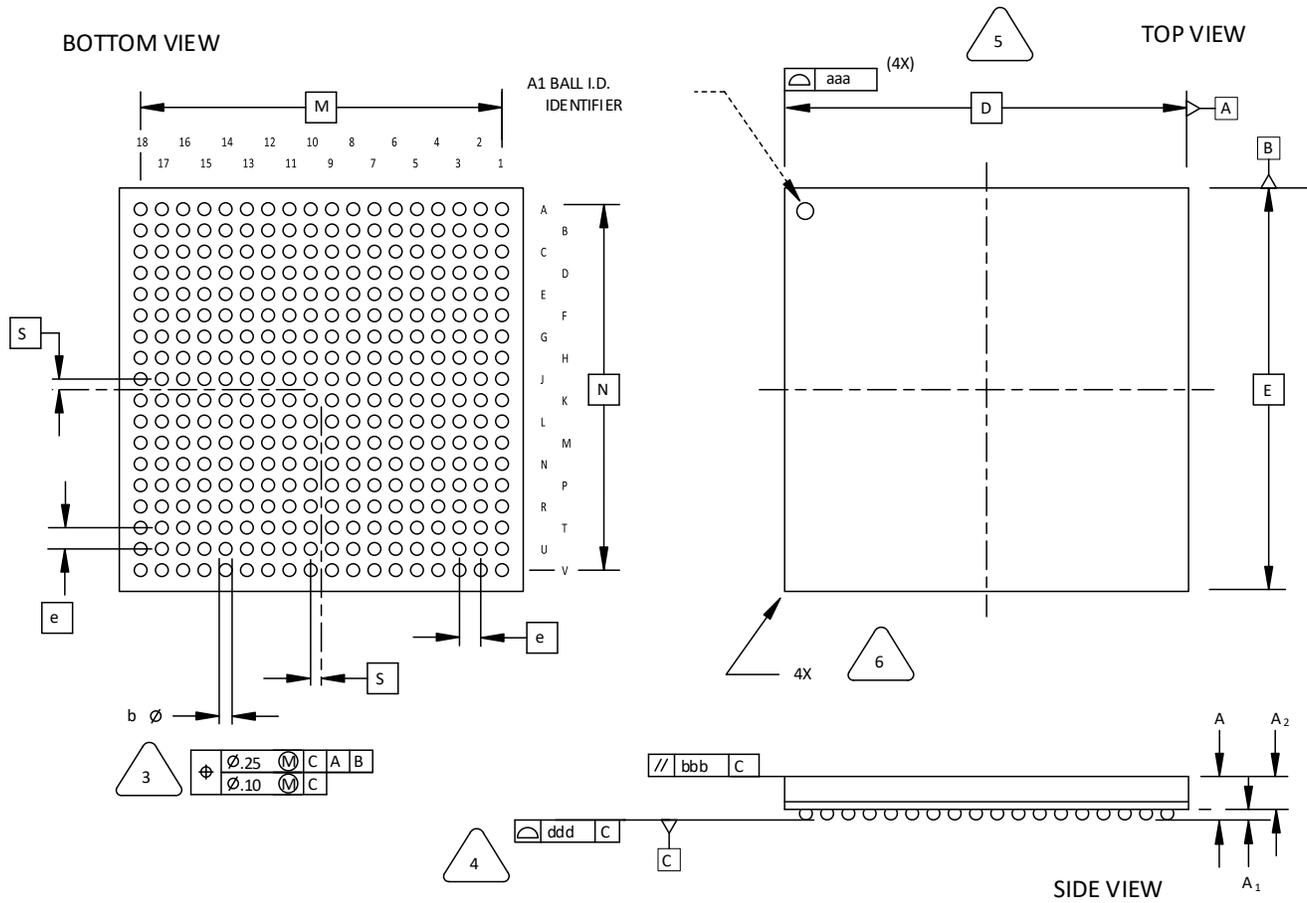


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.00
A1	0.15	0.24	-
A2	-	0.66	-
D/E	10.00 BSC		
M/N	8.50 BSC		
S	0.25 BSC		
b	0.25	0.30	0.35
e	0.50 BSC		
aaa	0.10		
bbb	0.10		
ccc	0.08		
ddd	0.15		
eee	0.05		

110. 324-Ball ftBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM $\square C$



PRIMARY DATUM $\square C$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

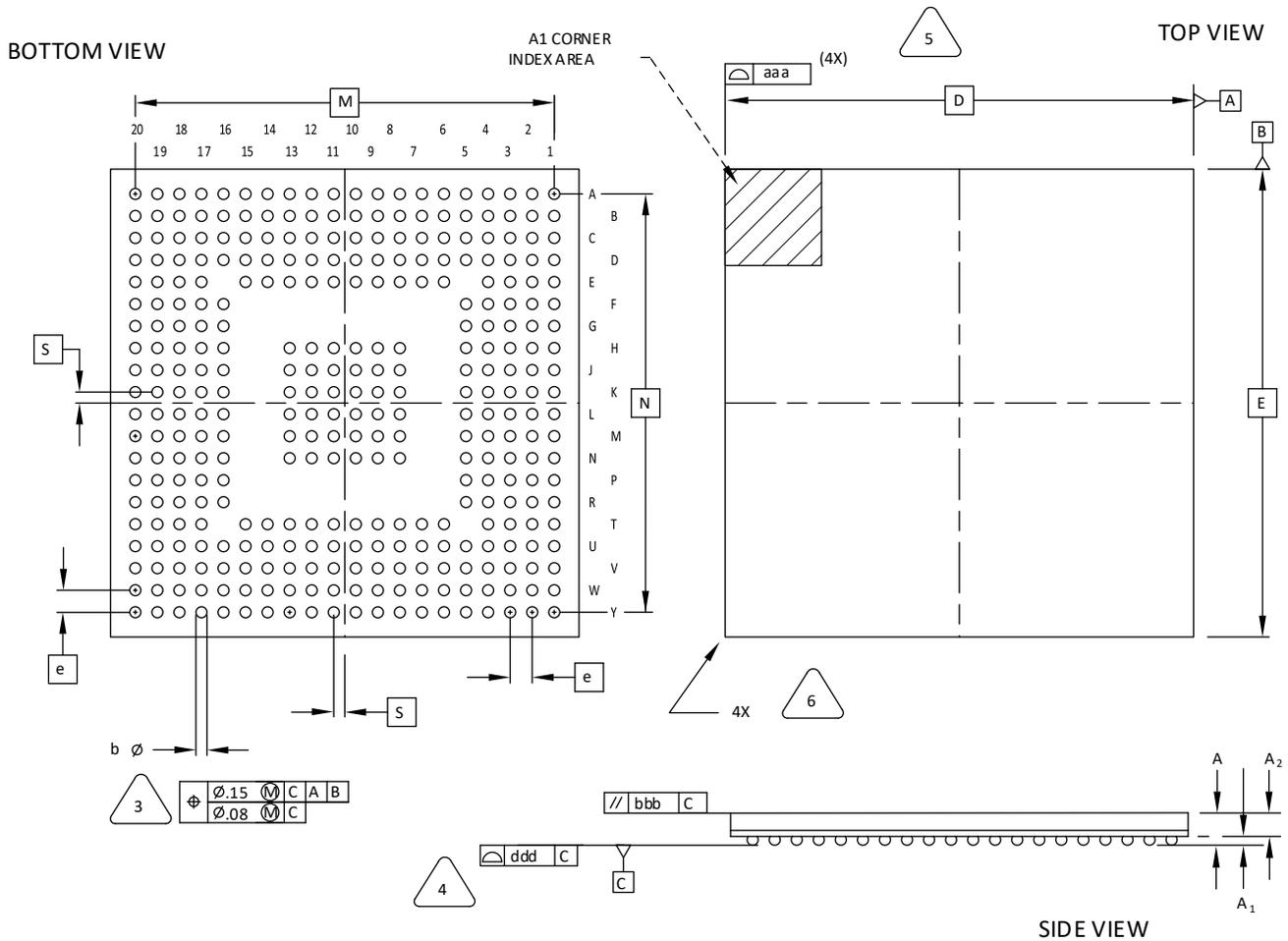


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.25	1.50	1.70
A1	0.30	-	-
A2	-	-	1.40
D/E	19.0 BSC		
M/N	17.0 BSC		
S	0.50 BSC		
b	0.40	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ddd	-	-	0.20

112. 332-Ball caBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM $\square C$



PRIMARY DATUM $\square C$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

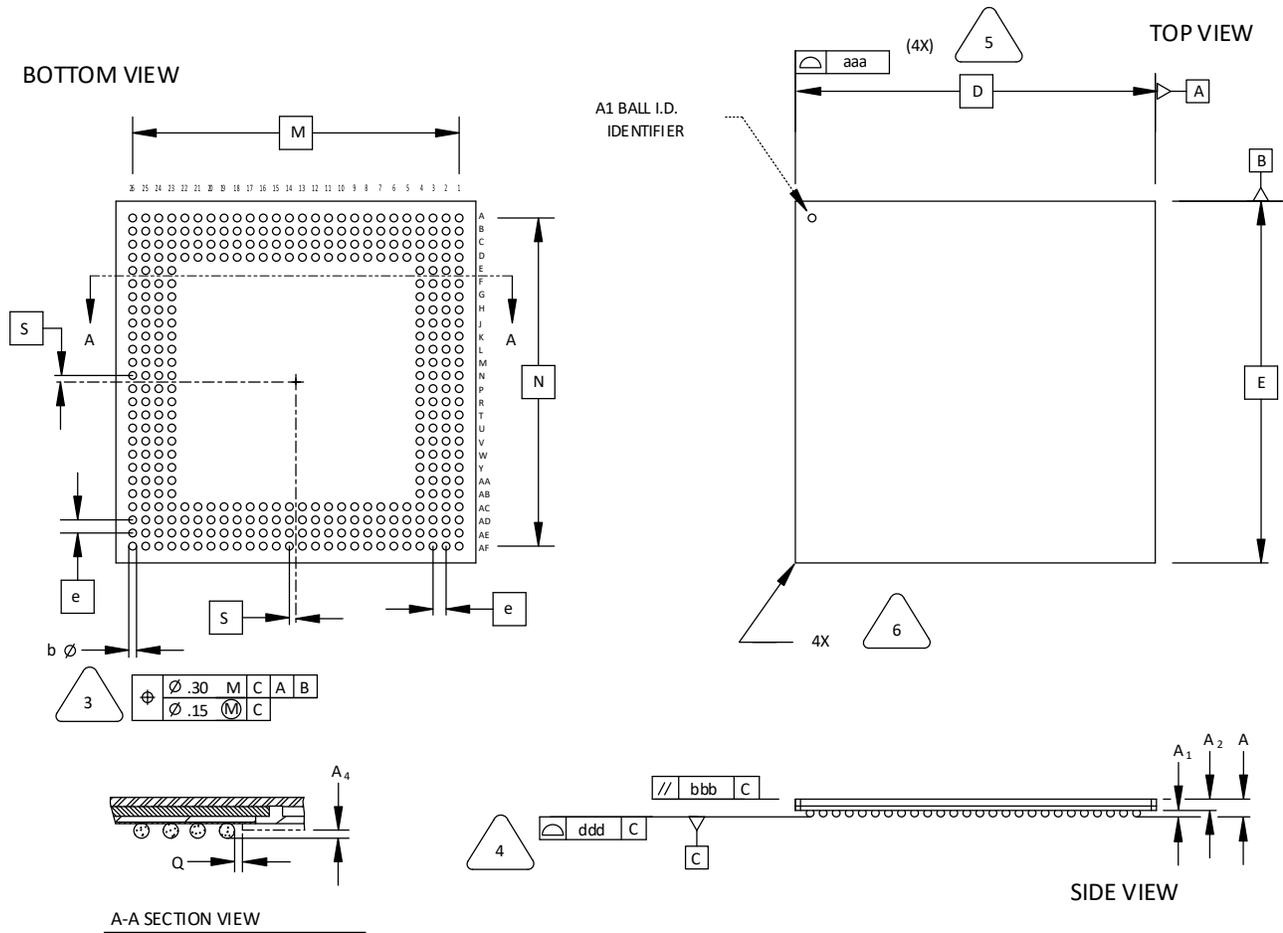


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	2.00
A1	0.25	-	-
A2	0.65	-	-
D/E	17.0 BSC		
M/N	15.2 BSC		
S	0.40 BSC		
b	0.40	0.45	0.50
e	0.80 BSC		
aaa	-	-	0.15
bbb	-	-	0.20
ddd	-	-	0.20

113. 352-Ball SBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

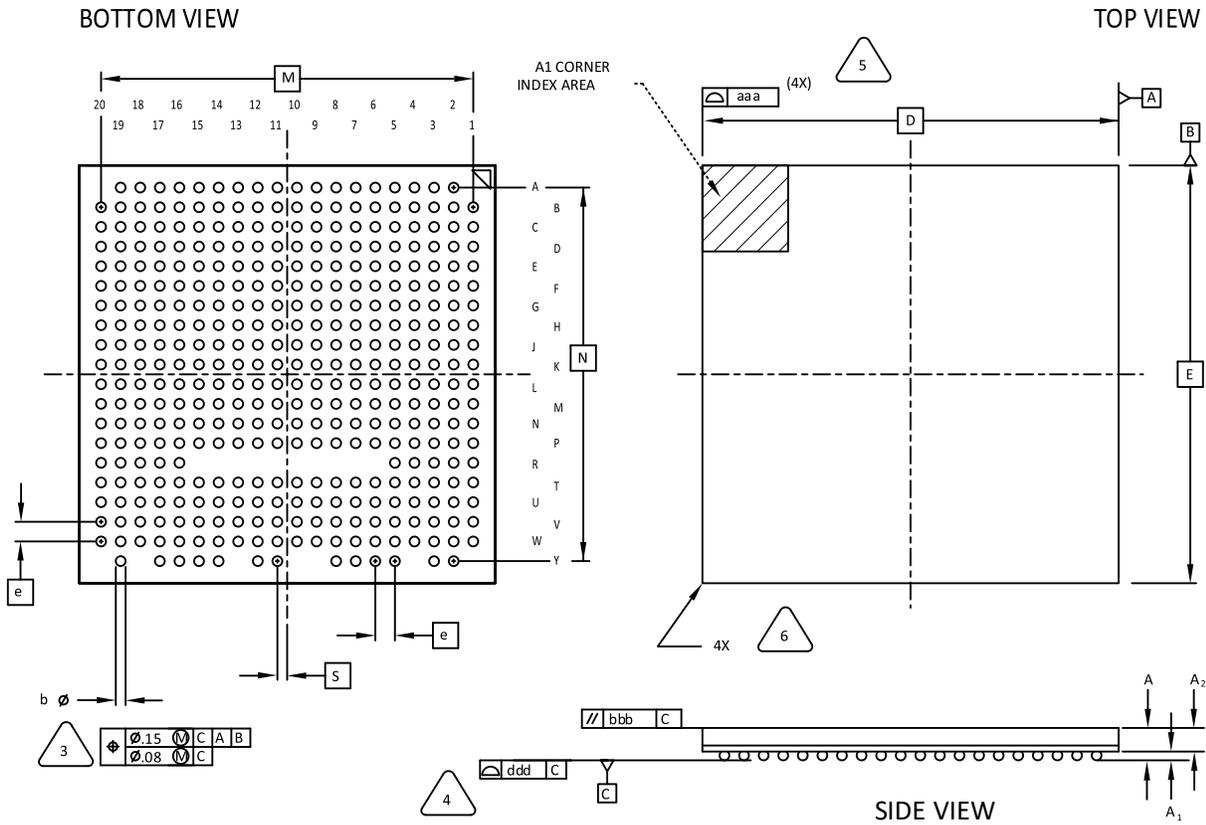
1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.

- 3. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM $\square C$.
- 4. PRIMARY DATUM $\square C$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 5. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
- 6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.70
A1	0.50	0.65	0.80
A2	0.80	0.90	1.00
D/E	35.00 BSC		
M/N	31.75 BSC		
S	0.635 BSC		
b	0.60	0.75	0.90
e	1.27 BSC		
Q	0.25	-	-
A4	0.10	-	-
aaa	-	-	0.20
bbb	-	-	0.25
ddd	-	-	0.20

114. 381-Ball caBGA Package Option 1: All Except LAE5UM-45F

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

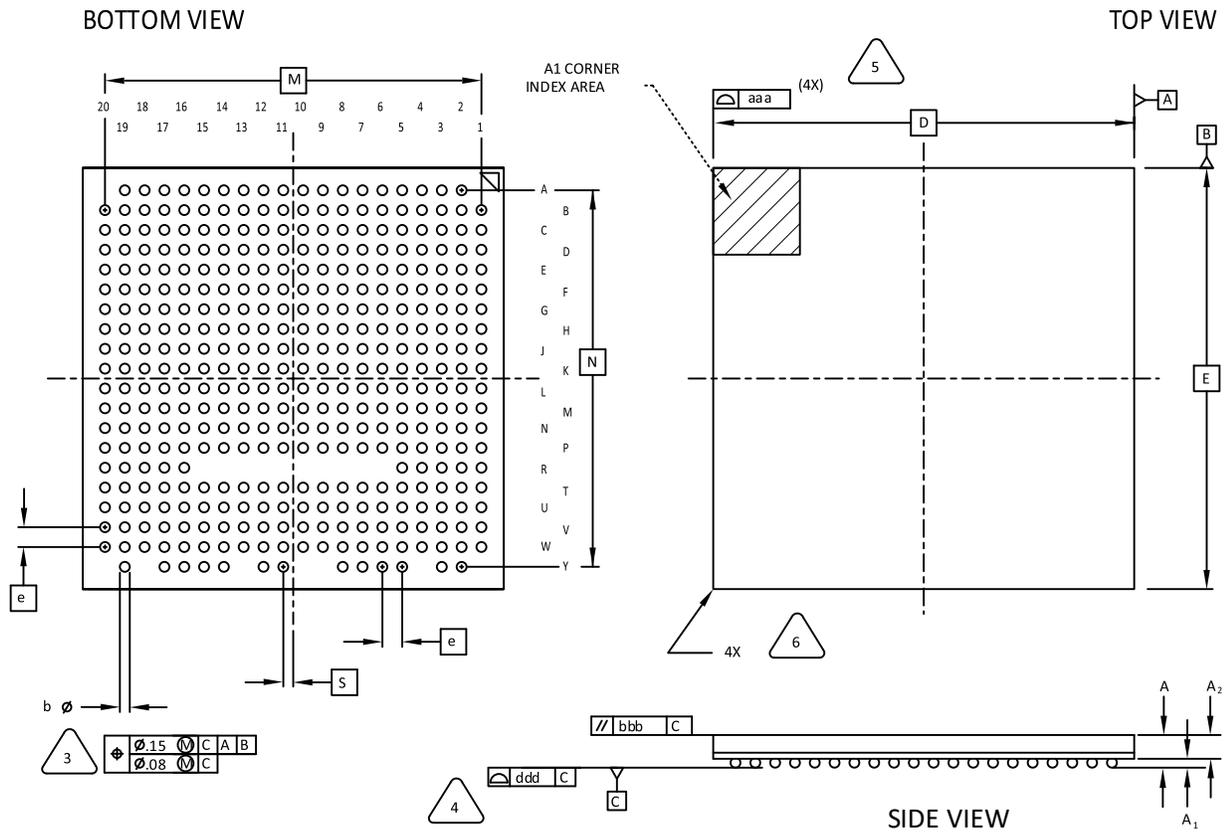


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.76
A1	0.25	0.30	0.35
A2	0.80	-	-
D/E	17.00 BSC		
M/N	15.20 BSC		
S	0.40 BSC		
b	0.35	0.40	0.45
e	0.80 BSC		
aaa	-	-	0.15
bbb	-	-	0.20
ddd	-	-	0.12

115. 381-Ball caBGA Package Option 2: LAE5UM-45F

Dimensions in Millimeters



NOTES : UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y 14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM \square C



PRIMARY DATUM \square C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

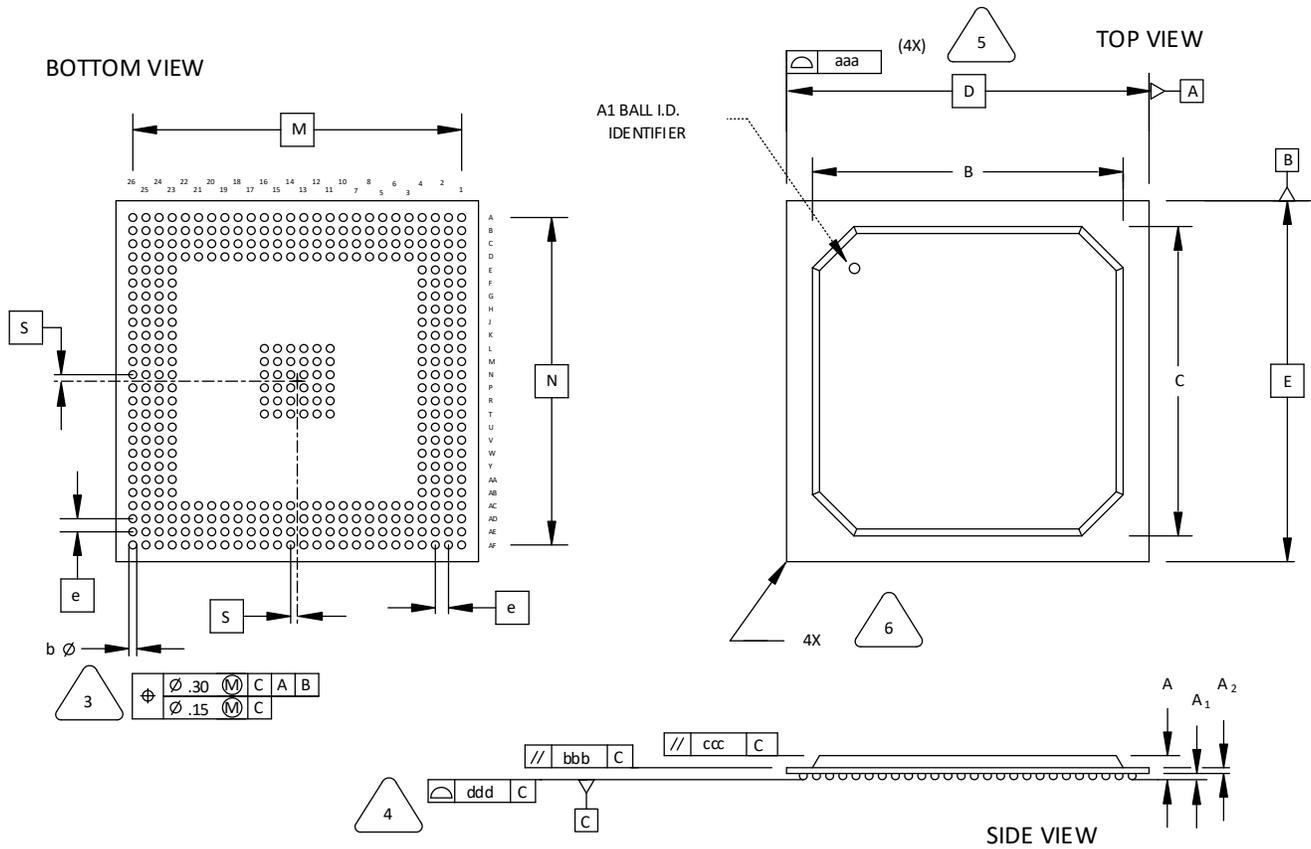


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.76
A1	0.25	0.30	0.35
A2	0.80	-	-
D/E	17.00 BSC		
M/N	15.20 BSC		
S	0.40 BSC		
b	0.35	0.40	0.45
e	0.80 BSC		
aaa	-	-	0.15
bbb	-	-	0.20
ddd	-	-	0.10

116. 388-Ball BGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

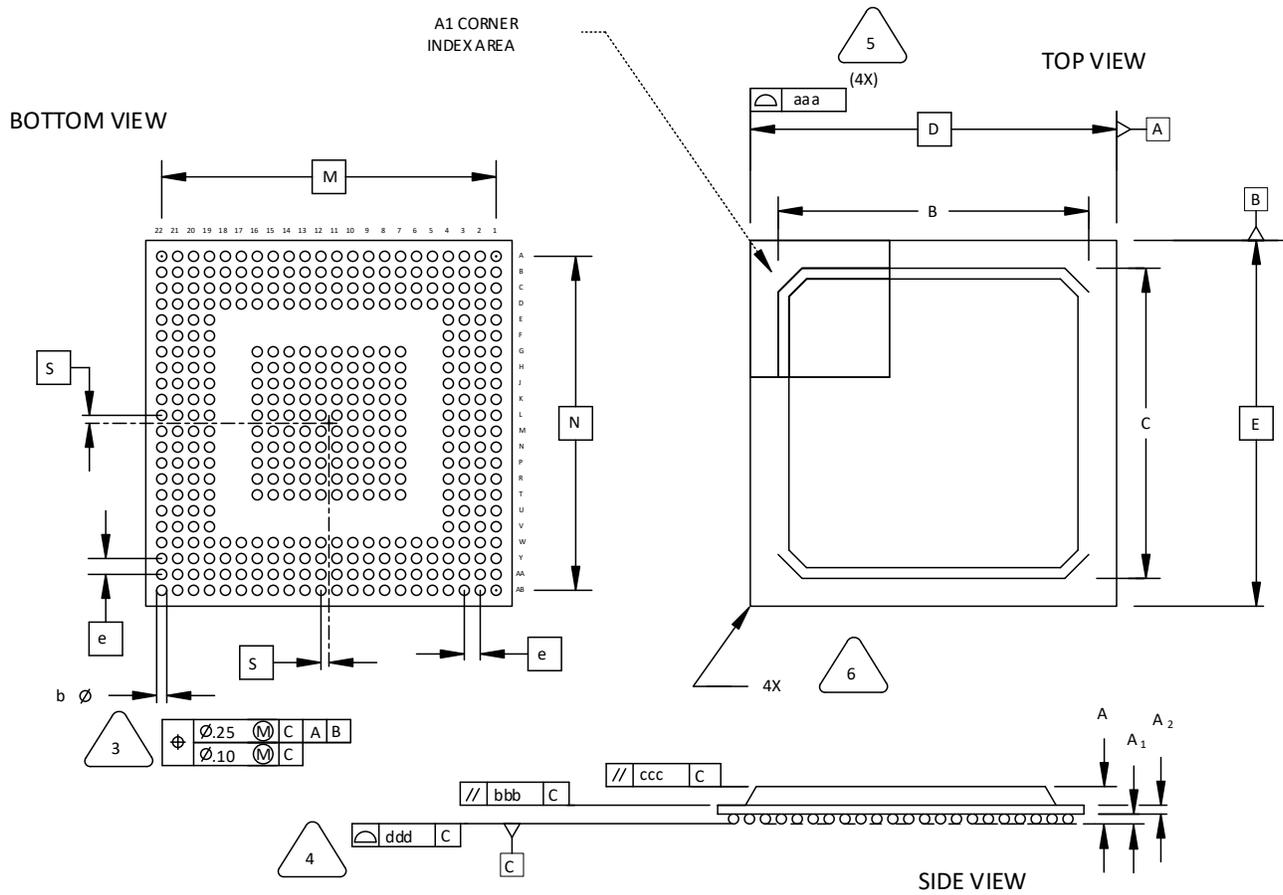


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.90	2.80	3.25
A1	0.50	0.65	0.80
A2	0.28	0.54	0.80
B/C	29.80	31.80	33.80
D/E	35.00 BSC		
M/N	31.75 BSC		
S	0.635 BSC		
b	0.60	0.75	0.90
e	1.27 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

117. 388-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM $\square C$



PRIMARY DATUM $\square C$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

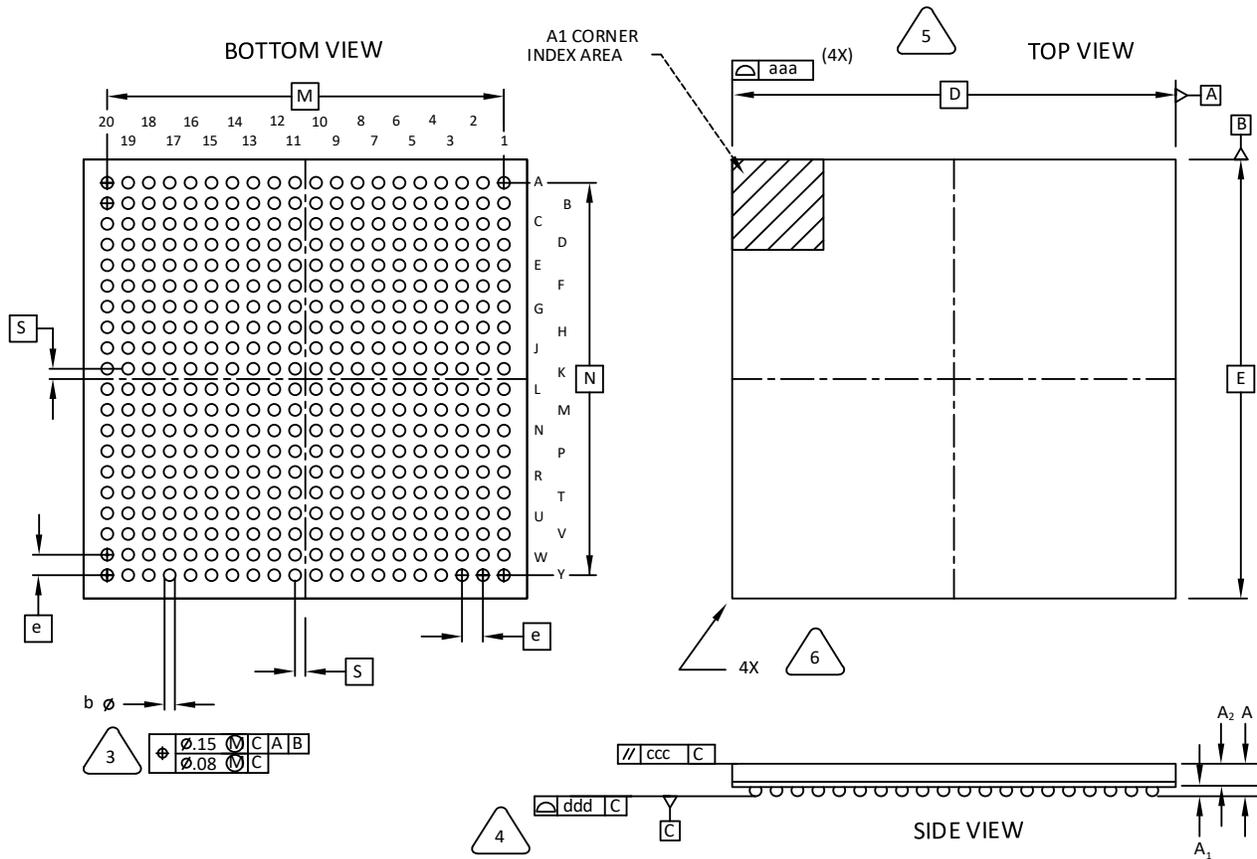


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.70	2.15	2.60
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	19.30	19.80	20.30
D/E	23.00 BSC		
M/N	21.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

118. 400-Ball BBG/caBGA Package Option 1

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C].



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



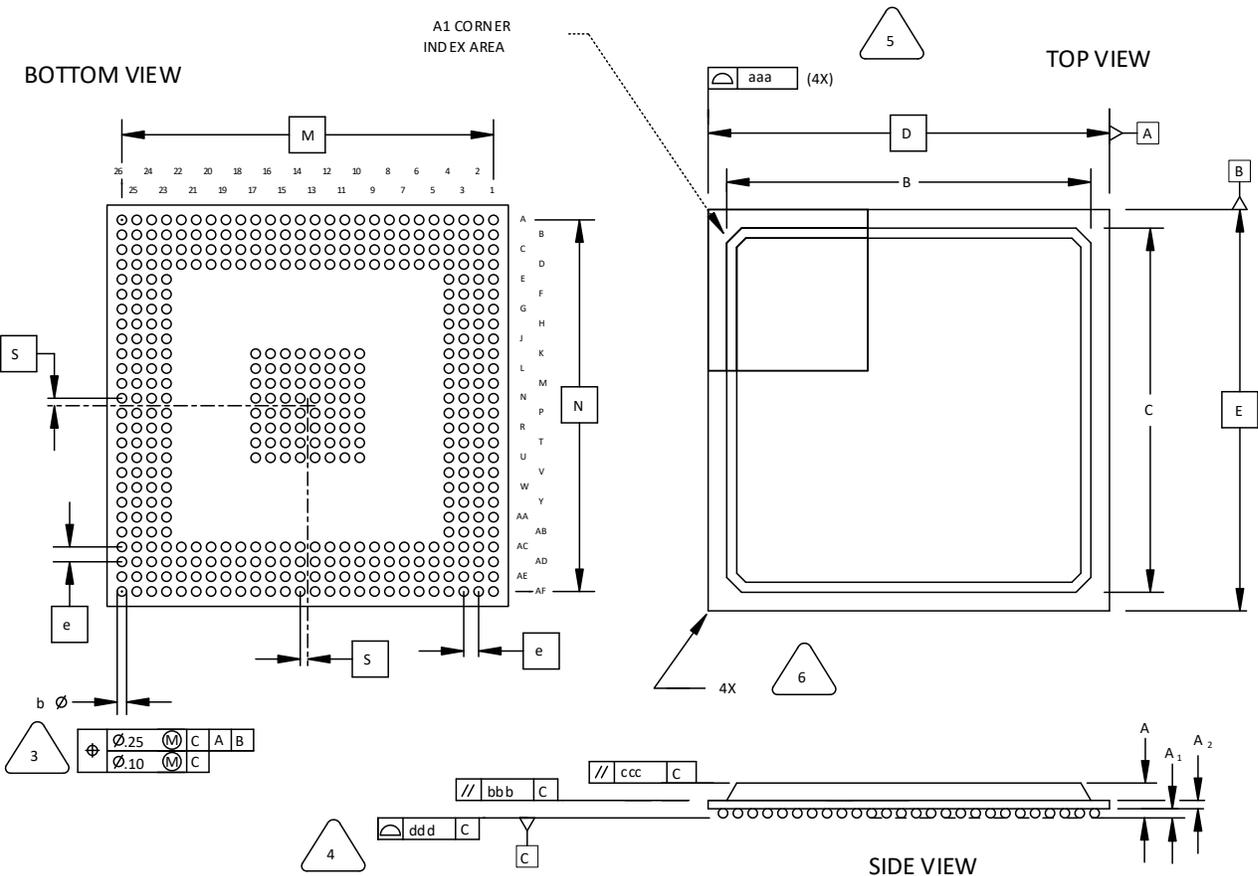
EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.70
A1	0.25	0.35	-
A2	0.80	1.00	-
D/E	17.0 BSC		
M/N	15.2 BSC		
S	0.40 BSC		
b	0.40	0.45	0.50
e	0.80 BSC		
aaa	-	-	0.15
ccc	-	-	0.20
ddd	-	-	0.20

*This Package Outline Drawing and related information apply to MachXO3 devices.

120. 416-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM \square C



PRIMARY DATUM \square C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

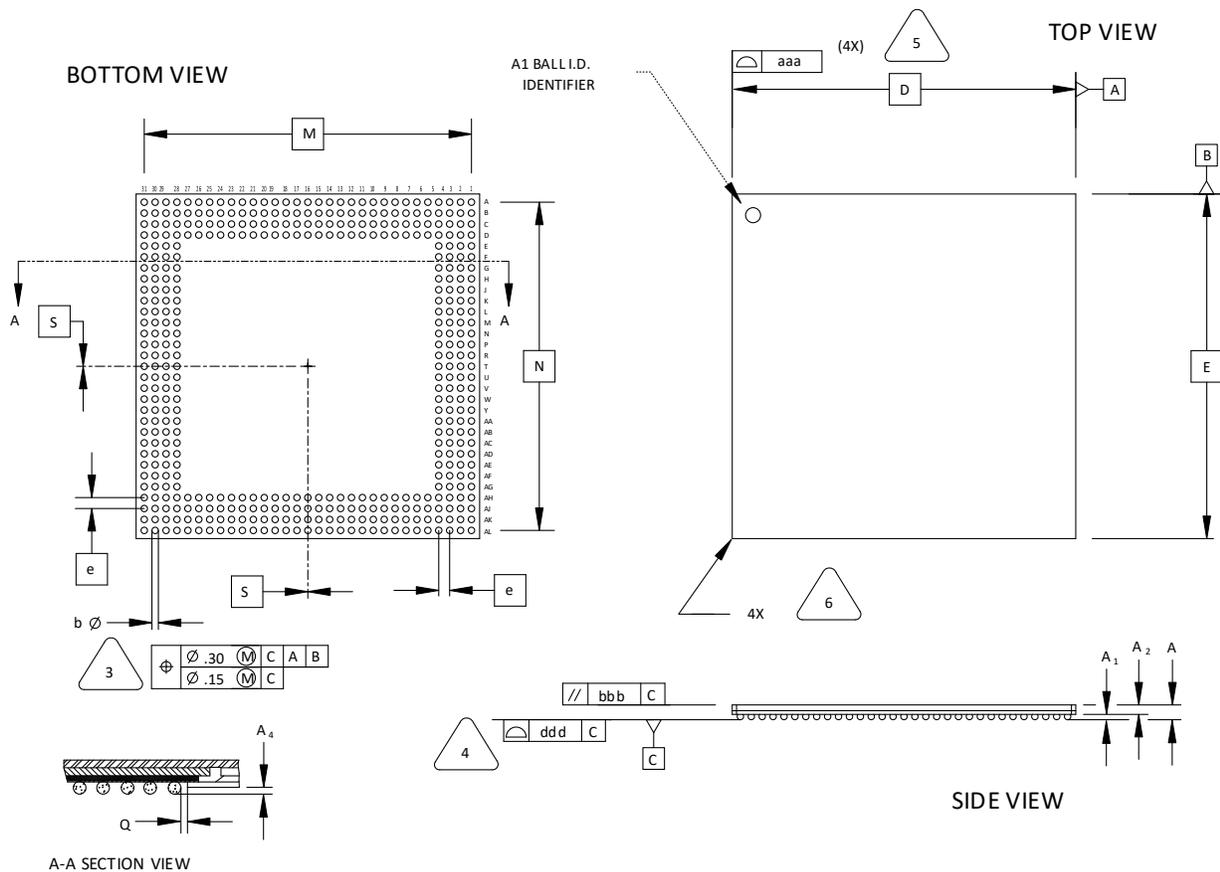


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.70	2.15	2.60
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	23.80	24.80	25.80
D/E	27.00 BSC		
M/N	25.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

121. 432-Ball SBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM \square C



PRIMARY DATUM \square C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

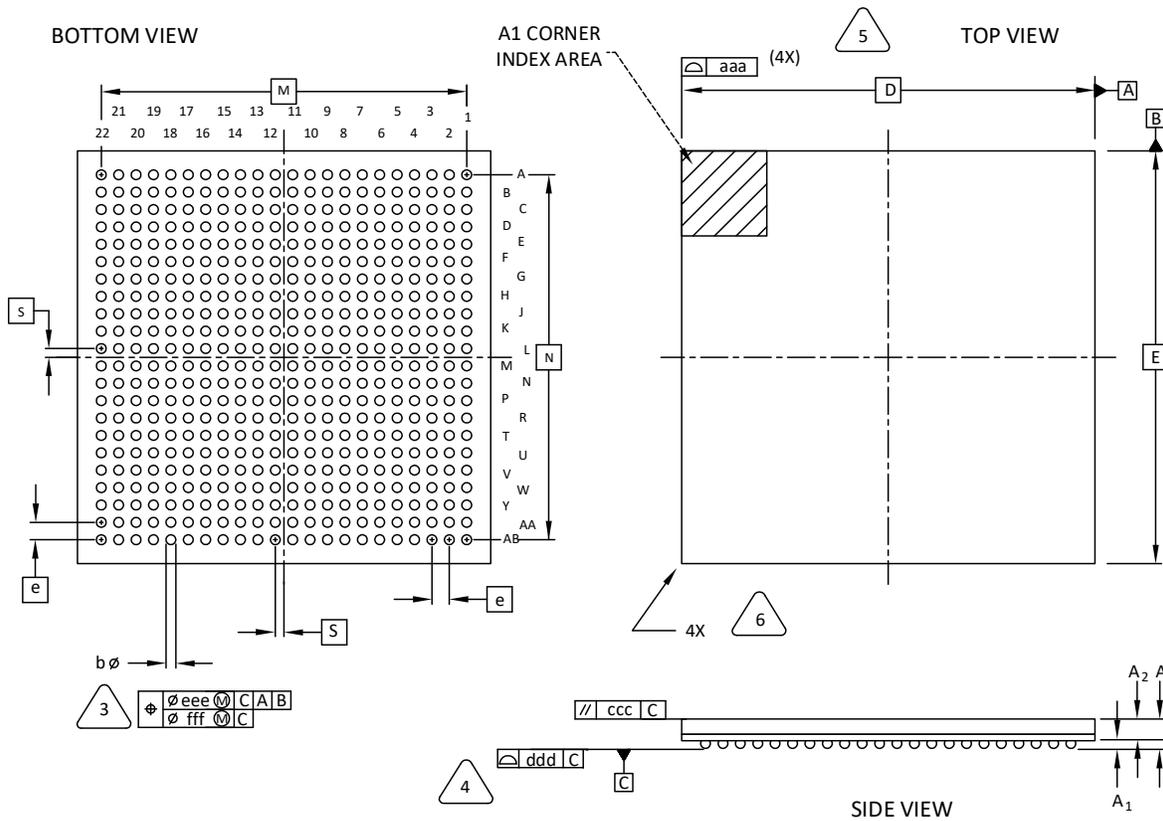


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.70
A1	0.50	0.65	0.80
A2	0.80	0.90	1.00
D/E	40.00 BSC		
M/N	38.10 BSC		
S	0.00 BSC		
b	0.60	0.75	0.90
e	1.27 BSC		
Q	0.25	-	-
A4	0.10	-	-
aaa	-	-	0.20
bbb	-	-	0.25
ddd	-	-	0.20

122. 484-Ball BBG/caBGA Package Option 1

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.

3. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C
4. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

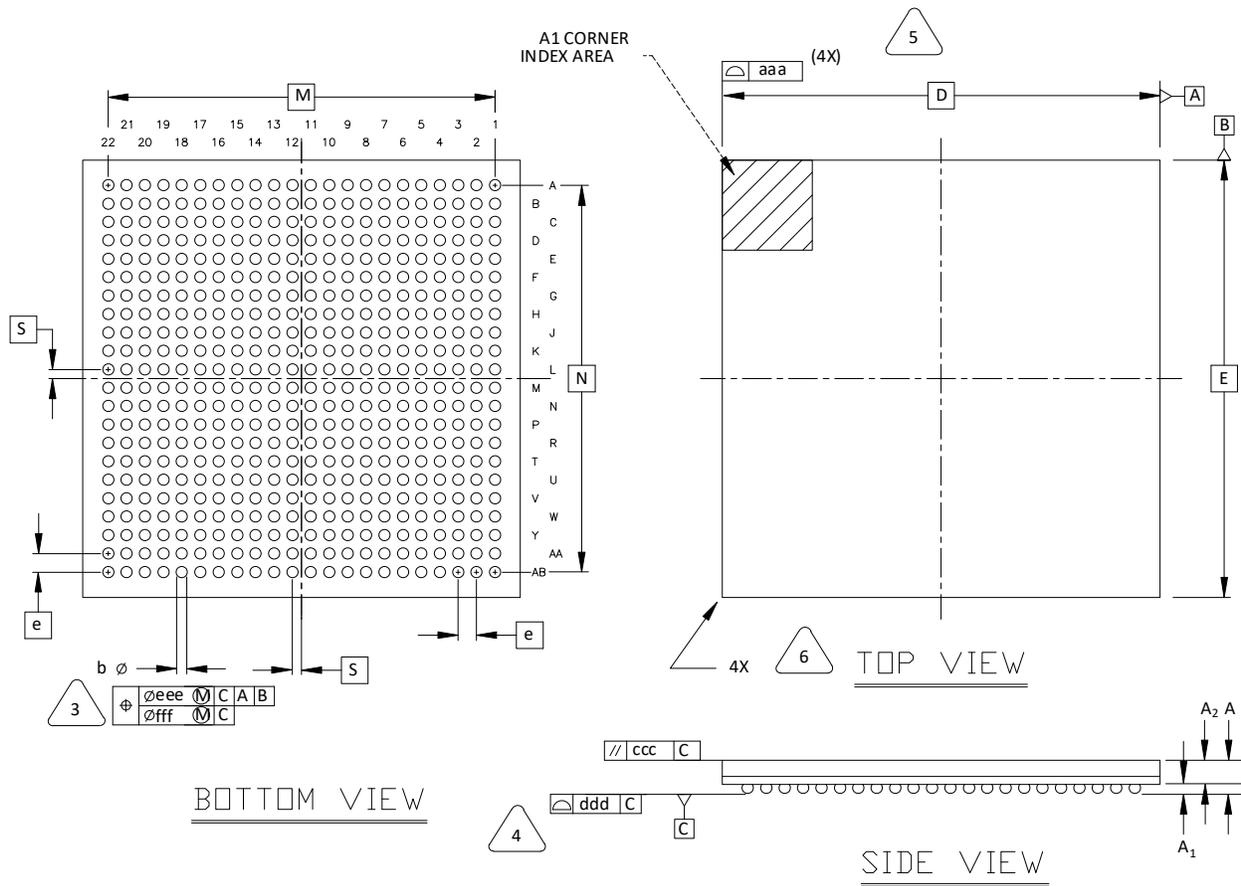
7. JEDEC REFERENCE: MO-275A

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.70
A1	0.25	-	-
A2	0.65	-	-
D/E	19.0 BSC		
M/N	16.8 BSC		
S	0.40 BSC		
b	0.40	0.45	0.50
e	0.80 BSC		
aaa	-	-	0.15
ccc	-	-	0.20
ddd	-	-	0.20
eee	-	-	0.15
fff	-	-	0.08

*This Package Outline Drawing and related information applies to MachXO3/MachXO3D devices.

123. 484-Ball BBG/caBGA Package Option 2

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.

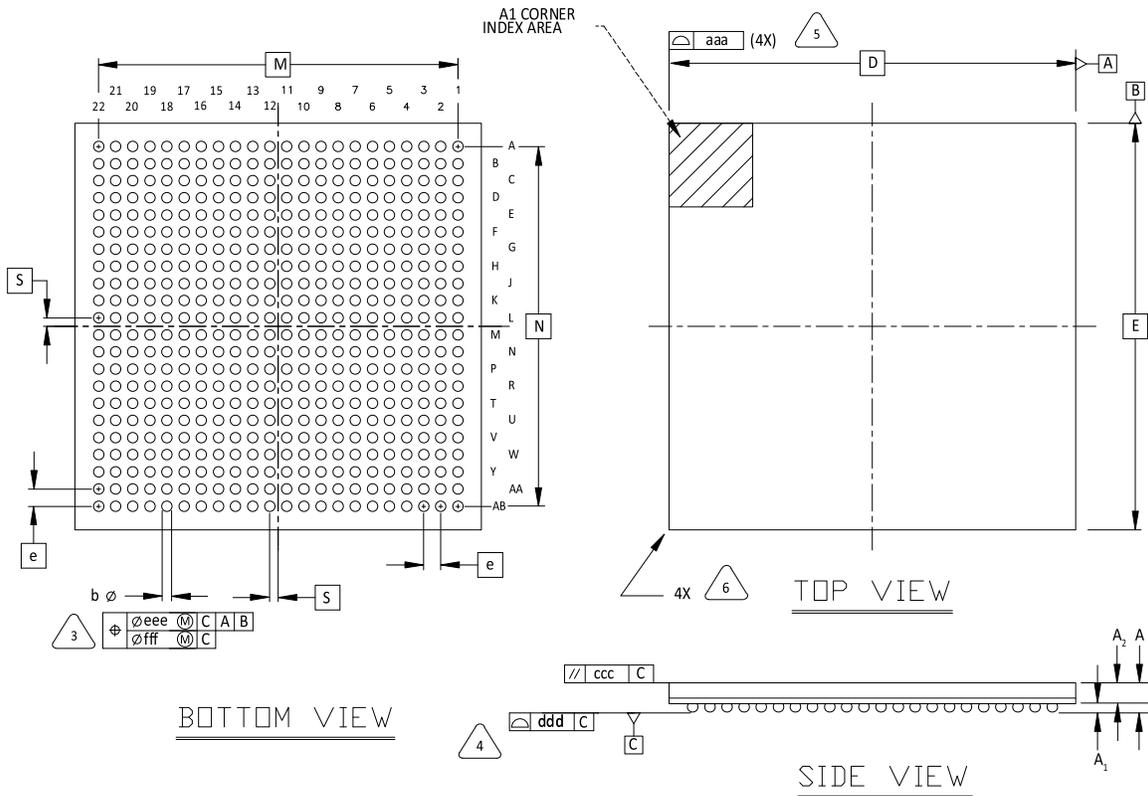
- 3 DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C
- 4 PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 5 BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
- 6 EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
- 7 JEDEC REFERENCE: MO-275A

SYMBOL	MIN.	NOM.	MAX.
A	1.374	1.450	1.500
A1	0.360	0.410	0.460
A2	0.960	1.040	1.120
D/E	19.0 BSC		
M/N	16.8 BSC		
S	0.40 BSC		
b	0.45	0.50	0.55
e	0.80 BSC		
aaa	0.15		
ccc	0.20		
ddd	0.20		
eee	0.15		
fff	0.08		

*This Package Outline Drawing and related information apply to CertusPro-NX devices.

124. 484-Ball BBG/caBGA Package Option 3

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

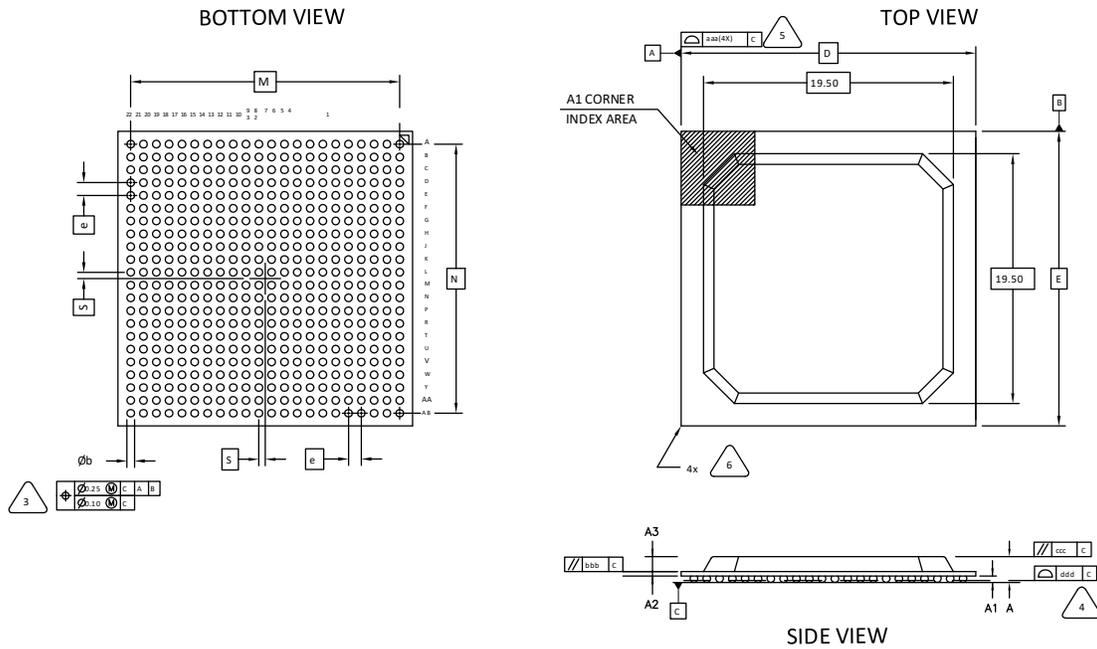
1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS
3. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]
4. PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
7. JEDEC REFERENCE: MO-275A

SYMBOL	MIN.	NOM.	MAX.
A	1.296	1.372	1.500
A1	0.360	0.410	0.460
A2	0.882	0.962	1.042
D/E	19.0 BSC		
M/N	16.8 BSC		
s	0.40 BSC		
b	0.45	0.50	0.55
e	0.80 BSC		
aaa	0.15		
ccc	0.20		
ddd	0.20		
eee	0.15		
fff	0.08		

* This Package Outline Drawing and related information applies to MachXO5-NX and Certus-NX devices.

125. 484-Ball BFG484/PBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM \square C



PRIMARY DATUM \square C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

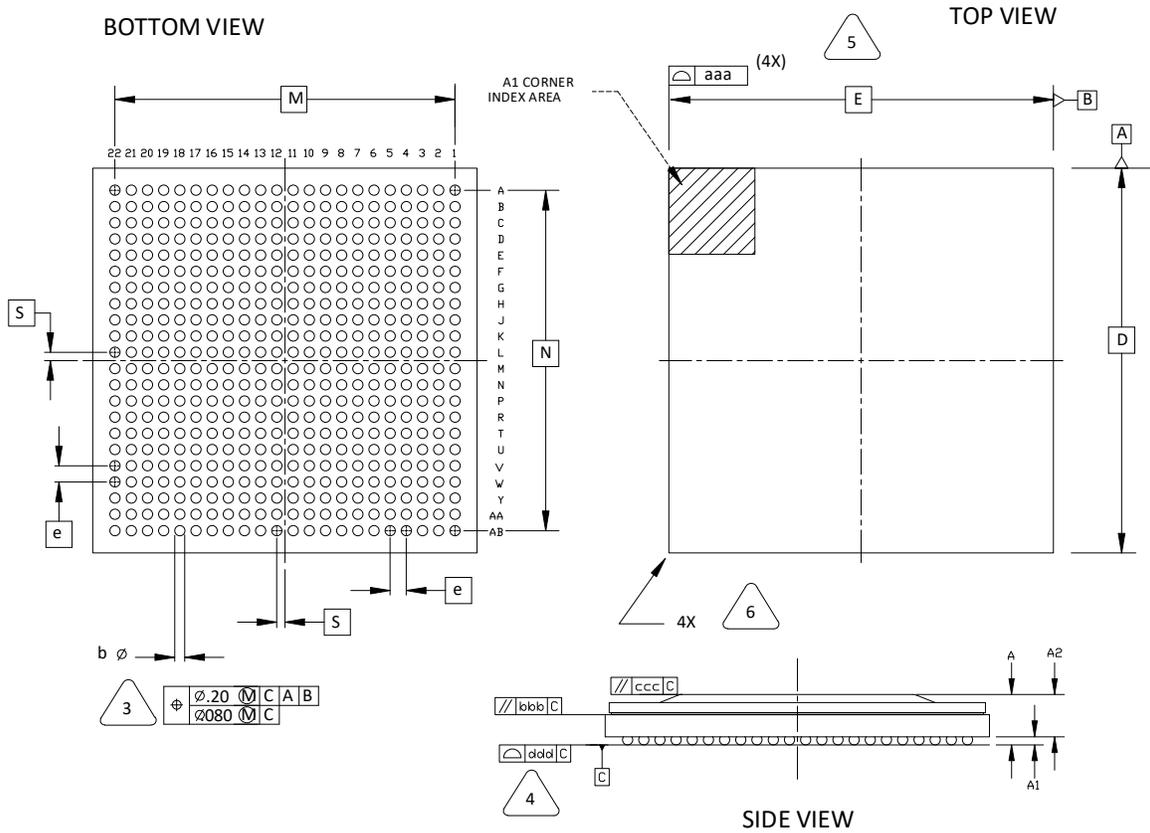
7. JEDEC REFERENCE: MO-318B

SYMBOL	MIN.	NOM.	MAX.
A	-	-	2.20
A1	0.30	-	-
A2	-	-	1.90
A3	1.170 Ref		
D/E	23.0 BSC		
M/N	21.0 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	0.20		
bbb	0.25		
ccc	0.35		
ddd	0.20		

**This Package Outline Drawing and related information apply to CertusPro-NX devices.*

126. 484-Ball fcBGA Package

Dimensions in Millimeters



NOTES:

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO PRIMARY DATUM $\square C$



PRIMARY DATUM $\square C$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

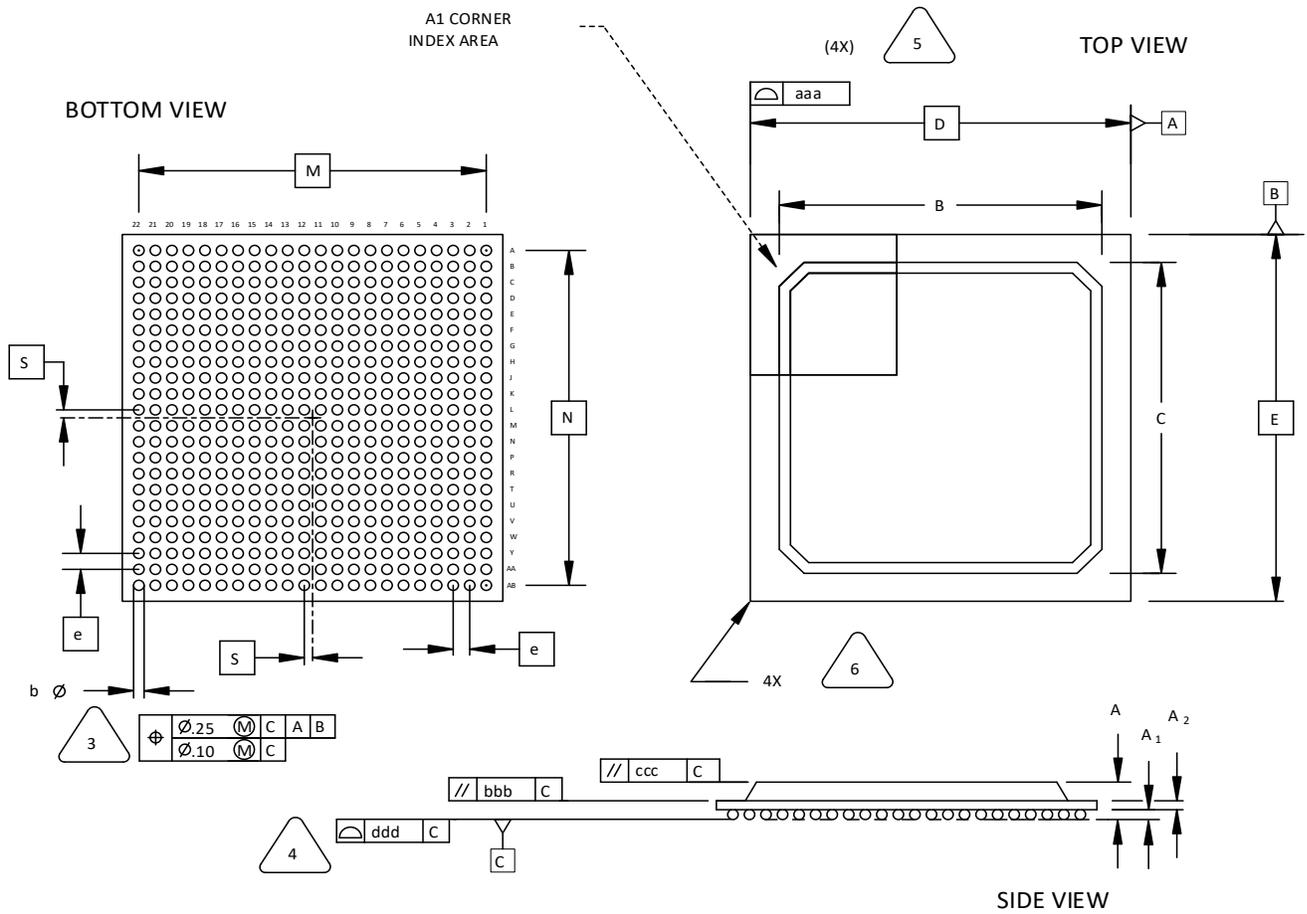
7. JEDEC REFERENCE: JEP95 DR 4.5

SYMBOL	MIN.	NOM.	MAX.
A	-	-	2.736
A1	0.27	-	-
A2	2.086 REF		
D/E	19.00 BSC		
M/N	16.80 BSC		
S	0.40 BSC		
b	0.45	0.50	0.55
e	0.80 BSC		
aaa	-	-	0.15
bbb	-	-	0.10
ccc	-	-	0.35
ddd	-	-	0.20

**This Package Outline Drawing and related information apply to Mach-NX devices.*

127. 484-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM \boxed{C}



PRIMARY DATUM \boxed{C} AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

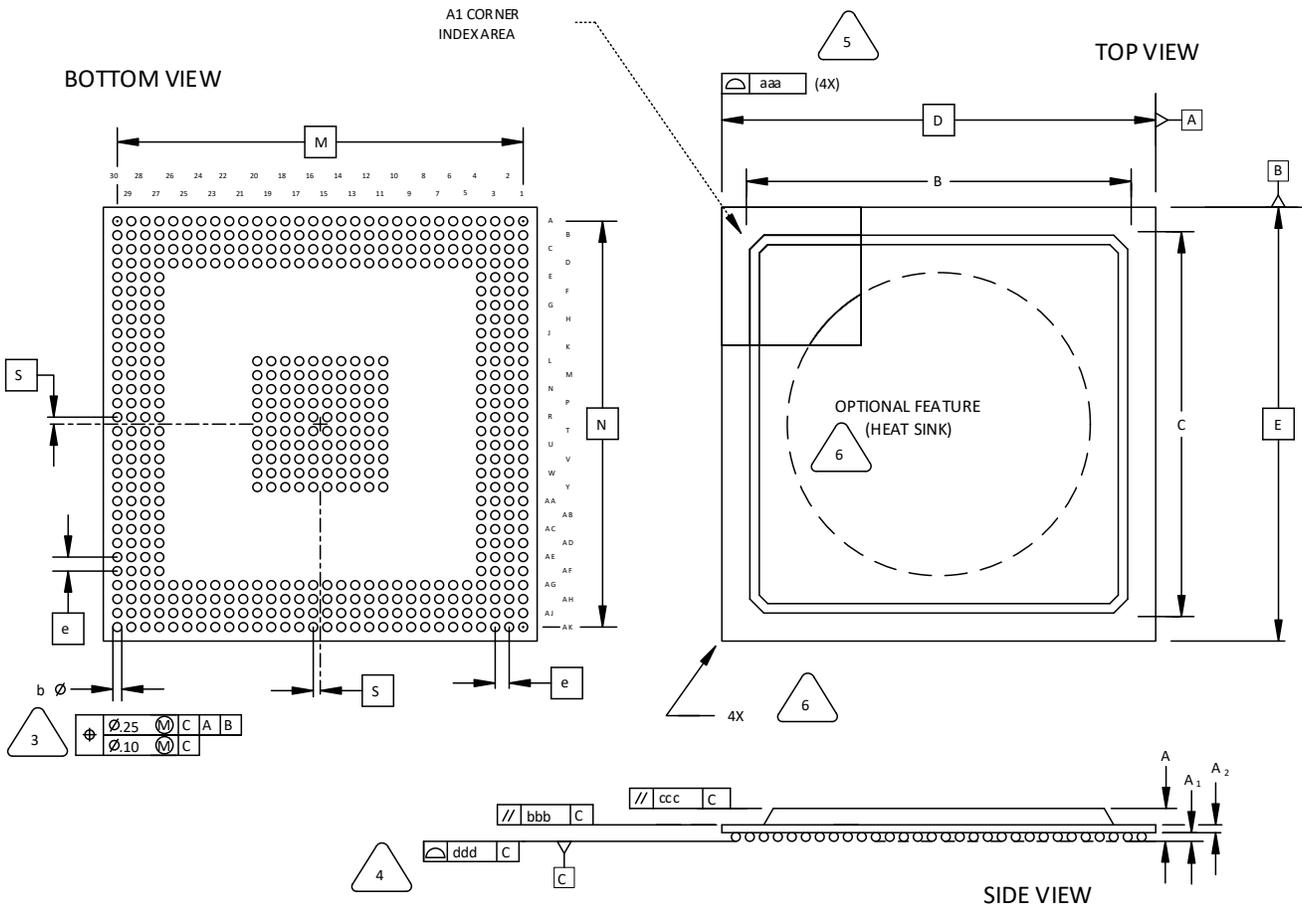


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.70	2.15	2.60
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	19.30	19.80	20.30
D/E	23.00 BSC		
M/N	21.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

128. 516-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

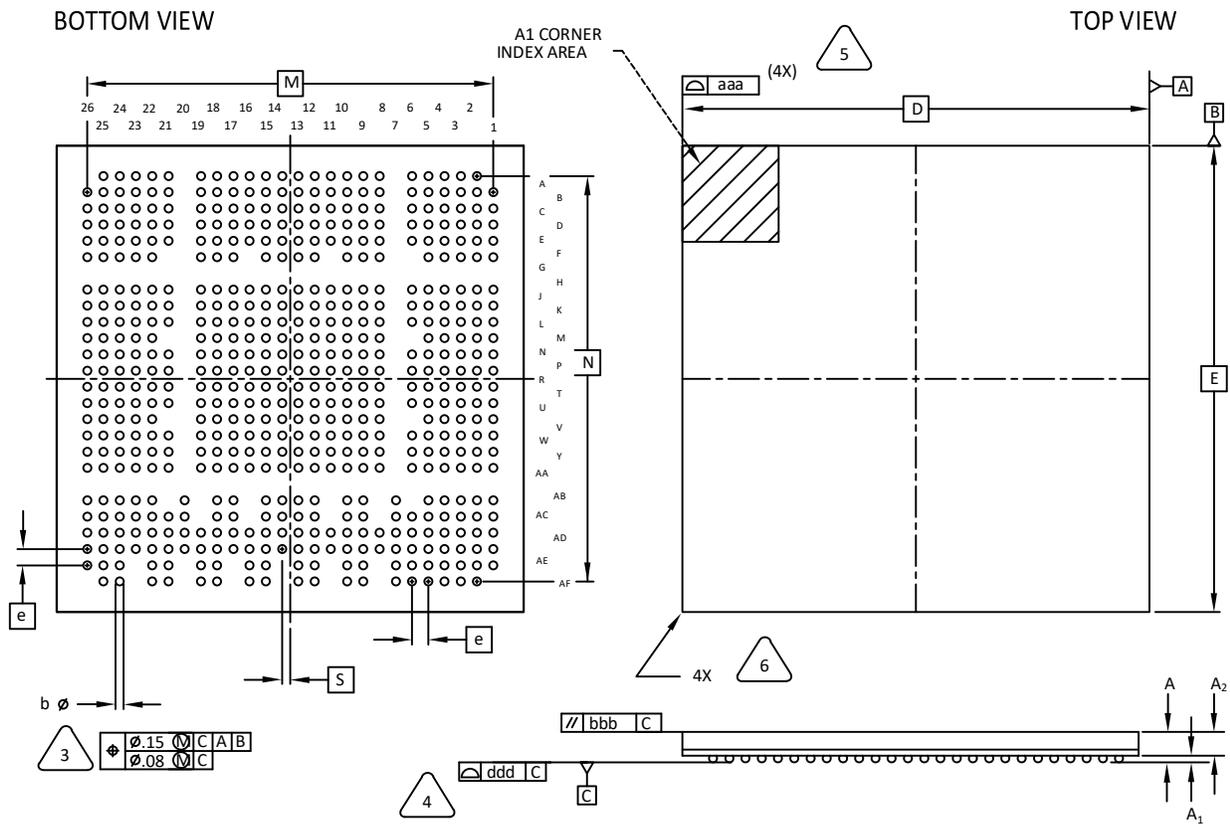


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.70	2.15	2.60
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	25.80	27.55	29.30
D/E	31.00 BSC		
M/N	29.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

129. 554-Ball caBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

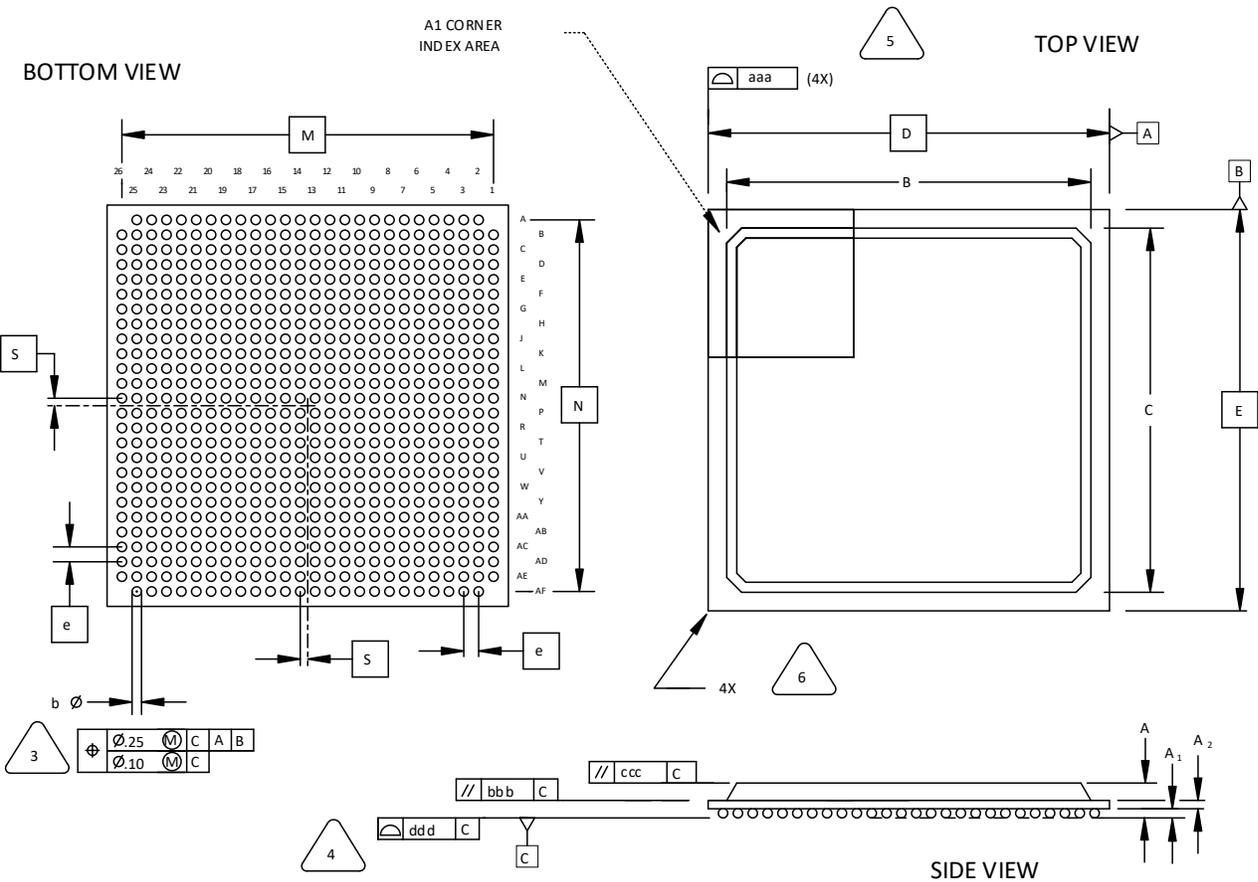


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.76
A1	0.25	0.30	0.35
A2	0.80	-	-
D/E	23.0 BSC		
M/N	20.0 BSC		
S	0.40 BSC		
b	0.35	0.40	0.45
e	0.80 BSC		
aaa	-	-	0.15
bbb	-	-	0.20
ddd	-	-	0.12

130. 672-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.

3. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM \square C

4. PRIMARY DATUM \square C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

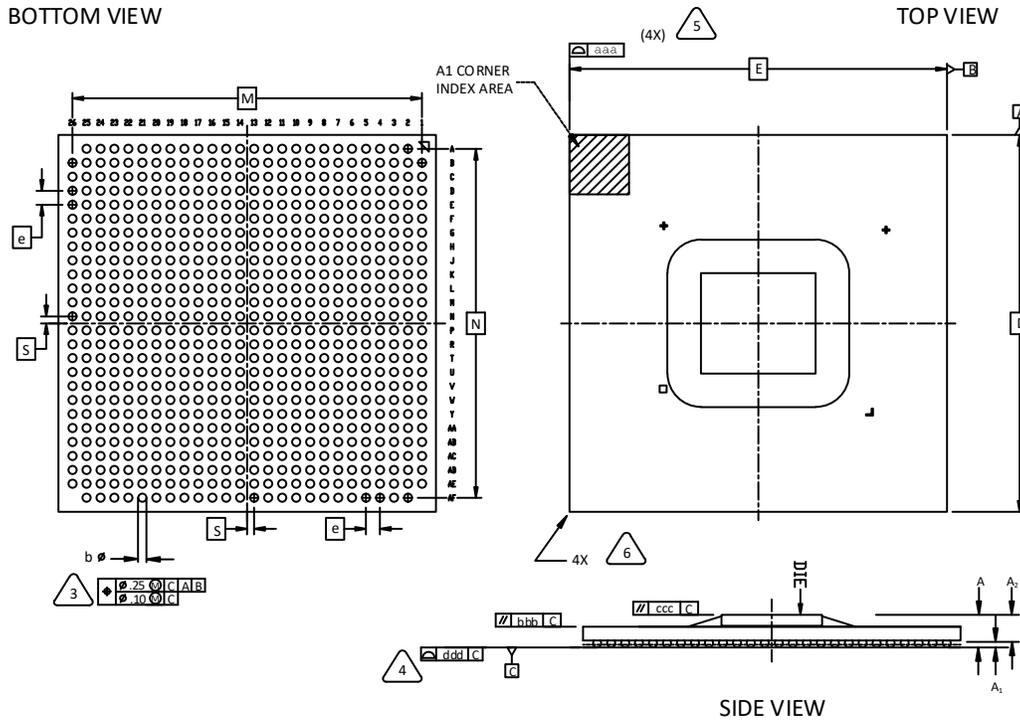
5. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.70	2.15	2.60
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	23.80	24.80	25.80
D/E	27.00 BSC		
M/N	25.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

131. 672-Ball LFG672/fcBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

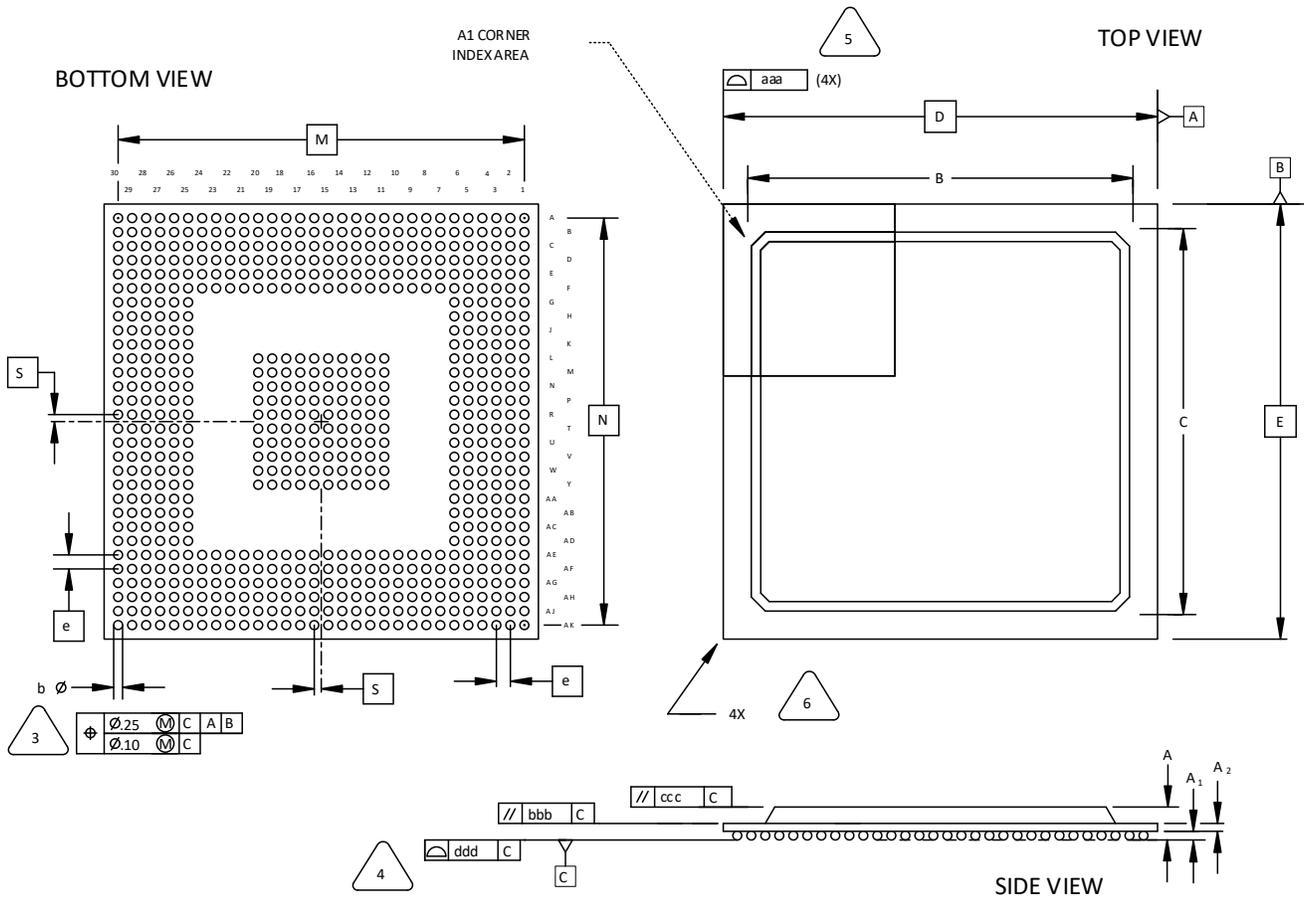
1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM $\square C$
4. PRIMARY DATUM $\square C$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
7. JEDEC REFERENCE: JEP 95 DR4.4

SYMBOL	MIN.	NOM.	MAX.
A	-	-	2.586
A1	0.300	-	-
A2	1.836 REF		
D/E	27.00 BSC		
M/N	25.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.20
ddd	-	-	0.20

**This Package Outline Drawing and related information apply to CertusPro-NX devices.*

132. 676-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

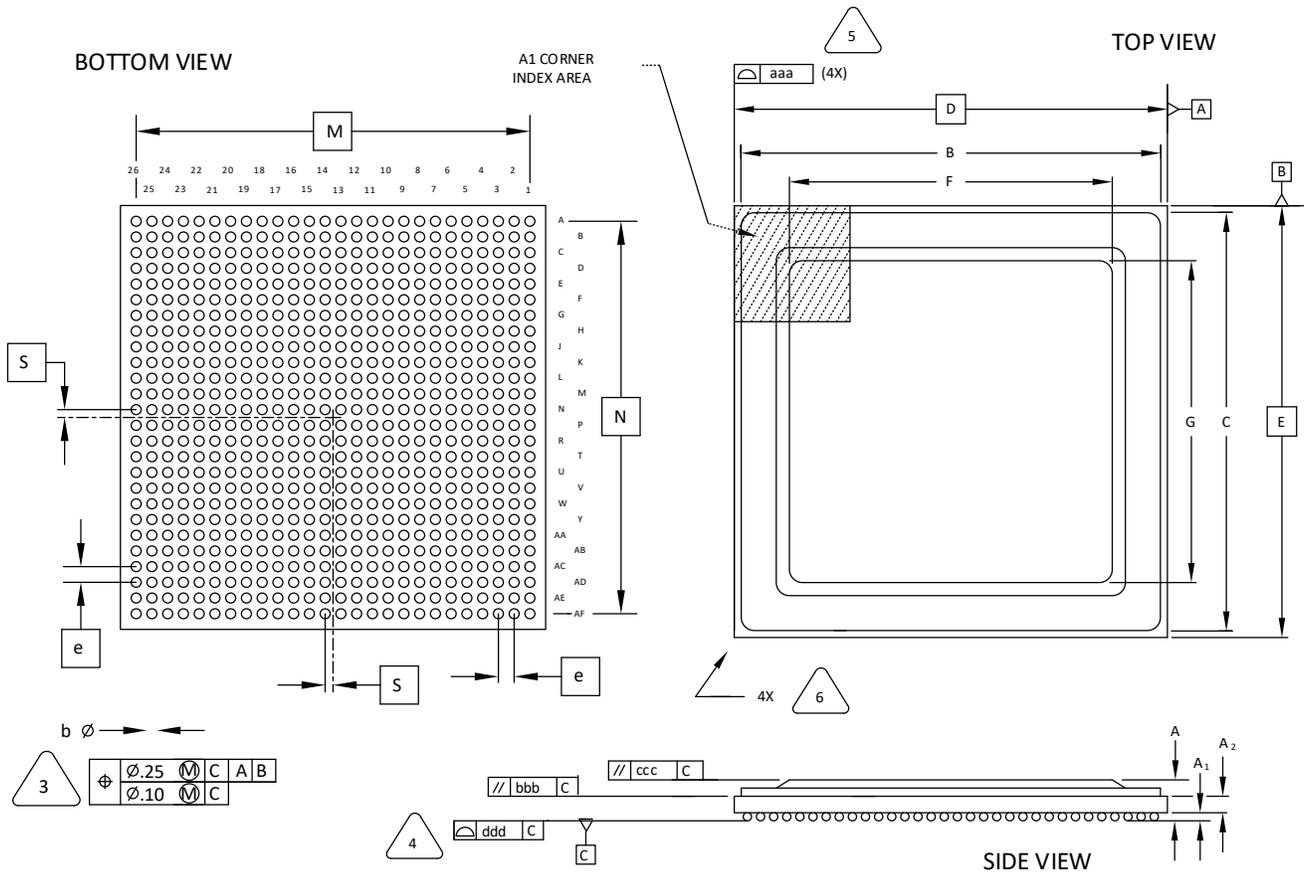


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.70	2.15	2.60
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	25.80	27.55	29.30
D/E	31.00 BSC		
M/N	29.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

133. 676-Ball fcBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

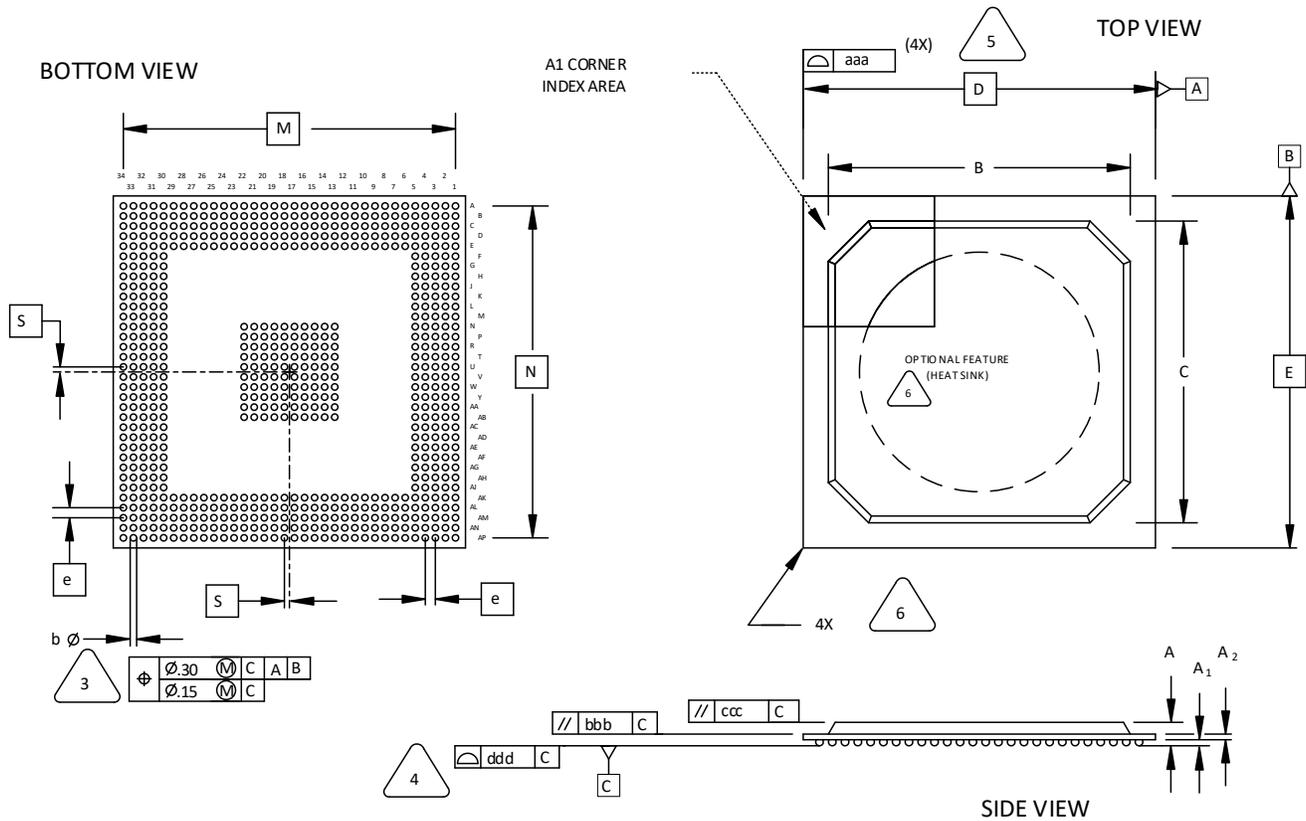
- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.

- DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C].
- PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
- EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	2.55	2.90	3.25
A1	0.40	0.50	0.60
A2	1.20 REF		
B/C	26.55	26.60	26.65
D/E	27.00 BSC		
F/G	18.55	18.60	18.65
M/N	25.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

134. 680-Ball fpBGA Package

(With or without Internal Heat Spreader) Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

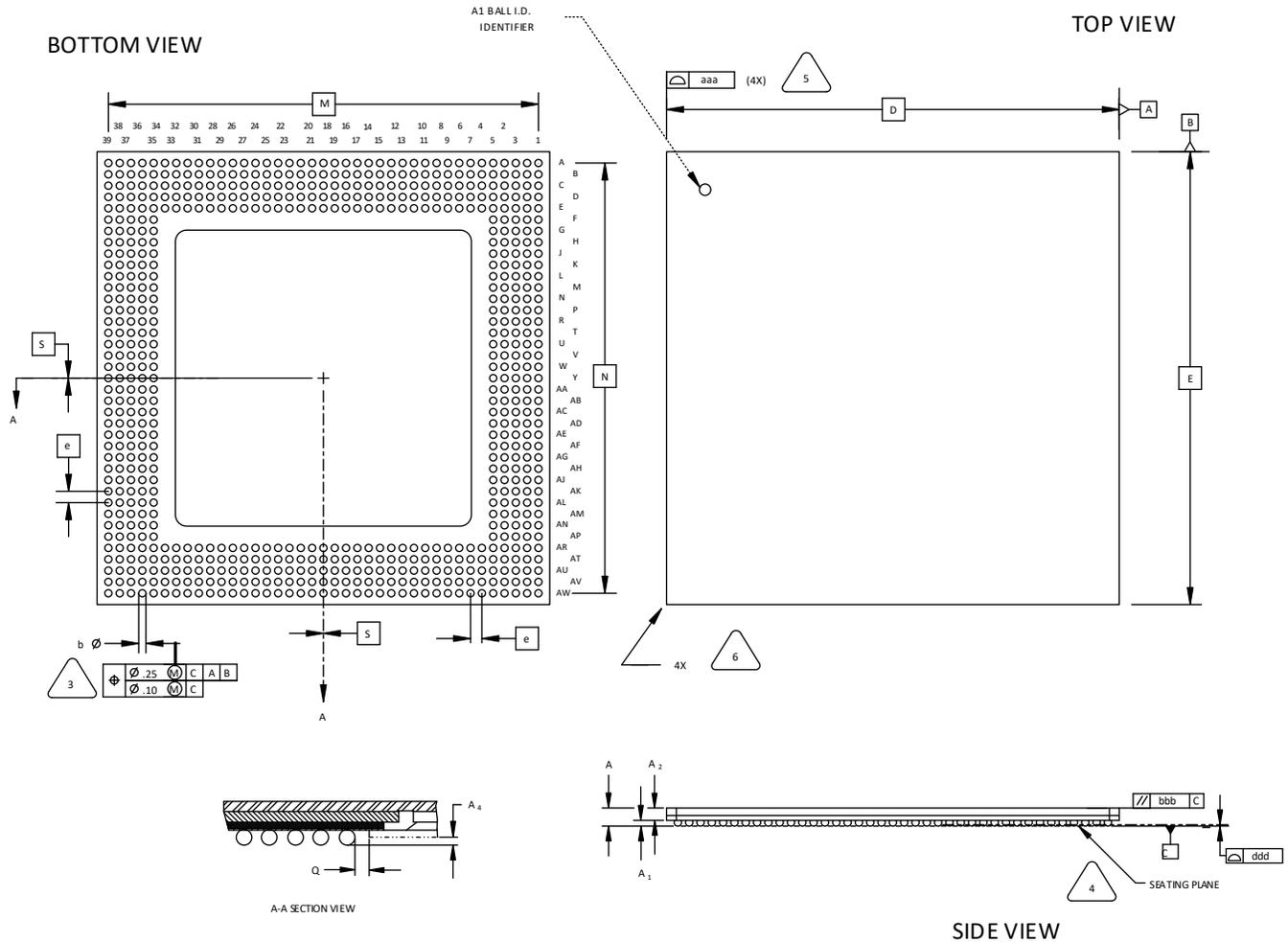


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.90	2.25	2.60
A1	0.30	0.50	0.70
A2	0.40	0.60	0.80
B/C	29.80	30.30	30.80
D/E	35.00 BSC		
M/N	33.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

135. 680-Ball fpSBGA Package

Dimensions in Millimeters



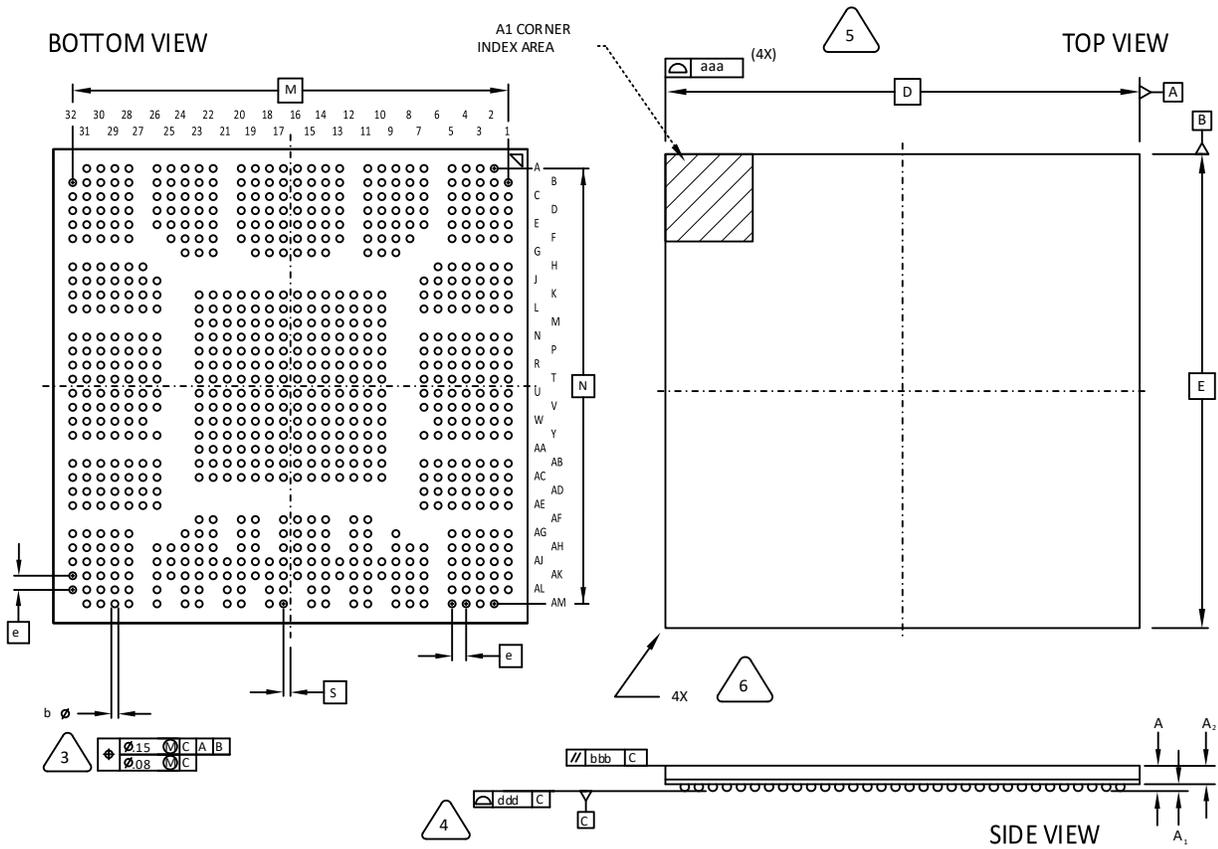
NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM \square C
 - PRIMARY DATUM \square C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 - BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
 - EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.70
A1	0.45	0.53	0.60
A2	0.90	0.98	1.05
D/E	40.00 BSC		
M/N	38.00 BSC		
S	0.00 BSC		
b	0.50	0.65	0.80
e	1.00 BSC		
Q	0.25	-	-
A4	0.10	-	-
aaa	-	-	0.20
bbb	-	-	0.25
ddd	-	-	0.20

136. 756-Ball caBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM \square C



PRIMARY DATUM \square C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

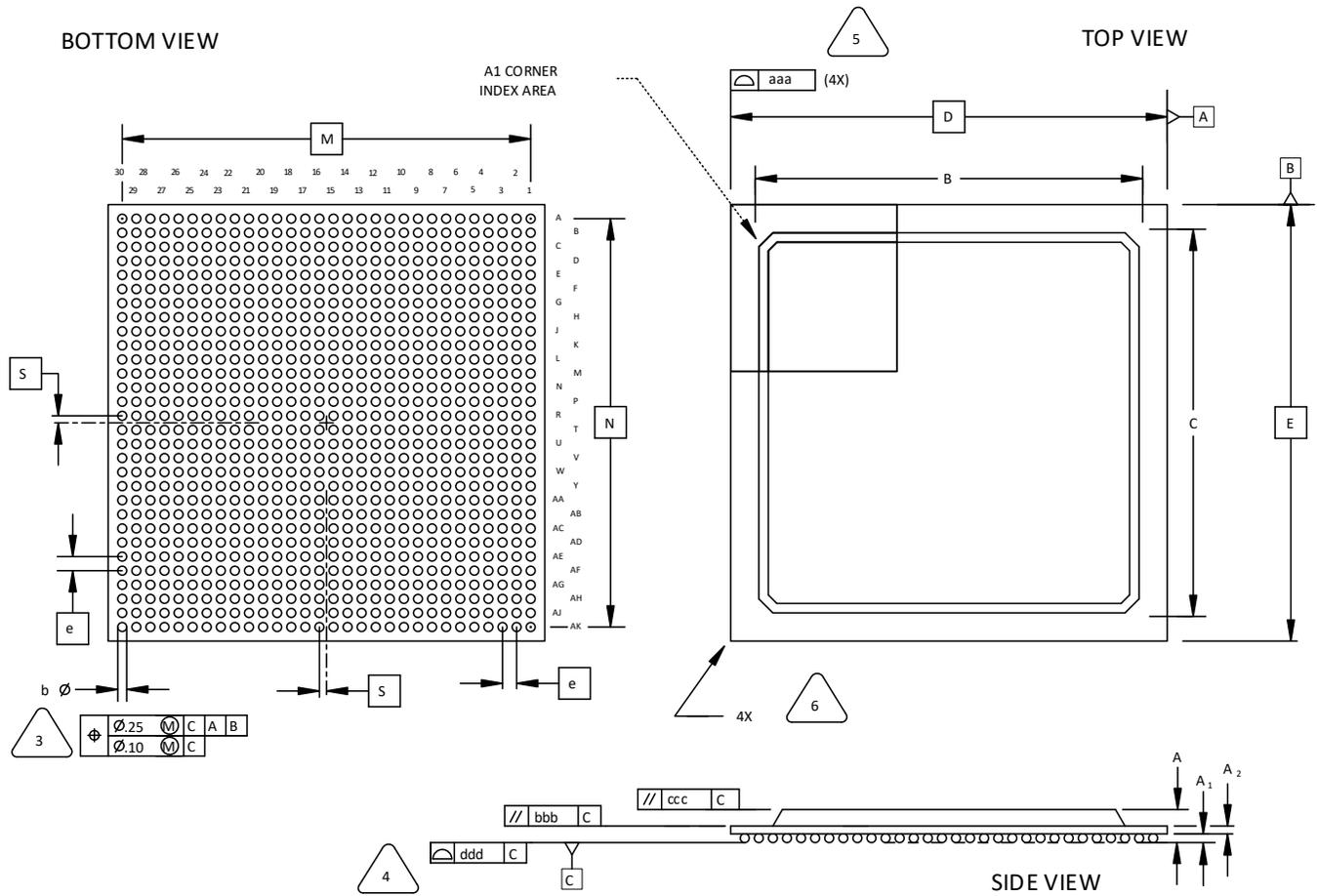


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.76
A1	0.25	0.30	0.35
A2	0.80	-	-
D/E	27.00 BSC		
M/N	24.80 BSC		
S	0.40 BSC		
b	0.35	0.40	0.45
e	0.80 BSC		
aaa	-	-	0.15
bbb	-	-	0.20
ddd	-	-	0.12

137. 900-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

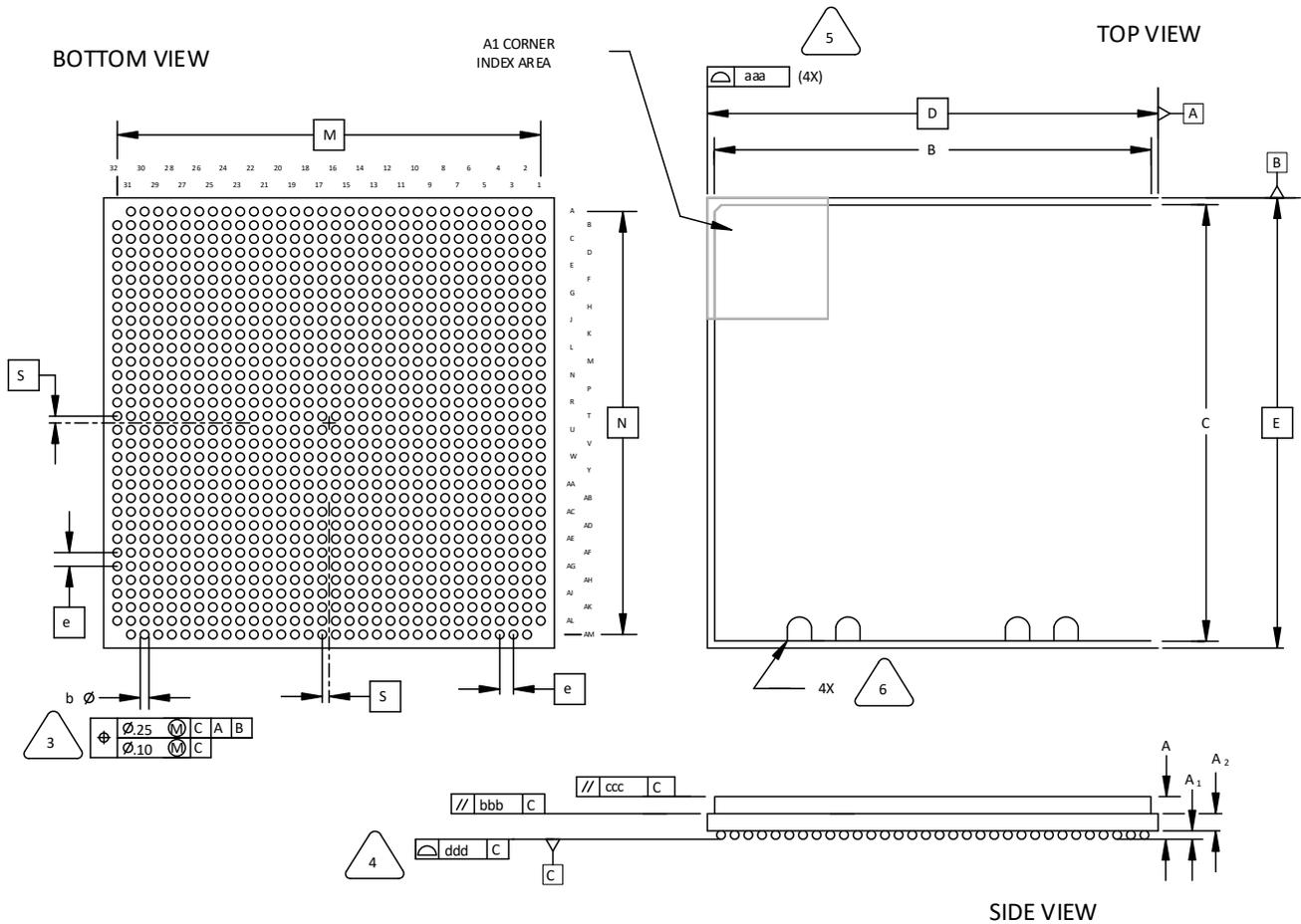


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.70	2.15	2.60
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	25.80	27.55	29.30
D/E	31.00 BSC		
M/N	29.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

138. 1020-Ball Organic fcBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

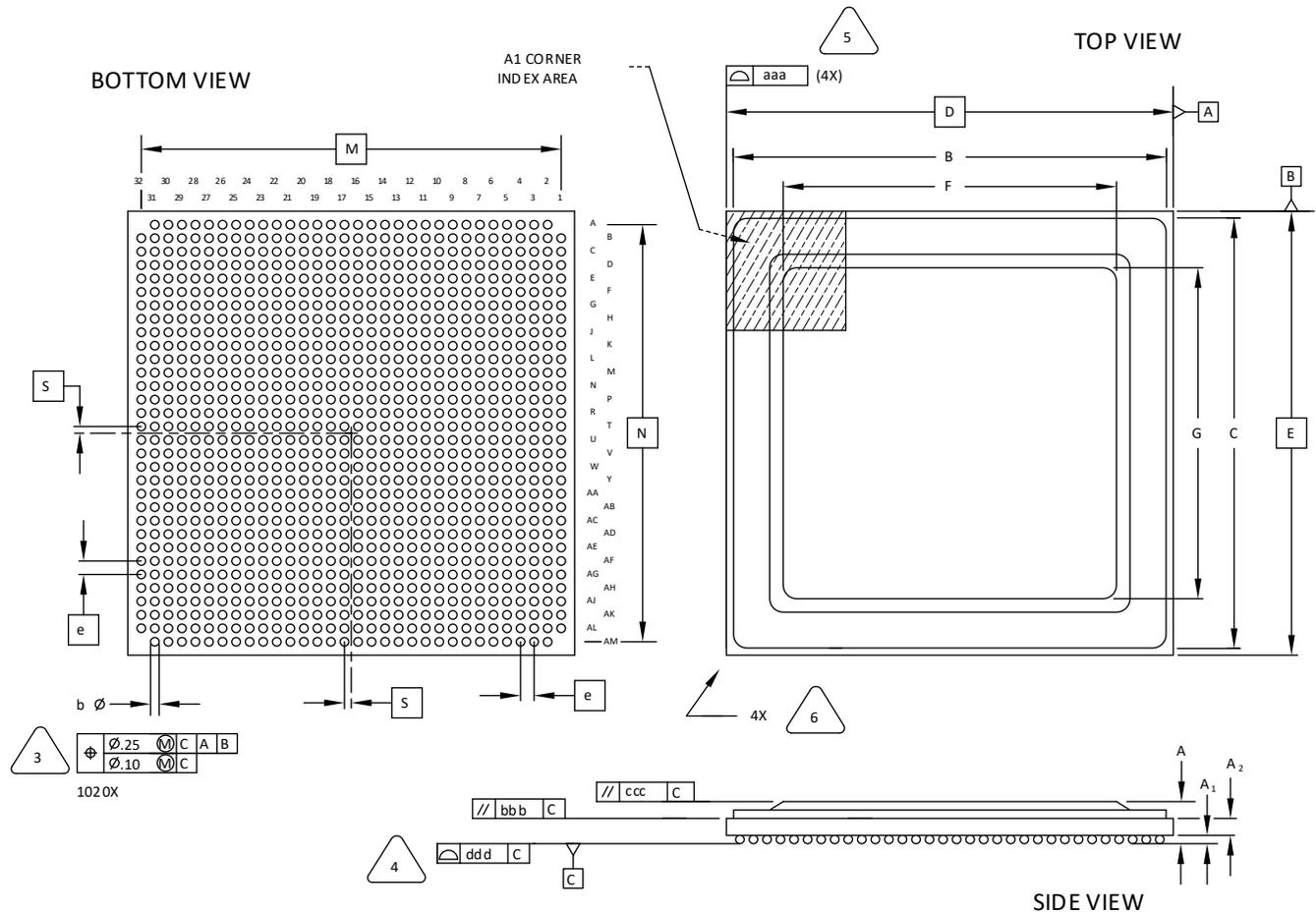


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	2.52	3.12	3.82
A1	0.30	0.50	0.70
A2	1.24 REF		
B/C	31.10	32.00	32.90
D/E	33.00 BSC		
M/N	31.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

139. 1020-Ball Organic fcBGA Package Rev. 2

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM $\square C$



PRIMARY DATUM $\square C$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

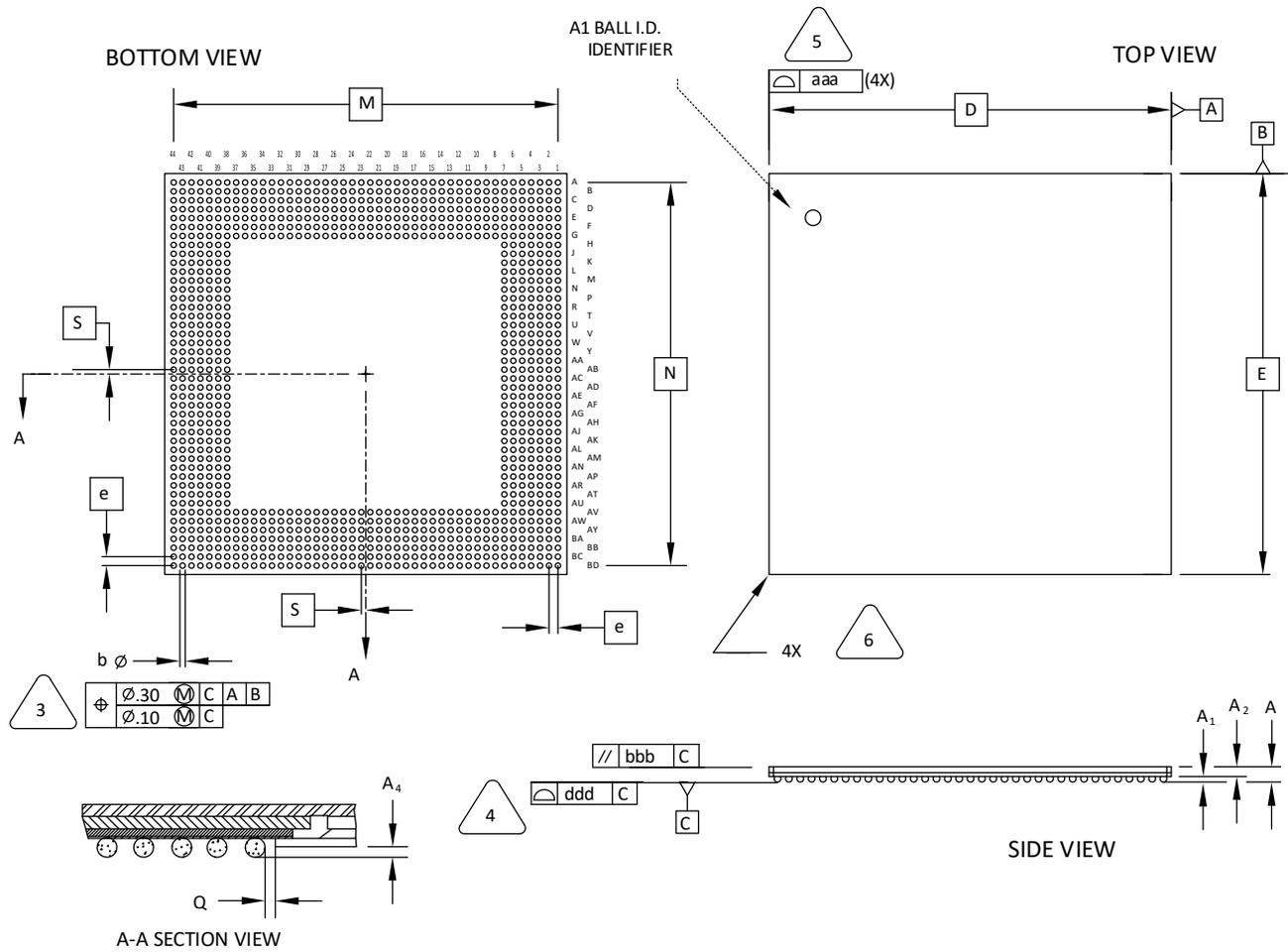


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	2.55	2.90	3.25
A1	0.40	0.50	0.60
A2	1.20 REF		
B/C	32.40	32.60	32.80
D/E	33.00 BSC		
F/G	24.50	24.60	24.70
M/N	31.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

140. 1036-Ball ftSBGA Package

Dimensions in Millimeters



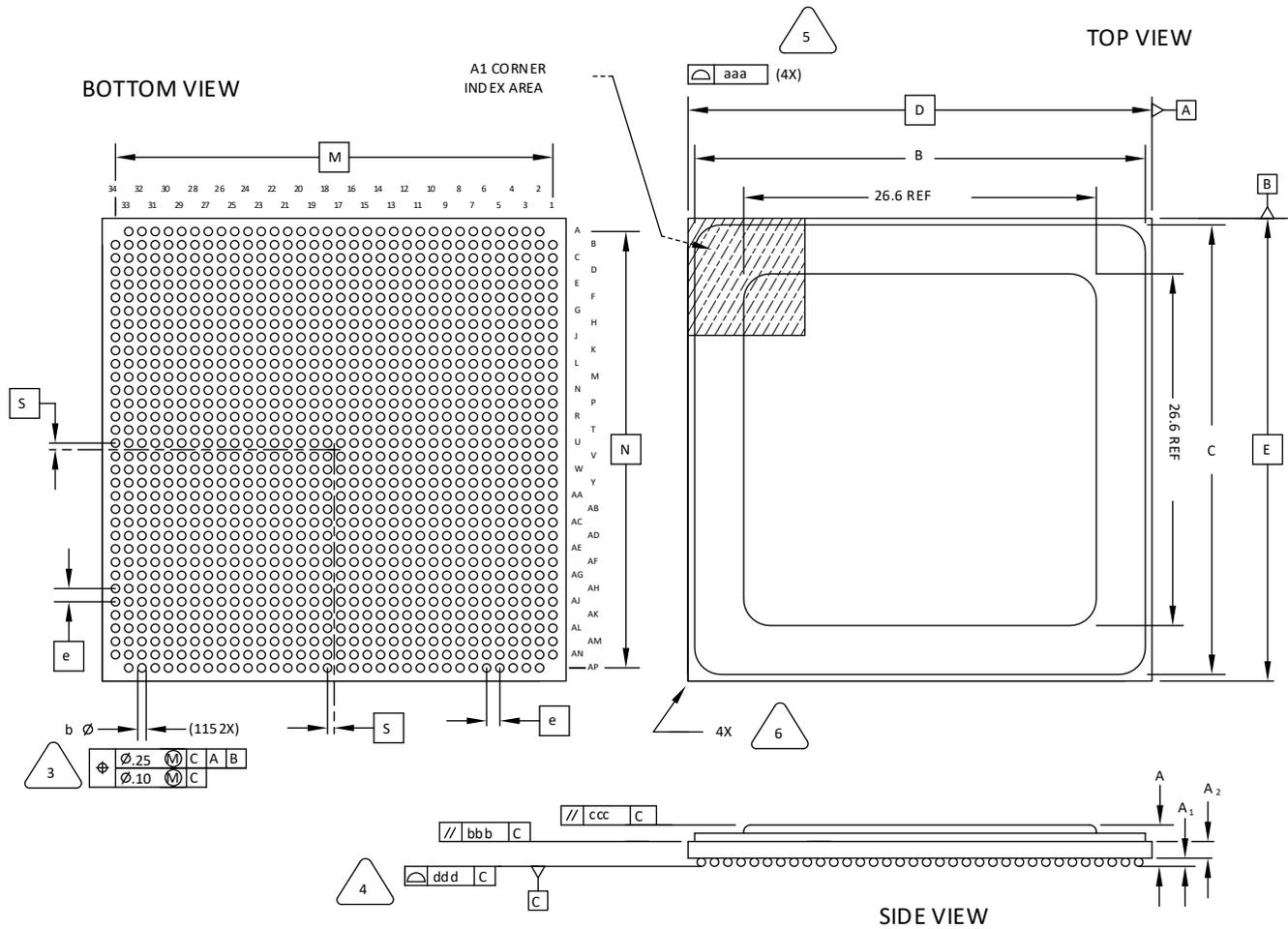
NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
 2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C].
4. PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.80
A1	0.40	0.55	0.70
A2	0.90	0.98	1.10
D/E	45.00 BSC		
M/N	43.00 BSC		
S	0.50 BSC		
b	0.50	0.65	0.80
e	1.00 BSC		
Q	0.25	-	-
A4	0.10	-	-
aaa	-	-	0.20
bbb	-	-	0.35
ddd	-	-	0.20

141. 1152-Ball Organic fcBGA Package Option 1: LatticeSC™/SCM40

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

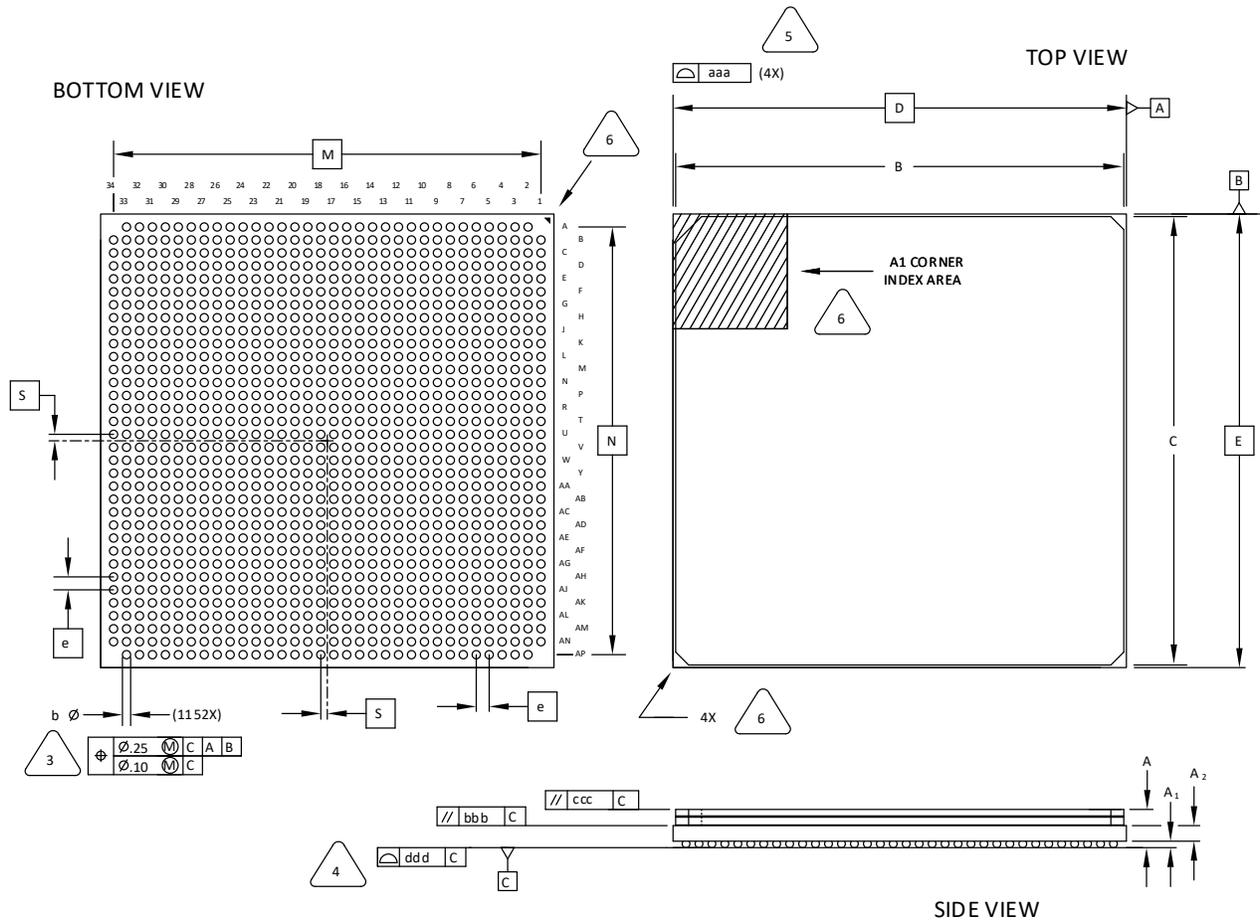


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	2.55	2.90	3.25
A1	0.35	0.50	0.65
A2	1.20 REF		
B/C	34.25	34.50	34.75
D/E	35.00 BSC		
M/N	33.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

142. 1152-Ball Organic fcBGA Package Option 2: LatticeSC/SCM80 and SC/SCM115

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM \square C.



PRIMARY DATUM \square C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

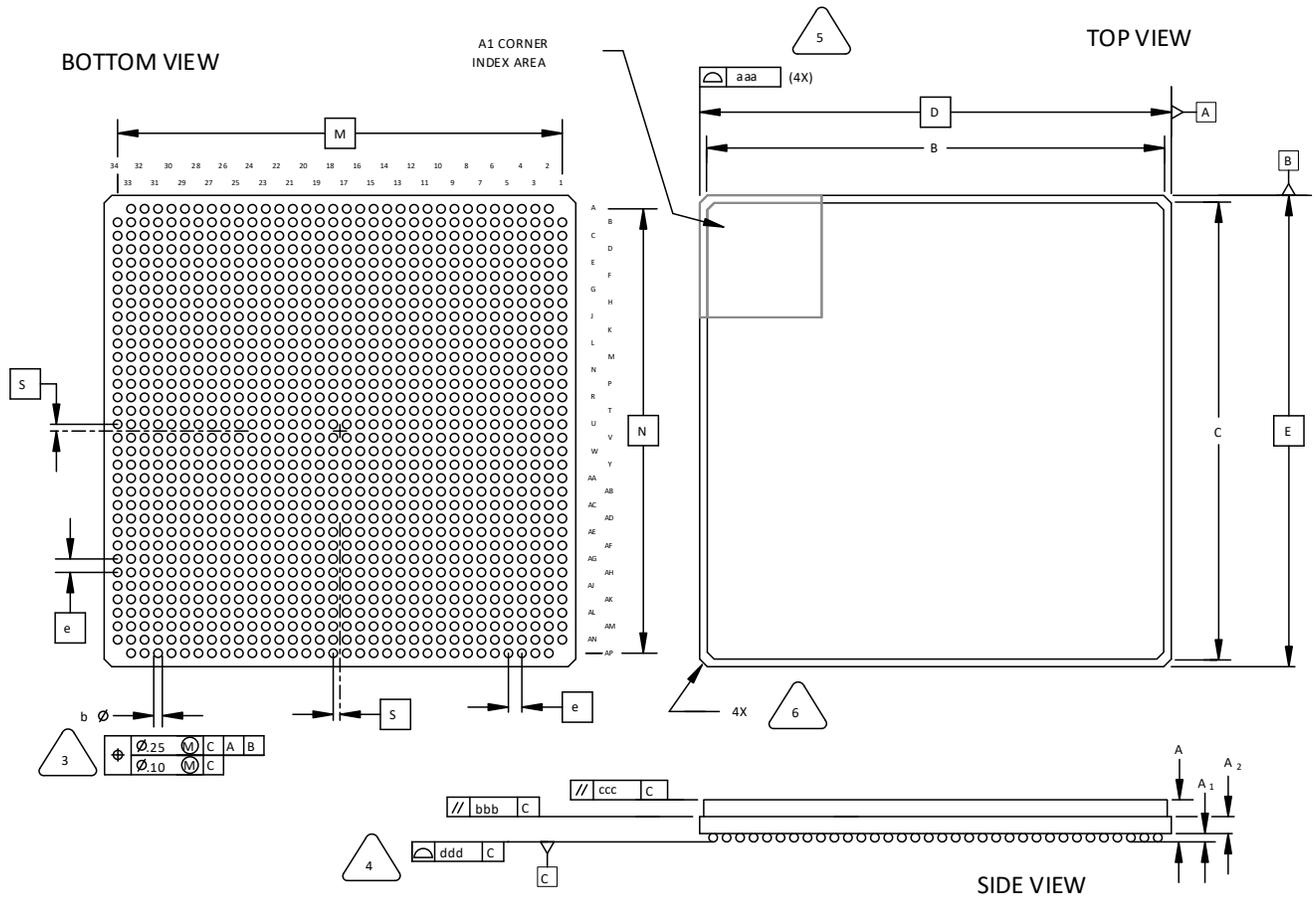


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	2.80	3.15	3.50
A1	0.35	0.50	0.65
A2	1.20 REF		
B/C	34.30	34.60	34.90
D/E	35.00 BSC		
M/N	33.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.23

143. 1152-Ball Ceramic fcBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

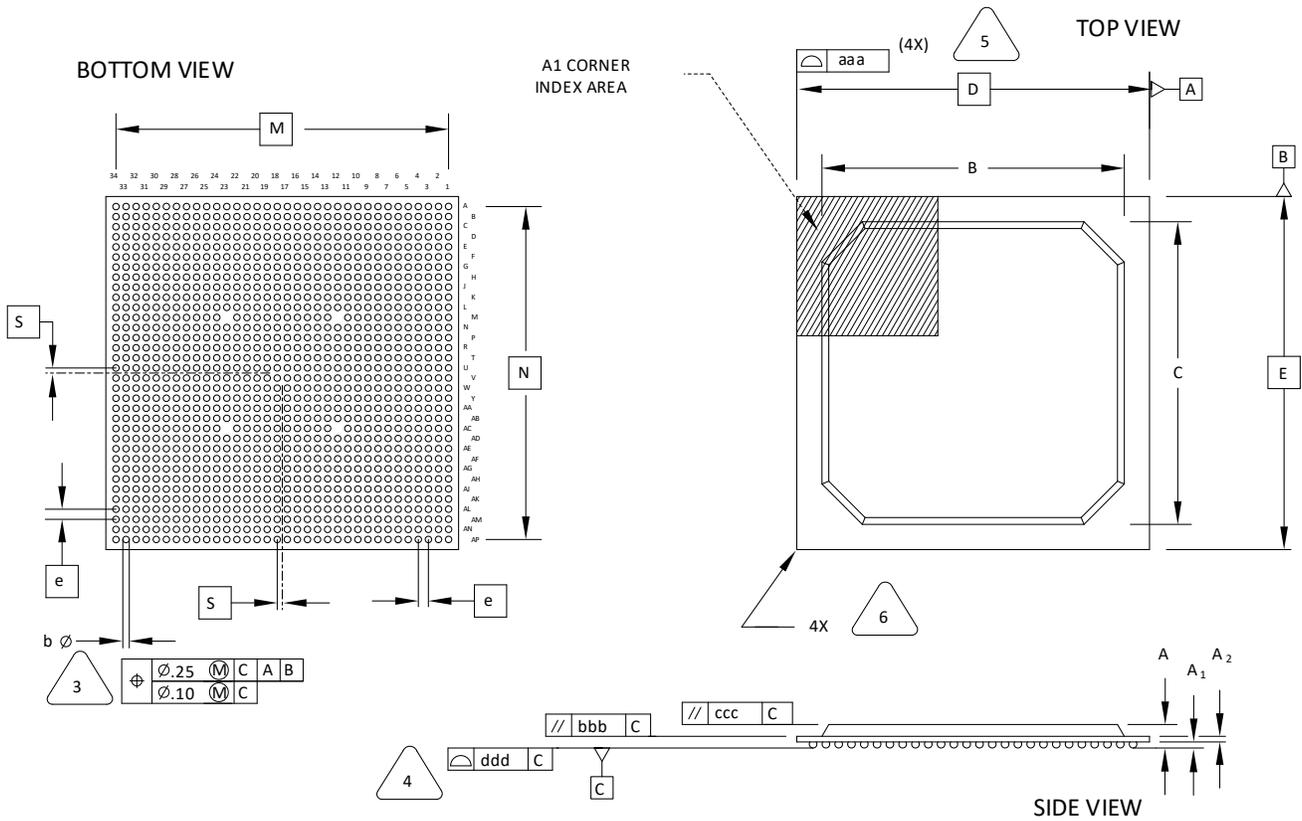


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	4.00	4.60	5.20
A1	0.30	0.50	0.70
A2	1.40 REF		
B/C	33.10	34.00	34.90
D/E	35.00 BSC		
M/N	33.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
a a a	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

144. 1152-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.

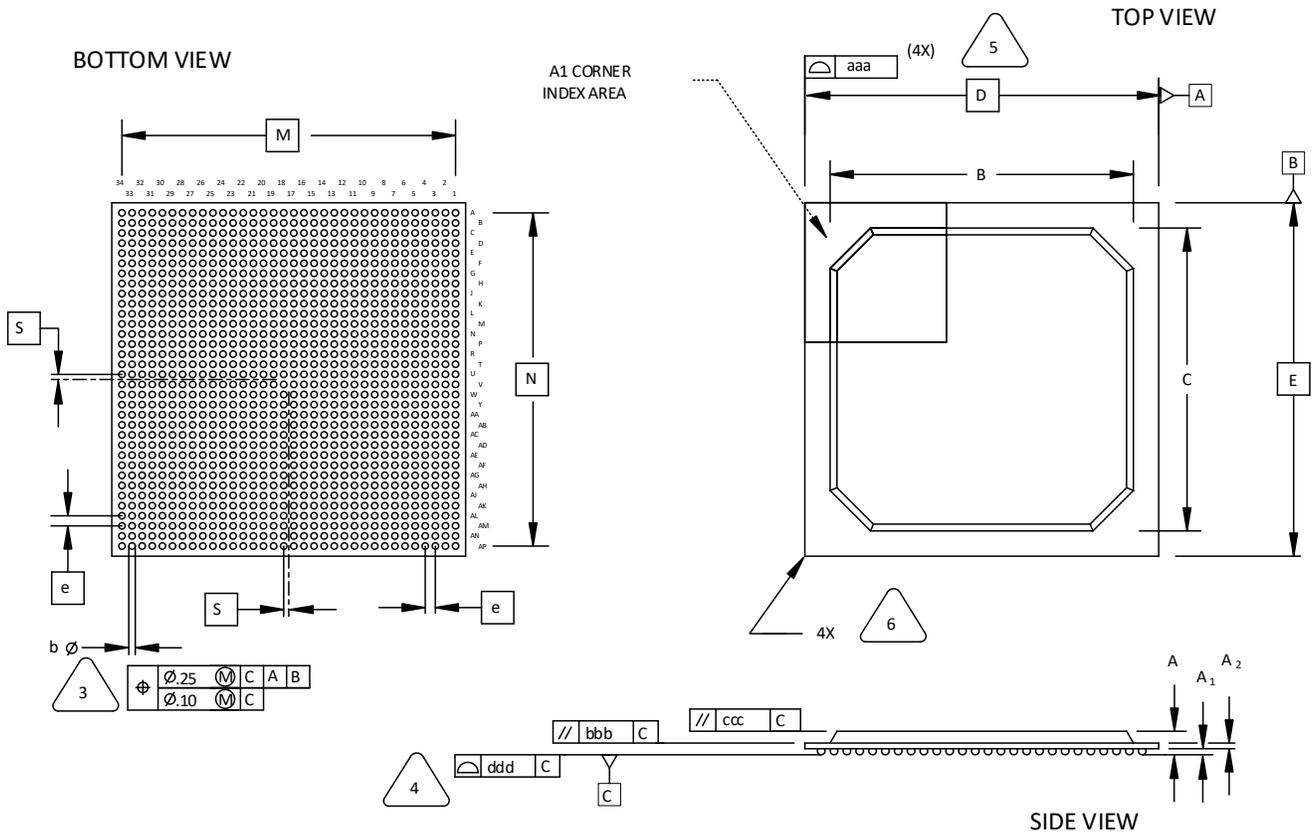
- 3. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
- 4. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 5. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
- 6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

Note: Depopulated ball locations are M12, M23, AC12, and AC23.

SYMBOL	MIN.	NOM.	MAX.
A	1.90	2.25	2.60
A1	0.30	0.50	0.70
A2	0.40	0.60	0.80
B/C	29.80	30.30	30.80
D/E	35.00 BSC		
M/N	33.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

145. 1156-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

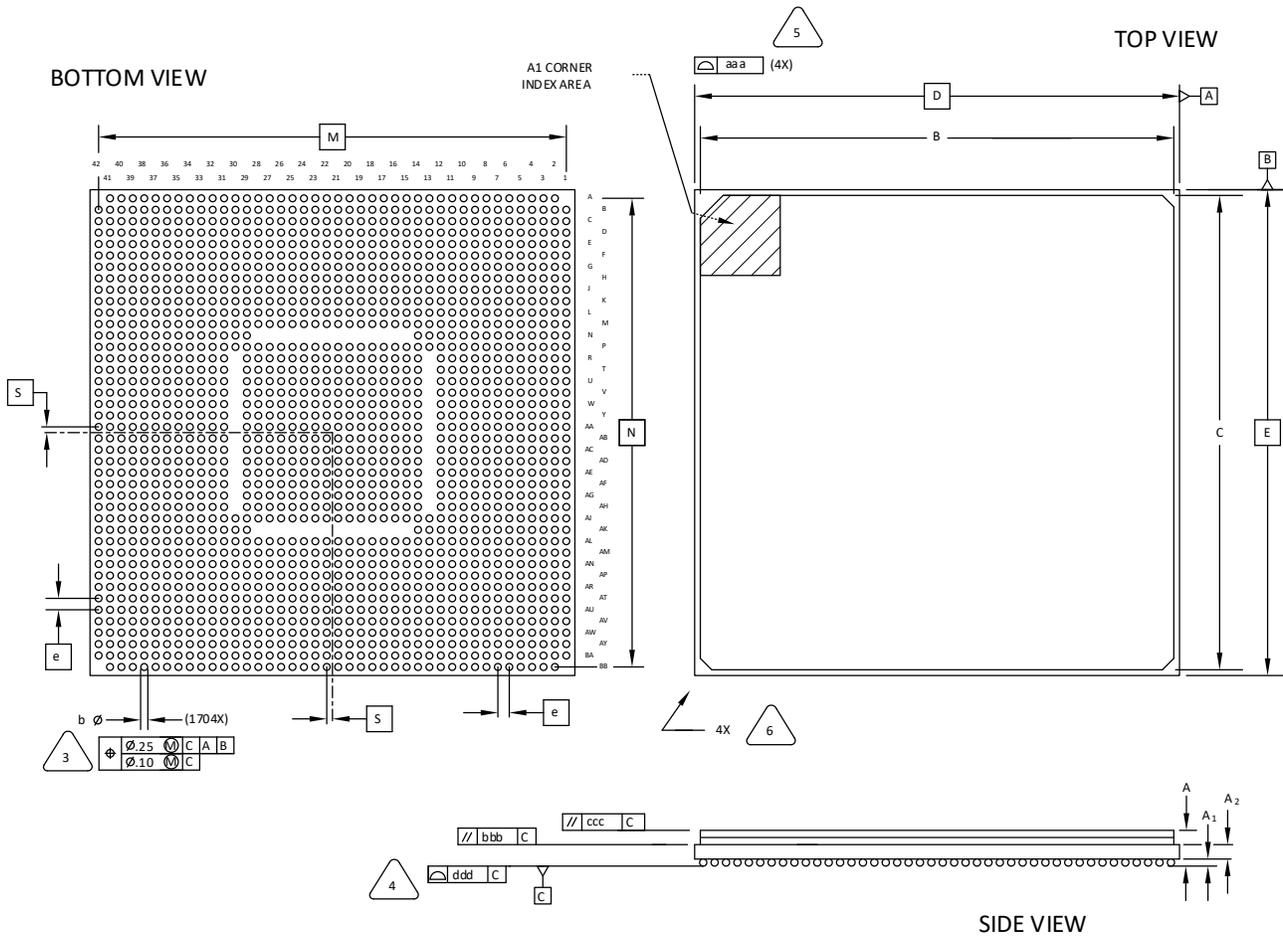


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.90	2.25	2.60
A1	0.30	0.50	0.70
A2	0.40	0.60	0.80
B/C	29.80	30.30	30.80
D/E	35.00 BSC		
M/N	33.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

146. 1704-Ball Organic fcBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

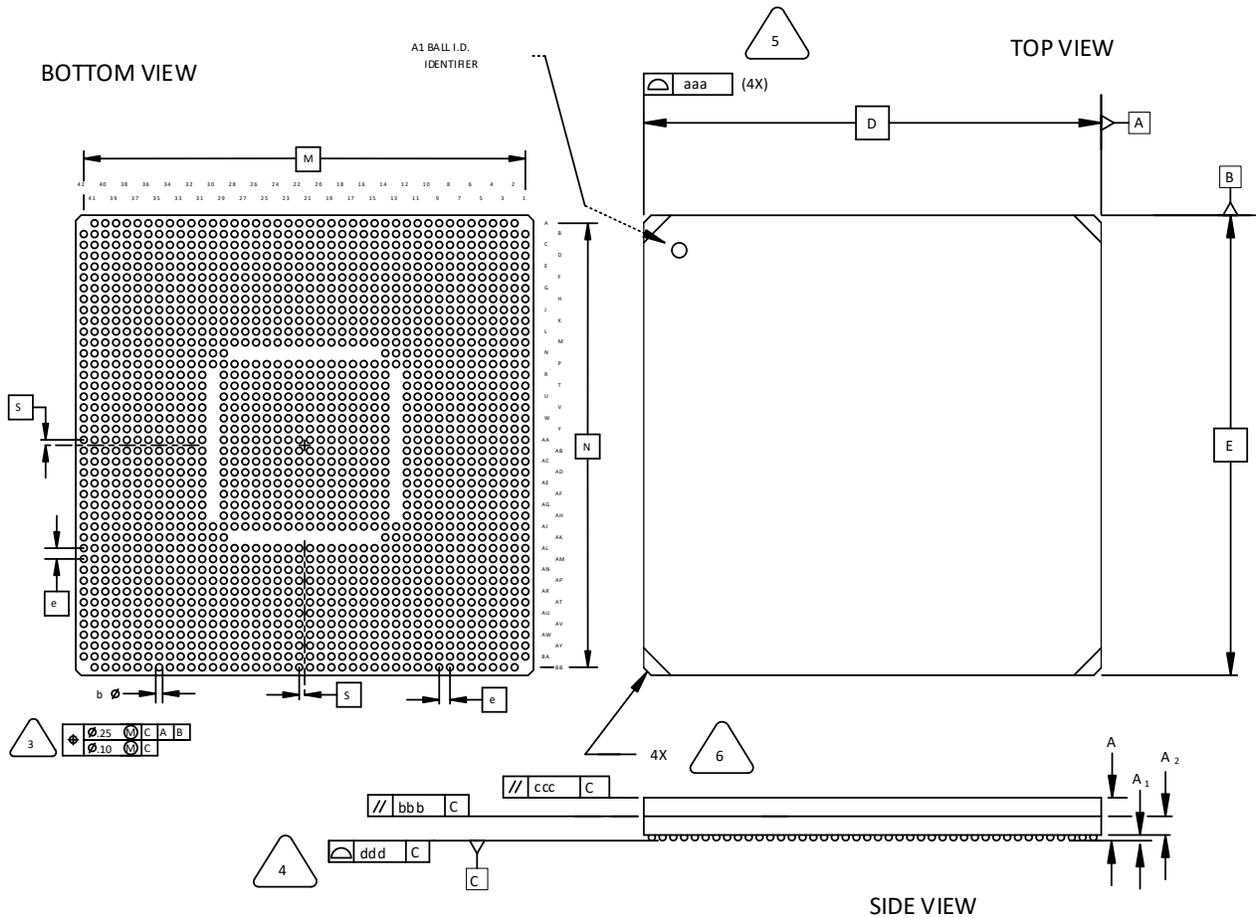


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	2.55	2.90	3.25
A1	0.35	0.50	0.65
A2	1.20 REF		
B/C	41.70	42.00	42.30
D/E	42.50 BSC		
M/N	42.50 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.23

147. 1704-Ball Ceramic fcBGA Package

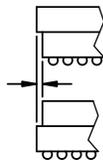
Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
 - ALL DIMENSIONS ARE IN MILLIMETERS.
3. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C
4. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY. PACKAGE BODY INCLUDES SUBSTRATE AND LID.

MAXIMUM OFFSET: 0.20 mm



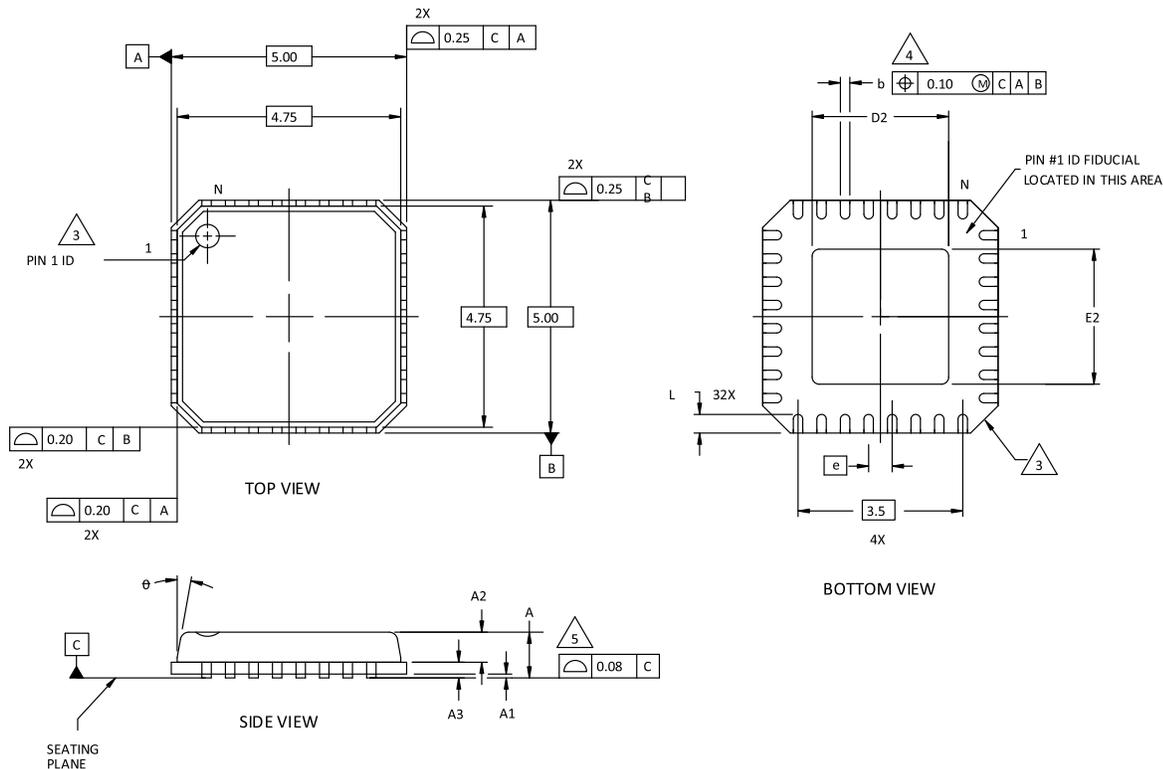
6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	4.30	4.80	5.30
A1	0.30	0.50	0.70
A2	1.30	1.60	1.90
D/E	42.50 BSC		
M/N	41.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

Appendix A – Package Archive

32-Pin QFN (Punch Singulated) Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.

EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.20 AND 0.25 mm FROM TERMINAL TIP.

APPLIES TO EXPOSED PORTION OF TERMINALS.

SYMBOL	MIN.	NOM.	MAX.
A	-	0.85	1.00
A1	0.00	0.01	0.05
A2	0.00	0.65	1.00
A3	0.20 REF		
D2	1.25	2.70	3.25
E2	1.25	2.70	3.25
e	0.50 BSC		
b	0.18	0.24	0.30
L	0.30	0.40	0.50
θ	-	-	12

Technical Support Assistance

Submit a technical support case through www.latticesemi.com/techsupport.

For frequently asked questions, refer to the Lattice Answer Database at www.latticesemi.com/Support/AnswerDatabase.

Revision History

Revision 8.6, January 2026

Section	Change Summary
36-Ball WLCSP Package Option 1	<ul style="list-style-type: none"> Renamed section from <i>36-Ball WLCSP Package Option 1: iCE40 Ultra</i> to <i>36-Ball WLCSP Package Option 1</i>. Moved the iCE40 Ultra device support from heading to footer.
36-Ball WLCSP Package Option 2	<ul style="list-style-type: none"> Updated the package drawing and specifications. Renamed section from <i>36-Ball WLCSP Package Option 2: MachXO2, MachXO3</i> to <i>36-Ball WLCSP Package Option 2</i>. Moved the MachXO2 and MachXO3 device support from heading to footer.
36-Ball WLCSP Package Option 3	Renamed section from 36-Ball WLCSP Package to 36-Ball WLCSP Package Option 3.
49-Ball WLCSP Package	Updated the package drawing and specifications.
81-Ball WLCSP Package	Updated the package drawing and specifications.

Revision 8.5, July 2025

Section	Change Summary
256-Ball BBG/caBGA Package Option 1	<ul style="list-style-type: none"> Updated the package drawing and specifications. Renamed section from <i>256-Ball BBG/caBGA Package</i> to <i>256-Ball BBG/caBGA Package Option 1</i>.
256-Ball BBG/caBGA Package Option 2	Renamed section from <i>256-Ball caBGA Package Option 1</i> to <i>256-Ball BBG/caBGA Package Option 2</i> .
256-Ball caBGA Package	Renamed section from <i>256-Ball caBGA Package Option 2</i> to <i>256-Ball caBGA Package</i> .
400-Ball BBG/caBGA Package Option 1	<ul style="list-style-type: none"> Renamed section from <i>400-Ball caBGA Package Option 1: MachXO3</i> to <i>400-Ball BBG/caBGA Package Option 1</i>. Moved the MachXO3 device support from heading to footer.
400-Ball BBG/caBGA Package Option 2	<ul style="list-style-type: none"> Updated the package drawing and specifications. Added <i>Certus-NX</i> device to footnote. Renamed section from <i>400-Ball BBG/caBGA Package</i> to <i>400-Ball BBG/caBGA Package Option 2</i>.
484-Ball BBG/caBGA Package Option 1	<ul style="list-style-type: none"> Renamed section from <i>484-Ball caBGA Package (19 mm x 19 mm Body) Option 1: MachXO3/MachXO3D</i> to <i>484-Ball BBG/caBGA Package Option 1</i>. Moved the MachXO3/MachXO3D device support from heading to footnote.
484-Ball BBG/caBGA Package Option 2	Renamed section from <i>484-Ball BBG484/caBGA Package</i> to <i>484-Ball BBG/caBGA Package Option 2</i> .
484-Ball BBG/caBGA Package Option 3	Added this new package drawing.

Revision 8.4, December 2024

Section	Change Summary
256-Ball caBGA Package Option 1	Added <i>MachXO2</i> device on the footer.

Revision 8.3, November 2024

Section	Change Summary
72-Pin QFN Package Option 2: MachXO3D	Updated POD to correct the notch position.

Revision 8.2, September 2024

Section	Change Summary
256-Ball caBGA Package Option 2	Added this package option 2 for MachXO3D-4300HC-FTG256.
676-Ball LFG/fcBGA Package	Removed this Avant package in this document.
1156-Ball LFG1156/fcBGA Package	Removed this Avant package in this document.

Revision 8.1, July 2024

Section	Change Summary
100-Pin LQFP/TQFP Package Option 1	<ul style="list-style-type: none"> Added the MachXO3 device. Updated the <i>MIN</i> and <i>NOM</i> value of A. Updated the <i>NOM</i> values of A1. Removed the <i>NOM</i> values of c and c1.
132-Ball csBGA Package Option 3	Updated the <i>MIN</i> , <i>NOM</i> , and <i>MAX</i> values of A1, A2, and b.

Revision 8.0, March 2024

Section	Change Summary
104-Ball CTG/fcCSP Package	Updated the <i>MIN</i> , <i>NOM</i> and <i>MAX</i> values.
132-Ball csBGA Package	Added the 132-Ball csBGA Package Option 3.

Revision 7.9, March 2024

Section	Change Summary
196-Ball caBGA Package	Updated the <i>MIN</i> , <i>NOM</i> and <i>MAX</i> values.

Revision 7.8, January 2024

Section	Change Summary
256-Ball caBGA Package Option 1	<ul style="list-style-type: none"> Removed MachXO3 in the title. Added a footnote stating that, <i>This Package Outline Drawing and related information apply to MachXO3 and ECP5.</i>
256-Ball BBG/caBGA Package	Minor editorial fixes: <ul style="list-style-type: none"> Moved the title <i>Bottom view</i> and <i>Top view</i> to the bottom of the drawing. Added package code BBG in the title.
400-Ball BBG/ caBGA Package	Minor editorial fixes <ul style="list-style-type: none"> Moved the title <i>Bottom view</i> and <i>Top view</i> to the bottom of the drawing. Fixed the row for symbols aaa, ccc and ddd. Added package code BBG in the title.

Revision 7.7, November 2023

Section	Change Summary
72-Pin QFN Package Option 2: MachXO3D™	Changed the order of the pin number for bottom view.

Revision 7.6, October 2023

Section	Change Summary
84-Ball USG/WLCSP Package (7.492 mm × 3.054 mm Body)	Changed <i>CrossLink-NX-33U</i> to <i>CrossLinkU-NX</i> .
104-Ball CTG/fcCSP Package	Changed <i>CrossLink-NX-33U</i> to <i>CrossLinkU-NX</i> .

Revision 7.5, September 2023

Section	Change Summary
69-Ball WLCSP Package	Moved 69-Ball WLCSP Package device support information from heading to footnote.
72-Pin QFN Package	Moved 72-Pin QFN Package device support information from heading to footnote.
72-Pin WLCSP Package	Moved 72-Pin WLCSP Package device support information from heading to footnote.
80-Ball ckgBGA Package	Updated the 80-Ball ckgBGA Package to align table dimensions with the POD. Moved device support information from heading to footnote.
84-Ball USG/WLCSP Package (7.492 mm x 3.054 mm Body)	Added the 84-Ball USG/WLCSP Package (7.492 mm x 3.054 mm Body) for CrossLinkU-NX.
84-Ball USG/WLCSP Package (7.275 mm x 3.054 mm Body)	Updated the 84-Ball USG/WLCSP Package (7.275 mm x 3.054 mm Body). Changed the heading and indicated device support information in footnote (CrossLink-NX-33).
84-Ball USG/WLCSP Package - Option 1 (7.275 mm x 3.054 mm Body)	Added the 84-Ball USG/WLCSP Package - Option 1 (7.275 mm x 3.054 mm Body) for CrossLink-NX-33. This is for a specific customer only.
104-Ball CTG/fcCSP Package	Added the 104-Ball CTG/fcCSP Package for CrossLinkU-NX.
121-Ball csfBGA Package	Moved 121-Ball csfBGA Package device support information from heading to footnote.
196-Ball caBGA Package	Moved 196-Ball caBGA Package device support information from heading to footnote.
256-Ball ASG256/FOWLP Package	Moved 256-Ball ASG256/FOWLP Package device support information from heading to footnote.
256-Ball BBG/caBGA Package	Moved 256-Ball BBG/caBGA Package device support information from heading to footnote.
256-Ball CBG256/csfBGA Package	Moved 256-Ball CBG256/csfBGA Package device support information from heading to footnote.
256-Ball CBG256/csfBGA Package	Moved 256-Ball CBG256/csfBGA Package device support information from heading to footnote.
289-Ball csBGA Package (9.5 mm x 9.5 mm Body)	Moved 289-Ball csBGA Package (9.5 mm x 9.5 mm Body) device support information from heading to footnote.
400-Ball caBGA Package	Moved 400-Ball caBGA Package device support information from heading to footnote.
484-Ball BBG484/caBGA Package	Moved 484-Ball BBG484/caBGA Package device support information from heading to footnote.
484-Ball BFG484/PBGA Package	Moved 484-Ball BFG484/PBGA Package device support information from heading to footnote.
484-Ball fcBGA Package	Updated the 484-Ball fcBGA Package to align table dimensions with the POD. Moved device support information from heading to footnote.
672-Ball LFG672/fcBGA Package	Moved 672-Ball LFG672/fcBGA Package device support information from heading to footnote.
676-Ball LFG/fcBGA Package	Updated 676-Ball LFG/fcBGA Package.

Revision 7.4, June 2023

Section	Change Summary
72-Pin QFN Package Option 2: MachXO3D™	Added 9.75 mm value for D1 and E1.

Revision 7.3, April 2023

Section	Change Summary
256-Ball CBG256/csfBGA Package	Added the 256-Ball CBG256/csfBGA Package Option 1: Mach™-NX section.
256-Ball CBG256/csfBGA	Changed the heading from 256-Ball CBG256/csfBGA Package to 256-Ball CBG256/csfBGA Package Option 2: CertusPro-NX.
672-Ball LFG672/fcBGA Package	For the 672-Ball LFG672/fcBGA Package, corrected the M/N dimension value from 27.00 BSC to 25.00 BSC.

Revision 7.2, December 2022

Section	Change Summary
256-Ball caBGA Package Option 1:	Updated heading to 256-Ball caBGA Package Option 1: MachXO3.
256-Ball BBG/caBGA Package	Added 256-Ball BBG256/caBGA Package Option 2: MachXO5-NX.

Section	Change Summary
400-Ball caBGA Package	Added ball count and ball matrix information.
Technical Support Assistance	Added reference to the Lattice Answer Database on the Lattice website.

Revision 7.1, November 2022

Section	Change Summary
672-Ball LFG672/fcBGA Package	Updated 672-Ball LFG672/fcBGA Package.
1156-Ball LFG1156/fcBGA Package	Updated 1156-Ball LFG1156/fcBGA Package.

Revision 7.0.1, June 2022

Section	Change Summary
1156-Ball LFG1156/fcBGA Package	Added 1156-Ball LFG1156/fcBGA Package.

Revision 7.0, June 2022

Section	Change Summary
84-Ball USG/WLCSP Package (7.275 mm x 3.054 mm Body)	Added 84-Ball WLCSP Package (7.257 mm x 3.054 mm Body) for CrossLink-NX-33.

Revision 6.9, May 2022

Section	Change Summary
400-Ball caBGA Package	Updated heading to include MachXO5-NX.

Revision 6.8, December 2021

Section	Change Summary
32-Pin QFN Package Option 2: MachXO2™ 256HC/ZE	Updated heading to include 256HC/ZE.
32-Pin QFN Package Option 3: MachXO2 1200HC/ZE	Updated heading to change SG32C to 1200HC/ZE
484-Ball caBGA Package (19 mm x 19 mm Body) Option 1: MachXO3/MachXO3D	Added 484-Ball caBGA Package (19 mm x 19 mm Body) option for MachXO3 and MachXO3D.
484-Ball BBG484/caBGA Package	Indicated <i>Option 2: CertusPro-NX</i> to heading.

Revision 6.7, November 2021

Section	Change Summary
100-Pin LQFP/TQFP Package Option 1: MachXO2, MachXO™, ispMACH® 4000	Added <i>TQFP</i> to heading.
144-Pin LQFP/TQFP Package	Added <i>TQFP</i> to heading.
176-Pin LQFP/TQFP Package	Added <i>TQFP</i> to heading.
381-Ball caBGA Package Option 1: All Except LAE5UM-45F	Updated heading to 381-Ball caBGA Package Option 1: All Except LAE5UM-45F.
381-Ball caBGA Package Option 2: LAE5UM-45F	Added 381-Ball caBGA Package Option 2: LAE5UM-45F.

Revision 6.6, September 2021

Section	Change Summary
69-Ball WLCSP Package	Added 69-Ball WLCSP Package to support MachXO3D.
256-Ball CBG256/csfBGA Package	Added 256-Ball CBG256/csfBGA Package to support CertusPro™-NX
400-Ball caBGA Package Option 1: MachXO3	Updated heading to 400-Ball caBGA Package Option 1: MachXO3.
400-Ball caBGA Package	Added 400-Ball caBGA Package Option 2: CrossLink-NX.
484-Ball BFG484/PBGA Package	Added 484-Ball BFG484/PBGA Package to support CertusPro-NX.

Revision 6.5, July 2021

Section	Change Summary
256-Ball ASG256/FOWLP Package	Added 256-Ball ASG256/FOWLP Package.

Revision 6.4, June 2021

Section	Change Summary
484-Ball BBG484/caBGA Package	Updated 484-Ball BBG484/caBGA Package to support CertusPro-NX.
672-Ball LFG672/fcBGA Package	Added 672-Ball LFG672/fcBGA Package.

Revision 6.3, April 2021

Section	Change Summary
44-Pin TQFP Package	Removed (<i>1.0 mm thick</i>)
44-Pin LQFP Package	Changed TQFP to LQFP. Removed (<i>1.4 mm thick</i>)
48-Pin TQFP Package	Removed (<i>1.0 mm thick</i>)
48-Pin LQFP Package	Removed (<i>1.4 mm thick</i>)
64-Pin LQFP Package	Changed TQFP to LQFP.
100-Pin LQFP/TQFP Package Option 1: MachXO2, MachXO™, ispMACH® 4000	Changed TQFP to LQFP.
144-Pin LQFP/TQFP Package	Changed TQFP to LQFP.
128-Pin LQFP Package	Changed TQFP to LQFP.
176-Pin LQFP/TQFP Package	Changed TQFP to LQFP.

Revision 6.2, March 2021

Section	Change Summary
—	Removed 48-Pin QFN Package Option 1.
48-Pin QFN Package: L-ASC10, iCE40 Ultra, iCE40 UltraPlus™, MachXO2	Removed <i>Option 2</i> from heading.

Revision 6.1, January 2021

Section	Change Summary
36-Ball WLCSP Package Option 2: MachXO2, MachXO3™	Added MachXO2.
36-Ball WLCSP Package Option 3: CrossLink™	Added ball labels and changed LIFMD to CrossLink.
72-Pin QFN Package Option 1: CrossLink™-NX	Indicated Pin 1.

Section	Change Summary
72-Pin QFN Package Option 2: CrossLink™-NX	Indicated Pin 1.
Multiple	Restored labels that indicate top, bottom, and side views in the following packages: <ul style="list-style-type: none"> 36-Ball ucBGA Package 81-Ball csfBGA Package 237-Ball ftBGA Package 256-Ball ftBGA Package Option 1: ispMACH 4000, MachXO, LatticeXP2 285-Ball csfBGA Package 484-Ball caBGA Package (19 mm x 19 mm Body)
Multiple	Corrected alignment of pin order labeling.

Revision 6.0, December 2020

Section	Change Summary
All	Updated document template.
196-Ball caBGA Package	Added 196-Ball caBGA Package.
484-Ball fcBGA Package for Mach-NX	Added 484-Ball fcBGA Package: Mach-NX.

Revision 5.9, August 2020

Section	Change Summary
All	<ul style="list-style-type: none"> Added table of contents Changed WLCSP Package to WLCSP Package in all heading. Moved Disclaimers to second page.
30-Ball WLCSP Package	Corrected the 30-Ball WLCSP Package sD and sE values. Fixed heading typo.
72-Pin WLCSP Package: CrossLink-NX	Added 72-Pin WLCSP Package: CrossLink-NX.
121-Ball csBGA Package	Updated D and E dimension lines in 121-Ball csBGA Package.

Revision 5.8, August 2020

Section	Change Summary
36-Ball ucBGA Package	Removed Option 1 from 36-Ball ucBGA Package heading.
48-Pin LQFP Package (1.4 mm thick)	Changed 48-Pin TQFP Package (1.4 mm thick) heading to 48-Pin LQFP Package (1.4 mm thick).
Multiple	Specified device(s) in the following packages: <ul style="list-style-type: none"> 48-Pin QFN Package Option 1: L-ASC10, iCE40 LP, iCE40 UltraPlus, MachXO2 72-Pin QFN Package Option 1: CrossLink™-NX 72-Pin QFN Package Option 2: MachXO3D
289-Ball csBGA Package (9.5 mm x 9.5 mm Body).	Added 289-Ball csBGA Package (9.5 mm x 9.5 mm Body).

Revision 5.7, November 2019

Section	Change Summary
48-Pin QFN Package Option 2: L-ASC10, iCE40 Ultra, iCE40 UltraPlus, MachXO2	Updated 48-Pin QFN Package Option 2: L-ASC10, iCE40 Ultra, iCE40 UltraPlus, MachXO2. Revised values for Lead Width (b) and Bottom Pad (E2, D2).
72-Pin QFN Package Option 2: MachXO3D	Added 72-Pin QFN Package Option 2: MachXO3D.
Disclaimers	Added this section.

Revision 5.6, April 2019

Section	Change Summary
All	Changed document ID from pkg to FPGA-DS-02053. When downloaded from the Lattice website, the PDF file name is now FPGA-DS-02053-<X-X>-Package-Diagrams.pdf (previously PackageDiagrams.pdf).
72-Pin QFN Package	Added 72-Pin QFN Package.

Revision 5.5, November 2017

Section	Change Summary
80-Ball ckgBGA Package	Added 80-Ball ckgBGA Package.

Revision 5.4, March 2017

Section	Change Summary
100-Pin TQFP Package Option 1: MachXO2, MachXO™, ispMACH® 4000	Added ispMACH 4000 to 100-Pin TQFP Package Option 1: MachXO2, MachXO™, ispMACH® 4000.
121-Ball caBGA Package (9 mm x 9 mm Body)	Added 121-Ball caBGA Package (9 mm x 9 mm Body).

Revision 5.3, December 2016

Section	Change Summary
32-Pin QFN Package	Updated “32-Pin QFNS Package” headings to “32-Pin QFN Package”.
32-Pin QFN Package Option 3: MachXO2 SG32C	Added 32-Pin QFN Package Option 3: MachXO2 SG32C.
30-Ball WLCSP Package	Added 30-Ball WLCSP Package.
48-Pin QFN Package Option 2: L-ASC10, iCE40 Ultra, iCE40 UltraPlus, MachXO2	Added iCE40 UltraPlus and MachXO2 to 48-Pin QFN Package Option 2: L-ASC10, iCE40 Ultra, iCE40 UltraPlus, MachXO2.
484-Ball caBGA Package	Added 484-Ball caBGA Package.

Revision 5.2, June 2016

Section	Change Summary
285-ball csfBGA Package	Updated 285-ball csfBGA package outline drawing.
36-Ball WLCSP Package Option 3: LIFMD	Added 36-Ball WLCSP Package Option 3: LIFMD.
48-Pin QFN Package Option 2: L-ASC10, iCE40 Ultra, iCE40 UltraPlus, MachXO2	Fixed typo in 48-Pin QFN Package Option 2: L-ASC10, iCE40 Ultra, iCE40 UltraPlus, MachXO2.
64-Ball ucfBGA Package	Added 64-Ball ucfBGA Package.
72-Pin QFN Package Option 2: MachXO3D	Added 72-Pin QFN Package Option 2: MachXO3D.
81-Ball csfBGA Package	Added 81-Ball csfBGA Package.

Revision 5.1, February 2015

Section	Change Summary
36-Ball ucfBGA Package: iCE40 Ultra	Added 36-Ball ucfBGA Package: iCE40 Ultra.
36-Ball ucBGA Package Option 1	Updated 36-Ball ucBGA Package heading to 36-Ball ucBGA Package Option 1.

Section	Change Summary
48-Pin QFN Package Option 2: L-ASC10, iCE40 Ultra	Updated 48-Pin QFN Package Option 2: L-ASC10 heading to 48-Pin QFN Package Option 2: L-ASC10, iCE40 Ultra.

Revision 5.0, January 2015

Section	Change Summary
16-Ball WLCSP Package Option 2: iCE40 UltraLite	Added 16-Ball WLCSP Package Option 2: iCE40 UltraLite.
16-Ball WLCSP Package Option 1: iCE40 LP	Updated 16-Ball WLCSP Package heading to 16-Ball WLCSP Package Option 1: iCE40 LP.

Revision 4.9, October 2014

Section	Change Summary
48-Pin QFN Package	Updated 48-Pin QFN Package heading and moved the section after 48-Pin QFN Package Option 1 (previously Option 2).

Revision 4.8, October 2014

Section	Change Summary
—	Removed 20-Ball WLCSP Package.

Revision 4.7, October 2014

Section	Change Summary
121-Ball csfBGA Package	Updated 121-Ball csfBGA Package. Revised M/N dimension.

Revision 4.6, September 2014

Section	Change Summary
84-Pin QFN Package	Updated 84-Pin QFN Package. Revised pin numbers from A36 and B27 to A37 and B28.

Revision 4.5, August 2014

Section	Change Summary
16-Ball WLCSP Package	Updated 16-Ball WLCSP Package. Changed second E to e in REF. column.
36-Ball WLCSP Package Option 1: iCE40 Ultra	Updated 36-Ball WLCSP Package Option 1: iCE40 Ultra heading.
36-Ball WLCSP Package Option 2: MachXO3	Added 36-Ball WLCSP Package Option 2: MachXO3.
81-Ball WLCSP Package	Added 81-Ball WLCSP Package.
121-Ball csfBGA Package	Added 121-Ball csfBGA Package.
256-Ball csfBGA Package	Added 256-Ball csfBGA Package.
324-Ball caBGA Package	Added 324-Ball caBGA Package.
324-Ball csfBGA Package	Added 324-Ball csfBGA Package.
400-Ball caBGA Package	Added 400-Ball caBGA Package.
84-Pin QFN Package	Updated 84-Pin QFN Package. Revised dimension “b” maximum value.
256-Ball ftBGA Package Option 1: ispMACH 4000, MachXO, LatticeXP2	Updated 256-Ball ftBGA Package Option 1: ispMACH 4000, MachXO, LatticeXP2. Revised dimension “A” values.

Revision 4.4, June 2014

Section	Change Summary
48-Pin QFN Package	Updated 48-Pin QFN Package to 48-Pin QFN Package.
48-Pin QFN Package Option 2	Added 48-Pin QFN Package Option 2.
49-Ball WLCSP Package	Added 49-Ball WLCSP Package.
237-Ball ftBGA Package	Added 237-Ball ftBGA Package.
285-Ball csfBGA Package	Added 285-Ball csfBGA Package.
20-Ball WLCSP Package	Added 20-Ball WLCSP Package.
36-Ball WLCSP Package	Added 36-Ball WLCSP Package.

Revision 4.3, March 2014

Section	Change Summary
All	Restored references to indicate top, bottom, and side views.
381-Ball caBGA Package	Added 381-Ball caBGA Package.
554-Ball caBGA Package	Added 554-Ball caBGA Package.
756-Ball caBGA Package	Added 756-Ball caBGA Package.

Revision 4.2, December 2013

Section	Change Summary
100-Pin TQFP Package Option 1: MachXO2, MachXO	Added "1" and "N" characters to 100-Pin TQFP Package Option 1: MachXO2, MachXO diagram (Top View).

Revision 4.1, September 2013

Section	Change Summary
16-ball WLCSP Package	Added 16-ball WLCSP package.
25-Ball WLCSP Package (0.40 mm Pitch)	Revised 25-Ball WLCSP Package title to 25-Ball WLCSP Package (0.40mm Pitch).
25-Ball WLCSP Package (0.35 mm Pitch)	Added 25-Ball WLCSP Package (0.35mm Pitch).
All	Added references to indicate top, bottom, and side views.

Revision 4.0, August 2013

Section	Change Summary
144-pin TQFP Package	Revised 144-pin TQFP package diagram.

Revision 3.9, February 2013

Section	Change Summary
184-ball csBGA Package.	Added 184-ball csBGA package.

Revision 3.8, November 2012

Section	Change Summary
32-pin QFN Option 1	Added iCE40 to the list of applicable products for the 32-pin QFN Option 1 package.

Revision 3.7, October 2012

Section	Change Summary
324-ball ftBGA Package	Revised 324-ball ftBGA package drawing.

Revision 3.6, September 2012

Section	Change Summary
iCE40 100-Pin VQFP Package Option 2	Nomenclature change – “iCE40 100-Pin TQFP Package Option 2” changed to “iCE40 100-Pin VQFP Package Option 2”.

Revision 3.5, August 2012

Section	Change Summary
Multiple	Added 36-ball ucBGA, 49-ball ucBGA, 81-ball ucBGA, 81-ball csBGA, 84-pin QFN, 100-pin TQFP Option 2, 121-ball csBGA, 121-ball ucBGA, 132-ball csBGA Option 2, 196-ball csBGA, 225-ball ucBGA, 284-ball csBGA packages.

Revision 3.4, July 2012

Section	Change Summary
676-ball fcBGA Package	Added 676-ball fcBGA package.

Revision 3.3, March 2012

Section	Change Summary
Appendix A	Added new 32-Pin QFNS Package Option 2 for MachXO2. Moved 32-pin QFN (punch singulated) package drawing to new Package Archive Appendix.

Revision 3.2, February 2012

Section	Change Summary
All	Updated document with new corporate logo.

Revision 3.1, December 2011

Section	Change Summary
Multiple	Updated WLCSP package offering.

Revision 3.0, October 2011

Section	Change Summary
Multiple	Added 49-ball WLCSP package and updated 25-ball WLCSP package.

Revision 2.9, October 2011

Section	Change Summary
328-ball csBGA Package	Added 328-ball csBGA package.

Revision 2.8, July 2011

Section	Change Summary
Multiple	Included revised diagrams for the following packages: 56-ball csBGA, 100-ball csBGA and 132-ball csBGA. Added new 256-ball ftBGA Option 3 package.

Revision 2.7, May 2011

Section	Change Summary
256 ftBGA Option 1 Package	Added MachXO2 to the list of applicable products for the 256 ftBGA Option 1 package outline.

Revision 2.6, November 2010

Section	Change Summary
Multiple	Added 25-ball WLCSP and 332-ball caBGA package drawings. Revised 100-pin PQFP, 120-pin PQFP, 128-pin PQFP, 160-pin PQFP and 208-pin PQFP package drawings. Removed obsolete packages including 144-, 240- and 304-pin PQFP packages.

Revision 2.5, October 2010

Section	Change Summary
208-ball ftBGA Package	Added 208-ball ftBGA package.

Revision 2.4, September 2010

Section	Change Summary
Multiple	Revised maximum coplanarity values on Organic 1152 Flip Chip BGA – Option 2 and on Organic 1704 Flip Chip BGA from 0.20 mm to 0.23 mm.

Revision 2.3, March 2010

Section	Change Summary
Multiple	Added new 1020-ball Organic fcBGA rev.2, 1152-ball Organic fcBGA, and 1704-ball Organic fcBGA package drawings. Removed obsolete 492-Ball BGA package.

Revision 2.2, February 2010

Section	Change Summary
256-Ball caBGA Package	Revised 256-ball caBGA nominal solder ball diameter from 0.5 mm to 0.45 mm to better match actual dimension.

Revision 2.1, December 2009

Section	Change Summary
256-ball caBGA Package	Revised 256-ball caBGA package to specify correct JEDEC reference number.

Revision 2.0, May 2009

Section	Change Summary
Multiple	Added new 256-ball caBGA and 256-ball ftBGA (Option A) packages.

Revision 1.9, April 2009

Section	Change Summary
Multiple	Added 24-pin QFNS package diagram. Removed discontinued and obsolete packages (16 SOIC, 20 SOIC, 24 SOIC, 28 SOIC, 16 PDIP, 240 MQFP, 269 fcBGA, 304 MQFP, 600 SBGA).

Revision 1.8, December 2008

Section	Change Summary
Multiple	Added 32-pin QFNS, 48-pin QFNS and 64-pin QFNS package diagrams.

Revision 1.7, November 2008

Section	Change Summary
Multiple	Added 64-ball ucBGA and 132-ball ucBGA package diagrams.

Revision 1.6, April 2008

Section	Change Summary
Multiple	Added 64-ball csBGA and 144-ball csBGA package diagrams.

Revision 1.5, November 2007

Section	Change Summary
1152-ball fpBGA Package	Added 1152-ball fpBGA package diagram.

Revision 1.4, October 2007

Section	Change Summary
1036 ftSBGA Package	Revised 1036 ftSBGA package diagram. Removed 1036 fpSBGA.

Revision 1.3, June 2007

Section	Change Summary
1036 ftSBGA Package	Added 1036 ftSBGA package diagram.

Revision 1.2, February 2007

Section	Change Summary
1704 fcBGA Package	Revised 1704 fcBGA package drawing: removed lid dimension, clarified package body dimension as the combination of substrate and lid.

Revision 1.1, January 2007

Section	Change Summary
Multiple	Added Marking Orientation text for all TQFP packages (1.0 mm and 1.4 mm thick).

Revision 1.0, January 2007

Section	Change Summary
Multiple	Added 64-pin TQFP and 1704-ball fcBGA package diagrams.



www.latticesemi.com